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# H8/3006, H8/3007

## Hardware Manual

Renesas 16-Bit Single-Chip **Microcomputer** H8 Family/H8/300H Series

H8/3006 HD6413006 H8/3007 HD6413007

**Renesas Electronics** www renesas com

Rev.5.00 2007.09

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1. Handling of Unused Pins

Handle unused pins in accord with the directions given under Handling of Unused Pins in the manual.

- ⎯ The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of LSI, an associated shoot-through current flows internally, and malfunctions may occur due to the false recognition of the pin state as an input signal. Unused pins should be handled as described under Handling of Unused Pins in the manual.
- 2. Processing at Power-on

The state of the product is undefined at the moment when power is supplied.

⎯ The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the moment when power is supplied.

In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the moment when power is supplied until the reset process is completed.

In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the moment when power is supplied until the power reaches the level at which resetting has been specified.

3. Prohibition of Access to Reserved Addresses

Access to reserved addresses is prohibited.

- ⎯ The reserved addresses are provided for the possible future expansion of functions. Do not access these addresses; the correct operation of LSI is not guaranteed if they are accessed.
- 4. Clock Signals

After applying a reset, only release the reset line after the operating clock signal has become stable. When switching the clock signal during program execution, wait until the target clock signal has stabilized.

- ⎯ When the clock signal is generated with an external resonator (or from an external oscillator) during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Moreover, when switching to a clock signal produced with an external resonator (or by an external oscillator) while program execution is in progress, wait until the target clock signal is stable.
- 5. Differences between Products

Before changing from one product to another, i.e. to one with a different type number, confirm that the change will not lead to problems.

⎯ The characteristics of MPU/MCU in the same group but having different type numbers may differ because of the differences in internal memory capacity and layout pattern. When changing to products of different type numbers, implement a system-evaluation test for each of the products.





## Preface

The H8/3006 and H8/3007 are a series of high-performance microcontrollers that integrate system supporting functions together with an H8/300H CPU core.

The H8/300H CPU has a 32-bit internal architecture with sixteen 16-bit general registers, and a concise, optimized instruction set designed for speed. It can address a 16-Mbyte linear address space.

The on-chip supporting functions include RAM, 16-bit timers, 8-bit timers, a programmable timing pattern controller (TPC), a watchdog timer (WDT), a serial communication interface (SCI), an A/D converter, a D/A converter, I/O ports, and a DMA controller (DMAC).

The address space is divided into eight areas. The data bus width and access cycle length can be selected independently in each area, simplifying the connection of different types of memory. Four MCU operating modes (modes 1 to 4) are provided, offering a choice of data bus width initial value and address space.

With these features, the H8/3006 and H8/3007 offer easy implementation of compact, highperformance systems.

This manual describes the H8/3006 and H8/3007 Group hardware. For details of the instruction set, refer to the H8/300H Series Software Manual.





## Main Revisions for This Edition







#### $\mathsf{PA}_\mathsf{o}/\mathsf{TP}_\mathsf{o}/\mathsf{TCLKA}/\mathsf{\overline{TEND}}_\mathsf{o}$

#### Table amended

#### **Pin Pin Functions and Selection Method**

PA /TP / TCLKA/<br>TEND<sub>0</sub> Bit MDF in TMDR, bits TPSC2 to TPSC0 in 16TCR2 to 16TCR0 of the 16-bit timer, bits CKS2 to CKS0 in 8TCR1 of the 8-bit timer, bit NDER0 in NDERA, and bit PA<sub>0</sub>DDR select the pin function as follows.



Notes: 1. TCLKA input when  $MDF = 1$  in TMDR, or  $TPSC2 = 1$ ,  $TPSC1 = 0$  and TPSC0 = 0 in any of 16TCR2 to 16TCR0, or bits CKS2 to CKS0 in 8TCR0 are as shown in (1) in the table below.

> 2. When an external request is specified as a DMAC activation source,  $\overline{\text{TEND}}_{\text{o}}$  output regardless of bits PA $_{\text{o}}$ DDR and NDER0.















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## Contents

































## Section 1 Overview

#### **1.1 Overview**

The H8/3006 and H8/3007 are a series of microcontrollers (MCUs) that integrate system supporting functions together with an H8/300H CPU core having an original Renesas architecture.

The H8/300H CPU has a 32-bit internal architecture with sixteen 16-bit general registers, and a concise, optimized instruction set designed for speed. It can address a 16-Mbyte linear address space. Its instruction set is upward-compatible at the object-code level with the H8/300 CPU, enabling easy porting of software from the H8/300 Series.

The on-chip system supporting functions include RAM, a 16-bit timer, an 8-bit timer, a programmable timing pattern controller (TPC), a watchdog timer (WDT), a serial communication interface (SCI), an A/D converter, a D/A converter, I/O ports, a direct memory access controller (DMAC), and other facilities.

Four MCU operating modes offer a choice of bus width and address space size.

Table 1.1 summarizes the features of the H8/3006 and H8/3007.





#### 1. Overview





#### **1.2 Internal Block Diagram**

Figure 1.1 shows an internal block diagram.



**Figure 1.1 Block Diagram** 

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## **1.3 Pin Description**

#### **1.3.1 Pin Arrangement**

The pin arrangement of the H8/3006, H8/3007 FP-100B and TFP-100B packages is shown in figure 1.2, and that of the FP-100A package in figure 1.3.



**Figure 1.2 Pin Arrangement (FP-100B or TFP-100B, Top View)** 



**Figure 1.3 Pin Arrangement (FP-100A, Top View)** 

#### **1.3.2 Pin Functions**

Table 1.2 summarizes the pin functions.

#### **Table 1.2 Pin Functions**









#### 1. Overview





#### **1.3.3 Pin Assignments in Each Mode**

Table 1.3 lists the pin assignments in each mode.





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reset, but they can be changed by software.

2. In modes 2 and 4, the D<sub>0</sub> to D<sub>7</sub> functions of pins P4<sub>0</sub> $/D$ <sub>0</sub> to P4<sub>1</sub> $/D$ <sub>2</sub> are selected after a reset, but they can be changed by software.

1. Overview



# Section 2 CPU

### **2.1 Overview**

The H8/300H CPU is a high-speed central processing unit with an internal 32-bit architecture that is upward-compatible with the H8/300 CPU. The H8/300H CPU has sixteen 16-bit general registers, can address a 16-Mbyte linear address space, and is ideal for realtime control.

#### **2.1.1 Features**

The H8/300H CPU has the following features.

- Upward compatibility with H8/300 CPU Can execute H8/300 Series object programs
- General-register architecture Sixteen 16-bit general registers (also usable as sixteen 8-bit registers or eight 32-bit registers)
- Sixty-two basic instructions
	- 8/16/32-bit data transfer, arithmetic and logic instructions
	- Multiply and divide instructions
	- ⎯ Powerful bit-manipulation instructions
- Eight addressing modes
	- Register direct [Rn]
	- Register indirect [@ERn]
	- Register indirect with displacement  $[@(d:16, ERn)$  or  $@(d:24, ERn)]$
	- Register indirect with post-increment or pre-decrement  $[@ERn+ or @-ERn]$
	- Absolute address  $[@aa:8, @aa:16, or @aa:24]$
	- Immediate  $[#xx:8, #xx:16, or #xx:32]$
	- Program-counter relative  $[@(d:8, PC)$  or  $@(d:16, PC)]$
	- Memory indirect  $[@@aa:8]$
- 16-Mbyte linear address space

- High-speed operation
	- ⎯ All frequently-used instructions execute in two to four states
	- $-$  Maximum clock frequency: 20 MHz
	- 8/16/32-bit register-register add/subtract: 100 ns
	- $8 \times 8$ -bit register-register multiply: 700 ns
	- $16 \div 8$ -bit register-register divide: 700 ns
	- $16 \times 16$ -bit register-register multiply: 1.1 µs
	- $\frac{32 \div 16}{5}$ -bit register-register divide: 1.1 µs
- Two CPU operating modes
	- ⎯ Normal mode (not available in the H8/3006 and H8/3007)
	- $-$  Advanced mode
- Low-power mode

Transition to power-down state by SLEEP instruction

#### **2.1.2 Differences from H8/300 CPU**

In comparison to the H8/300 CPU, the H8/300H has the following enhancements.

• More general registers

Eight 16-bit registers have been added.

- Expanded address space
	- Advanced mode supports a maximum 16-Mbyte address space.
	- ⎯ Normal mode supports the same 64-kbyte address space as the H8/300 CPU.
- Enhanced addressing

The addressing modes have been enhanced to make effective use of the 16-Mbyte address space.

- Enhanced instructions
	- Data transfer, arithmetic, and logic instructions can operate on 32-bit data.
	- $\overline{\phantom{a}}$  Signed multiply/divide instructions and other instructions have been added.



## **2.2 CPU Operating Modes**

The H8/300H CPU has two operating modes: normal and advanced. Normal mode supports a maximum 64-kbyte address space. Advanced mode supports up to 16 Mbytes.



**Figure 2.1 CPU Operating Modes** 

## **2.3 Address Space**

Figure 2.2 shows a simple memory map for the H8/3006 and H8/3007. The H8/300H CPU can address a linear address space with a maximum size of 64 kbytes in normal mode, and 16 Mbytes in advanced mode. For further details see section 3.6, Memory Map in Each Operating Mode.

The 1-Mbyte operating modes use 20-bit addressing. The upper 4 bits of effective addresses are ignored.



**Figure 2.2 Memory Map** 

### **2.4 Register Configuration**

#### **2.4.1 Overview**

The H8/300H CPU has the internal registers shown in figure 2.3. There are two types of registers: general registers and control registers.





#### **2.4.2 General Registers**

The H8/300H CPU has eight 32-bit general registers. These general registers are all functionally alike and can be used without distinction between data registers and address registers. When a general register is used as a data register, it can be accessed as a 32-bit, 16-bit, or 8-bit register. When the general registers are used as 32-bit registers or as address registers, they are designated by the letters ER (ER0 to ER7).

The ER registers divide into 16-bit general registers designated by the letters E (E0 to E7) and R (R0 to R7). These registers are functionally equivalent, providing a maximum sixteen 16-bit registers. The E registers (E0 to E7) are also referred to as extended registers.

The R registers divide into 8-bit general registers designated by the letters RH (R0H to R7H) and RL (R0L to R7L). These registers are functionally equivalent, providing a maximum sixteen 8-bit registers.

Figure 2.4 illustrates the usage of the general registers. The usage of each register can be selected independently.



**Figure 2.4 Usage of General Registers** 

General register ER7 has the function of stack pointer (SP) in addition to its general-register function, and is used implicitly in exception handling and subroutine calls. Figure 2.5 shows the stack.



**Figure 2.5 Stack** 

#### **2.4.3 Control Registers**

The control registers are the 24-bit program counter (PC) and the 8-bit condition code register (CCR).

**Program Counter (PC):** This 24-bit counter indicates the address of the next instruction the CPU will execute. The length of all CPU instructions is 2 bytes (one word) or a multiple of 2 bytes, so the least significant PC bit is ignored. When an instruction is fetched, the least significant PC bit is regarded as 0.

**Condition Code Register (CCR):** This 8-bit register contains internal CPU status information, including the interrupt mask bit  $(I)$  and half-carry  $(H)$ , negative  $(N)$ , zero  $(Z)$ , overflow  $(V)$ , and carry (C) flags.

**Bit 7—Interrupt Mask Bit (I):** Masks interrupts other than NMI when set to 1. NMI is accepted regardless of the I bit setting. The I bit is set to 1 at the start of an exception-handling sequence.

**Bit 6—User Bit or Interrupt Mask Bit (UI):** Can be written and read by software using the LDC, STC, ANDC, ORC, and XORC instructions. This bit can also be used as an interrupt mask bit. For details see section 5, Interrupt Controller.

**Bit 5—Half-Carry Flag (H):** When the ADD.B, ADDX.B, SUB.B, SUBX.B, CMP.B, or NEG.B instruction is executed, this flag is set to 1 if there is a carry or borrow at bit 3, and cleared to 0 otherwise. When the ADD.W, SUB.W, CMP.W, or NEG.W instruction is executed, the H flag is set to 1 if there is a carry or borrow at bit 11, and cleared to 0 otherwise. When the ADD.L, SUB.L, CMP.L, or NEG.L instruction is executed, the H flag is set to 1 if there is a carry or borrow at bit 27, and cleared to 0 otherwise.

**Bit 4—User Bit (U):** Can be written and read by software using the LDC, STC, ANDC, ORC, and XORC instructions.

**Bit 3—Negative Flag (N):** Stores the value of the most significant bit of data, regarded as the sign bit.

**Bit 2—Zero Flag (Z):** Set to 1 to indicate zero data, and cleared to 0 to indicate non-zero data.

**Bit 1—Overflow Flag (V):** Set to 1 when an arithmetic overflow occurs, and cleared to 0 at other times.

**Bit 0—Carry Flag (C):** Set to 1 when a carry is generated by execution of an operation, and cleared to 0 otherwise. Used by:

- Add instructions, to indicate a carry
- Subtract instructions, to indicate a borrow
- Shift and rotate instructions

The carry flag is also used as a bit accumulator by bit manipulation instructions.

Some instructions leave flag bits unchanged. Operations can be performed on CCR by the LDC, STC, ANDC, ORC, and XORC instructions. The N, Z, V, and C flags are used by conditional branch (Bcc) instructions.

For the action of each instruction on the flag bits, see appendix A.1, Instruction List. For the I and UI bits, see section 5, Interrupt Controller.

#### **2.4.4 Initial CPU Register Values**

In reset exception handling, PC is initialized to a value loaded from the vector table, and the I bit in CCR is set to 1. The other CCR bits and the general registers are not initialized. In particular, the initial value of the stack pointer (ER7) is also undefined. The stack pointer (ER7) must therefore be initialized by an MOV.L instruction executed immediately after a reset.



### **2.5 Data Formats**

The H8/300H CPU can process 1-bit, 4-bit (BCD), 8-bit (byte), 16-bit (word), and 32-bit (longword) data. Bit-manipulation instructions operate on 1-bit data by accessing bit n  $(n = 0, 1, 1)$ 2, …, 7) of byte operand data. The DAA and DAS decimal-adjust instructions treat byte data as two digits of 4-bit BCD data.

#### **2.5.1 General Register Data Formats**

Figures 2.6 and 2.7 show the data formats in general registers.

Data Type	General Register	<b>Data Format</b>
1-bit data	RnH	$\overline{7}$ $\mathbf 0$ Don't care 7 6   5 4 3 2 $\mathbf{1}$ 0
1-bit data	RnL	7 0 7 6 5 4 3 2 1 Don't care 10
4-bit BCD data	RnH	4 3 $\overline{7}$ $\mathbf 0$ Don't care Upper digit Lower digit
4-bit BCD data	RnL	43 7 $\mathbf 0$ Don't care Upper digit Lower digit
Byte data	RnH	0 7 Don't care <b>LSB</b> <b>MSB</b>
Byte data	RnL	7 0 Don't care <b>MSB</b> <b>LSB</b>
Legend: General register RH RnH: General register RL RnL:		

**Figure 2.6 General Register Data Formats (1)** 



**Figure 2.7 General Register Data Formats (2)** 

#### **2.5.2 Memory Data Formats**

Figure 2.8 shows the data formats on memory. The H8/300H CPU can access word data and longword data on memory, but word or longword data must begin at an even address. If an attempt is made to access word or longword data at an odd address, no address error occurs but the least significant bit of the address is regarded as 0, so the access starts at the preceding address. This also applies to instruction fetches.





**Figure 2.8 Memory Data Formats** 

When ER7 (SP) is used as an address register to access the stack, the operand size should be word size or longword size.

## **2.6 Instruction Set**

#### **2.6.1 Instruction Set Overview**

The H8/300H CPU has 64 types of instructions, which are classified in table 2.1.





Total 64 types

- Notes: 1. POP.W Rn is identical to MOV.W @SP+, Rn. PUSH.W Rn is identical to MOV.W Rn, @–SP. POP.L ERn is identical to MOV.L @SP+, Rn. PUSH.L ERn is identical to MOV.L Rn, @–SP.
	- 2. Not available in the H8/3006 and H8/3007.
	- 3. Bcc is a generic branching instruction.



#### **2.6.2 Instructions and Addressing Modes**

Table 2.2 indicates the instructions available in the H8/300H CPU.

#### **Table 2.2 Instructions and Addressing Modes**



#### **2.6.3 Tables of Instructions Classified by Function**

Tables 2.3 to 2.10 summarize the instructions in each functional category. The operation notation used in these tables is defined next.

#### **Operation Notation**



to R7, E0 to E7), and 32-bit data or address registers (ER0 to ER7).





#### **Table 2.4 Arithmetic Operation Instructions**





#### **Table 2.5 Logic Operation Instructions**



L: Longword

#### **Table 2.6 Shift Instructions**



W: Word

L: Longword





#### 2. CPU



B: Byte

#### **Table 2.8 Branching Instructions**

#### **Instruction Size Function**

Bcc **Example 3** Branches to a specified address if address specified condition is met. The branching conditions are listed below.





**Table 2.9 System Control Instructions** 

B: Byte

W: Word





#### **Table 2.10 Block Transfer Instruction**

#### **2.6.4 Basic Instruction Formats**

The H8/300H instructions consist of 2-byte (1-word) units. An instruction consists of an operation field (OP field), a register field (r field), an effective address extension (EA field), and a condition field (cc).

**Operation Field:** Indicates the function of the instruction, the addressing mode, and the operation to be carried out on the operand. The operation field always includes the first 4 bits of the instruction. Some instructions have two operation fields.

**Register Field:** Specifies a general register. Address registers are specified by 3 bits, data registers by 3 bits or 4 bits. Some instructions have two register fields. Some have no register field.

**Effective Address Extension:** Eight, 16, or 32 bits specifying immediate data, an absolute address, or a displacement. A 24-bit address or displacement is treated as 32-bit data in which the first 8 bits are 0 (H'00).

**Condition Field:** Specifies the branching condition of Bcc instructions.

Figure 2.9 shows examples of instruction formats.

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#### **Figure 2.9 Instruction Formats**

#### **2.6.5 Notes on Use of Bit Manipulation Instructions**

The BSET, BCLR, BNOT, BST, and BIST instructions read a byte of data, modify a bit in the byte, then write the byte back. Care is required when these instructions are used to access registers with write-only bits, or to access ports.



**Example 1:** BCLR is executed to clear bit 0 in the port 4 data direction register (P4DDR) under the following conditions.

> P4<sub>7</sub>, P4<sub>6</sub> : Input pins  $P4_5 - P4_0$ : Output pins

The intended purpose of this BCLR instruction is to switch  $P4<sub>0</sub>$  from output to input.




#### **Execution of BCLR Instruction**

BCLR #0, @P4DDR ; Execute BCLR instruction on DDR

#### **After Execution of BCLR Instruction**



**Explanation:** To execute the BCLR instruction, the CPU begins by reading P4DDR. Since P4DDR is a write-only register, it is read as H'FF, even though its true value is H'3F.

Next the CPU clears bit 0 of the read data, changing the value to H'FE.

Finally, the CPU writes this value (H'FE) back to P4DDR to complete the BCLR instruction.

As a result, P4<sub>0</sub>DDR is cleared to 0, making P4<sub>0</sub> an input pin. In addition, P4<sub>7</sub>DDR and P4<sub>6</sub>DDR are set to 1, making  $P4<sub>7</sub>$  and  $P4<sub>6</sub>$  output pins.

The BCLR instruction can be used to clear flags in the on-chip registers to 0. In the case of the IRQ status register (ISR), for example, a flag must be read as a condition for clearing it, but when using the BCLR instruction, if it is known that a flag has been set to 1 in an interrupt-handling routine, for instance, it is not necessary to read the flag ahead of time.

# **2.7 Addressing Modes and Effective Address Calculation**

### **2.7.1 Addressing Modes**

The H8/300H CPU supports the eight addressing modes listed in table 2.11. Each instruction uses a subset of these addressing modes. Arithmetic and logic instructions can use the register direct and immediate modes. Data transfer instructions can use all addressing modes except programcounter relative and memory indirect. Bit manipulation instructions use register direct, register indirect, or absolute (@aa:8) addressing mode to specify an operand, and register direct (BSET, BCLR, BNOT, and BTST instructions) or immediate (3-bit) addressing mode to specify a bit number in the operand.



#### **Table 2.11 Addressing Modes**

**1 Register Direct—Rn:** The register field of the instruction code specifies an 8-, 16-, or 32-bit register containing the operand. R0H to R7H and R0L to R7L can be specified as 8-bit registers. R0 to R7 and E0 to E7 can be specified as 16-bit registers. ER0 to ER7 can be specified as 32-bit registers.

**2 Register Indirect—@ERn:** The register field of the instruction code specifies an address register (ERn), the lower 24 bits of which contain the address of the operand.

**3 Register Indirect with Displacement—@(d:16, ERn) or @(d:24, ERn):** A 16-bit or 24-bit displacement contained in the instruction code is added to the contents of an address register (ERn) specified by the register field of the instruction, and the lower 24 bits of the sum specify the address of a memory operand. A 16-bit displacement is sign-extended when added.

#### **4 Register Indirect with Post-Increment or Pre-Decrement—@ERn+ or @–ERn:**

Register indirect with post-increment—@ERn+

The register field of the instruction code specifies an address register (ERn) the lower 24 bits of which contain the address of a memory operand. After the operand is accessed, 1, 2, or 4 is added to the address register contents (32 bits) and the sum is stored in the address register. The value added is 1 for byte access, 2 for word access, or 4 for longword access. For word or longword access, the register value should be even.

• Register indirect with pre-decrement—@–ERn The value 1, 2, or 4 is subtracted from an address register (ERn) specified by the register field in the instruction code, and the lower 24 bits of the result become the address of a memory operand. The result is also stored in the address register. The value subtracted is 1 for byte access, 2 for word access, or 4 for longword access. For word or longword access, the resulting register value should be even.

**5 Absolute Address—@aa:8, @aa:16, or @aa:24:** The instruction code contains the absolute address of a memory operand. The absolute address may be 8 bits long (@aa:8), 16 bits long (@aa:16), or 24 bits long (@aa:24). For an 8-bit absolute address, the upper 16 bits are all assumed to be 1 (H'FFFF). For a 16-bit absolute address the upper 8 bits are a sign extension. A 24-bit absolute address can access the entire address space. Table 2.12 indicates the accessible address ranges.



#### **Table 2.12 Absolute Address Access Ranges**

**6 Immediate**⎯**#xx:8, #xx:16, or #xx:32:** The instruction code contains 8-bit (#xx:8), 16-bit (#xx:16), or 32-bit (#xx:32) immediate data as an operand.

The instruction codes of the ADDS, SUBS, INC, and DEC instructions contain immediate data implicitly. The instruction codes of some bit manipulation instructions contain 3-bit immediate data specifying a bit number. The TRAPA instruction code contains 2-bit immediate data specifying a vector address.

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**7 Program-Counter Relative—@(d:8, PC) or @(d:16, PC):** This mode is used in the Bcc and BSR instructions. An 8-bit or 16-bit displacement contained in the instruction code is signextended to 24 bits and added to the 24-bit PC contents to generate a 24-bit branch address. The PC value to which the displacement is added is the address of the first byte of the next instruction, so the possible branching range is  $-126$  to  $+128$  bytes (-63 to +64 words) or  $-32766$  to +32768 bytes (–16383 to +16384 words) from the branch instruction. The resulting value should be an even number.

**8 Memory Indirect—@@aa:8:** This mode can be used by the JMP and JSR instructions. The instruction code contains an 8-bit absolute address specifying a memory operand. This memory operand contains a branch address. The memory operand is accessed by longword access. The first byte of the memory operand is ignored, generating a 24-bit branch address. See figure 2.10. The upper bits of the 8-bit absolute address are assumed to be 0 (H'0000), so the address range is 0 to 255 (H'000000 to H'0000FF). Note that the first part of this range is also the exception vector area. For further details see section 5, Interrupt Controller.



**Figure 2.10 Memory-Indirect Branch Address Specification** 

When a word-size or longword-size memory operand is specified, or when a branch address is specified, if the specified memory address is odd, the least significant bit is regarded as 0. The accessed data or instruction code therefore begins at the preceding address. See section 2.5.2, Memory Data Formats.

### **2.7.2 Effective Address Calculation**

Table 2.13 explains how an effective address is calculated in each addressing mode. In the 1-Mbyte operating modes the upper 4 bits of the calculated address are ignored in order to generate a 20-bit effective address.



**Table 2.13 Effective Address Calculation** 

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# **2.8 Processing States**

### **2.8.1 Overview**

The H8/300H CPU has five processing states: the program execution state, exception-handling state, power-down state, reset state, and bus-released state. The power-down state includes sleep mode, software standby mode, and hardware standby mode. Figure 2.11 classifies the processing states. Figure 2.13 indicates the state transitions.



**Figure 2.11 Processing States** 

#### **2.8.2 Program Execution State**

In this state the CPU executes program instructions in normal sequence.

#### **2.8.3 Exception-Handling State**

The exception-handling state is a transient state that occurs when the CPU alters the normal program flow due to a reset, interrupt, or trap instruction. The CPU fetches a starting address from the exception vector table and branches to that address. In interrupt and trap exception handling the CPU references the stack pointer (ER7) and saves the program counter and condition code register.

**Types of Exception Handling and Their Priority:** Exception handling is performed for resets, interrupts, and trap instructions. Table 2.14 indicates the types of exception handling and their priority. Trap instruction exceptions are accepted at all times in the program execution state.





Note: \* Interrupts are not detected at the end of the ANDC, ORC, XORC, and LDC instructions, or immediately after reset exception handling.

Figure 2.12 classifies the exception sources. For further details about exception sources, vector numbers, and vector addresses, see section 4, Exception Handling, and section 5, Interrupt Controller.



**Figure 2.12 Classification of Exception Sources** 



**Figure 2.13 State Transitions** 

#### **2.8.4 Exception-Handling Sequences**

**Reset Exception Handling:** Reset exception handling has the highest priority. The reset state is entered when the RES signal goes low. Reset exception handling starts after that, when RES changes from low to high. When reset exception handling starts the CPU fetches a start address from the exception vector table and starts program execution from that address. All interrupts, including NMI, are disabled during the reset exception-handling sequence and immediately after it ends.

**Interrupt Exception Handling and Trap Instruction Exception Handling:** When these exception-handling sequences begin, the CPU references the stack pointer (ER7) and pushes the program counter and condition code register on the stack. Next, if the UE bit in the system control register (SYSCR) is set to 1, the CPU sets the I bit in the condition code register to 1. If the UE bit is cleared to 0, the CPU sets both the I bit and the UI bit in the condition code register to 1. Then the CPU fetches a start address from the exception vector table and execution branches to that address.



Figure 2.14 shows the stack after the exception-handling sequence.

#### **Figure 2.14 Stack Structure after Exception Handling**

### **2.8.5 Bus-Released State**

In this state the bus is released to a bus master other than the CPU, in response to a bus request. The bus masters other than the CPU are the DMA controller, the DRAM interface, and an external bus master. While the bus is released, the CPU halts except for internal operations. Interrupt requests are not accepted. For details see section 6.10, Bus Arbiter.

#### **2.8.6 Reset State**

When the RES input goes low all current processing stops and the CPU enters the reset state. The I bit in the condition code register is set to 1 by a reset. All interrupts are masked in the reset state. Reset exception handling starts when the RES signal changes from low to high.

The reset state can also be entered by a watchdog timer overflow. For details see section 12, Watchdog Timer.

### **2.8.7 Power-Down State**

In the power-down state the CPU stops operating to conserve power. There are three modes: sleep mode, software standby mode, and hardware standby mode.

**Sleep Mode:** A transition to sleep mode is made if the SLEEP instruction is executed while the SSBY bit is cleared to 0 in the system control register (SYSCR). CPU operations stop immediately after execution of the SLEEP instruction, but the contents of CPU registers are retained.

**Software Standby Mode:** A transition to software standby mode is made if the SLEEP instruction is executed while the SSBY bit is set to 1 in SYSCR. The CPU and clock halt and all on-chip supporting modules stop operating. The on-chip supporting modules are reset, but as long as a specified voltage is supplied the contents of CPU registers and on-chip RAM are retained. The I/O ports also remain in their existing states.

**Hardware Standby Mode:** A transition to hardware standby mode is made when the STBY input goes low. As in software standby mode, the CPU and all clocks halt and the on-chip supporting modules are reset, but as long as a specified voltage is supplied, on-chip RAM contents are retained.

For further information see section 19, Power-Down State.



### **2.9 Basic Operational Timing**

#### **2.9.1 Overview**

The H8/300H CPU operates according to the system clock (φ). The interval from one rise of the system clock to the next rise is referred to as a "state." A memory cycle or bus cycle consists of two or three states. The CPU uses different methods to access on-chip memory, the on-chip supporting modules, and the external address space. Access to the external address space can be controlled by the bus controller.

#### **2.9.2 On-Chip Memory Access Timing**

On-chip memory is accessed in two states. The data bus is 16 bits wide, permitting both byte and word access. Figure 2.15 shows the on-chip memory access cycle. Figure 2.16 indicates the pin states.



**Figure 2.15 On-Chip Memory Access Cycle** 



**Figure 2.16 Pin States during On-Chip Memory Access** 

### **2.9.3 On-Chip Supporting Module Access Timing**

The on-chip supporting modules are accessed in three states. The data bus is 8 or 16 bits wide, depending on the internal I/O register being accessed. Figure 2.17 shows the on-chip supporting module access timing. Figure 2.18 indicates the pin states.



**Figure 2.17 Access Cycle for On-Chip Supporting Modules** 





#### **2.9.4 Access to External Address Space**

The external address space is divided into eight areas (areas 0 to 7). Bus-controller settings determine whether each area is accessed via an 8-bit or 16-bit bus, and whether it is accessed in two or three states. For details see section 6, Bus Controller.

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# Section 3 MCU Operating Modes

### **3.1 Overview**

### **3.1.1 Operating Mode Selection**

The H8/3006 and H8/3007 have four operating modes (modes 1 to 4) that are selected by the mode pins  $(MD_2$  to  $MD_0$ ) as indicated in table 3.1. The input at these pins determines the size of the address space and the initial bus mode.



#### **Table 3.1 Operating Mode Selection**

Notes: 1. In modes 1 to 4, an 8-bit or 16-bit data bus can be selected on a per-area basis by settings made in the area bus width control register (ABWCR). For details see section 6, Bus Controller.

2. If the RAME bit in SYSCR is cleared to 0, these addresses become external addresses.

For the address space size there are two choices: 1 Mbyte, or 16 Mbyte. The external data bus is either 8 or 16 bits wide depending on ABWCR settings. If 8-bit access is selected for all areas, 8 bit bus mode is used. For details see section 6, Bus Controller.

Modes 1 and 2 support a maximum address space of 1 Mbyte. Modes 3 and 4 support a maximum address space of 16 Mbytes.

The H8/3006 and H8/3007 can be used only in modes 1 to 4. The inputs at the mode pins must select one of these four modes. The inputs at the mode pins must not be changed during operation.

#### 3. MCU Operating Modes

When changing the mode, the chip must be placed in the reset state before the mode pin inputs are changed.

#### **3.1.2 Register Configuration**

The H8/3006 and H8/3007 have a mode control register (MDCR) that indicates the inputs at the mode pins  $(MD_2$  to  $MD_0$ ), and a system control register (SYSCR). Table 3.2 summarizes these registers.

#### **Table 3.2 Registers**



Note: \* Lower 20 bits of the address in advanced mode.

### **3.2 Mode Control Register (MDCR)**

MDCR is an 8-bit read-only register that indicates the current operating mode of the H8/3006 and H8/3007.



Note:  $*$  Determined by pins MD<sub>2</sub> to MD<sub>0</sub>.

**Bits 7 and 6—Reserved:** These bits can not be modified and are always read as 1.

**Bits 5 to 3—Reserved:** These bits can not be modified and are always read as 0.

**Bits 2 to 0—Mode Select 2 to 0 (MDS2 to MDS0):** These bits indicate the logic levels at pins  $MD_2$  to  $MD_0$  (the current operating mode). MDS2 to MDS0 correspond to  $MD_2$  to  $MD_0$ . MDS2 to MDS0 are read-only bits. The mode pin  $(MD_2$  to  $MD_0)$  levels are latched into these bits when MDCR is read.

### **3.3 System Control Register (SYSCR)**

SYSCR is an 8-bit register that controls the operation of the H8/3006 and H8/3007.



**Bit 7—Software Standby (SSBY):** Enables transition to software standby mode. (For further information about software standby mode see section 19, Power-Down State.)

When software standby mode is exited by an external interrupt and a transition is made to normal operation, this bit remains set to 1. To clear this bit, write 0.



#### 3. MCU Operating Modes

**Bits 6 to 4—Standby Timer Select 2 to 0 (STS2 to STS0):** These bits select the length of time the CPU and on-chip supporting modules wait for the internal clock oscillator to settle when software standby mode is exited by an external interrupt.

When using a crystal oscillator, set these bits so that the waiting time will be at least 7 ms at the system clock rate.

For further information about waiting time selection, see section 19.4.3, Selection of Waiting Time for Exit from Software Standby Mode.



**Bit 3—User Bit Enable (UE):** Selects whether to use the UI bit in the condition code register as a user bit or an interrupt mask bit.



**Bit 2—NMI Edge Select (NMIEG):** Selects the valid edge of the NMI input.



**Bit 1—Software Standby Output Port Enable (SSOE):** Specifies whether the address bus and bus control signals ( $\overline{CS}_0$  to  $\overline{CS}_7$ ,  $\overline{AS}$ ,  $\overline{RD}$ ,  $\overline{HWR}$ ,  $\overline{LWR}$ ,  $\overline{UCAS}$ ,  $\overline{LCAS}$ , and  $\overline{RFSH}$ ) are kept as outputs or fixed high, or placed in the high-impedance state in software standby mode.



**Bit 0—RAM Enable (RAME):** Enables or disables the on-chip RAM. The RAME bit is initialized by the rising edge of the  $\overline{\text{RES}}$  signal. It is not initialized in software standby mode.



### **3.4 Operating Mode Descriptions**

#### **3.4.1 Mode 1**

A maximum 1-Mbyte address space can be accessed. The initial bus mode after a reset is 8 bits, with 8-bit access to all areas. If at least one area is designated for 16-bit access in ABWCR, the bus mode switches to 16 bits.

#### **3.4.2 Mode 2**

A maximum 1-Mbyte address space can be accessed. The initial bus mode after a reset is 16 bits, with 16-bit access to all areas. If all areas are designated for 8-bit access in ABWCR, the bus mode switches to 8 bits.

### **3.4.3 Mode 3**

Part of port A function as address pins  $A_{23}$  to  $A_{20}$ , permitting access to a maximum 16-Mbyte address space. The initial bus mode after a reset is 8 bits, with 8-bit access to all areas. If at least one area is designated for 16-bit access in ABWCR, the bus mode switches to 16 bits.  $A_{21}$  to  $A_{31}$ are valid when 0 is written in bits 7 to 5 of the bus release control register (BRCR). (In this mode  $A_{20}$  is always used for address output.)

#### **3.4.4 Mode 4**

Part of port A function as address pins  $A_{23}$  to  $A_{20}$ , permitting access to a maximum 16-Mbyte address space. The initial bus mode after a reset is 16 bits, with 16-bit access to all areas. If all areas are designated for 8-bit access in ABWCR, the bus mode switches to 8 bits.  $A_{21}$  to  $A_{21}$  are valid when 0 is written in bits 7 to 5 of BRCR. (In this mode  $A_{20}$  is always used for address output.)

### **3.5 Pin Functions in Each Operating Mode**

The pin functions of port 4 and port A vary depending on the operating mode. Table 3.3 indicates their functions in each operating mode.





Notes: 1. Initial state. The bus mode can be switched by settings in ABWCR. These pins function as P4<sub>7</sub> to P4<sub>0</sub> in 8-bit bus mode, and as D<sub>7</sub> to D<sub>0</sub> in 16-bit bus mode.

2. Initial state.  $A_{z_0}$  is always an address output pin. PA<sub>6</sub> to PA<sub>4</sub> are switched over to A<sub>23</sub> to  $A_{21}$  output by writing 0 in bits 7 to 5 of BRCR.

### **3.6 Memory Map in Each Operating Mode**

Figures 3.1 and 3.2 show a memory maps of the H8/3006 and H8/3007. The address space is divided into eight areas.

The initial bus mode differs between modes 1 and 2, and also between modes 3 and 4.

The address locations of the on-chip RAM and internal I/O registers differ between the 1-Mbyte modes (modes 1, 2), and the 16-Mbyte modes (modes 3, 4). The address range specifiable by the CPU in the 8- and 16-bit absolute addressing modes (@aa:8 and @aa:16) also differs.

### **3.6.1 Note on Reserved Areas**

The memory map of the H8/3006 and H8/3007 includes reserved areas to which read/write access is prohibited. Note that normal operation is not guaranteed if the following reserved areas are accessed.

The internal I/O register space of the H8/3006 and H8/3007 includes a reserved area to which access is prohibited. For details, see Appendix B, Internal I/O Registers.

#### 3. MCU Operating Modes

Modes 1 and 2 (1 Mbyte)				Modes 3 and 4 (16 Mbytes)			
H'00000				H'000000			
<b>H'000FF</b>	Vector area	Memory-indirect branch addresses	16-bit absolute	<b>H'0000FF</b>	Vector area	Memory-indirect branch addresses	16-bit absolute addresses
H'07FFF			addresses	H'007FFF			
H'1FFFF		Area <sub>0</sub>				Area <sub>0</sub>	
H'20000 H'3FFFF H'40000		Area 1		H'1FFFFF H'200000			
H'5FFFF H'60000 H'7FFFF	<b>External address</b> space	Area 2 Area <sub>3</sub>		H'3FFFFF H'400000		Area 1	
H'80000 H'9FFFF H'A0000		Area 4		H'5FFFFF		Area 2	
<b>H'BFFFF</b> <b>H'C0000</b> <b>H'DFFFF</b>		Area 5 Area 6		H'600000	External address	Area 3	
<b>H'E0000</b> H'EE000		Area 7		H'7FFFFF H'800000	space		
<b>H'EE0FF</b>	Internal I/O registers (1)			H'9FFFFF H'A00000		Area 4	
H'F8000	External address space					Area <sub>5</sub>	
H'FEF1F H'FEF20	On-chip RAM*			<b>H'BFFFFFF</b> H'C00000		Area 6	
H'FFF00 H'FFF1F		8-bit absolute addresses	16-bit absolute addresses	<b>H'DFFFFF</b> H'E00000			
H'FFF20	Internal I/O registers (2)			H'FEE000	Internal I/O	Area <sub>7</sub>	
H'FFFE9 <b>H'FFFEA</b>	External address			<b>H'FEE0FF</b>	registers (1) <b>External address</b>		
<b>H'FFFFF</b>	space			<b>H'FF8000</b> H'FFEF1F	space		
				H'FFEF20 H'FFFF00	On-chip RAM*		
				H'FFFF1F H'FFFF20			
				H'FFFFE9	Internal I/O registers (2)	8-bit absolute addresses	16-bit absolute addresses
				<b>H'FFFFEA</b>	External address space		
				<b>H'FFFFFF</b>			

**Figure 3.1 H8/3007 Memory Map in Each Operating Mode** 



#### **Figure 3.2 H8/3006 Memory Map in Each Operating Mode**



# Section 4 Exception Handling

### **4.1 Overview**

### **4.1.1 Exception Handling Types and Priority**

As table 4.1 indicates, exception handling may be caused by a reset, interrupt, or trap instruction. Exception handling is prioritized as shown in table 4.1. If two or more exceptions occur simultaneously, they are accepted and processed in priority order. Trap instruction exceptions are accepted at all times in the program execution state.

<b>Priority</b>	<b>Exception Type</b>	<b>Start of Exception Handling</b>				
High	Reset	Starts immediately after a low-to-high transition at the RES pin				
	Interrupt	Interrupt requests are handled when execution of the current instruction or handling of the current exception is completed				
Low	Trap instruction (TRAPA)	Started by execution of a trap instruction (TRAPA)				

**Table 4.1 Exception Types and Priority** 

### **4.1.2 Exception Handling Operation**

Exceptions originate from various sources. Trap instructions and interrupts are handled as follows.

- 1. The program counter (PC) and condition code register (CCR) are pushed onto the stack.
- 2. The CCR interrupt mask bit is set to 1.
- 3. A vector address corresponding to the exception source is generated, and program execution starts from that address.

Note: For a reset exception, steps 2 and 3 above are carried out.

### **4.1.3 Exception Vector Table**

The exception sources are classified as shown in figure 4.1. Different vectors are assigned to different exception sources. Table 4.2 lists the exception sources and their vector addresses.



**Figure 4.1 Exception Sources** 





#### **Table 4.2 Exception Vector Table**

Notes: 1. Lower 16 bits of the address.

2. For the internal interrupt vectors, see section 5.3.3, Interrupt Vector Table.

3. Normal mode is not available in the H8/3006 and H8/3007.

### **4.2 Reset**

### **4.2.1 Overview**

A reset is the highest-priority exception. When the RES pin goes low, all processing halts and the chip enters the reset state. A reset initializes the internal state of the CPU and the registers of the on-chip supporting modules. Reset exception handling begins when the  $\overline{RES}$  pin changes from low to high.

The chip can also be reset by overflow of the watchdog timer. For details see section 12, Watchdog Timer.

### **4.2.2 Reset Sequence**

The chip enters the reset state when the  $\overline{RES}$  pin goes low.

To ensure that the chip is properly reset, hold the RES pin low for at last 20 ms at power-up. To reset the chip during operation, hold the RES pin low for at least 10 system clock  $(\phi)$  cycles. See appendix D.2, Pin States at Reset, for the states of the pins in the reset state.

When the RES pin goes high after being held low for the necessary time, the chip starts reset exception handling as follows.

- The internal state of the CPU and the registers of the on-chip supporting modules are initialized, and the I bit is set to 1 in CCR.
- The contents of the reset vector address (H'0000 to H'0003) are read, and program execution starts from the address indicated in the vector address.

Figure 4.2 shows the reset sequence in modes 1 and 3. Figure 4.3 shows the reset sequence in modes 2 and 4.





**Figure 4.2 Reset Sequence (Modes 1 and 3)** 



**Figure 4.3 Reset Sequence (Modes 2 and 4)** 

### **4.2.3 Interrupts after Reset**

If an interrupt is accepted after a reset but before the stack pointer (SP) is initialized, PC and CCR will not be saved correctly, leading to a program crash. To prevent this, all interrupt requests, including NMI, are disabled immediately after a reset. The first instruction of the program is always executed immediately after the reset state ends. This instruction should initialize the stack pointer (example: MOV.L #xx:32, SP).

### **4.3 Interrupts**

Interrupt exception handling can be requested by seven external sources (NMI,  $IRQ_0$  to  $IRQ_5$ ), and 36 internal sources in the on-chip supporting modules. Figure 4.4 classifies the interrupt sources and indicates the number of interrupts of each type.

The on-chip supporting modules that can request interrupts are the watchdog timer (WDT), DRAM interface, 16-bit timer, 8-bit timer, DMA controller (DMAC), serial communication interface (SCI), and A/D converter. Each interrupt source has a separate vector address.

NMI is the highest-priority interrupt and is always accepted. Interrupts are controlled by the interrupt controller. The interrupt controller can assign interrupts other than NMI to two priority levels, and arbitrate between simultaneous interrupts. Interrupt priorities are assigned in interrupt priority registers A and B (IPRA and IPRB) in the interrupt controller.

For details on interrupts see section 5, Interrupt Controller.



#### **Figure 4.4 Interrupt Sources and Number of Interrupts**

# **4.4 Trap Instruction**

Trap instruction exception handling starts when a TRAPA instruction is executed. If the UE bit is set to 1 in the system control register (SYSCR), the exception handling sequence sets the I bit to 1 in CCR. If the UE bit is 0, the I and UI bits are both set to 1. The TRAPA instruction fetches a start address from a vector table entry corresponding to a vector number from 0 to 3, which is specified in the instruction code.

# **4.5 Stack Status after Exception Handling**

Figure 4.5 shows the stack after completion of trap instruction exception handling and interrupt exception handling.



**Figure 4.5 Stack after Completion of Exception Handling** 

### **4.6 Notes on Stack Usage**

When accessing word data or longword data, the H8/3006 and H8/3007 regard the lowest address bit as 0. The stack should always be accessed by word access or longword access, and the value of the stack pointer (SP: ER7) should always be kept even.

Use the following instructions to save registers:



Use the following instructions to restore registers:



Setting SP to an odd value may lead to a malfunction. Figure 4.6 shows an example of what happens when the SP value is odd.



#### **Figure 4.6 Operation when SP Value Is Odd**


# Section 5 Interrupt Controller

## **5.1 Overview**

### **5.1.1 Features**

The interrupt controller has the following features:

- Interrupt priority registers (IPRs) for setting interrupt priorities Interrupts other than NMI can be assigned to two priority levels on a module-by-module basis in interrupt priority registers A and B (IPRA and IPRB).
- Three-level enable/disable state setting possible by means of the I and UI bits in the CPU's condition code register (CCR) and the UE bit in the system control register (SYSCR)
- Seven external interrupt pins

NMI has the highest priority and is always accepted; either the rising or falling edge can be selected. For each of  $IRQ_0$  to  $IRQ_5$ , sensing of the falling edge or level sensing can be selected independently.

### **5.1.2 Block Diagram**



Figure 5.1 shows a block diagram of the interrupt controller.

**Figure 5.1 Interrupt Controller Block Diagram** 

#### **5.1.3 Pin Configuration**

Table 5.1 lists the interrupt pins.

#### **Table 5.1 Interrupt Pins**



#### **5.1.4 Register Configuration**

Table 5.2 lists the registers of the interrupt controller.

#### **Table 5.2 Interrupt Controller Registers**



Notes: 1. Lower 20 bits of the address in advanced mode.

2. Only 0 can be written, to clear flags.

## **5.2 Register Descriptions**

### **5.2.1 System Control Register (SYSCR)**

SYSCR is an 8-bit readable/writable register that controls software standby mode, selects the action of the UI bit in CCR, selects the NMI edge, and enables or disables the on-chip RAM.

Only bits 3 and 2 are described here. For the other bits, see section 3.3, System Control Register (SYSCR).

SYSCR is initialized to H'09 by a reset and in hardware standby mode. It is not initialized in software standby mode.



**Bit 3—User Bit Enable (UE):** Selects whether to use the UI bit in CCR as a user bit or an interrupt mask bit.







### **5.2.2 Interrupt Priority Registers A and B (IPRA, IPRB)**

IPRA and IPRB are 8-bit readable/writable registers that control interrupt priority.

**Interrupt Priority Register A (IPRA):** IPRA is an 8-bit readable/writable register in which interrupt priority levels can be set.



Selects the priority level of  $\text{IRQ}_0$  interrupt requests

IPRA is initialized to H'00 by a reset and in hardware standby mode.



**Bit 7—Priority Level A7 (IPRA7):** Selects the priority level of IRQ<sub>0</sub> interrupt requests.



**Bit 6—Priority Level A6 (IPRA6):** Selects the priority level of IRQ<sub>1</sub> interrupt requests.



**Bit 5—Priority Level A5 (IPRA5):** Selects the priority level of IRQ<sub>2</sub> and IRQ<sub>3</sub> interrupt requests.



**Bit 4—Priority Level A4 (IPRA4):** Selects the priority level of IRQ<sub>4</sub> and IRQ<sub>5</sub> interrupt requests.



**Bit 3—Priority Level A3 (IPRA3):** Selects the priority level of WDT, DRAM interface, and A/D converter interrupt requests.



**Bit 2—Priority Level A2 (IPRA2):** Selects the priority level of 16-bit timer channel 0 interrupt requests.

#### **Bit 2**



**Bit 1—Priority Level A1 (IPRA1):** Selects the priority level of 16-bit timer channel 1 interrupt requests.

### **Bit 1**



**Bit 0—Priority Level A0 (IPRA0):** Selects the priority level of 16-bit timer channel 2 interrupt requests.





**Interrupt Priority Register B (IPRB):** IPRB is an 8-bit readable/writable register in which interrupt priority levels can be set.



Selects the priority level of 8-bit timer channel 0, 1 interrupt requests

IPRB is initialized to H'00 by a reset and in hardware standby mode.

**Bit 7—Priority Level B7 (IPRB7):** Selects the priority level of 8-bit timer channel 0, 1 interrupt requests.

### **Bit 7 IPRB7 Description**  0 8-bit timer channel 0, 1 interrupt requests have priority level 0 (low priority)(Initial value) 1 8-bit timer channel 0, 1 interrupt requests have priority level 1 (high priority)

**Bit 6—Priority Level B6 (IPRB6):** Selects the priority level of 8-bit timer channel 2, 3 interrupt requests.

### **Bit 6 IPRB6 Description**  0 8-bit timer channel 2, 3 interrupt requests have priority level 0 (low priority)(Initial value) 1 8-bit timer channel 2, 3 interrupt requests have priority level 1 (high priority)

**Bit 5—Priority Level B5 (IPRB5):** Selects the priority level of DMAC interrupt requests (channels 0 and 1).

### **Bit 5 IPRB5 Description**  0 DMAC interrupt requests (channels 0 and 1) have priority level 0 (Initial value) (low priority) 1 DMAC interrupt requests (channels 0 and 1) have priority level 1 (high priority)

**Bit 4—Reserved:** This bit can be written and read, but it does not affect interrupt priority.

**Bit 3—Priority Level B3 (IPRB3):** Selects the priority level of SCI channel 0 interrupt requests.



**Bit 2—Priority Level B2 (IPRB2):** Selects the priority level of SCI channel 1 interrupt requests.



**Bit 1—Priority Level B1 (IPRB1):** Selects the priority level of SCI channel 2 interrupt requests.



**Bit 0—Reserved:** This bit can be written and read, but it does not affect interrupt priority.

#### **5.2.3 IRQ Status Register (ISR)**

ISR is an 8-bit readable/writable register that indicates the status of  $IRQ_0$  to  $IRQ_5$  interrupt requests.



Note:  $*$  Only 0 can be written, to clear flags.

ISR is initialized to H'00 by a reset and in hardware standby mode.

**Bits 7 and 6—Reserved:** These bits can not be modified and are always read as 0.

**Bits 5 to 0—IRQ<sub>5</sub>** to IRQ<sub>0</sub> Flags (IRQ5F to IRQ0F): These bits indicate the status of IRQ<sub>5</sub> to  $IRQ<sub>0</sub>$  interrupt requests.

### **Bits 5 to 0 IRQ5F to IRQ0F Description**



#### **5.2.4 IRQ Enable Register (IER)**

IER is an 8-bit readable/writable register that enables or disables  $IRQ_0$  to  $IRQ_5$  interrupt requests.



IER is initialized to H'00 by a reset and in hardware standby mode.

**Bits 7 and 6—Reserved:** These bits can be written and read, but they do not enable or disable interrupts.

**Bits 5 to 0—IRQ**, to IRQ<sub>0</sub> Enable (IRQ5E to IRQ0E): These bits enable or disable  $IRQ<sub>5</sub>$  to  $IRQ<sub>0</sub>$  interrupts.

#### **Bits 5 to 0 IRQ5E to IRQ0E Description**



### **5.2.5 IRQ Sense Control Register (ISCR)**

ISCR is an 8-bit readable/writable register that selects level sensing or falling-edge sensing of the inputs at pins  $\overline{\text{IRQ}}_5$  to  $\overline{\text{IRQ}}_0$ .



ISCR is initialized to H'00 by a reset and in hardware standby mode.

**Bits 7 and 6—Reserved:** These bits can be written and read, but they do not select level or falling-edge sensing.

Bits 5 to 0—IRQ<sub>5</sub> to IRQ<sub>0</sub> Sense Control (IRQ5SC to IRQ0SC): These bits select whether interrupts IRQ<sub>5</sub> to IRQ<sub>0</sub> are requested by level sensing of pins  $\overline{\text{IRQ}}_5$  to  $\overline{\text{IRQ}}_0$ , or by falling-edge sensing.

#### **Bits 5 to 0 IRQ5SC to IRQ0SC Description**



## **5.3 Interrupt Sources**

The interrupt sources include external interrupts (NMI,  $IRQ_0$  to  $IRQ_5$ ) and 36 internal interrupts.

### **5.3.1 External Interrupts**

There are seven external interrupts: NMI, and  $IRQ_0$  to  $IRQ_s$ . Of these, NMI,  $IRQ_0$ ,  $IRQ_1$ , and  $IRQ<sub>2</sub>$  can be used to exit software standby mode.

**NMI:** NMI is the highest-priority interrupt and is always accepted, regardless of the states of the I and UI bits in CCR. The NMIEG bit in SYSCR selects whether an interrupt is requested by the rising or falling edge of the input at the NMI pin. NMI interrupt exception handling has vector number 7.

**IRQ**<sub>0</sub> to IRQ<sub>5</sub> Interrupts: These interrupts are requested by input signals at pins  $\overline{\text{IRQ}}_0$  to  $\overline{\text{IRQ}}_5$ . The IRQ<sub>0</sub> to IRQ<sub>5</sub> interrupts have the following features.

- ISCR settings can select whether an interrupt is requested by the low level of the input at pins  $\overline{\text{IRQ}}_0$  to  $\overline{\text{IRQ}}_5$ , or by the falling edge.
- IER settings can enable or disable the IRQ<sub>0</sub> to IRQ<sub>5</sub> interrupts. Interrupt priority levels can be assigned by four bits in IPRA (IPRA7 to IPRA4).
- The status of  $IRQ_0$  to  $IRQ_5$  interrupt requests is indicated in ISR. The ISR flags can be cleared to 0 by software.





**Figure 5.2** Block Diagram of Interrupts IRQ<sub>0</sub> to IRQ<sub>5</sub>

Figure 5.3 shows the timing of the setting of the interrupt flags (IRQnF).



#### **Figure 5.3 Timing of Setting of IRQnF**

Interrupts IRQ<sub>0</sub> to IRQ<sub>5</sub> have vector numbers 12 to 17. These interrupts are detected regardless of whether the corresponding pin is set for input or output. When using a pin for external interrupt input, clear its DDR bit to 0 and do not use the pin for chip select output, refresh output, SCI input/output, or A/D external trigger input.

### **5.3.2 Internal Interrupts**

Thirty-Six internal interrupts are requested from the on-chip supporting modules.

- Each on-chip supporting module has status flags for indicating interrupt status, and enable bits for enabling or disabling interrupts.
- Interrupt priority levels can be assigned in IPRA and IPRB.
- 16-bit timer, SCI, and A/D converter interrupt requests can activate the DMAC, in which case no interrupt request is sent to the interrupt controller, and the I and UI bits are disregarded.

### **5.3.3 Interrupt Vector Table**

Table 5.3 lists the interrupt sources, their vector addresses, and their default priority order. In the default priority order, smaller vector numbers have higher priority. The priority of interrupts other than NMI can be changed in IPRA and IPRB. The priority order after a reset is the default order shown in table 5.3.



### **Table 5.3 Interrupt Sources, Vector Addresses, and Priority**



#### 5. Interrupt Controller



Note:  $*$  Lower 16 bits of the address.



### **5.4 Interrupt Operation**

### **5.4.1 Interrupt Handling Process**

The H8/3006 and H8/3007 handle interrupts differently depending on the setting of the UE bit. When  $UE = 1$ , interrupts are controlled by the I bit. When  $UE = 0$ , interrupts are controlled by the I and UI bits. Table 5.4 indicates how interrupts are handled for all setting combinations of the UE, I, and UI bits.

NMI interrupts are always accepted except in the reset and hardware standby states. IRQ interrupts and interrupts from the on-chip supporting modules have their own enable bits. Interrupt requests are ignored when the enable bits are cleared to 0.

<b>SYSCR</b>		CCR	
UE.		UI	<b>Description</b>
	0		All interrupts are accepted. Interrupts with priority level 1 have higher priority.
			No interrupts are accepted except NMI.
$\Omega$	Ω		All interrupts are accepted. Interrupts with priority level 1 have higher priority.
		O	NMI and interrupts with priority level 1 are accepted.
			No interrupts are accepted except NMI.

**Table 5.4 UE, I, and UI Bit Settings and Interrupt Handling** 

 $UE = 1$ : Interrupts  $IRQ_0$  to  $IRQ_5$  and interrupts from the on-chip supporting modules can all be masked by the I bit in the CPU's CCR. Interrupts are masked when the I bit is set to 1, and unmasked when the I bit is cleared to 0. Interrupts with priority level 1 have higher priority. Figure 5.4 is a flowchart showing how interrupts are accepted when  $UE = 1$ .

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**Figure 5.4 Process Up to Interrupt Acceptance when UE = 1** 

- If an interrupt condition occurs and the corresponding interrupt enable bit is set to 1, an interrupt request is sent to the interrupt controller.
- When the interrupt controller receives one or more interrupt requests, it selects the highestpriority request, following the IPR interrupt priority settings, and holds other requests pending. If two or more interrupts with the same IPR setting are requested simultaneously, the interrupt controller follows the priority order shown in table 5.3.
- The interrupt controller checks the I bit. If the I bit is cleared to 0, the selected interrupt request is accepted. If the I bit is set to 1, only NMI is accepted; other interrupt requests are held pending.
- When an interrupt request is accepted, interrupt exception handling starts after execution of the current instruction has been completed.
- In interrupt exception handling, PC and CCR are saved to the stack area. The PC value that is saved indicates the address of the first instruction that will be executed after the return from the interrupt service routine.
- Next the I bit is set to 1 in CCR, masking all interrupts except NMI.
- The vector address of the accepted interrupt is generated, and the interrupt service routine starts executing from the address indicated by the contents of the vector address.

**UE = 0:** The I and UI bits in the CPU's CCR and the IPR bits enable three-level masking of  $IRQ<sub>o</sub>$  to  $IRQ<sub>s</sub>$  interrupts and interrupts from the on-chip supporting modules.

- Interrupt requests with priority level 0 are masked when the I bit is set to 1, and are unmasked when the I bit is cleared to 0.
- Interrupt requests with priority level 1 are masked when the I and UI bits are both set to 1, and are unmasked when either the I bit or the UI bit is cleared to 0.
- For example, if the interrupt enable bits of all interrupt requests are set to 1, IPRA is set to  $H20$ , and IPRB is set to  $H00$  (giving IRQ<sub>2</sub> and IRQ<sub>3</sub> interrupt requests priority over other interrupts), interrupts are masked as follows:
	- a. If  $I = 0$ , all interrupts are unmasked (priority order: NMI > IRQ<sub>2</sub> > IRQ<sub>3</sub> > IRQ<sub>0</sub> ...).
	- b. If  $I = 1$  and  $UI = 0$ , only NMI,  $IRQ_2$ , and  $IRQ_3$  are unmasked.
	- c. If  $I = 1$  and  $UI = 1$ , all interrupts are masked except NMI.

Figure 5.5 shows the transitions among the above states.





Figure 5.6 is a flowchart showing how interrupts are accepted when  $UE = 0$ .

- If an interrupt condition occurs and the corresponding interrupt enable bit is set to 1, an interrupt request is sent to the interrupt controller.
- When the interrupt controller receives one or more interrupt requests, it selects the highestpriority request, following the IPR interrupt priority settings, and holds other requests pending. If two or more interrupts with the same IPR setting are requested simultaneously, the interrupt controller follows the priority order shown in table 5.3.
- The interrupt controller checks the I bit. If the I bit is cleared to 0, the selected interrupt request is accepted regardless of its IPR setting, and regardless of the UI bit. If the I bit is set to 1 and the UI bit is cleared to 0, only NMI and interrupts with priority level 1 are accepted; interrupt requests with priority level 0 are held pending. If the I bit and UI bit are both set to 1, interrupt requests are held pending.
- When an interrupt request is accepted, interrupt exception handling starts after execution of the current instruction has been completed.
- In interrupt exception handling, PC and CCR are saved to the stack area. The PC value that is saved indicates the address of the first instruction that will be executed after the return from the interrupt service routine.
- The I and UI bits are set to 1 in CCR, masking all interrupts except NMI.
- The vector address of the accepted interrupt is generated, and the interrupt service routine starts executing from the address indicated by the contents of the vector address.



**Figure 5.6 Process Up to Interrupt Acceptance when UE = 0** 

### **5.4.2 Interrupt Sequence**

Figure 5.7 shows the interrupt sequence in mode 2 when the program code and stack are in an external memory area accessed in two states via a 16-bit bus.





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#### **5.4.3 Interrupt Response Time**

Table 5.5 indicates the interrupt response time from the occurrence of an interrupt request until the first instruction of the interrupt service routine is executed.

#### **Table 5.5 Interrupt Response Time**



Notes: 1. 1 state for internal interrupts.

 2. Prefetch after the interrupt is accepted and prefetch of the first instruction in the interrupt service routine.

 3. Internal processing after the interrupt is accepted and internal processing after vector fetch.

4. The number of states increases if wait states are inserted in external memory access.

## **5.5 Usage Notes**

### **5.5.1 Contention between Interrupt and Interrupt-Disabling Instruction**

When an instruction clears an interrupt enable bit to 0 to disable the interrupt, the interrupt is not disabled until after execution of the instruction is completed. If an interrupt occurs while a BCLR, MOV, or other instruction is being executed to clear its interrupt enable bit to 0, at the instant when execution of the instruction ends the interrupt is still enabled, so its interrupt exception handling is carried out. If a higher-priority interrupt is also requested, however, interrupt exception handling for the higher-priority interrupt is carried out, and the lower-priority interrupt is ignored. This also applies to the clearing of an interrupt flag to 0.

Figure 5.8 shows an example in which an IMIEA bit is cleared to 0 in the 16-bit timer's TISRA register.



**Figure 5.8 Contention between Interrupt and Interrupt-Disabling Instruction** 

This type of contention will not occur if the interrupt is masked when the interrupt enable bit or flag is cleared to 0.

### **5.5.2 Instructions that Inhibit Interrupts**

The LDC, ANDC, ORC, and XORC instructions inhibit interrupts. When an interrupt occurs, after determining the interrupt priority, the interrupt controller requests a CPU interrupt. If the CPU is currently executing one of these interrupt-inhibiting instructions, however, when the instruction is completed the CPU always continues by executing the next instruction.

#### **5.5.3 Interrupts during EEPMOV Instruction Execution**

The EEPMOV.B and EEPMOV.W instructions differ in their reaction to interrupt requests.

When the EEPMOV.B instruction is executing a transfer, no interrupts are accepted until the transfer is completed, not even NMI.

When the EEPMOV.W instruction is executing a transfer, interrupt requests other than NMI are not accepted until the transfer is completed. If NMI is requested, NMI exception handling starts at a transfer cycle boundary. The PC value saved on the stack is the address of the next instruction. Programs should be coded as follows to allow for NMI interrupts during EEPMOV.W execution:

 L1: EEPMOV.W MOV.W R4,R4 BNE L1



# Section 6 Bus Controller

### **6.1 Overview**

The H8/3006 and H8/3007 have an on-chip bus controller (BSC) that manages the external address space divided into eight areas. The bus specifications, such as bus width and number of access states, can be set independently for each area, enabling multiple memories to be connected easily.

The bus controller also has a bus arbitration function that controls the operation of the internal bus masters-the CPU, DMA controller (DMAC), and DRAM interface and can release the bus to an external device.

### **6.1.1 Features**

The features of the bus controller are listed below.

- Manages external address space in area units
	- Manages the external space as eight areas (0 to 7) of 128 kbytes in 1M-byte modes, or 2 Mbytes in 16-Mbyte modes
	- Bus specifications can be set independently for each area
	- DRAM/burst ROM interfaces can be set
- Basic bus interface
	- Chip select  $(CS_0$  to  $CS_7)$  can be output for areas 0 to 7
	- $-$  8-bit access or 16-bit access can be selected for each area
	- ⎯ Two-state access or three-state access can be selected for each area
	- Program wait states can be inserted for each area
	- Pin wait insertion capability is provided
- DRAM interface
	- DRAM interface can be set for areas 2 to 5
	- Row address/column address multiplexed output (8/9/10 bits)
	- 2-CAS byte access mode
	- Burst operation (fast page mode)
	- $-\mathsf{T}_{\rm P}$  cycle insertion to secure RAS precharging time
	- Choice of CAS-before-RAS refreshing or self-refreshing

- Burst ROM interface
	- Burst ROM interface can be set for area 0
	- Selection of two- or three-state burst access
- Idle cycle insertion
	- An idle cycle can be inserted in case of an external read cycle between different areas
	- An idle cycle can be inserted when an external read cycle is immediately followed by an external write cycle
- Bus arbitration function
	- $-$  A built-in bus arbiter grants the bus right to the CPU, DMAC, DRAM interface, or an external bus master
- Other features
	- The refresh counter (refresh timer) can be used as an interval timer

### **6.1.2 Block Diagram**

Figure 6.1 shows a block diagram of the bus controller.





#### **Figure 6.1 Block Diagram of Bus Controller**

### **6.1.3 Pin Configuration**

Table 6.1 summarizes the input/output pins of the bus controller.







#### **6.1.4 Register Configuration**

Table 6.2 summarizes the bus controller's registers.

#### **Table 6.2 Bus Controller Registers**



Notes: 1. Lower 20 bits of the address in advanced mode.

2. In modes 2 and 4, the initial value is H'00.

3. In modes 3 and 4, the initial value is H'EE.

4. For Bit 7, only 0 can be written to clear the flag.

### **6.2 Register Descriptions**

### **6.2.1 Bus Width Control Register (ABWCR)**



ABWCR is an 8-bit readable/writable register that selects 8-bit or 16-bit access for each area.

When ABWCR contains H'FF (selecting 8-bit access for all areas), the chip operates in 8-bit bus mode: the upper data bus  $(D_{15}$  to  $D_8$ ) is valid, and port 4 is an input/output port. When at least one bit is cleared to 0 in ABWCR, the chip operates in 16-bit bus mode with a 16-bit data bus  $(D_{15}$  to D<sub>0</sub>). In modes 1 and 3, ABWCR is initialized to H'FF by a reset and in hardware standby mode. In modes 2 and 4, ABWCR is initialized to H'00 by a reset and in hardware standby mode. It is not initialized in software standby mode.

**Bits 7 to 0—Area 7 to 0 Bus Width Control (ABW7 to ABW0):** These bits select 8-bit access or 16-bit access for the corresponding areas.



ABWCR specifies the data bus width of external memory areas. The data bus width of on-chip memory and registers is fixed, and does not depend on ABWCR settings.

#### **6.2.2 Access State Control Register (ASTCR)**

ASTCR is an 8-bit readable/writable register that selects whether each area is accessed in two states or three states.





Bits selecting number of states for access to each area

ASTCR is initialized to H'FF by a reset and in hardware standby mode. It is not initialized in software standby mode.

**Bits 7 to 0—Area 7 to 0 Access State Control (AST7 to AST0):** These bits select whether the corresponding area is accessed in two or three states.



ASTCR specifies the number of states in which external areas are accessed. On-chip memory and registers are accessed in a fixed number of states that does not depend on ASTCR settings.

When the corresponding area is designated as DRAM space by bits DRAS2 to DRAS0 in DRAM control register A (DRCRA), the number of access states does not depend on the AST bit setting. When an AST bit is cleared to 0, programmable wait insertion is not performed.

#### **6.2.3 Wait Control Registers H and L (WCRH, WCRL)**

WCRH and WCRL are 8-bit readable/writable registers that select the number of program wait states for each area.

On-chip memory and registers are accessed in a fixed number of states that does not depend on WCRH/WCRL settings.

WCRH and WCRL are initialized to H'FF by a reset and in hardware standby mode. They are not initialized in software standby mode.

#### **WCRH**



**Bits 7 and 6—Area 7 Wait Control 1 and 0 (W71, W70):** These bits select the number of program wait states when area 7 in external space is accessed while the AST7 bit in ASTCR is set to 1.



**Bits 5 and 4—Area 6 Wait Control 1 and 0 (W61, W60):** These bits select the number of program wait states when area 6 in external space is accessed while the AST6 bit in ASTCR is set to 1.


**Bits 3 and 2—Area 5 Wait Control 1 and 0 (W51, W50):** These bits select the number of program wait states when area 5 in external space is accessed while the AST5 bit in ASTCR is set to 1.



Bits 1 and 0—Area 4 Wait Control 1 and 0 (W41, W40): These bits select the number of program wait states when area 4 in external space is accessed while the AST4 bit in ASTCR is set to 1.



#### **WCRL**



**Bits 7 and 6—Area 3 Wait Control 1 and 0 (W31, W30):** These bits select the number of program wait states when area 3 in external space is accessed while the AST3 bit in ASTCR is set to 1.



**Bits 5 and 4—Area 2 Wait Control 1 and 0 (W21, W20):** These bits select the number of program wait states when area 2 in external space is accessed while the AST2 bit in ASTCR is set to 1.



**Bits 3 and 2—Area 1 Wait Control 1 and 0 (W11, W10):** These bits select the number of program wait states when area 1 in external space is accessed while the AST1 bit in ASTCR is set to 1.



**Bits 1 and 0**—Area 0 Wait Control 1 and 0 (W01, W00): These bits select the number of program wait states when area 0 in external space is accessed while the AST0 bit in ASTCR is set to 1.



#### **6.2.4 Bus Release Control Register (BRCR)**

BRCR is an 8-bit readable/writable register that enables address output on bus lines  $A_{23}$  to  $A_{20}$  and enables or disables release of the bus to an external device.



BRCR is initialized to H'FE in modes 1 and 2, and to H'EE in modes 3 and 4, by a reset and in hardware standby mode. It is not initialized in software standby mode.

**Bit 7—Address 23 Enable (A23E):** Enables  $PA_4$  to be used as the  $A_{23}$  address output pin. Writing 0 in this bit enables  $A_{23}$  output from PA<sub>4</sub>. In modes 1 and 2, this bit cannot be modified and PA<sub>4</sub> has its ordinary port functions.



**Bit 6—Address 22 Enable (A22E):** Enables  $PA_5$  to be used as the  $A_{22}$  address output pin. Writing 0 in this bit enables  $A_{22}$  output from PA<sub>5</sub>. In modes 1 and 2, this bit cannot be modified and PA<sub>5</sub> has its ordinary port functions.



**Bit 5—Address 21 Enable (A21E):** Enables  $PA_6$  to be used as the  $A_{21}$  address output pin. Writing 0 in this bit enables  $A_{21}$  output from PA<sub>6</sub>. In modes 1 and 2, this bit cannot be modified and PA<sub>6</sub> has its ordinary port functions.



**Bit 4—Address 20 Enable (A20E):** Initial value of this bit varies depending on the mode. This bit can not be modified.



**Bits 3 to 1—Reserved:** These bits cannot be modified and are always read as 1.



**Bit 0—Bus Release Enable (BRLE):** Enables or disables release of the bus to an external device.

#### **6.2.5 Bus Control Register (BCR)**



BCR is an 8-bit readable/writable register that enables or disables idle cycle insertion, selects the area division unit, and enables or disables WAIT pin input.

BCR is initialized to H'C6 by a reset and in hardware standby mode. It is not initialized in software standby mode.

**Bit 7—Idle Cycle Insertion 1 (ICIS1):** Selects whether one idle cycle state is to be inserted between bus cycles in case of consecutive external read cycles for different areas.



**Bit 6—Idle Cycle Insertion 0 (ICIS0):** Selects whether one idle cycle state is to be inserted between bus cycles in case of consecutive external read and write cycles.



**Bit 5—Burst ROM Enable (BROME):** Selects whether area 0 is a burst ROM interface area.



**Bit 4—Burst Cycle Select 1 (BRSTS1):** Selects the number of burst cycle states for the burst ROM interface.

### **Bit 4 BRSTS1 Description**  0 **Burst access cycle comprises 2 states** (Initial value) 1 Burst access cycle comprises 3 states

**Bit 3—Burst Cycle Select 0 (BRSTS0):** Selects the number of words that can be accessed in a burst ROM interface burst access.



Bit 2-Reserved: Read-only bit, always read as 1.

**Bit 1—Area Division Unit Select (RDEA):** Selects the memory map area division units. This bit is valid in modes 3 and 4, and is invalid in modes 1 and 2.



**Bit 0—WAIT Pin Enable (WAITE):** Enables or disables wait insertion by means of the WAIT pin.



#### **6.2.6 Chip Select Control Register (CSCR)**

CSCR is an 8-bit readable/writable register that enables or disables output of chip select signals  $(\overline{\text{CS}}_7$  to  $\overline{\text{CS}}_4$ ).

If output of a chip select signal is enabled by a setting in this register, the corresponding pin functions a chip select signal  $(\overline{CS}_7)$  to  $\overline{CS}_4$ ) output regardless of any other settings.



CSCR is initialized to H'0F by a reset and in hardware standby mode. It is not initialized in software standby mode.

**Bits 7 to 4—Chip Select 7 to 4 Enable (CS7E to CS4E):** These bits enable or disable output of the corresponding chip select signal.



**Bits 3 to 0—Reserved:** These bits cannot be modified and are always read as 1.

### **6.2.7 DRAM Control Register A (DRCRA)**



DRCRA is an 8-bit readable/writable register that selects the areas that have a DRAM interface function, and the access mode, and enables or disables self-refreshing and refresh pin output.

DRCRA is initialized to H'10 by a reset and in hardware standby mode. It is not initialized in software standby mode.

**Bits 7 to 5—DRAM Area Select (DRAS2 to DRAS0):** These bits select which of areas 2 to 5 are to function as DRAM interface areas (DRAM space), and at the same time select the RAS output pin corresponding to each DRAM space.



Note:  $*$  A single  $\overline{\text{CSn}}$  pin serves as a common  $\overline{\text{RAS}}$  output pin for a number of areas. Unused CSn pins can be used as input/output ports.

When any of bits DRAS2 to DRAS0 is set to 1, it is not possible to write to DRCRB, RTMCSR, RTCNT, or RTCOR. However, 0 can be written to the CMF flag in RTMCSR to clear the flag.

When an arbitrary value has been set in DRAS2 to DRAS0, a write of a different value other than 000 must not be performed.

**Bit 4—Reserved:** This bit cannot be modified and is always read as 1.

**Bit 3—Burst Access Enable (BE):** Enables or disables burst access to DRAM space. DRAM space burst access is performed in fast page mode.



**Bit 2—RAS Down Mode (RDM):** Selects whether to wait for the next DRAM access with the RAS signal held low (RAS down mode), or to drive the RAS signal high again (RAS up mode), when burst access is enabled for DRAM space  $(BE = 1)$ , and access to DRAM is interrupted.

Caution is required when the  $\overline{HWR}$  and  $\overline{LWR}$  are used as the  $\overline{UCAS}$  and  $\overline{LCAS}$  output pins. For details, see RAS Down Mode and RAS Up Mode in section 6.5.10, Burst Operation.



**Bit 1—Self-Refresh Mode (SRFMD):** Specifies DRAM self-refreshing in software standby mode.

When any of areas 2 to 5 is designated as DRAM space, DRAM self-refreshing is possible when a transition is made to software standby mode after the SRFMD bit has been set to 1.

The normal access state is restored when software standby mode is exited, regardless of the SRFMD setting.



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**Bit 0—Refresh Pin Enable (RFSHE):** Enables or disables **RFSH** pin refresh signal output. If areas 2 to 5 are not designated as DRAM space, this bit should not be set to 1.



#### **6.2.8 DRAM Control Register B (DRCRB)**



DRCRB is an 8-bit readable/writable register that selects the number of address multiplex column address bits for the DRAM interface, the column address strobe output pin, enabling or disabling of refresh cycle insertion, the number of precharge cycles, enabling or disabling of wait state insertion between  $\overline{RAS}$  and  $\overline{CAS}$ , and enabling or disabling of wait state insertion in refresh cycles.

DRCRB is initialized to H'08 by a reset and in hardware standby mode. It is not initialized in software standby mode.

The settings in this register are invalid when bits DRAS2 to DRAS0 in DRCRA are all 0.



**Bits 7 and 6—Multiplex Control 1 and 0 (MXC1, MXC0):** These bits select the row address/column address multiplexing method used on the DRAM interface. In burst operation, the row address used for comparison is determined by the setting of these bits and the bus width of the relevant area set in ABWCR.



**Bit 5—CAS** Output Pin Select (CSEL): Selects the UCAS and LCAS output pins when areas 2 to 5 are designated as DRAM space.



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**Bit 4—Refresh Cycle Enable (RCYCE):** CAS-before-RAS enables or disables refresh cycle insertion. When none of areas 2 to 5 has been designated as DRAM space, refresh cycles are not inserted regardless of the setting of this bit.



**Bit 3—Reserved:** This bit cannot be modified and is always read as 1.

**Bit 2—TP Cycle Control (TPC):** Selects whether a 1-state or two-state precharge cycle (Tp) is to be used for DRAM read/write cycles and CAS-before-RAS refresh cycles. The setting of this bit does not affect the self-refresh function.



**Bit 1—RAS-CAS Wait (RCW):** Controls wait state (Trw) insertion between T<sub>r</sub> and T<sub>c1</sub> in DRAM read/write cycles. The setting of this bit does not affect refresh cycles.



**Bit 0—Refresh Cycle Wait Control (RLW):** Controls wait state  $(T_{RW})$  insertion for CAS-before-RAS refresh cycles. The setting of this bit does not affect DRAM read/write cycles.



#### **6.2.9 Refresh Timer Control/Status Register (RTMCSR)**



RTMCSR is an 8-bit readable/writable register that selects the refresh timer counter clock. When the refresh timer is used as an interval timer, RTMCSR also enables or disables interrupt requests. Bits 7 and 6 of RTMCSR are initialized to 0 by a reset and in the standby modes. Bits 5 to 3 are initialized to 0 by a reset and in hardware standby mode; they are not initialized in software standby mode.

Note: Only 0 can be written to clear the flag.

**Bit 7—Compare Match Flag (CMF):** Status flag that indicates a match between the values of RTCNT and RTCOR.



**Bit 6—Compare Match Interrupt Enable (CMIE):** Enables or disables the CMI interrupt requested when the CMF flag is set to 1 in RTMCSR. The CMIE bit is always cleared to 0 when any of areas 2 to 5 is designated as DRAM space.



**Bits 5 to 3—Refresh Counter Clock Select (CKS2 to CKS0):** These bits select the clock to be input to RTCNT from among 7 clocks obtained by dividing the system clock (φ). When the input clock is selected with bits CKS2 to CKS0, RTCNT begins counting up.



**Bits 2 to 0—Reserved:** These bits cannot be modified and are always read as 1.





RTCNT is an 8-bit readable/writable up-counter.

RTCNT is incremented by an internal clock selected by bits CKS2 to CKS0 in RTMCSR. When RTCNT matches RTCOR (compare match), the CMF flag in RTMCSR is set to 1 and RTCNT is cleared to H'00. If the RCYCE bit in DRCRB is set to 1 at this time, a refresh cycle is started. Also, if the CMIE bit in RTMCSR is set to 1, a compare match interrupt (CMI) is generated.

RTCNT is initialized to H'00 by a reset and in standby mode.



#### **6.2.11 Refresh Time Constant Register (RTCOR)**



RTCOR is an 8-bit readable/writable register that sets the RTCNT compare-match interval.

RTCOR and RTCNT are constantly compared. When their values match, the CMF flag is set to 1 in RTMCSR, and RTCNT is simultaneously cleared to H'00.

RTCOR is initialized to H'FF by a reset and in hardware standby mode. It is not initialized in software standby mode.

Note: Only byte access should be used with this register.

# **6.3 Operation**

# **6.3.1 Area Division**

The external address space is divided into areas 0 to 7. Each area has a size of 128 kbytes in the 1- Mbyte modes, or 2-Mbytes in the 16-Mbyte modes. Figure 6.2 shows a general view of the memory map.

H'00000		H'000000	Area 0 (2 Mbytes)		
H'1FFFF	Area 0 (128 kbytes)	H'1FFFFF			
H'20000		H'200000			
H'3FFFF	Area 1 (128 kbytes)	H'3FFFFF	Area 1 (2 Mbytes)		
H'40000		H'400000	Area 2 (2 Mbytes)		
H'5FFFF	Area 2 (128 kbytes)	H'5FFFFF			
H'60000		H'600000			
H'7FFFF	Area 3 (128 kbytes)	H'7FFFFF	Area 3 (2 Mbytes)		
H'80000		H'800000	Area 4 (2 Mbytes)		
H'9FFFF	Area 4 (128 kbytes)	H'9FFFFF			
H'A0000		H'A00000			
<b>H'BFFFF</b>	Area 5 (128 kbytes)	<b>H'BFFFFF</b>	Area 5 (2 Mbytes)		
<b>H'C0000</b>		H'C00000			
<b>H'DFFFF</b>	Area 6 (128 kbytes)	<b>H'DFFFFF</b>	Area 6 (2 Mbytes)		
<b>H'E0000</b>	Area 7 (128 Mbytes)	H'E00000	Area 7 (2 Mbytes)		
H'FFFFF		H'FFFFFF			
	(a) 1-Mbyte modes (modes 1 and 2)		(b) 16-Mbyte modes (modes 3 and 4)		

**Figure 6.2 Access Area Map for Each Operating Mode** 

Chip select signals ( $\overline{CS}_0$  to  $\overline{CS}_7$ ) can be output for areas 0 to 7. The bus specifications for each area are selected in ABWCR, ASTCR, WCRH, and WCRL.

In 16-Mbyte mode, the area division units can be selected with the RDEA bit in BCR.



**Figure 6.3 Memory Map in 16-Mbyte Mode (H8/3007)** 

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### **6.3.2 Bus Specifications**

The external space bus specifications consist of three elements: (1) bus width, (2) number of access states, and (3) number of program wait states.

The bus width and number of access states for on-chip memory and registers are fixed, and are not affected by the bus controller.

**Bus Width:** A bus width of 8 or 16 bits can be selected with ABWCR. An area for which an 8-bit bus is selected functions as an 8-bit access space, and an area for which a 16-bit bus is selected functions as a16-bit access space.

If all areas are designated for 8-bit access, 8-bit bus mode is set; if any area is designated for 16-bit access, 16-bit bus mode is set.

**Number of Access States:** Two or three access states can be selected with ASTCR. An area for which two-state access is selected functions as a two-state access space, and an area for which three-state access is selected functions as a three-state access space.

DRAM space is accessed in four states regardless of the ASTCR settings.

When two-state access space is designated, wait insertion is disabled.

**Number of Program Wait States:** When three-state access space is designated in ASTCR, the number of program wait states to be inserted automatically is selected with WCRH and WCRL. From 0 to 3 program wait states can be selected.

When ASTCR is cleared to 0 for DRAM space, a program wait  $(T_{c1}-T_{c2})$  wait) is not inserted. Also, no program wait is inserted in burst ROM space burst cycles.

Table 6.3 shows the bus specifications for each basic bus interface area.



.				$=$ $\frac{1}{2}$ $\frac{1}{2$			
<b>ABWn</b>	ASTn	Wn1	Wn0	<b>Bus Width</b>	<b>Access States</b>	<b>Program Wait States</b>	
0 0				16	2	0	
		$\Omega$			3		
						2	
						3	
				8	2	O	
		$\Omega$	ი		3	ი	
						2	
						3	

**Table 6.3 Bus Specifications for Each Area (Basic Bus Interface)** 



### **6.3.3 Memory Interfaces**

The H8/3006 and H8/3007 memory interfaces comprise a basic bus interface that allows direct connection of ROM, SRAM, and so on; a DRAM interface that allows direct connection of DRAM; and a burst ROM interface that allows direct connection of burst ROM. The interface can be selected independently for each area.

An area for which the basic bus interface is designated functions as normal space, an area for which the DRAM interface is designated functions as DRAM space, and area 0 for which the burst ROM interface is designated functions as burst ROM space.

### **6.3.4 Chip Select Signals**

For each of areas 0 to 7, the H8/3006 and H8/3007 can output a chip select signal  $(CS_0$  to  $CS_7$ ) that goes low when the corresponding area is selected. Figure 6.4 shows the output timing of a  $\overline{CS}n$ signal.

**Output of**  $\overline{CS}_0$  **to**  $\overline{CS}_3$ **: Output of**  $CS_0$  **to**  $CS_3$  **is enabled or disabled in the data direction register** (DDR) of the corresponding port.

A reset leaves pin  $CS_0$  in the output state and pins  $CS_1$  to  $CS_3$  in the input state. To output chip select signals  $\overline{CS}_1$  to  $\overline{CS}_3$ , the corresponding DDR bits must be set to 1. For details, see section 8, I/O Ports.

**Output of**  $\overline{CS}_4$  **to**  $\overline{CS}_7$ **:** Output of  $\overline{CS}_4$  to  $\overline{CS}_7$  is enabled or disabled in the chip select control register (CSCR). A reset leaves pins  $\overline{CS}_4$  to  $\overline{CS}_7$  in the input state. To output chip select signals  $\overline{CS}_4$ to  $\overline{CS}_7$ , the corresponding CSCR bits must be set to 1. For details, see section 8, I/O Ports.



Figure 6.4  $\overline{\text{CS}}$ n Signal Output Timing (n = 0 to 7)

When the on-chip RAM and on-chip registers are accessed,  $\overline{CS}_0$  to  $\overline{CS}_7$  remain high. The  $\overline{CS}_n$ signals are decoded from the address signals. They can be used as chip select signals for SRAM and other devices.

# **6.4 Basic Bus Interface**

# **6.4.1 Overview**

The basic bus interface enables direct connection of ROM, SRAM, and so on.

The bus specifications can be selected with ABWCR, ASTCR, WCRH, and WCRL (see table 6.3).

# **6.4.2 Data Size and Data Alignment**

Data sizes for the CPU and other internal bus masters are byte, word, and longword. The bus controller has a data alignment function, and when accessing external space, controls whether the upper data bus ( $D_{15}$  to  $D_8$ ) or lower data bus ( $D_7$  to  $D_0$ ) is used according to the bus specifications for the area being accessed (8-bit access area or 16-bit access area) and the data size.



**8-Bit Access Areas:** Figure 6.5 illustrates data alignment control for 8-bit access space. With 8-bit access space, the upper data bus  $(D_{15}$  to  $D_8)$  is always used for accesses. The amount of data that can be accessed at one time is one byte: a word access is performed as two byte accesses, and a longword access, as four byte accesses.



**Figure 6.5 Access Sizes and Data Alignment Control (8-Bit Access Area)** 

**16-Bit Access Areas:** Figure 6.6 illustrates data alignment control for 16-bit access areas. With 16-bit access areas, the upper data bus  $(D_{15}$  to  $D_8$ ) and lower data bus  $(D_7$  to  $D_0$ ) are used for accesses. The amount of data that can be accessed at one time is one byte or one word, and a longword access is executed as two word accesses.

In byte access, whether the upper or lower data bus is used is determined by whether the address is even or odd. The upper data bus is used for an even address, and the lower data bus for an odd address.



**Figure 6.6 Access Sizes and Data Alignment Control (16-Bit Access Area)** 

#### **6.4.3 Valid Strobes**

Table 6.4 shows the data buses used, and the valid strobes, for the access spaces.

In a read, the  $\overline{RD}$  signal is valid for both the upper and the lower half of the data bus.

In a write, the  $\overline{HWR}$  signal is valid for the upper half of the data bus, and the  $\overline{LWR}$  signal for the lower half.



#### **Table 6.4 Data Buses Used and Valid Strobes**

Notes: 1. Undetermined data means that unpredictable data is output.

2. Invalid means that the bus is in the input state and the input is ignored.

#### **6.4.4 Memory Areas**

The initial state of each area is basic bus interface, three-state access space. The initial bus width is selected according to the operating mode. The bus specifications described here cover basic items only, and the following sections should be referred to for further details: 6.4, Basic Bus Interface, 6.5, DRAM Interface, 6.8, Burst ROM Interface.

**Area 0:** When area 0 external space is accessed, the  $\overline{CS}_0$  signal can be output. Either basic bus interface or burst ROM interface can be selected for area 0. The size of area 0 is 128 kbytes in modes 1 and 2, and 2 Mbytes in modes 3 and 4.

**Areas 1 and 6:** When area 1 and 6 external space is accessed, the  $CS_1$  and  $CS_6$  pin signals respectively can be output.

Only the basic bus interface can be used for areas 1 and 6.



The size of areas 1 and 6 is 128 kbytes in modes 1 and 2, and 2 Mbytes in modes 3 and 4.

**Areas 2 to 5:** When area 2 to 5 external space is accessed, signals  $\overline{CS}_2$  to  $\overline{CS}_5$  can be output. Basic bus interface or DRAM interface can be selected for areas 2 to 5. With the DRAM interface, signals  $\overline{CS}_2$  to  $\overline{CS}_5$  are used as  $\overline{RAS}$  signals.

The size of areas 2 to 5 is 128 kbytes in modes 1 and 2, and 2 Mbytes in modes 3 and 4.

**Area 7:** Area 7 includes the on-chip RAM and registers. The space excluding the on-chip RAM and registers is external space. The on-chip RAM is enabled when the RAME bit in the system control register (SYSCR) is set to 1; when the RAME bit is cleared to 0, the on-chip RAM is disabled and the corresponding space becomes external space .

When area 7 external space is accessed, the  $CS<sub>7</sub>$  signal can be output.

Only the basic bus interface can be used for the area 7 memory interface.

The size of area 7 is 128 kbytes in modes 1 and 2, and 2 Mbytes in modes 3 and 4.

### **6.4.5 Basic Bus Control Signal Timing**

**8-Bit, Three-State-Access Areas:** Figure 6.7 shows the timing of bus control signals for an 8-bit, three-state-access area. The upper data bus  $(D_{15}$  to  $D_8$ ) is used in accesses to these areas. The LWR pin is always high. Wait states can be inserted.



**Figure 6.7 Bus Control Signal Timing for 8-Bit, Three-State-Access Area** 

**8-Bit, Two-State-Access Areas:** Figure 6.8 shows the timing of bus control signals for an 8-bit, two-state-access area. The upper data bus ( $D_{15}$  to  $D_8$ ) is used in accesses to these areas. The  $\overline{\rm LWR}$ pin is always high. Wait states cannot be inserted.



**Figure 6.8 Bus Control Signal Timing for 8-Bit, Two-State-Access Area** 

**16-Bit, Three-State-Access Areas:** Figures 6.9 to 6.11 show the timing of bus control signals for a 16-bit, three-state-access area. In these areas, the upper data bus  $(D_{15}$  to  $D_8)$  is used in accesses to even addresses and the lower data bus  $(D_7$  to  $D_0$ ) in accesses to odd addresses. Wait states can be inserted.







**Figure 6.10 Bus Control Signal Timing for 16-Bit, Three-State-Access Area (2) (Byte Access to Odd Address)** 

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**Figure 6.11 Bus Control Signal Timing for 16-Bit, Three-State-Access Area (3) (Word Access)** 

**16-Bit, Two-State-Access Areas:** Figures 6.12 to 6.14 show the timing of bus control signals for a 16-bit, two-state-access area. In these areas, the upper data bus  $(D_{15}$  to  $D_8$ ) is used in accesses to even addresses and the lower data bus  $(D_7$  to  $D_0$ ) in accesses to odd addresses. Wait states cannot be inserted.



**Figure 6.12 Bus Control Signal Timing for 16-Bit, Two-State-Access Area (1) (Byte Access to Even Address)** 



**Figure 6.13 Bus Control Signal Timing for 16-Bit, Two-State-Access Area (2) (Byte Access to Odd Address)** 



**Figure 6.14 Bus Control Signal Timing for 16-Bit, Two-State-Access Area (3) (Word Access)** 

#### **6.4.6 Wait Control**

When accessing external space, the H8/3006 and H8/3007 can extend the bus cycle by inserting one or more wait states  $(T_w)$ . There are two ways of inserting wait states: (1) program wait insertion and (2) pin wait insertion using the  $\overline{WAIT}$  pin.

**Program Wait Insertion:** From 0 to 3 wait states can be inserted automatically between the T<sub>2</sub> state and  $T_3$  state on an individual area basis in three-state access space, according to the settings of WCRH and WCRL.

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**Pin Wait Insertion:** Setting the WAITE bit in BCR to 1 enables wait insertion by means of the  $\overline{WAIT}$  pin. When external space is accessed in this state, a program wait is first inserted. If the WAIT pin is low at the falling edge of  $\phi$  in the last  $T_2$  or  $T_w$  state, another  $T_w$  state is inserted. If the  $\overline{WAIT}$  pin is held low,  $T_w$  states are inserted until it goes high.

This is useful when inserting four or more  $T_w$  states, or when changing the number of  $T_w$  states for different external devices.

The WAITE bit setting applies to all areas. Pin waits cannot be inserted in DRAM space.

Figure 6.15 shows an example of the timing for insertion of one program wait state in 3-state space.



**Figure 6.15 Example of Wait State Insertion Timing** 

# **6.5 DRAM Interface**

### **6.5.1 Overview**

The H8/3006 and H8/3007 are provided with a DRAM interface with functions for DRAM control signal  $(RAS, \overline{UCAS}, \overline{LCAS}, \overline{WE})$  output, address multiplexing, and refreshing, that direct connection of DRAM. In the expanded modes, external address space areas 2 to 5 can be designated as DRAM space accessed via the DRAM interface. A data bus width of 8 or 16 bits can be selected for DRAM space by means of a setting in ABWCR. When a 16-bit data bus width is selected, CAS is used for byte access control. In the case of  $\times$  16-bit organization DRAM, therefore, the 2-CAS type can be connected. A fast page mode is supported in addition to the normal read and write access modes.

### **6.5.2 DRAM Space and** RAS **Output Pin Settings**

Designation of areas 2 to 5 as DRAM space, and selection of the  $\overline{RAS}$  output pin for each area designated as DRAM space, is performed by setting bits DRAS2 to DRAS0 in DRCRA. Table 6.5 shows the correspondence between the settings of bits DRAS2 to DRAS0 and the selected DRAM space and  $\overline{RAS}$  output pin.

When an arbitrary value has been set in DRAS2 to DRAS0, a write of a different value other than 000 must not be performed.



### **Table 6.5 Settings of Bits DRAS2 to DRAS0 and Corresponding DRAM Space (**RAS **Output Pin)**

Note: \* A single  $\overline{\text{CS}}_{n}$  pin serves as a common RAS output pin for a number of areas. Unused  $\overline{\text{CS}}_n$  pins can be used as input/output ports.

### **6.5.3 Address Multiplexing**

When DRAM space is accessed, the row address and column address are multiplexed. The address multiplexing method is selected with bits MXC1 and MXC0 in DRCRB according to the number of bits in the DRAM column address. Table 6.6 shows the correspondence between the settings of MXC1 and MXC0 and the address multiplexing method.



### **Table 6.6 Settings of Bits MXC1 and MXC0 and Address Multiplexing Method**

Note:  $*$  Row address bit  $A_{20}$  is not multiplexed in 1-Mbyte mode.

#### **6.5.4 Data Bus**

If the bit in ABWCR corresponding to an area designated as DRAM space is set to 1, that area is designated as 8-bit DRAM space; if the bit is cleared to 0, the area is designated as 16-bit DRAM space. In 16-bit DRAM space,  $\times$  16-bit organization DRAM can be connected directly.

In 8-bit DRAM space the upper half of the data bus,  $D_{15}$  to  $D_{8}$ , is enabled, while in 16-bit DRAM space both the upper and lower halves of the data bus,  $D_{15}$  to  $D_{0}$ , are enabled.

Access sizes and data alignment are the same as for the basic bus interface: see section 6.4.2, Data Size and Data Alignment.

#### **6.5.5 Pins Used for DRAM Interface**

Table 6.7 shows the pins used for DRAM interfacing and their functions.

#### **Table 6.7 DRAM Interface Pins**



Note:  $*$  Fixed high in a read access.

#### **6.5.6 Basic Timing**

Figure 6.16 shows the basic access timing for DRAM space. The basic DRAM access timing is four states: one precharge cycle  $(T_p)$  state, one row address output cycle  $(T_p)$  state, and two column address output cycle  $(T_c, T_c)$  states. Unlike the basic bus interface, the corresponding bits in ASTCR control only enabling or disabling of wait insertion between  $T_{c1}$  and  $T_{c2}$ , and do not affect the number of access states. When the corresponding bit in ASTCR is cleared to 0, wait states cannot be inserted between  $T_{c1}$  and  $T_{c2}$  in the DRAM access cycle.

If a DRAM read/write cycle is followed by an access cycle for an external area other than DRAM space when  $\overline{HWR}$  and  $\overline{LWR}$  are selected as the  $\overline{UCAS}$  and  $\overline{LCAS}$  output pins, an idle cycle (Ti) is inserted unconditionally immediately after the DRAM access cycle. See section 6.9, Idle Cycle, for details.



**Figure 6.16 Basic Access Timing (CSEL = 0 in DRCRB)**
#### **6.5.7 Precharge State Control**

In the H8/3006 and H8/3007, provision is made for the DRAM RAS precharge time by always inserting one RAS precharge state  $(T_p)$  when DRAM space is accessed. This can be changed to two  $T_{p}$  states by setting the TPC bit to 1 in DRCRB. The optimum number of  $T_{p}$  cycles should be set according to the DRAM connected and the operating frequency of the H8/3006 and H8/3007 chip. Figure 6.17 shows the timing when two  $T_{p}$  states are inserted.

When the TCP bit is set to 1, two  $T_p$  states are also used for CAS-before-RAS refresh cycles.



**Figure 6.17 Timing with Two Precharge States (CSEL = 0 in DRCRB)** 

#### **6.5.8 Wait Control**

In a DRAM access cycle, wait states can be inserted (1) between the  $T_r$  state and  $T_{cl}$  state, and (2) between the  $T_{c1}$  state and  $T_{c2}$  state.

**Insertion of**  $T_{rw}$  **Wait State between**  $T_r$  **and**  $T_{ct}$ **: One**  $T_{rw}$  **state can be inserted between**  $T_r$  **and**  $T_{ct}$ by setting the RCW bit to 1 in DRCRB.

**Insertion of T<sub>w</sub>** Wait State(s) between T<sub>c1</sub> and T<sub>c2</sub>: When the bit in ASTCR corresponding to an area designated as DRAM space is set to 1, from 0 to 3  $T_w$  states can be inserted between the  $T_{\text{cl}}$ state and  $T_c$  state by means of settings in WCRH and WCRL.

Figure 6.18 shows an example of the timing for wait state insertion.

The settings of the RCW bit in DRCRB and of ASTCR, WCRH, and WCRL do not affect refresh cycles. Wait states cannot be inserted in a DRAM space access cycle by means of the WAIT pin.



**Figure 6.18 Example of Wait State Insertion Timing (CSEL = 0)** 

### **6.5.9 Byte Access Control and** CAS **Output Pin**

When an access is made to DRAM space designated as a 16-bit-access area in ABWCR, column address strobes (UCAS and LCAS) corresponding to the upper and lower halves of the external data bus are output. In the case of  $\times$  16-bit organization DRAM, the 2-CAS type can be connected.

Either PB4 and PB5, or  $\overline{HWR}$  and  $\overline{LWR}$ , can be used as the  $\overline{UCAS}$  and  $\overline{LCAS}$  output pins, the selection being made with the CSEL bit in DRCRB. Table 6.8 shows the CSEL bit settings and corresponding output pin selections.

When an access is made to DRAM space designated as an 8-bit-access area in ABWCR, only  $\overline{UCAS}$  is output. When the entire DRAM space is designated as 8-bit-access space and CSEL = 0, PB5 can be used as an input/output port.

Note that  $\overline{RAS}$  down mode cannot be used when a device other than DRAM is connected to external space and  $\overline{HWR}$  and  $\overline{LWR}$  are used as write strobes. In this case, also, an idle cycle (Ti) is always inserted when an external access to other than DRAM space occurs after a DRAM space access. For details, see section 6.9, Idle Cycle.



#### **Table 6.8 CSEL Settings and** UCAS **and** LCAS **Output Pins**

Figure 6.19 shows the control timing.



**Figure 6.19 Control Timing (Upper-Byte Write Access When CSEL = 0)** 

### **6.5.10 Burst Operation**

With DRAM, in addition to full access (normal access) in which data is accessed by outputting a row address for each access, a fast page mode is also provided which can be used when making a number of consecutive accesses to the same row address. This mode enables fast (burst) access of data by simply changing the column address after the row address has been output. Burst access can be selected by setting the BE bit to 1 in DRCRA.

**Burst Access (Fast Page Mode) Operation Timing:** Figure 6.20 shows the operation timing for burst access. When there are consecutive access cycles for DRAM space, the column address and CAS signal output cycles (two states) continue as long as the row address is the same for consecutive access cycles. In burst access, too, the bus cycle can be extended by inserting wait states between  $T_{c1}$  and  $T_{c2}$ . The wait state insertion method and timing are the same as for full access: see section 6.5.8, Wait Control, for details.

The row address used for the comparison is determined by the bus width of the relevant area set in bits MXC1 and MXC0 in BRCRB, and in ABWCR. Table 6.9 shows the compared row addresses corresponding to the various settings of bits MXC1 and MXC0, and ABWCR.



**Figure 6.20 Operation Timing in Fast Page Mode** 



**Table 6.9 Correspondence between Settings of MXC1 and MXC0 Bits and ABWCR, and Row Address Compared in Burst Access** 

Note:  $n = 2$  to 5

**RAS Down Mode and RAS Up Mode:** With DRAM provided with fast page mode, as long as accesses are to the same row address, burst operation can be continued without interruption even if accesses are not consecutive by holding the RAS signal low.

#### RAS Down Mode

To select RAS down mode, set the BE and RDM bits to 1 in DRCRA. If access to DRAM space is interrupted and another space is accessed, the RAS signal is held low during the access to the other space, and burst access is performed if the row address of the next DRAM space access is the same as the row address of the previous DRAM space access. Figure 6.21 shows an example of the timing in RAS down mode.



**Figure 6.21 Example of Operation Timing in RAS Down Mode (CSEL = 0)** 

When RAS down mode is selected, the conditions for an asserted  $\overline{RAS}$  signal to return to the high level are as shown below. The timing in these cases is shown in figure 6.22.

- When DRAM space with a different row address is accessed
- Immediately before a CAS-before-RAS refresh cycle
- When the BE bit or RDM bit is cleared to 0 in DRCRA
- Immediately before release of the external bus

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**Figure 6.22** RAS**n Negation Timing when RAS Down Mode Is Selected** 

When RAS down mode is selected, the CAS-before-RAS refresh function provided with this DRAM interface must always be used as the DRAM refreshing method. When a refresh operation is performed, the RAS signal goes high immediately beforehand. The refresh interval setting must be made so that the maximum DRAM RAS pulse width specification is observed.

When the self-refresh function is used, the RDM bit must be cleared to 0, and RAS up mode selected, before executing a SLEEP instruction in order to enter software standby mode. Select RAS down mode again after exiting software standby mode.

Note that RAS down mode cannot be used when  $\overline{HWR}$  and  $\overline{LWR}$  are selected for  $\overline{UCAS}$  and  $\overline{LCAS}$ , a device other than DRAM is connected to external space, and  $\overline{HWR}$  and  $\overline{LWR}$  are used as write strobes.

RAS Up Mode

To select RAS up mode, clear the RDM bit to 0 in DRCRA. Each time access to DRAM space is interrupted and another space is accessed, the RAS signal returns to the high level. Burst operation is only performed if DRAM space is continuous. Figure 6.23 shows an example of the timing in RAS up mode.



**Figure 6.23 Example of Operation Timing in RAS Up Mode** 

#### **6.5.11 Refresh Control**

The H8/3006 and H8/3007 are provided with a CAS-before-RAS (CBR) function and self-refresh function as DRAM refresh control functions.

**CAS-Before-RAS (CBR) Refreshing:** To select CBR refreshing, set the RCYCE bit to 1 in DRCRB.

With CBR refreshing, RTCNT counts up using the input clock selected by bits CKS2 to CKS0 in RTMCSR, and a refresh request is generated when the count matches the value set in RTCOR (compare match). At the same time, RTCNT is reset and starts counting up again from H'00. Refreshing is thus repeated at fixed intervals determined by RTCOR and bits CKS2 to CKS0. A refresh cycle is executed after this refresh request has been accepted and the DRAM interface has acquired the bus. Set a value in bits CKS2 to CKS0 in RTCOR that will meet the refresh interval specification for the DRAM used. When RAS down mode is used, set the refresh interval so that the maximum RAS pulse width specification is met.

RTCNT starts counting up when bits CKS2 to CKS0 are set. RTCNT and RTCOR settings should therefore be completed before setting bits CKS2 to CKS0.

Also note that a repeat refresh request generated during a bus request, or a refresh request during refresh cycle execution, will be ignored.

RTCNT operation is shown in figure 6.24, compare match timing in figure 6.25, and CBR refresh timing in figures 6.26 and 6.27.



**Figure 6.24 RTCNT Operation** 



**Figure 6.25 Compare Match Timing** 



Figure 6.26 CBR Refresh Timing (CSEL =  $0$ , TPC =  $0$ , RLW =  $0$ )

The basic CBS refresh cycle timing comprises three states: one RAS precharge cycle  $(T_{RP})$  state, and two RAS output cycle  $(T_{R1}, T_{R2})$  states. Either one or two states can be selected for the RAS precharge cycle. When the TPC bit is set to 1 in DRCRB, RAS signal output is delayed by one cycle. This does not affect the timing of UCAS and LCAS output.

Use the RLW bit in DRCRB to adjust the RAS signal width. A single refresh wait state  $(T_{\text{ew}})$  can be inserted between the  $T_{R1}$  state and  $T_{R2}$  state by setting the RLW bit to 1.

The RLW bit setting is valid only for CBR refresh cycles, and does not affect DRAM read/write cycles. The number of states in the CBR refresh cycle is not affected by the settings in ASTCR, WCRH, or WCRL, or by the state of the WAIT pin.



Figure 6.27 shows the timing when the TPC bit and RLW bit are both set to 1.

**Figure 6.27 CBR Refresh Timing (CSEL = 0, TPC = 1, RLW = 1)** 

DRAM must be refreshed immediately after powering on in order to stabilize its internal state. When using the H8/3006 and H8/3007 CAS-before-RAS refresh function, therefore, a DRAM stabilization period should be provided by means of interrupts by another timer module, or by counting the number of times bit 7 (CMF) of RTMCSR is set, for instance, immediately after bits DRAS2 to DRAS0 have been set in DRCRA.

**Self-Refreshing:** A self-refresh mode (battery backup mode) is provided for DRAM as a kind of standby mode. In this mode, refresh timing and refresh addresses are generated within the DRAM. The H8/3006 and H8/3007 have a function that places the DRAM in self-refresh mode when the chip enters software standby mode.

To use the self-refresh function, set the SRFMD bit to 1 in DRCRA. When a SLEEP instruction is subsequently executed in order to enter software standby mode, the CAS and RAS signals are output and the DRAM enters self-refresh mode, as shown in figure 6.28.

When the chip exits software standby mode,  $\overline{CAS}$  and  $\overline{RAS}$  outputs go high.

The following conditions must be observed when the self-refresh function is used:

- When burst access is selected, RAS up mode must be selected before executing a SLEEP instruction in order to enter software standby mode. Therefore, if RAS down mode has been selected, the RDM bit in DRCRA must be cleared to 0 and RAS up mode selected before executing the SLEEP instruction. Select RAS down mode again after exiting software standby mode.
- The instruction immediately following a SLEEP instruction must not be located in an area designated as DRAM space.

The self-refresh function will not work properly unless the above conditions are observed.



**Figure 6.28 Self-Refresh Timing (CSEL = 0)** 

**Refresh Signal (RFSH):** A refresh signal (RFSH) that transmits a refresh cycle off-chip can be output by setting the RFSHE bit to 1 in DRCRA. RFSH output timing is shown in figures 6.26, 6.27, and 6.28.

#### **6.5.12 Examples of Use**

Examples of DRAM connection and program setup procedures are shown below. When the DRAM interface is used, check the DRAM device characteristics and choose the most appropriate method of use for that device.



#### **Connection Examples**

• Figure 6.29 shows typical interconnections when using two 2-CAS type 16-Mbit DRAMs using  $a \times 16$ -bit organization, and the corresponding address map. The DRAMs used in this example are of the 10-bit row address  $\times$  10-bit column address type. Up to four DRAMs can be connected by designating areas 2 to 5 as DRAM space.



**Figure 6.29 Interconnections and Address Map for 2-CAS 16-Mbit DRAMs with** × **16-Bit Organization** 

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Figure 6.30 shows typical interconnections when using two 16-Mbit DRAMs using  $a \times 8$ -bit organization, and the corresponding address map. The DRAMs used in this example are of the 11-bit row address  $\times$  10-bit column address type. The CS2 pin is used as a common RAS output pin for area 2 and area 3. When the  $\overline{DRAM}$  address space spans a number of contiguous areas, as in this example, the appropriate setting of bits DRAS2 to DRAS0 enables a single  $\overline{CS}$ pin to be used as the common RAS output pin for a number of areas, and makes it possible to directly connect large-capacity DRAM with address space that spans a maximum of four areas. Any unused  $\overline{CS}$  pins (in this example, the  $\overline{CS}$ 3 pin) can be used as input/output ports.



**Figure 6.30 Interconnections and Address Map for 16-Mbit DRAMs with** × **8-Bit Organization** 

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• Figure 6.31 shows typical interconnections when using two 4-Mbit DRAMs, and the corresponding address map. The DRAMs used in this example are of the 9-bit row address  $\times$ 9-bit column address type. In this example, upper address decoding allows multiple DRAMs to be connected to a single area. The  $\overline{RFSH}$  pin is used in this case, since both DRAMs must be refreshed simultaneously. However, note that RAS down mode cannot be used in this interconnection example.



**Figure 6.31 Interconnections and Address Map for 2-CAS 4-Mbit DRAMs with** × **16-Bit Organization** 

**Example of Program Setup Procedure:** Figure 6.32 shows an example of the program setup procedure.



**Figure 6.32 Example of Setup Procedure when Using DRAM Interface** 

### **6.5.13 Usage Notes**

Note the following points when using the DRAM refresh function.

- Refresh cycles will not be executed when the external bus released state, software standby mode, or a bus cycle is extended by means of wait state insertion. Refreshing must therefore be performed by other means in these cases.
- If a refresh request is generated internally while the external bus is released, the first request is retained and a single refresh cycle will be executed after the bus-released state is cleared. Figure 6.33 shows the bus cycle in this case.
- When a bus cycle is extended by means of wait state insertion, the first request is retained in the same way as when the external bus has been released.

In the event of contention with a bus request from an external bus master when a transition is made to software standby mode, the BACK and strobe states may be indeterminate after the transition to software standby mode (see figure 6.34).

When software standby mode is used, the BRLE bit should be cleared to 0 in BRCR before executing the SLEEP instruction.

Similar contention in a transition to self-refresh mode may prevent dependable strobe waveform output. This can also be avoided by clearing the BRLW bit to 0 in BRCR.

• Immediately after self-refreshing is cleared, external bus release is possible during a given period until the start of a CPU cycle. Attention must be paid to the  $\overline{RAS}$  state to ensure that the specification for the  $\overline{RAS}$  precharge time immediately after self-refreshing is met.











**Figure 6.35 Self-Refresh Clearing** 

# **6.6 Interval Timer**

### **6.6.1 Operation**

When DRAM is not connected to the H8/3006 and H8/3007 chip, the refresh timer can be used as an interval timer by clearing bits DRAS2 to DRAS0 in DRCRA to 0. After setting RTCOR, selection a clock source with bits CKS2 to CKS0 in RTMCSR, and set the CMIE bit to 1.

**Timing of Setting of Compare Match Flag and Clearing by Compare Match:** The CMF flag in RTMCSR is set to 1 by a compare match output when the RTCOR and RTCNT values match. The compare match signal is generated in the last state in which the values match (when RTCNT is updated from the matching value to a new value). Accordingly, when RTCNT and RTCOR match, the compare match signal is not generated until the next counter clock pulse. Figure 6.36 shows the timing.





**Figure 6.36 Timing of CMF Flag Setting** 

**Operation in Power-Down State:** The interval timer operates in sleep mode. It does not operate in hardware standby mode. In software standby mode, RTCNT and RTMCSR bits 7 and 6 are initialized, but RTMCSR bits 5 to 3 and RTCOR retain their settings prior to the transition to software standby mode.

**Contention between RTCNT Write and Counter Clear:** If a counter clear signal occurs in the  $T<sub>3</sub>$  state of an RTCNT write cycle, clearing of the counter takes priority and the write is not performed. See figure 6.37.







**Contention between RTCNT Write and Increment:** If an increment pulse occurs in the  $T_3$  state of an RTCNT write cycle, writing takes priority and RTCNT is not incremented. See figure 6.38.

**Figure 6.38 Contention between RTCNT Write and Increment** 

**Contention between RTCOR Write and Compare Match:** If a compare match occurs in the T<sub>3</sub> state of an RTCOR write cycle, writing takes priority and the compare match signal is inhibited. See figure 6.39.



**Figure 6.39 Contention between RTCOR Write and Compare Match** 

**RTCNT Operation at Internal Clock Source Switchover:** Switching internal clock sources may cause RTCNT to increment, depending on the switchover timing. Table 6.10 shows the relation between the time of the switchover (by writing to bits CKS2 to CKS0) and the operation of RTCNT.

The RTCNT input clock is generated from the internal clock source by detecting the falling edge of the internal clock. If a switchover is made from a high clock source to a low clock source, as in case No. 3 in table 6.10, the switchover will be regarded as a falling edge, an RTCNT clock pulse will be generated, and RTCNT will be incremented.



#### **Table 6.10 Internal Clock Switchover and RTCNT Operation**



Notes: 1. Including switchovers from a low clock source to the halted state, and from the halted state to a low clock source.

- 2. Including switchover from the halted state to a high clock source.
- 3. Including switchover from a high clock source to the halted state.
- 4. The switchover is regarded as a falling edge, causing RTCNT to increment.

## **6.7 Interrupt Sources**

Compare match interrupts (CMI) can be generated when the refresh timer is used as an interval timer. Compare match interrupt requests are masked/unmasked with the CMIE bit in RTMCSR.

## **6.8 Burst ROM Interface**

### **6.8.1 Overview**

With the H8/3006 and H8/3007, external space area 0 can be designated as burst ROM space, and burst ROM space interfacing can be performed. The burst ROM interface enables ROM with burst access capability to be accessed at high speed. Area 0 is designated as burst ROM space by means of the BROME bit in BCR.

Continuous burst access of a maximum or four or eight words can be performed on external space area 0. Two or three states can be selected for burst access.

#### **6.8.2 Basic Timing**

The number of states in the initial cycle (full access) and a burst cycle of the burst ROM interface is determined by the setting of the AST0 bit in ASTCR. When the AST0 bit is set to 1, wait states can also be inserted in the initial cycle. Wait states cannot be inserted in a burst cycle.

Burst access of up to four words is performed when the BRSTS0 bit is cleared to 0 in BCR, and burst access of up to eight words when the BRSTS0 bit is set to 1. The number of burst access states is two when the BRSTS1 bit is cleared to 0, and three when the BRSTS1 bit is set to 1.

The basic access timing for burst ROM space is shown in figure 6.40.





**Figure 6.40 Example of Burst ROM Access Timing** 

#### **6.8.3 Wait Control**

As with the basic bus interface, either program wait insertion or pin wait insertion using the  $\overline{WAIT}$ pin can be used in the initial cycle (full access) of the burst ROM interface.

Wait states cannot be inserted in a burst cycle.

## **6.9 Idle Cycle**

### **6.9.1 Operation**

When the H8/3006 and H8/3007 chip accesses external space, it can insert a 1-state idle cycle  $(T<sub>1</sub>)$ between bus cycles in the following cases: (1) when read accesses between different areas occur consecutively, (2) when a write cycle occurs immediately after a read cycle, and (3) when external address space other than DRAM space is accessed immediately after a DRAM space access. By inserting an idle cycle it is possible, for example, to avoid data collisions between ROM, which has a long output floating time, and high-speed memory, I/O interfaces, and so on.

The ICIS1 and ICIS0 bits in BCR both have an initial value of 1, so that an idle cycle is inserted in the initial state. If there are no data collisions, the ICIS bits can be cleared.

**Consecutive Reads between Different Areas:** If consecutive reads between different areas occur while the ICIS1 bit is set to 1 in BCR, an idle cycle is inserted at the start of the second read cycle.

Figure 6.41 shows an example of the operation in this case. In this example, bus cycle A is a read cycle from ROM with a long output floating time, and bus cycle B is a read cycle from SRAM, each being located in a different area. In (a), an idle cycle is not inserted, and a collision occurs in cycle B between the read data from ROM and that from SRAM. In (b), an idle cycle is inserted, and a data collision is prevented.



**Figure 6.41 Example of Idle Cycle Operation (1) (ICIS1 = 1)** 

**Write after Read:** If an external write occurs after an external read while the ICIS0 bit is set to 1 in BCR, an idle cycle is inserted at the start of the write cycle.

Figure 6.42 shows an example of the operation in this case. In this example, bus cycle A is a read cycle from ROM with a long output floating time, and bus cycle B is a CPU write cycle.



In (a), an idle cycle is not inserted, and a collision occurs in cycle B between the read data from ROM and the CPU write data. In (b), an idle cycle is inserted, and a data collision is prevented.

**Figure 6.42 Example of Idle Cycle Operation (2) (ICIS0 = 1)** 

**External Address Space Access Immediately after DRAM Space Access:** If a DRAM space access is followed by a non-DRAM external access when  $\overline{HWR}$  and  $\overline{LWR}$  have been selected as the UCAS and LCAS output pins by means of the CSEL bit in DRCRB, a Ti cycle is inserted regardless of the settings of bits ICIS0 and ICIS1 in BCR. Figure 6.43 shows an example of the operation.

This is done to prevent simultaneous changing of the  $\overline{HWR}$  and  $\overline{LWR}$  signals used as  $\overline{UCAS}$  and  $\overline{LCAS}$  in DRAM space and  $\overline{CS}$ n for the space in the next cycle, and so avoid an erroneous write to the external device in the next cycle.

A T<sub>i</sub> cycle is not inserted when PB4 and PB5 have been selected as the  $\overline{UCAS}$  and  $\overline{LCAS}$  output pins.

In the case of consecutive DRAM space access precharge cycles (Tp), the ICIS0 and ICIS1 bit settings are invalid. In the case of consecutive reads between different areas, for example, if the second access is a DRAM access, only a  $T_p$  cycle is inserted, and a  $T_i$  cycle is not. The timing in this case is shown in figure 6.44.



**Figure 6.43 Example of Idle Cycle Operation (3) (**HWR**/**LWR **Used as** UCAS**/**LCAS**)** 



**Figure 6.44 Example of Idle Cycle Operation (4) (Consecutive Precharge Cycles)** 

**Usage Notes:** When non-insertion of idle cycles is set, the rise (negation) of RD and the fall (assertion) of CSn may occur simultaneously. An example of the operation is shown in figure 6.45.

If consecutive reads between different external areas occur while the ICIS1 bit is cleared to 0 in BCR, or if a write cycle to a different external area occurs after an external read while the ICIS0 bit is cleared to 0, the  $\overline{RD}$  negation in the first read cycle and the  $\overline{CSn}$  assertion in the following bus cycle will occur simultaneously. Therefore, depending on the output delay time of each signal, it is possible that the low-level output of  $\overline{RD}$  in the preceding read cycle and the low-level output of CSn in the following bus cycle will overlap.

A setting whereby idle cycle insertion is not performed can be made only when  $\overline{RD}$  and  $\overline{CSn}$  do not change simultaneously, or when it does not matter if they do.





#### **6.9.2 Pin States in Idle Cycle**

Table 6.11 shows the pin states in an idle cycle.





Note: \* Remains low in DRAM space RAS down mode.

# **6.10 Bus Arbiter**

The bus controller has a built-in bus arbiter that arbitrates between different bus masters. There are four bus masters: the CPU, DMA controller (DMAC), DRAM interface, and an external bus master. When a bus master has the bus right it can carry out read, write, or refresh access. Each bus master uses a bus request signal to request the bus right. At fixed times the bus arbiter determines priority and uses a bus acknowledge signal to grant the bus to a bus master, which can the operate using the bus.

The bus arbiter checks whether the bus request signal from a bus master is active or inactive, and returns an acknowledge signal to the bus master. When two or more bus masters request the bus, the highest-priority bus master receives an acknowledge signal. The bus master that receives an acknowledge signal can continue to use the bus until the acknowledge signal is deactivated.

The bus master priority order is:

(High) External bus master  $>$  DRAM interface  $>$  DMAC  $>$  CPU (Low)

The bus arbiter samples the bus request signals and determines priority at all times, but it does not always grant the bus immediately, even when it receives a bus request from a bus master with higher priority than the current bus master. Each bus master has certain times at which it can release the bus to a higher-priority bus master.

## **6.10.1 Operation**

**CPU:** The CPU is the lowest-priority bus master. If the DMAC, DRAM interface, or an external bus master requests the bus while the CPU has the bus right, the bus arbiter transfers the bus right to the bus master that requested it. The bus right is transferred at the following times:

- The bus right is transferred at the boundary of a bus cycle. If word data is accessed by two consecutive byte accesses, however, the bus right is not transferred between the two byte accesses.
- If another bus master requests the bus while the CPU is performing internal operations, such as executing a multiply or divide instruction, the bus right is transferred immediately. The CPU continues its internal operations.
- If another bus master requests the bus while the CPU is in sleep mode, the bus right is transferred immediately.



**DMAC:** When the DMAC receives an activation request, it requests the bus right from the bus arbiter. If the DMAC is bus master and the DRAM interface or an external bus master requests the bus, the bus arbiter transfers the bus right from the DMAC to the bus master that requested the bus. The bus right is transferred at the following times.

The bus right is transferred when the DMAC finishes transferring one byte or one word. A DMAC transfer cycle consists of a read cycle and a write cycle. The bus right is not transferred between the read cycle and the write cycle.

There is a priority order among the DMAC channels. For details see section 7.4.9, Multiple-Channel Operation.

**DRAM Interface:** The DRAM interface requests the bus right from the bus arbiter when a refresh cycle request is issued, and releases the bus at the end of the refresh cycle. For details see section 6.5, DRAM Interface.

**External Bus Master:** When the BRLE bit is set to 1 in BRCR, the bus can be released to an external bus master. The external bus master has highest priority, and requests the bus right from the bus arbiter y driving the BREQ signal low. Once the external bus master acquires the bus, it keeps the bus until the BREQ signal goes high. While the bus is released to an external bus master, the H8/3006 and H8/3007 chip holds the address bus, data bus, bus control signals (AS, RD, HWR, and LWR), and chip select signals ( $\overline{CSn}$ :  $n = 7$  to 0) in the high-impedance state, and holds the BACK pin in the low output state.

The bus arbiter samples the  $\overline{BREQ}$  pin at the rise of the system clock ( $\phi$ ). If  $\overline{BREQ}$  is low, the bus is released to the external bus master at the appropriate opportunity. The BREQ signal should be held low until the  $\overline{BACK}$  signal goes low.

When the BREQ pin is high in two consecutive samples, the BACK pin is driven high to end the bus-release cycle.

Figure 6.46 shows the timing when the bus right is requested by an external bus master during a read cycle in a two-state access area. There is a minimum interval of three states from when the BREQ signal goes low until the bus is released.



**Figure 6.46 Example of External Bus Master Operation** 

In the event of contention with a bus request from an external bus master when a transition is made to software standby mode, the  $\overline{BACK}$  and strobe states may be indeterminate after the transition to software standby mode (see figure 6.34).

When software standby mode is used, the BRLE bit should be cleared to 0 in BRCR before executing the SLEEP instruction.



### **6.11 Register and Pin Input Timing**

#### **6.11.1 Register Write Timing**

#### **ABWCR, ASTCR, WCRH, and WCRL Write Timing:** Data written to ABWCR, ASTCR,

WCRH, and WCRL takes effect starting from the next bus cycle. Figure 6.47 shows the timing when an instruction fetched from area 0 changes area 0 from three-state access to two-state access.



**Figure 6.47 ASTCR Write Timing** 

**DDR and CSCR Write Timing:** Data written to DDR or CSCR for the port corresponding to the CSn pin to switch between CSn output and generic input takes effect starting from the  $T_3$  state of the DDR write cycle. Figure 6.48 shows the timing when the  $\overline{CS}_1$  pin is changed from generic input to  $\overline{\text{CS}}_1$  output.



**Figure 6.48 DDR Write Timing** 

**BRCR Write Timing:** Data written to BRCR to switch between  $A_{23}$ ,  $A_{21}$ ,  $A_{21}$ , or  $A_{20}$  output and generic input or output takes effect starting from the  $T_3$  state of the BRCR write cycle. Figure 6.49 shows the timing when a pin is changed from generic input to  $A_{23}$ ,  $A_{22}$ ,  $A_{21}$ , or  $A_{20}$  output.



**Figure 6.49 BRCR Write Timing** 

# **6.11.2** BREQ **Pin Input Timing**

After driving the  $\overline{BREQ}$  pin low, hold it low until  $\overline{BACK}$  goes low. If  $\overline{BREQ}$  returns to the high level before  $\overline{BACK}$  goes lows, the bus arbiter may operate incorrectly.

To terminate the external-bus-released state, hold the  $\overline{BREQ}$  signal high for at least three states. If BREQ is high for too short an interval, the bus arbiter may operate incorrectly.


# Section 7 DMA Controller

### **7.1 Overview**

The H8/3006 and H8/3007 have an on-chip DMA controller (DMAC) that can transfer data on up to four channels.

When the DMA controller is not used, it can be independently halted to conserve power. For details see section 19.6, Module Standby Function.

#### **7.1.1 Features**

DMAC features are listed below.

- Selection of short address mode or full address mode
	- Short address mode
	- ⎯ 8-bit source address and 24-bit destination address, or vice versa
	- ⎯ Maximum four channels available
	- Selection of I/O mode, idle mode, or repeat mode

Full address mode

- ⎯ 24-bit source and destination addresses
- ⎯ Maximum two channels available
- Selection of normal mode or block transfer mode
- Directly addressable 16-Mbyte address space
- Selection of byte or word transfer
- Activation by internal interrupts, external requests, or auto-request (depending on transfer mode)
	- $\sim$  16-bit integrated timer unit (ITU) compare match/input capture interrupts ( $\times$ 3)
	- ⎯ Serial communication interface (SCI channel 0) transmit-data-empty/receive-data-full interrupts
	- External requests
	- Auto-request
	- A/D converter conversion-end interrupt

### **7.1.2 Block Diagram**

Figure 7.1 shows a DMAC block diagram.



**Figure 7.1 Block Diagram of DMAC** 

### **7.1.3 Functional Overview**

Table 7.1 gives an overview of the DMAC functions.





### **7.1.4 Pin Configuration**

Table 7.2 lists the DMAC pins.

#### **Table 7.2 DMAC Pins**



Note: External requests cannot be made to channel A in short address mode.

#### **7.1.5 Register Configuration**

Table 7.3 lists the DMAC registers.

### **Table 7.3 DMAC Registers**





Note: \* The lower 20 bits of the address are indicated.

### **7.2 Register Descriptions (1) (Short Address Mode)**

In short address mode, transfers can be carried out independently on channels A and B. Short address mode is selected by bits DTS2A and DTS1A in data transfer control register A (DTCRA) as indicated in table 7.4.

#### **Table 7.4 Selection of Short and Full Address Modes**



### **7.2.1 Memory Address Registers (MAR)**

A memory address register (MAR) is a 32-bit readable/writable register that specifies a source or destination address. The transfer direction is determined automatically from the activation source.

An MAR consists of four 8-bit registers designated MARR, MARE, MARH, and MARL. All bits of MARR are reserved; they cannot be modified and are always read as 1.



Source or destination address

An MAR functions as a source or destination address register depending on how the DMAC is activated: as a destination address register if activation is by a receive-data-full interrupt from the serial communication interface (SCI) (channel 0) or by a conversion-end interrupt from the A/D converter, and as a source address register otherwise.

The MAR value is incremented or decremented each time one byte or word is transferred, automatically updating the source or destination memory address. For details, see section 7.3.4, Data Transfer Control Registers (DTCR).

The MARs are not initialized by a reset or in standby mode.

### **7.2.2 I/O Address Registers (IOAR)**

An I/O address register (IOAR) is an 8-bit readable/writable register that specifies a source or destination address. The IOAR value is the lower 8 bits of the address. The upper 16 address bits are all 1 (H'FFFF).



An IOAR functions as a source or destination address register depending on how the DMAC is activated: as a source address register if activation is by a receive-data-full interrupt from the SCI

(channel 0) or by a conversion-end interrupt from the A/D converter, and as a destination address register otherwise.

The IOAR value is held fixed. It is not incremented or decremented when a transfer is executed.

The IOARs are not initialized by a reset or in standby mode.

#### **7.2.3 Execute Transfer Count Registers (ETCR)**

An execute transfer count register (ETCR) is a 16-bit readable/writable register that specifies the number of transfers to be executed. These registers function in one way in I/O mode and idle mode, and another way in repeat mode.

I/O mode and idle mode



In I/O mode and idle mode, ETCR functions as a 16-bit counter. The count is decremented by 1 each time one transfer is executed. The transfer ends when the count reaches H'0000.

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Repeat mode

Bit Initial value Read/Write 7 R/W 6 R/W 5 R/W 4 R/W 3 R/W 0 R/W 2 R/W 1 R/W Undetermined Transfer counter **ETCRH** Bit Initial value Read/Write 7 R/W 6 R/W 5 R/W 4 R/W 3 R/W 0 R/W 2 R/W 1 R/W Undetermined Initial count **ETCRL** 

In repeat mode, ETCRH functions as an 8-bit transfer counter and ETCRL holds the initial transfer count. ETCRH is decremented by 1 each time one transfer is executed. When ETCRH reaches H'00, the value in ETCRL is reloaded into ETCRH and the same operation is repeated.

The ETCRs are not initialized by a reset or in standby mode.



#### **7.2.4 Data Transfer Control Registers (DTCR)**

A data transfer control register (DTCR) is an 8-bit readable/writable register that controls the operation of one DMAC channel.



The DTCRs are initialized to H'00 by a reset and in standby mode.

**Bit 7—Data Transfer Enable (DTE):** Enables or disables data transfer on a channel. When the DTE bit is set to 1, the channel waits for a transfer to be requested, and executes the transfer when activated as specified by bits DTS2 to DTS0. When DTE is 0, the channel is disabled and does not accept transfer requests. DTE is set to 1 by reading the register when DTE is 0, then writing 1.



If DTIE is set to 1, a CPU interrupt is requested when DTE is cleared to 0.

**Bit 6—Data Transfer Size (DTSZ):** Selects the data size of each transfer.



**Bit 5—Data Transfer Increment/Decrement (DTID):** Selects whether to increment or decrement the memory address register (MAR) after a data transfer in I/O mode or repeat mode.



MAR is not incremented or decremented in idle mode.

Bit 4-Repeat Enable (RPE): Selects whether to transfer data in I/O mode, idle mode, or repeat mode.



Operations in these modes are described in sections 7.4.2, I/O Mode, 7.4.3, Idle Mode, and 7.4.4, Repeat Mode.

**Bit 3—Data Transfer Interrupt Enable (DTIE):** Enables or disables the CPU interrupt (DEND) requested when the DTE bit is cleared to 0.



**Bits 2 to 0—Data Transfer Select (DTS2 to DTS0):** These bits select the data transfer activation source. Some of the selectable sources differ between channels A and B.\*

Note: \* See section 7.3.4, Data Transfer Control Registers (DTCR).



The same internal interrupt can be selected as an activation source for two or more channels at once. In that case the channels are activated in a priority order, highest-priority channel first. For the priority order, see section 7.4.9, Multiple-Channel Operation.

When a channel is enabled ( $DTE = 1$ ), its selected DMAC activation source cannot generate a CPU interrupt.

## **7.3 Register Descriptions (2) (Full Address Mode)**

In full address mode the A and B channels operate together. Full address mode is selected as indicated in table 7.4.

### **7.3.1 Memory Address Registers (MAR)**

A memory address register (MAR) is a 32-bit readable/writable register. MARA functions as the source address register of the transfer, and MARB as the destination address register.

An MAR consists of four 8-bit registers designated MARR, MARE, MARH, and MARL. All bits of MARR are reserved; they cannot be modified and are always read as 1. (Write is invalid.)



Source or destination address

The MAR value is incremented or decremented each time one byte or word is transferred, automatically updating the source or destination memory address. For details, see section 7.3.4, Data Transfer Control Registers (DTCR).

The MARs are not initialized by a reset or in standby mode.

### **7.3.2 I/O Address Registers (IOAR)**

The I/O address registers (IOARs) are not used in full address mode.



#### **7.3.3 Execute Transfer Count Registers (ETCR)**

An execute transfer count register (ETCR) is a 16-bit readable/writable register that specifies the number of transfers to be executed. The functions of these registers differ between normal mode and block transfer mode.

Normal mode

• ETCRA



ETCRB: Is not used in normal mode.

In normal mode ETCRA functions as a 16-bit transfer counter. The count is decremented by 1 each time one transfer is executed. The transfer ends when the count reaches H'0000. ETCRB is not used.

Block transfer mode

• ETCRA





In block transfer mode, ETCRAH functions as an 8-bit block size counter. ETCRAL holds the initial block size. ETCRAH is decremented by 1 each time one byte or word is transferred. When the count reaches H'00, ETCRAH is reloaded from ETCRAL. Blocks consisting of an arbitrary number of bytes or words can be transferred repeatedly by setting the same initial block size value in ETCRAH and ETCRAL.

In block transfer mode ETCRB functions as a 16-bit block transfer counter. ETCRB is decremented by 1 each time one block is transferred. The transfer ends when the count reaches H'0000.

The ETCRs are not initialized by a reset or in standby mode.



### **7.3.4 Data Transfer Control Registers (DTCR)**

The data transfer control registers (DTCRs) are 8-bit readable/writable registers that control the operation of the DMAC channels. A channel operates in full address mode when bits DTS2A and DTS1A are both set to 1 in DTCRA. DTCRA and DTCRB have different functions in full address mode.

### **DTCRA**



DTCRA is initialized to H'00 by a reset and in standby mode.

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**Bit 7—Data Transfer Enable (DTE):** Together with the DTME bit in DTCRB, this bit enables or disables data transfer on the channel. When the DTME and DTE bits are both set to 1, the channel is enabled. If auto-request is specified, data transfer begins immediately. Otherwise, the channel waits for transfers to be requested. When the specified number of transfers have been completed, the DTE bit is automatically cleared to 0. When DTE is 0, the channel is disabled and does not accept transfer requests. DTE is set to 1 by reading the register when DTE is 0, then writing 1.



If DTIE is set to 1, a CPU interrupt is requested when DTE is cleared to 0.





#### **Bit 5**⎯**Source Address Increment/Decrement (SAID) and,**

**Bit 4**⎯**Source Address Increment/Decrement Enable (SAIDE):** These bits select whether the source address register (MARA) is incremented, decremented, or held fixed during the data transfer.



**Bit 3—Data Transfer Interrupt Enable (DTIE):** Enables or disables the CPU interrupt (DEND) requested when the DTE bit is cleared to 0.



**Bits 2 and 1—Data Transfer Select 2A and 1A (DTS2A, DTS1A):** A channel operates in full address mode when DTS2A and DTS1A are both set to 1.

Bit 0-Data Transfer Select 0A (DTS0A): Selects normal mode or block transfer mode.



Operations in these modes are described in sections 7.4.5, Normal Mode, and 7.4.6, Block Transfer Mode.

### **DTCRB**



DTCRB is initialized to H'00 by a reset and in standby mode.

**Bit 7—Data Transfer Master Enable (DTME):** Together with the DTE bit in DTCRA, this bit enables or disables data transfer. When the DTME and DTE bits are both set to 1, the channel is enabled. When an NMI interrupt occurs DTME is cleared to 0, suspending the transfer so that the CPU can use the bus. The suspended transfer resumes when DTME is set to 1 again. For further information on operation in block transfer mode, see section 7.6.6, NMI Interrupts and Block Transfer Mode.

DTME is set to 1 by reading the register while DTME = 0, then writing 1.



Bit 6—Reserved: Although reserved, this bit can be written and read.

#### Bit 5-Destination Address Increment/Decrement (DAID) and,

**Bit 4**⎯**Destination Address Increment/Decrement Enable (DAIDE):** These bits select whether the destination address register (MARB) is incremented, decremented, or held fixed during the data transfer.



**Bit 3—Transfer Mode Select (TMS):** Selects whether the source or destination is the block area in block transfer mode.



**Bits 2 to 0**⎯**Data Transfer Select 2B to 0B (DTS2B, DTS1B, DTS0B):** These bits select the data transfer activation source. The selectable activation sources differ between normal mode and block transfer mode.

Normal mode



Block transfer mode



The same internal interrupt can be selected to activate two or more channels. The channels are activated in a priority order, highest priority first. For the priority order, see section 7.4.9, Multiple-Channel Operation.

### **7.4 Operation**

#### **7.4.1 Overview**

Table 7.5 summarizes the DMAC modes.

#### **Table 7.5 DMAC Modes**



A summary of operations in these modes follows.

**I/O Mode:** One byte or word is transferred per request. A designated number of these transfers are executed. A CPU interrupt can be requested at completion of the designated number of transfers. One 24-bit address and one 8-bit address are specified. The transfer direction is determined automatically from the activation source.

**Idle Mode:** One byte or word is transferred per request. A designated number of these transfers are executed. A CPU interrupt can be requested at completion of the designated number of transfers. One 24-bit address and one 8-bit address are specified. The addresses are held fixed. The transfer direction is determined automatically from the activation source.

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**Repeat Mode:** One byte or word is transferred per request. A designated number of these transfers are executed. When the designated number of transfers are completed, the initial address and counter value are restored and operation continues. No CPU interrupt is requested. One 24-bit address and one 8-bit address are specified. The transfer direction is determined automatically from the activation source.

### **Normal Mode**

Auto-request

The DMAC is activated by register setup alone, and continues executing transfers until the designated number of transfers have been completed. A CPU interrupt can be requested at completion of the transfers. Both addresses are 24-bit addresses.

- Cycle-steal mode

The bus is released to another bus master after each byte or word is transferred.

- Burst mode

Unless requested by a higher-priority bus master, the bus is not released until the designated number of transfers have been completed.

• External request

One byte or word is transferred per request. A designated number of these transfers are executed. A CPU interrupt can be requested at completion of the designated number of transfers. Both addresses are 24-bit addresses.

**Block Transfer Mode:** One block of a specified size is transferred per request. A designated number of block transfers are executed. At the end of each block transfer, one address is restored to its initial value. When the designated number of blocks have been transferred, a CPU interrupt can be requested. Both addresses are 24-bit addresses.



#### **7.4.2 I/O Mode**

I/O mode can be selected independently for each channel.

One byte or word is transferred at each transfer request in I/O mode. A designated number of these transfers are executed. One address is specified in the memory address register (MAR), the other in the I/O address register (IOAR). The direction of transfer is determined automatically from the activation source. The transfer is from the address specified in IOAR to the address specified in MAR if activated by an SCI channel 0 receive-data-full interrupt or an A/D converter conversion end interrupt, and from the address specified in MAR to the address specified in IOAR otherwise.

Table 7.6 indicates the register functions in I/O mode.





Legend:

MAR: Memory address register

IOAR: I/O address register

ETCR: Execute transfer count register

MAR and IOAR specify the source and destination addresses. MAR specifies a 24-bit source or destination address, which is incremented or decremented as each byte or word is transferred.

IOAR specifies the lower 8 bits of a fixed address. The upper 16 bits are all 1s. IOAR is not incremented or decremented.

Figure 7.2 illustrates how I/O mode operates.



**Figure 7.2 Operation in I/O Mode** 

The transfer count is specified as a 16-bit value in ETCR. The ETCR value is decremented by 1 at each transfer. When the ETCR value reaches H'0000, the DTE bit is cleared and the transfer ends. If the DTIE bit is set to 1, a CPU interrupt is requested at this time. The maximum transfer count is 65,536, obtained by setting ETCR to H'0000.

Transfers can be requested (activated) by compare match/input capture A interrupts from 16-bit timer channels 0 to 2, transmit-data-empty and receive-data-full interrupts from SCI channel 0, conversion-end interrupts from the A/D converter, and external request signals.

For the detailed settings see section 7.2.4, Data Transfer Control Registers (DTCR).

Figure 7.3 shows a sample setup procedure for I/O mode.



**Figure 7.3 I/O Mode Setup Procedure (Example)** 

### **7.4.3 Idle Mode**

Idle mode can be selected independently for each channel.

One byte or word is transferred at each transfer request in idle mode. A designated number of these transfers are executed. One address is specified in the memory address register (MAR), the other in the I/O address register (IOAR). The direction of transfer is determined automatically from the activation source. The transfer is from the address specified in IOAR to the address specified in MAR if activated by an SCI channel 0 receive-data-full interrupt or an A/D converter conversion end interrupt, and from the address specified in MAR to the address specified in IOAR otherwise.

Table 7.7 indicates the register functions in idle mode.

### **Table 7.7 Register Functions in Idle Mode**



Legend:

MAR: Memory address register

IOAR: I/O address register

ETCR: Execute transfer count register

MAR and IOAR specify the source and destination addresses. MAR specifies a 24-bit source or destination address. IOAR specifies the lower 8 bits of a fixed address. The upper 16 bits are all 1s. MAR and IOAR are not incremented or decremented.

Figure 7.4 illustrates how idle mode operates.





**Figure 7.4 Operation in Idle Mode** 

The transfer count is specified as a 16-bit value in ETCR. The ETCR value is decremented by 1 at each transfer. When the ETCR value reaches H'0000, the DTE bit is cleared, the transfer ends, and a CPU interrupt is requested. The maximum transfer count is 65,536, obtained by setting ETCR to H'0000.

Transfers can be requested (activated) by compare match/input capture A interrupts from 16-bit timer channels 0 to 2, transmit-data-empty and receive-data-full interrupts from SCI channel 0, conversion-end interrupts from the A/D converter, and external request signals.

For the detailed settings see section 7.3.4, Data Transfer Control Registers (DTCR).

Figure 7.5 shows a sample setup procedure for idle mode.



**Figure 7.5 Idle Mode Setup Procedure (Example)** 

### **7.4.4 Repeat Mode**

Repeat mode is useful for cyclically transferring a bit pattern from a table to the programmable timing pattern controller (TPC) in synchronization, for example, with 16-bit timer compare match. Repeat mode can be selected for each channel independently.

One byte or word is transferred per request in repeat mode, as in I/O mode. A designated number of these transfers are executed. One address is specified in the memory address register (MAR), the other in the I/O address register (IOAR). At the end of the designated number of transfers, MAR and ETCRH are restored to their original values and operation continues. The direction of transfer is determined automatically from the activation source. The transfer is from the address specified in IOAR to the address specified in MAR if activated by an SCI channel 0 receive-datafull interrupt or an A/D converter conversion end interrupt, and from the address specified in MAR to the address specified in IOAR otherwise.

Table 7.8 indicates the register functions in repeat mode.





Legend:

MAR: Memory address register

IOAR: I/O address register

ETCR: Execute transfer count register

In repeat mode ETCRH is used as the transfer counter while ETCRL holds the initial transfer count. ETCRH is decremented by 1 at each transfer until it reaches H'00, then is reloaded from ETCRL. MAR is also restored to its initial value, which is calculated from the DTSZ and DTID bits in DTCR. Specifically, MAR is restored as follows:

 $MAR \leftarrow MAR - (-1)^{DTID} \bullet 2^{DTSZ} \bullet ETCRL$ 

ETCRH and ETCRL should be initially set to the same value.

In repeat mode transfers continue until the CPU clears the DTE bit to 0. After DTE is cleared to 0, if the CPU sets DTE to 1 again, transfers resume from the state at which DTE was cleared. No CPU interrupt is requested.

As in I/O mode, MAR and IOAR specify the source and destination addresses. MAR specifies a 24-bit source or destination address. IOAR specifies the lower 8 bits of a fixed address. The upper 16 bits are all 1s. IOAR is not incremented or decremented.

Figure 7.6 illustrates how repeat mode operates.



**Figure 7.6 Operation in Repeat Mode** 

The transfer count is specified as an 8-bit value in ETCRH and ETCRL. The maximum transfer count is 255, obtained by setting both ETCRH and ETCRL to H'FF.

Transfers can be requested (activated) by compare match/input capture A interrupts from 16-bit timer channels 0 to 2, transmit-data-empty and receive-data-full interrupts from SCI channel 0, conversion-end interrupts from the A/D converter, and external request signals.

For the detailed settings see section 7.2.4, Data Transfer Control Registers (DTCR).

Figure 7.7 shows a sample setup procedure for repeat mode.



**Figure 7.7 Repeat Mode Setup Procedure (Example)** 

### **7.4.5 Normal Mode**

In normal mode, the A and B channels are combined. One byte or word is transferred per request. A designated number of these transfers are executed. Addresses are specified in MARA and MARB. Table 7.9 indicates the register functions in I/O mode.





Legend:

MARA: Memory address register A

MARB: Memory address register B

ETCRA: Execute transfer count register A

The source and destination addresses are both 24-bit addresses. MARA specifies the source address. MARB specifies the destination address. MARA and MARB can be independently incremented, decremented, or held fixed as data is transferred.

The transfer count is specified as a 16-bit value in ETCRA. The ETCRA value is decremented by 1 at each transfer. When the ETCRA value reaches H'0000, the DTE bit is cleared and the transfer ends. If the DTIE bit is set to 1, a CPU interrupt is requested at this time. The maximum transfer count is 65,536, obtained by setting ETCRA to H'0000.







#### **Figure 7.8 Operation in Normal Mode**

Transfers can be requested (activated) by an external request or auto-request. An auto-requested transfer is activated by the register settings alone. The designated number of transfers are executed automatically. Either cycle-steal or burst mode can be selected. In cycle-steal mode, the DMAC releases the bus temporarily after each transfer. In burst mode, the DMAC keeps the bus until the transfers are completed, unless there is a bus request from a higher-priority bus master.

For the detailed settings see section 7.3.4, Data Transfer Control Registers (DTCR).

Figure 7.9 shows a sample setup procedure for normal mode.



- 1. Set the initial source address in MARA.
- 2. Set the initial destination address in MARB.
- 3. Set the transfer count in ETCRA.
- 4. Set the DTCRB bits as follows.
	- Clear the DTME bit to 0.
	- Set the DAID and DAIDE bits to select whether MARB is incremented, decremented, or held fixed.
	- Select the DMAC activation source with bits DTS2B to DTS0B.
- 5. Set the DTCRA bits as follows.
	- Clear the DTE bit to 0.
	- Select byte or word size with the DTSZ bit.
	- Set the SAID and SAIDE bits to select whether MARA is incremented, decremented, or held fixed.
	- Set or clear the DTIE bit to enable or disable the CPU interrupt at the end of the transfer.
	- Clear the DTS0A bit to 0 and set the DTS2A and DTS1A bits to 1 to select normal mode.
- 6. Read DTCRB with DTME cleared to 0.
- 7. Set the DTME bit to 1 in DTCRB.
- 8. Read DTCRA with DTE cleared to 0.
- 9. Set the DTE bit to 1 in DTCRA to enable the transfer.



**Figure 7.9 Normal Mode Setup Procedure (Example)** 

#### **7.4.6 Block Transfer Mode**

In block transfer mode, the A and B channels are combined. One block of a specified size is transferred per request. A designated number of block transfers are executed. Addresses are specified in MARA and MARB. The block area address can be either held fixed or cycled.

Table 7.10 indicates the register functions in block transfer mode.





Legend:

MARA: Memory address register A

MARB: Memory address register B

ETCRA: Execute transfer count register A

ETCRB: Execute transfer count register B

The source and destination addresses are both 24-bit addresses. MARA specifies the source address. MARB specifies the destination address. MARA and MARB can be independently incremented, decremented, or held fixed as data is transferred. One of these registers operates as a block area register: even if it is incremented or decremented, it is restored to its initial value at the end of each block transfer. The TMS bit in DTCRB selects whether the block area is the source or destination.

If M (1 to 255) is the size of the block transferred at each request and N (1 to 65,536) is the number of blocks to be transferred, then ETCRAH and ETCRAL should initially be set to M and ETCRB should initially be set to N.

Figure 7.10 illustrates how block transfer mode operates. In this figure, bit TMS is cleared to 0, meaning the block area is the destination.





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When activated by a transfer request, the DMAC executes a burst transfer. During the transfer MARA and MARB are updated according to the DTCR settings, and ETCRAH is decremented. When ETCRAH reaches H'00, it is reloaded from ETCRAL to restore the initial value. The memory address register of the block area is also restored to its initial value, and ETCRB is decremented. If ETCRB is not H'0000, the DMAC then waits for the next transfer request. ETCRAH and ETCRAL should be initially set to the same value.

The above operation is repeated until ETCRB reaches H'0000, at which point the DTE bit is cleared to 0 and the transfer ends. If the DTIE bit is set to 1, a CPU interrupt is requested at this time.

Figure 7.11 shows examples of a block transfer with byte data size when the block area is the destination. In (a), the block area address is cycled. In (b), the block area address is held fixed.

Transfers can be requested (activated) by compare match/input capture A interrupts from 16-bit timer channels 0 to 2, by a conversion-end interrupt from the A/D converter, and by external request signals.

For the detailed settings see section 7.3.4, Data Transfer Control Registers (DTCR).



**Figure 7.11 Block Transfer Mode Flowcharts** 

Figure 7.12 shows a sample setup procedure for block transfer mode.





## **7.4.7 DMAC Activation**

The DMAC can be activated by an internal interrupt, external request, or auto-request. The available activation sources differ depending on the transfer mode and channel as indicated in table 7.11.



#### **Table 7.11 DMAC Activation Sources**

**Activation by Internal Interrupts:** When an interrupt request is selected as a DMAC activation source and the DTE bit is set to 1, that interrupt request is not sent to the CPU. It is not possible for an interrupt request to activate the DMAC and simultaneously generate a CPU interrupt.

When the DMAC is activated by an interrupt request, the interrupt request flag is cleared automatically. If the same interrupt is selected to activate two or more channels, the interrupt request flag is cleared when the highest-priority channel is activated, but the transfer request is held pending on the other channels in the DMAC, which are activated in their priority order.

**Activation by External Request:** If an external request (DREQ pin) is selected as an activation source, the DREQ pin becomes an input pin and the corresponding TEND pin becomes an output pin, regardless of the port data direction register (DDR) settings. The DREQ input can be levelsensitive or edge-sensitive.

In short address mode and normal mode, an external request operates as follows. If edge sensing is selected, one byte or word is transferred each time a high-to-low transition of the  $\overline{DRED}$  input is detected. If the next edge is input before the transfer is completed, the next transfer may not be executed. If level sensing is selected, the transfer continues while DREQ is low, until the transfer is completed. The bus is released temporarily after each byte or word has been transferred, however. If the DREQ input goes high during a transfer, the transfer is suspended after the current byte or word has been transferred. When DREQ goes low, the request is held internally until one byte or word has been transferred. The TEND signal goes low during the last write cycle.

In block transfer mode, an external request operates as follows. Only edge-sensitive transfer requests are possible in block transfer mode. Each time a high-to-low transition of the DREQ input is detected, a block of the specified size is transferred. The TEND signal goes low during the last write cycle in each block.

**Activation by Auto-Request:** The transfer starts as soon as enabled by register setup, and continues until completed. Cycle-steal mode or burst mode can be selected.

In cycle-steal mode, the DMAC releases the bus temporarily after transferring each byte or word. Normally, DMAC cycles alternate with CPU cycles.

In burst mode, the DMAC keeps the bus until the transfer is completed, unless there is a higherpriority bus request. If there is a higher-priority bus request, the bus is released after the current byte or word has been transferred.

#### **7.4.8 DMAC Bus Cycle**

Figure 7.13 shows an example of the timing of the basic DMAC bus cycle. This example shows a word-size transfer from a 16-bit two-state access area to an 8-bit three-state access area. When the DMAC gets the bus from the CPU, after one dead cycle  $(T_d)$ , it reads from the source address and writes to the destination address. During these read and write operations the bus is not released even if there is another bus request. DMAC cycles comply with bus controller settings in the same way as CPU cycles.



**Figure 7.13 DMA Transfer Bus Timing (Example)** 

Figure 7.14 shows the timing when the DMAC is activated by low input at a  $\overline{DREG}$  pin. This example shows a word-size transfer from a 16-bit two-state access area to another 16-bit two-state access area. The DMAC continues the transfer while the  $\overline{DREG}$  pin is held low.



**Figure 7.14 Bus Timing of DMA Transfer Requested by Low** DREQ **Input** 



Figure 7.15 shows an auto-requested burst-mode transfer. This example shows a transfer of three words from a 16-bit two-state access area to another 16-bit two-state access area.

**Figure 7.15 Burst DMA Bus Timing** 

When the DMAC is activated from a  $\overline{DRED}$  pin there is a minimum interval of four states from when the transfer is requested until the DMAC starts operating\*. The DREQ pin is not sampled during the time between the transfer request and the start of the transfer. In short address mode and normal mode, the pin is next sampled at the end of the read cycle. In block transfer mode, the pin is next sampled at the end of one block transfer.

Note: \* The minimum response time is also four states when the DMAC is activated by an internal module interrupt.

Figure 7.16 shows the timing when the DMAC is activated by the falling edge of DREQ in normal mode.



Figure 7.16 Timing of DMAC Activation by Falling Edge of **DREQ** in Normal Mode



Figure 7.17 shows the timing when the DMAC is activated by level-sensitive low  $\overline{DREQ}$  input in normal mode.



**Figure 7.17 Timing of DMAC Activation by Low** DREQ **Level in Normal Mode** 

Figure 7.18 shows the timing when the DMAC is activated by the falling edge of DREQ in block transfer mode.



Figure 7.18 Timing of DMAC Activation by Falling Edge of **DREQ** in Block Transfer Mode

#### **7.4.9 Multiple-Channel Operation**

The DMAC channel priority order is: channel  $0 >$  channel 1 and channel  $A >$  channel B.

Table 7.12 shows the complete priority order.

#### **Table 7.12 Channel Priority Order**



If transfers are requested on two or more channels simultaneously, or if a transfer on one channel is requested during a transfer on another channel, the DMAC operates as follows.

- When a transfer is requested, the DMAC requests the bus right. When it gets the bus right, it starts a transfer on the highest-priority channel at that time.
- Once a transfer starts on one channel, requests to other channels are held pending until that channel releases the bus.
- After each transfer in short address mode, and each externally-requested or cycle-steal transfer in normal mode, the DMAC releases the bus and returns to step 1. After releasing the bus, if there is a transfer request for another channel, the DMAC requests the bus again.
- After completion of a burst-mode transfer, or after transfer of one block in block transfer mode, the DMAC releases the bus and returns to step 1. If there is a transfer request for a higher-priority channel or a bus request from a higher-priority bus master, however, the DMAC releases the bus after completing the transfer of the current byte or word. After releasing the bus, if there is a transfer request for another channel, the DMAC requests the bus again.

Figure 7.19 shows the timing when channel 0A is set up for I/O mode and channel 1 for burst mode, and a transfer request for channel 0A is received while channel 1 is active.



**Figure 7.19 Timing of Multiple-Channel Operations**

#### **7.4.10 External Bus Requests, DRAM Interface, and DMAC**

During a DMAC transfer, if the bus right is requested by an external bus request signal (BREQ) or by the DRAM interface (refresh cycle), the DMAC releases the bus after completing the transfer of the current byte or word. If there is a transfer request at this point, the DMAC requests the bus right again. Figure 7.20 shows an example of the timing of insertion of a refresh cycle during a burst transfer on channel 0.



**Figure 7.20 Bus Timing of DRAM Interface and DMAC**

#### **7.4.11 NMI Interrupts and DMAC**

NMI interrupts do not affect DMAC operations in short address mode.

If an NMI interrupt occurs during a transfer in full address mode, the DMAC suspends operations. In full address mode, a channel is enabled when its DTE and DTME bits are both set to 1. NMI input clears the DTME bit to 0. After transferring the current byte or word, the DMAC releases the bus to the CPU. In normal mode, the suspended transfer resumes when the CPU sets the DTME bit to 1 again. Check that the DTE bit is set to 1 and the DTME bit is cleared to 0 before setting the DTME bit to 1.

Figure 7.21 shows the procedure for resuming a DMAC transfer in normal mode on channel 0 after the transfer was halted by NMI input.



**Figure 7.21 Procedure for Resuming a DMAC Transfer Halted by NMI (Example)** 

For information about NMI interrupts in block transfer mode, see section 7.6.6, NMI Interrupts and Block Transfer Mode.

## **7.4.12 Aborting a DMAC Transfer**

When the DTE bit in an active channel is cleared to 0, the DMAC halts after transferring the current byte or word. The DMAC starts again when the DTE bit is set to 1. In full address mode, the DTME bit can be used for the same purpose. Figure 7.22 shows the procedure for aborting a DMAC transfer by software.



**Figure 7.22 Procedure for Aborting a DMAC Transfer** 



#### **7.4.13 Exiting Full Address Mode**

Figure 7.23 shows the procedure for exiting full address mode and initializing the pair of channels. To set the channels up in another mode after exiting full address mode, follow the setup procedure for the relevant mode.



**Figure 7.23 Procedure for Exiting Full Address Mode (Example)** 

## **7.4.14 DMAC States in Reset State, Standby Modes, and Sleep Mode**

When the chip is reset or enters hardware standby mode or software standby mode, the DMAC is initialized and halts. DMAC operations continue in sleep mode. Figure 7.24 shows the timing of a cycle-steal transfer in sleep mode.



**Figure 7.24 Timing of Cycle-Steal Transfer in Sleep Mode** 

## **7.5 Interrupts**

The DMAC generates only DMA-end interrupts. Table 7.13 lists the interrupts and their priority.

## **Table 7.13 DMAC Interrupts**



Each interrupt is enabled or disabled by the DTIE bit in the corresponding data transfer control register (DTCR). Separate interrupt signals are sent to the interrupt controller.

The interrupt priority order among channels is channel  $0 >$  channel 1 and channel A  $>$  channel B.

Figure 7.25 shows the DMA-end interrupt logic. An interrupt is requested whenever  $DTE = 0$  and  $DTIE = 1.$ 



**Figure 7.25 DMA-End Interrupt Logic** 

The DMA-end interrupt for the B channels (DENDB) is unavailable in full address mode. The DTME bit does not affect interrupt operations.

## **7.6 Usage Notes**

#### **7.6.1 Note on Word Data Transfer**

Word data cannot be accessed starting at an odd address. When word-size transfer is selected, set even values in the memory and I/O address registers (MAR and IOAR).

#### **7.6.2 DMAC Self-Access**

The DMAC itself cannot be accessed during a DMAC cycle. DMAC registers cannot be specified as source or destination addresses.

## **7.6.3 Longword Access to Memory Address Registers**

A memory address register can be accessed as longword data at the MARR address.

Example

MOV.L #LBL, ER0 MOV.L ER0, @MARR

Four byte accesses are performed. Note that the CPU may release the bus between the second byte (MARE) and third byte (MARH).

Memory address registers should be written and read only when the DMAC is halted.

## **7.6.4 Note on Full Address Mode Setup**

Full address mode is controlled by two registers: DTCRA and DTCRB. Care must be taken to prevent the B channel from operating in short address mode during the register setup. The enable bits (DTE and DTME) should not be set to 1 until the end of the setup procedure.



#### **7.6.5 Note on Activating DMAC by Internal Interrupts**

When using an internal interrupt to activate the DMAC, make sure that the interrupt selected as the activating source does not occur during the interval after it has been selected but before the DMAC has been enabled. The on-chip supporting module that will generate the interrupt should not be activated until the DMAC has been enabled. If the DMAC must be enabled while the onchip supporting module is active, follow the procedure in figure 7.26.



#### **Figure 7.26 Procedure for Enabling DMAC while On-Chip Supporting Module Is Operating (Example)**

If the DTE bit is set to 1 but the DTME bit is cleared to 0, the DMAC is halted and the selected activating source cannot generate a CPU interrupt. If the DMAC is halted by an NMI interrupt, for example, the selected activating source cannot generate CPU interrupts. To terminate DMAC operations in this state, clear the DTE bit to 0 to allow CPU interrupts to be requested. To continue DMAC operations, carry out steps 2 and 4 in figure 7.26 before and after setting the DTME bit to 1.

When an ITU interrupt activates the DMAC, make sure the next interrupt does not occur before the DMA transfer ends. If one 16-bit timer interrupt activates two or more channels, make sure the next interrupt does not occur before the DMA transfers end on all the activated channels. If the next interrupt occurs before a transfer ends, the channel or channels for which that interrupt was selected may fail to accept further activation requests.

### **7.6.6 NMI Interrupts and Block Transfer Mode**

If an NMI interrupt occurs in block transfer mode, the DMAC operates as follows.

• When the NMI interrupt occurs, the DMAC finishes transferring the current byte or word, then clears the DTME bit to 0 and halts. The halt may occur in the middle of a block.

It is possible to find whether a transfer was halted in the middle of a block by checking the block size counter. If the block size counter does not have its initial value, the transfer was halted in the middle of a block.

- If the transfer is halted in the middle of a block, the activating interrupt flag is cleared to 0. The activation request is not held pending.
- While the DTE bit is set to 1 and the DTME bit is cleared to 0, the DMAC is halted and does not accept activating interrupt requests. If an activating interrupt occurs in this state, the DMAC does not operate and does not hold the transfer request pending internally. Neither is a CPU interrupt requested.

For this reason, before setting the DTME bit to 1, first clear the enable bit of the activating interrupt to 0. Then, after setting the DTME bit to 1, set the interrupt enable bit to 1 again. See section 7.6.5, Note on Activating DMAC by Internal Interrupts.

• When the DTME bit is set to 1, the DMAC waits for the next transfer request. If it was halted in the middle of a block transfer, the rest of the block is transferred when the next transfer request occurs. Otherwise, the next block is transferred when the next transfer request occurs.

## **7.6.7 Memory and I/O Address Register Values**

Table 7.14 indicates the address ranges that can be specified in the memory and I/O address registers (MAR and IOAR).



#### **Table 7.14 Address Ranges Specifiable in MAR and IOAR**

MAR bits 23 to 20 are ignored in 1-Mbyte mode.

#### **7.6.8 Bus Cycle when Transfer Is Aborted**

When a transfer is aborted by clearing the DTE bit or suspended by an NMI that clears the DTME bit, if this halts a channel for which the DMAC has a transfer request pending internally, a dead cycle may occur. This dead cycle does not update the halted channel's address register or counter value. Figure 7.27 shows an example in which an auto-requested transfer in cycle-steal mode on channel 0 is aborted by clearing the DTE bit in channel 0.



**Figure 7.27 Bus Timing at Abort of DMA Transfer in Cycle-Steal Mode** 

#### **7.6.9 Transfer Requests by A/D Converter**

When the A/D converter is set to scan mode and conversion is performed on more than one channel, the A/D converter generates a transfer request when all conversions are completed. The converted data is stored in the appropriate ADDR registers. Block transfer mode and full address mode should therefore be used to transfer all the conversion results at one time.

# Section 8 I/O Ports

## **8.1 Overview**

The H8/3006 and H8/3007 have 6 input/output ports (ports 4, 6, 8, 9, A, and B) and one input-only port (port 7). Table 8.1 summarizes the port functions. The pins in each port are multiplexed as shown in table 8.1.

Each port has a data direction register (DDR) for selecting input or output, and a data register (DR) for storing output data. In addition to these registers, port 4 has an input pull-up MOS control register (PCR) for switching input pull-up transistors on and off.

Ports 4, 6, and 8 can drive one TTL load and a 90-pF capacitive load. Ports 9, A, and B can drive one TTL load and a 30-pF capacitive load. Ports 4, 6 and 8 to B can drive a darlington transistor pair. Pins  $P8_2$  to  $P8_0$ ,  $PA_7$  to  $PA_0$  have Schmitt-trigger input circuits.

For block diagrams of the ports see appendix C, I/O Port Block Diagrams.

## **Table 8.1 Port Functions**





## **8.2 Port 4**

## **8.2.1 Overview**

Port 4 is an 8-bit input/output port with the pin configuration shown in figure 8.1.

When the bus width control register (ABWCR) designates areas 0 to 7 all as 8-bit-access areas, the chip operates in 8-bit bus mode and port 4 is a generic input/output port. When at least one of areas 0 to 7 is designated as a 16-bit-access area, the chip operates in 16-bit bus mode and port 4 becomes part of the data bus.

Port 4 has software-programmable built-in pull-up transistors.

Pins in port 4 can drive one TTL load and a 90-pF capacitive load. They can also drive a darlington transistor pair.

	Port 4 pins	Modes 1 to 4
Port 4	$P4_7/D_7$ $P4_6/D_6$ $P4_5/D_5$ $P4_4/D_4$ $P4_{3}/D_{3}$ P4 <sub>2</sub> /D <sub>2</sub> $P4_1/D_1$ $P4_0/D_0$	$P47$ (input/output)/D <sub>7</sub> (input/output) $P4_6$ (input/output)/ $D_6$ (input/output) $P4_5$ (input/output)/ $D_5$ (input/output) $P4_4$ (input/output)/ $D_4$ (input/output) $P4_3$ (input/output)/ $D_3$ (input/output) P4 <sub>2</sub> (input/output)/D <sub>2</sub> (input/output) $P4_1$ (input/output)/D <sub>1</sub> (input/output) $P4_0$ (input/output)/D <sub>0</sub> (input/output)

**Figure 8.1 Port 4 Pin Configuration** 

#### **8.2.2 Register Configuration**

Table 8.2 summarizes the registers of port 4.

#### **Table 8.2 Port 4 Registers**



Note: \* Lower 20 bits of the address in advanced mode.

**Port 4 Data Direction Register (P4DDR):** P4DDR is an 8-bit write-only register that can select input or output for each pin in port 4.



**Port 4 data direction 7 to 0**

These bits select input or output for port 4 pins

When all areas are designated as 8-bit-access areas by the bus controller's bus width control register (ABWCR), selecting 8-bit bus mode, port 4 functions as an input/output port. In this case, a pin in port 4 becomes an output port if the corresponding P4DDR bit is set to 1, and an input port if this bit is cleared to 0.

When at least one area is designated as a 16-bit-access area, selecting 16-bit bus mode, port 4 functions as part of the data bus, regardless of the P4DDR settings.

P4DDR is initialized to H'00 by a reset and in hardware standby mode. In software standby mode it retains its previous setting.

ABWCR and P4DDR are not initialized in software standby mode. When port 4 functions as a generic input/output port, if a P4DDR bit is set to 1, the corresponding pin maintains its output state in software standby mode.

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**Port 4 Data Register (P4DR):** P4DR is an 8-bit readable/writable register that stores output data for port 4. When port 4 functions as an output port, the value of this register is output. When a bit in P4DDR is set to 1, if port 4 is read the value of the corresponding P4DR bit is returned. When a bit in P4DDR is cleared to 0, if port 4 is read the corresponding pin level is read.



**Port 4 data 7 to 0** These bits store data for port 4 pins

P4DR is initialized to H'00 by a reset and in hardware standby mode. In software standby mode it retains its previous setting.

**Port 4 Input Pull-Up MOS Control Register (P4PCR):** P4PCR is an 8-bit readable/writable register that controls the MOS input pull-up transistors in port 4.



**Port 4 input pull-up control 7 to 0**

These bits control input pull-up transistors built into port 4

In 8-bit bus mode when a P4DDR bit is cleared to 0 (selecting generic input), if the corresponding P4PCR bit is set to 1, the input pull-up transistor is turned on.

P4PCR is initialized to H'00 by a reset and in hardware standby mode. In software standby mode it retains its previous setting.

Table 8.3 summarizes the states of the input pull-ups in each operating mode.







Legend:

Off: The input pull-up transistor is always off.

On/off: The input pull-up transistor is on if  $P4PCR = 1$  and  $P4DDR = 0$ . Otherwise, it is off.

#### **8.3 Port 6**

#### **8.3.1 Overview**

Port 6 is an 4-bit input/output port that is also used for input and output of bus control signals  $(\overline{BACK}, \overline{BREG}, \overline{WAIT})$  and for clock  $(\phi)$  output.

The port 6 pin configuration is shown in figure 8.2.

The pin in port 6 functions are  $P6_7$  (generic input)/ $\phi$ ,  $P6_7$  $\overline{BACK}$ ,  $P6_1$  $\overline{BREQ}$ , and  $P6_0$  $\overline{WAIT}$ . See table 8.5 for the selection of the pin functions.

See Section 19, Power-Down State, for clock output pin. See Section 6, Bus Controller, for bus control I/O pin (BACK, BREQ and WAIT).

Pins in port 6 can drive one TTL load and a 90-pF capacitive load. They can also drive a darlington transistor pair.





#### **8.3.2 Register Configuration**

Table 8.4 summarizes the registers of port 6.

#### **Table 8.4 Port 6 Registers**



Note: \* Lower 20 bits of the address in advanced mode.

**Port 6 Data Direction Register (P6DDR):** P6DDR is an 8-bit write-only register that can select input or output for each pin in port 6.

Bits 7 to 3 are reserved. Bit 7 is fixed at 1, and cannot be modified.



P6<sub>7</sub> functions as the clock output pin ( $\phi$ ) or an input port. P6<sub>7</sub> is the clock input pin ( $\phi$ ) if the PSTOP bit in MSTCRH is cleared to 0 (initial value), and an input port if this bit is set to 1.

When  $P6_2$  to  $P6_0$  function as input/output ports, the pin becomes an output port if the corresponding P6DDR bit is set to 1, and an input port if this bit is cleared to 0.

P6DDR is a write-only register. Its value cannot be read. All bits return 1 when read.

P6DDR is initialized to H'80 by a reset and in hardware standby mode. In software standby mode, it retains its previous setting. When port 6 functions as a generic input/output port, if a P6DDR bit is set to 1, the corresponding pin maintains its output state in software standby mode.

**Port 6 Data Register (P6DR):** P6DR is an 8-bit readable/writable register that stores output data for port 6. When port 6 functions as an output port, the value of this register is output.



Note:  $*$  Determined by pin  $P6<sub>7</sub>$ .

Bit 7 returns 1 if read when the PSTOP bit in MSTCRH is 0, and returns the logic level of pin P6. if read when the PSTOP bit is 1. This bit cannot be modified.

Bits 6 to 3 are reserved; they can be read and written to, but cannot be used as ports.

The P6DR value is returned if P6DR is read while the corresponding bit  $(P6,DDR)$  to P6,DDR) in P6DDR is set to 1, and an undefined value is returned if P6DR is read while the corresponding bit is cleared to 0.

For bits 2 to 0, the pin logic level is returned if the bit is read while the corresponding bit in P6DDR is cleared to 0, and the P6DR value is returned if the bit is read while the corresponding bit in P6DDR is set to 1.

P6DR is initialized to H'80 by a reset and in hardware standby mode. In software standby mode it retains its previous setting.



#### **Table 8.5 Port 6 Pin Functions**

## **8.4 Port 7**

#### **8.4.1 Overview**

Port 7 is an 8-bit input-only port that is also used for analog input to the A/D converter and analog output from the D/A converter. The pin functions are the same in all operating modes. Figure 8.3 shows the pin configuration of port 7.

See section 15, A/D Converter, for details of the A/D converter analog input pins, and section 16, D/A Converter, for details of the D/A converter analog output pins.



**Figure 8.3 Port 7 Pin Configuration** 

#### **8.4.2 Register Configuration**

Table 8.6 summarizes the port 7 register. Port 7 is an input-only port, and so has no data direction register.

#### **Table 8.6 Port 7 Data Register**



Note: \* Lower 20 bits of the address in advanced mode.

#### **Port 7 Data Register (P7DR)**



Note:  $*$  Determined by pins P7<sub>7</sub> to P7 $_0$ .

When port 7 is read, the pin logic levels are always read. P7DR cannot be modified.

## **8.5 Port 8**

#### **8.5.1 Overview**

Port 8 is a 5-bit input/output port that is also used for  $CS_3$  to  $CS_0$  output, RFSH output, IRQ<sub>3</sub> to  $\overline{\text{IRQ}}_0$  input, and A/D converter  $\overline{\text{ADTRG}}$  input. Figure 8.4 shows the pin configuration of port 8.

See table 8.8 for the selection of pin functions.

See section 15, A/D Converter, for a description of the A/D converter's ADTRG input pin.

The  $\overline{IRQ}_3$  to  $\overline{IRQ}_0$  functions are selected by IER settings, regardless of whether the pin is used for input or output. Caution is therefore required. For details see section 5, Interrupt Controller.

When DRAM is connected to areas 2 to 5, the  $\overline{CS}_3$  and  $\overline{CS}_2$  output pins function as  $\overline{RAS}$  output pins for each area. For details see section 6.5, DRAM Interface.

Pins in port 8 can drive one TTL load and a 90-pF capacitive load. They can also drive a darlington transistor pair.

Pins  $P8_2$  to  $P8_0$  have Schmitt-trigger inputs.







#### **8.5.2 Register Configuration**

Table 8.7 summarizes the registers of port 8.

#### **Table 8.7 Port 8 Registers**



Note: \* Lower 20 bits of the address in advanced mode.

**Port 8 Data Direction Register (P8DDR):** P8DDR is an 8-bit write-only register that can select input or output for each pin in port 8.

Bits 7 to 5 are reserved. They are fixed at 1, and cannot be modified.



When bits in P8DDR bit are set to 1,  $P8_4$  to  $P8_1$  become  $\overline{CS}_0$  to  $\overline{CS}_3$  output pins. When bits in P8DDR are cleared to 0, the corresponding pins become input ports. Following a reset  $P8<sub>4</sub>$ functions as the  $\overline{CS}_0$  output, while the other three pins are input ports.

When the refresh enable bit (RFSHE) in DRCRA is set to 1,  $P8_0$  is used for  $\overline{RFSH}$  output. When RFSHE is cleared to 0,  $P8_0$  becomes an input/output port according to the P8DDR setting. For details see table 8.8.

P8DDR is a write-only register. Its value cannot be read. All bits return 1 when read.

P8DDR is initialized to H'F0 by a reset and in hardware standby mode. In software standby mode P8DDR retains its previous setting. Therefore, when port 8 functions as an input/output port, if a transition is made to software standby mode while a P8DDR bit is set to 1, the corresponding pin maintains its output state.

**Port 8 Data Register (P8DR):** P8DR is an 8-bit readable/writable register that stores output data for port 8. When a bit in P8DDR is set to 1, if port 8 is read the value of the corresponding P8DR bit is returned. When a bit in P8DDR is cleared to 0, if port 8 is read the corresponding pin level is read.



Bits 7 to 5 are reserved. They cannot be modified and always are read as 1.

P8DR is initialized to H'E0 by a reset and in hardware standby mode. In software standby mode it retains its previous setting.


## **Table 8.8 Port 8 Pin Functions**



## **8.6 Port 9**

#### **8.6.1 Overview**

Port 9 is a 6-bit input/output port that is also used for input and output  $(TxD_0, TxD_1, RxD_0, RxD_1, yD_2, fD_2, fD_3, fD_4, fD_5, fD_6, fD_7, fD_8, fD_9, fD_1, fD_2, fD_3, fD_4, fD_5, fD_6, fD_7, fD_8, fD_9, fD_1, fD_2, fD_3, fD_4, fD_6, fD_7, fD_8,$ SCK<sub>0</sub>, SCK<sub>1</sub>) by serial communication interface channels 0 and 1 (SCI0 and SCI1), and for  $\overline{IRQ}_s$ and  $\overline{\text{IRQ}}_4$  input. See table 8.10 for the selection of pin functions.

The  $\overline{IRQ}_s$  and  $\overline{IRQ}_4$  functions are selected by IER settings, regardless of whether the pin is used for input or output. Caution is therefore required. For details see section 5.3.1, External Interrupts.

Port 9 has the same set of pin functions in all operating modes. Figure 8.5 shows the pin configuration of port 9.

Pins in port 9 can drive one TTL load and a 30-pF capacitive load. They can also drive a darlington transistor pair.



**Figure 8.5 Port 9 Pin Configuration** 

## **8.6.2 Register Configuration**

Table 8.9 summarizes the registers of port 9.

#### **Table 8.9 Port 9 Registers**



Note: \* Lower 20 bits of the address in advanced mode.

**Port 9 Data Direction Register (P9DDR):** P9DDR is an 8-bit write-only register that can select input or output for each pin in port 9.

Bits 7 and 6 are reserved. They cannot be modified and always read as 1.



When a pin in port 9 becomes an output port if the corresponding P9DDR bit is set to 1, and an input port if this bit is cleared to 0.

P9DDR is a write-only register. Its value cannot be read. All bits return 1 when read.

P9DDR is initialized to H'C0 by a reset and in hardware standby mode. In software standby mode it retains its previous setting. When transition is made to software standby mode while a P9DDR bit is set to 1, the corresponding pin maintains its output state.

**Port 9 Data Register (P9DR):** P9DR is an 8-bit readable/writable register that stores output data for port 9. When port 9 functions as an output port, the value of this register is output. When a bit in P9DDR is set to 1, if port 9 is read the value of the corresponding P9DR bit is returned. When a bit in P9DDR is cleared to 0, if port 9 is read the corresponding pin level is read.

Bits 7 and 6 are reserved. They cannot be modified and are always read as 1.



P9DR is initialized to H'C0 by a reset and in hardware standby mode. In software standby mode it retains its previous setting.

## **Table 8.10 Port 9 Pin Functions**





## **8.7 Port A**

## **8.7.1 Overview**

Port A is an 8-bit input/output port that is also used for output  $(TP_7$  to  $TP_0$ ) from the programmable timing pattern controller (TPC), input and output, (TIOCB<sub>2</sub>, TIOCA<sub>2</sub>, TIOCB<sub>1</sub>, TIOCA<sub>1</sub>, TIOCB<sub>0</sub>, TIOCA<sub>0</sub>, TCLKD, TCLKC, TCLKB, TCLKA) by the 16-bit timer, input (TCLKD, TCLKC, TCLKB, TCLKA) to the 8-bit timer, output  $(TEND_1, TEND_0)$  from the DMA controller (DMAC), and address output  $(A_{23}$  to  $A_{20}$ ). A reset or hardware standby transition leaves port A as an input port, except that in modes 3 and 4, one pin is always used for  $A_{20}$  output. See table 8.12 to 8.14 for the selection of pin functions.

Usage of pins for TPC, 16-bit timer, 8-bit timer, and DMAC input and output is described in the sections on those modules. For output of address bits  $A_{2}$  to  $A_{21}$  in modes 3 and 4, see section 6.2.4, Bus Release Control Register (BRCR). Pins not assigned to any of these functions are available for generic input/output. Figure 8.6 shows the pin configuration of port A.

Pins in port A can drive one TTL load and a 30-pF capacitive load. They can also drive a darlington transistor pair. Port A has Schmitt-trigger inputs.



## **Figure 8.6 Port A Pin Configuration**

#### **8.7.2 Register Configuration**

Table 8.11 summarizes the registers of port A.

#### **Table 8.11 Port A Registers**



Note: \* Lower 20 bits of the address in advanced mode.

**Port A Data Direction Register (PADDR):** PADDR is an 8-bit write-only register that can select input or output for each pin in port A. When pins are used for TPC output, the corresponding PADDR bits must also be set.



**Port A data direction 7 to 0**

These bits select input or output for port A pins

A pin in port A becomes an output port if the corresponding PADDR bit is set to 1, and an input port if this bit is cleared to 0. In modes 3 and 4,  $PA$ <sub>7</sub>DDR is fixed at 1 and  $PA$ <sub>7</sub> functions as an address output pin.

PADDR is a write-only register. Its value cannot be read. All bits return 1 when read.

PADDR is initialized to H'00 (modes 1 and 2) or H'80 (modes 3 and 4) by a reset and in hardware standby mode. In software standby mode it retains it previous setting. Therefore, if a transition is made to software standby mode while a PADDR bit is set to 1, the corresponding pin maintains its output state.

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**Port A Data Register (PADR):** PADR is an 8-bit readable/writable register that stores output data for port A. When port A functions as an output port, the value of this register is output. When a bit in PADDR is set to 1, if port A is read the value of the corresponding PADR bit is returned. When a bit in PADDR is cleared to 0, if port A is read the corresponding pin level is read.



**Port A data 7 to 0** These bits store data for port A pins

PADR is initialized to H'00 by a reset and in hardware standby mode. In software standby mode it retains its previous setting.

## **Table 8.12 Port A Pin Functions (Modes 1, 2)**



PA<sub>/</sub>TP<sub>/</sub>/ TIOCB<sub>2</sub> Bit PWM2 in TMDR, bits IOB2 to IOB0 in TIOR2, bit NDER7 in NDERA, and bit PA, DDR select the pin function as follows.



Note:  $*$  TIOCB<sub>2</sub> input when IOB2 = 1 and PWM2 = 0.







TIOCA,  $PA_4$ DDR select the pin function as follows.



Note:  $*$  TIOCA, input when IOA2 = 1.





## **Table 8.13 Port A Pin Functions (Modes 3, 4)**







 $\mathsf{PA}_\mathsf{s}\!/\mathsf{TP}_\mathsf{s}\!/$ 

 $TIOCB_{1}/A_{22}$  BRCR, and bit PA $_{5}$ DDR select the pin function as follows. Bit PWM1 in TMDR, bits IOB2 to IOB0 in TIOR1, bit NDER5 in NDERA, bit A22E in



Note:  $*$  TIOCB, input when IOB2 = 1 and PWM1 = 0.



 $\mathsf{PA}_\mathsf{4}/\mathsf{TP}_\mathsf{4} /$ 

TIOCA $_{i}$ /A $_{23}$  BRCR, and bit PA $_{4}$ DDR select the pin function as follows. Bit PWM1 in TMDR, bits IOA2 to IOA0 in TIOR1, bit NDER4 in NDERA, bit A23E in



#### Note:  $*$  TIOCA, input when IOA2 = 1.



## **Table 8.14 Port A Pin Functions (Modes 1 to 4)**

#### **Pin Pin Functions and Selection Method**

 $\mathsf{PA}_{\mathsf{s}}\!/\mathsf{TP}_{\mathsf{s}}\!/$ TIOCB $_{\rm o}$ / **TCLKD** Bit PWM0 in TMDR, bits IOB2 to IOB0 in TIOR0, bits TPSC2 to TPSC0 in 16TCR2 to 16TCR0 of the 16-bit timer, bits CKS2 to CKS0 in 8TCR2 of the 8-bit timer, bit NDER3 in NDERA, and bit PA<sub>2</sub>DDR select the pin function as follows.



Notes: 1. TIOCB0 input when  $1OB2 = 1$  and  $PWMO = 0$ .

2. TCLKD input when  $TPSC2 = TPSC1 = TPSC0 = 1$  in any of 16TCR2 to 16TCR0, or bits CKS2 to CKS0 in 8TCR2 are as shown in (3) in the table below.



 $\mathsf{PA_2}\!/\mathsf{TP_2}\!/$ TIOCA<sub>0</sub>/ **TCLKC** 

Bit PWM0 in TMDR, bits IOA2 to IOA0 in TIOR0, bits TPSC2 to TPSC0 in 16TCR2 to 16TCR0 of the 16-bit timer, bits CKS2 to CKS0 in 8TCR0 of the 8-bit timer, bit NDER2 in NDERA, and bit PA<sub>2</sub>DDR select the pin function as follows.



Notes: 1. TIOCA0 input when IOA2 = 1.

2. TCLKC input when  $TPSC2 = TPSC1 = 1$  and  $TPSC0 = 0$  in any of 16TCR2 to 16TCR0, or bits CKS2 to CKS0 in 8TCR0 are as shown in (3) in the table below.



 $\mathsf{PA}_{\mathsf{1}}/\mathsf{TP}_{\mathsf{1}}/$ TCLKB/ TEND. Bit MDF in TMDR, bits TPSC2 to TPSC0 in 16TCR2 to 16TCR0 of the 16-bit timer, bits CKS2 to CKS0 in 8TCR3 of the 8-bit timer, bit NDER1 in NDERA, and bit PA, DDR select the pin function as follows.



Notes: 1. TCLKB input when  $MDF = 1$  in TMDR, or TPSC2 = 1, TPSC1 = 0, and TPSC0 = 1 in any of 16TCR2 to 16TCR0, or bits CKS2 to CKS0 in 8TCR3 are as shown in (1) in the table below.

 2. When an external request is specified as a DMAC activation source,  $\overline{\text{TEND}}_1$  output regardless of bits PA<sub>1</sub>DDR and NDER1.





Bit MDF in TMDR, bits TPSC2 to TPSC0 in 16TCR2 to 16TCR0 of the 16-bit timer, bits CKS2 to CKS0 in 8TCR1 of the 8-bit timer, bit NDER0 in NDERA, and bit PA<sub>0</sub>DDR select the pin function as follows.



Notes: 1. TCLKA input when MDF = 1 in TMDR, or  $TPSC2 = 1$ ,  $TPSC1 = 0$  and TPSC0 = 0 in any of 16TCR2 to 16TCR0, or bits CKS2 to CKS0 in 8TCR0 are as shown in (1) in the table below.

 2. When an external request is specified as a DMAC activation source,  $\overline{\text{TEND}}_{\text{o}}$  output regardless of bits PA $_{\text{o}}$ DDR and NDER0.



# **8.8 Port B**

 $\mathsf{PA}_\mathsf{o}/\mathsf{TP}_\mathsf{o}/$ TCLKA/ TEND<sub>o</sub>

## **8.8.1 Overview**

Port B is an 8-bit input/output port that is also used for output  $(TP_{15}$  to  $TP_s)$  from the programmable timing pattern controller (TPC), input/output (TMIO<sub>3</sub>, TMO<sub>2</sub>, TMIO<sub>1</sub>, TMO<sub>0</sub>) by the 8-bit timer,  $CS_7$  to  $CS_4$  output, input (DREQ<sub>1</sub>, DREQ<sub>0</sub>) to the DMA controller (DMAC), input and output  $(TxD_2, RxD_2, SCK_2)$  by serial communication interface channel 2 (SCI2), and output (UCAS, LCAS) by the DRAM interface. See table 8.16 for the selection of pin functions.

A reset or hardware standby transition leaves port B as an input port. For output of  $\overline{CS}_1$  to  $\overline{CS}_4$  in modes 1 to 4, see section 6.3.4, Chip Select Signals. Pins not assigned to any of these functions are available for generic input/output. When DRAM is connected to areas 2 to 5, the  $CS_4$  and  $CS_5$ output pins function as  $\overline{RAS}$  output pins for each area. For details see section 6.5, DRAM Interface. Figure 8.7 shows the pin configuration of port B.

Pins in port B can drive one TTL load and a 30-pF capacitive load. They can also drive darlington transistor pair.



## **Figure 8.7 Port B Pin Configuration**

#### **8.8.2 Register Configuration**

Table 8.15 summarizes the registers of port B.

#### **Table 8.15 Port B Registers**



Note: \* Lower 20 bits of the address in advanced mode.

**Port B Data Direction Register (PBDDR):** PBDDR is an 8-bit write-only register that can select input or output for each pin in port B. When pins are used for TPC output, the corresponding PBDDR bits must also be set.



**Port B data direction 7 to 0**

These bits select input or output for port B pins

When a pin in port B becomes an output port if the corresponding PBDDR bit is set to 1, and an input port if this bit is cleared to 0.

PBDDR is a write-only register. Its value cannot be read. All bits return 1 when read.

PBDDR is initialized to H'00 by a reset and in hardware standby mode. In software standby mode it retains its previous setting. When transition is made to software standby mode while a PBDDR bit is set to 1, the corresponding pin maintains its output state.

**Port B Data Register (PBDR):** PBDR is an 8-bit readable/writable register that stores output data for pins port B. When port B functions as an output port, the value of this register is output. When a bit in PBDDR is set to 1, if port B is read the value of the corresponding PBDR bit is returned. When a bit in PBDDR is cleared to 0, if port B is read the corresponding pin level is read.



**Port B data 7 to 0** These bits store data for port B pins

PBDR is initialized to H'00 by a reset and in hardware standby mode. In software standby mode it retains its previous setting.

## **Table 8.16 Port B Pin Functions**



 $\mathsf{PB}_\mathrm{e}'\!\!\mathsf{TP}_{\scriptscriptstyle{14}}\!/\mathsf{P}$  $TxD<sub>2</sub>$ 

Bit TE in SCR of SCI2, bit SMIF in SCMR, bit NDER14 in NDERB, and bit PB, DDR select the pin function as follows.



Note:  $*$  Functions as the TxD<sub>2</sub> output pin, but there are two states: one in which the pin is driven, and another in which the pin is at high-impedance.

 $\mathsf{PB}_\mathsf{s}\!/\mathsf{TP}_{\mathsf{13}}\!/$  $SCK<sub>2</sub>/\overline{LCAS}$  bit PB<sub>s</sub>DDR select the pin function as follows. Bit C/A in SMR of SCI2, bits CKE0 and CKE1 in SCR, bit NDER13 in NDERB, and



Note: \*  $\overline{LCAS}$  output depending on bits DRAS2 to DRAS0 in DRCRA and bit CSEL in DRCRB, and regardless of bits C/A, CKE0 and CKE1, NDER13, and PB<sub>2</sub>DDR. For details, see section 6, Bus Controller.





 $PB_{4}/TP_{12}/$ 



 Note: \* UCAS output depending on bits DRAS2 to DRAS0 in DRCRA and bit CSEL in DRCRB, and regardless of bits NDER12 and PB, DDR. For details, see section 6, Bus Controller.

 $\mathsf{PB}_{\mathsf{3}}\!/\mathsf{TP}_{\mathsf{1}\mathsf{1}}\!/$  $\mathsf{TMIO}_3/$  $\overline{\mathsf{DREG}}_i/\overline{\mathsf{CS}}_4$  NDER11 in NDERB, and bit PB<sub>3</sub>DDR select the pin function as follows. The DRAM interface settings by bits DRAS2 to DRAS0 in DRCRA, bits OIS3/2 and OS1/0 in 8TCSR3, bits CCLR1 and CCLR0 in 8TCR3, bit CS4E in CSCR, bit



Notes: 1. TMIO3 input when CCLR1 = CCLR0 = 1.

- 2. When an external request is specified as a DMAC activation source, DREQ1 input regardless of bits OIS3 and OIS2, OS1 and OS0, CCLR1 and CCLR0, CS4E, NDER11, and PB3DDR.
- 3. CS4 is output as  $\overline{\text{RAS}}_{4}$ .



 $\mathsf{PB}_2\!/\mathsf{TP}_{\underline{\smash{10}}\boldsymbol{\!/}}$  $\mathsf{TMO}_{\mathbb{Z}}/\overline{\mathsf{CS}}_{\mathsf{s}}$ The DRAM interface settings by bits DRAS2 to DRAS0 in DRCRA, bits OIS3/2 and OS1/0 in 8TCSR2, bit CS5E in CSCR, bit NDER10 in NDERB, and bit PB2DDR select the pin function as follows.



Note:  $*$   $\overline{\text{CS}}_5$  is output as  $\overline{\text{RAS}}_5$ .



 $\mathsf{PB}_\mathsf{1}/\mathsf{TP}_\mathsf{9}/$  $TMIO_{1}$  $\overline{\mathsf{DREG}}_0 / \overline{\mathsf{CS}}_{_6}$ 

Bits OIS3/2 and OS1/0 in 8TCSR1, bits CCLR1 and CCLR0 in 8TCR0, bit CS6E in CSCR, bit NDER9 in NDERB, and bit PB<sub>1</sub>DDR select the pin function as follows.



Notes: 1. TMIO1 input when CCLR1 = CCLR0 = 1.

 2. DREQ0 input when an external request is specified as a DMAC activation source, regardless of bits OIS3/2, OS1/0, CCLR1/0, CS6E, NDER9, PB<sub>1</sub> DDR.

PB ${}_0\!\!/\mathrm{TP}_\mathrm{\underline{s}}\!/$ 

TMO<sub>0</sub>/CS<sub>7</sub> Bits OIS3/2 and OS1/0 in 8TCSR0, bit CS7E in CSCR, bit NDER8 in NDERB, and bit PB<sub>o</sub>DDR select the pin function as follows.



8. I/O Ports



# Section 9 16-Bit Timer

# **9.1 Overview**

The H8/3006 and H8/3007 have built-in 16-bit timer module with three 16-bit counter channels.

## **9.1.1 Features**

16-bit timer features are listed below.

- Capability to process up to 6 pulse outputs or 6 pulse inputs
- Six general registers (GRs, two per channel) with independently-assignable output compare or input capture functions
- Selection of eight counter clock sources for each channel: Internal clocks: φ, φ/2, φ/4, φ/8 External clocks: TCLKA, TCLKB, TCLKC, TCLKD
- Five operating modes selectable in all channels:
	- Waveform output by compare match
		- Selection of 0 output, 1 output, or toggle output (only 0 or 1 output in channel 2)
	- Input capture function
		- Rising edge, falling edge, or both edges (selectable)
	- Counter clearing function

Counters can be cleared by compare match or input capture

— Synchronization

Two or more timer counters (16TCNTs) can be preset simultaneously, or cleared simultaneously by compare match or input capture. Counter synchronization enables synchronous register input and output.

— PWM mode

PWM output can be provided with an arbitrary duty cycle. With synchronization, up to three-phase PWM output is possible

• Phase counting mode selectable in channel 2

Two-phase encoder output can be counted automatically.

- High-speed access via internal 16-bit bus The 16TCNTs and GRs can be accessed at high speed via a 16-bit bus.
- Any initial timer output value can be set

### 9. 16-Bit Timer

• Nine interrupt sources

Each channel has two compare match/input capture interrupts and an overflow interrupt. All interrupts can be requested independently.

• Output triggering of programmable timing pattern controller (TPC) Compare match/input capture signals from channels 0 to 2 can be used as TPC output triggers.

Table 9.1 summarizes the 16-bit timer functions.



## **Table 9.1 16-bit timer Functions**

#### **9.1.2 Block Diagrams**

**16-bit timer Block Diagram (Overall):** Figure 9.1 is a block diagram of the 16-bit timer.



**Figure 9.1 16-bit timer Block Diagram (Overall)** 

**Block Diagram of Channels 0 and 1:** 16-bit timer channels 0 and 1 are functionally identical. Both have the structure shown in figure 9.2.



**Figure 9.2 Block Diagram of Channels 0 and 1** 

**Block Diagram of Channel 2:** Figure 9.3 is a block diagram of channel 2



#### **Figure 9.3 Block Diagram of Channel 2**

## 9. 16-Bit Timer

## **9.1.3 Pin Configuration**

Table 9.2 summarizes the 16-bit timer pins.

# **Table 9.2 16-bit timer Pins**





## **9.1.4 Register Configuration**

Table 9.3 summarizes the 16-bit timer registers.

## **Table 9.3 16-bit timer Registers**





Notes: 1. The lower 20 bits of the address in advanced mode are indicated.

2. Only 0 can be written in bits 3 to 0, to clear the flags.

# **9.2 Register Descriptions**

## **9.2.1 Timer Start Register (TSTR)**

TSTR is an 8-bit readable/writable register that starts and stops the timer counter (16TCNT) in channels 0 to 2.



TSTR is initialized to H'F8 by a reset and in standby mode.

**Bits 7 to 3—Reserved:** These bits cannot be modified and are always read as 1.

**Bit 2—Counter Start 2 (STR2):** Starts and stops timer counter 2 (16TCNT2).



**Bit 1—Counter Start 1 (STR1):** Starts and stops timer counter 1 (16TCNT1).



**Bit 0—Counter Start 0 (STR0):** Starts and stops timer counter 0 (16TCNT0).



## **9.2.2 Timer Synchro Register (TSNC)**

TSNC is an 8-bit readable/writable register that selects whether channels 0 to 2 operate independently or synchronously. Channels are synchronized by setting the corresponding bits to 1.



TSNC is initialized to H'F8 by a reset and in standby mode.

**Bits 7 to 3—Reserved:** These bits cannot be modified and are always read as 1.

**Bit 2—Timer Sync 2 (SYNC2):** Selects whether channel 2 operates independently or synchronously.



**Bit 1—Timer Sync 1 (SYNC1):** Selects whether channel 1 operates independently or synchronously.

## **Bit 1**



**Bit 0—Timer Sync 0 (SYNC0):** Selects whether channel 0 operates independently or synchronously.




### **9.2.3 Timer Mode Register (TMDR)**

TMDR is an 8-bit readable/writable register that selects PWM mode for channels 0 to 2. It also selects phase counting mode and the overflow flag (OVF) setting conditions for channel 2.



TMDR is initialized to H'98 by a reset and in standby mode.

**Bit 7—Reserved:** This bit cannot be modified and is always read as 1.

**Bit 6—Phase Counting Mode Flag (MDF):** Selects whether channel 2 operates normally or in phase counting mode.



When MDF is set to 1 to select phase counting mode, 16TCNT2 operates as an up/down-counter and pins TCLKA and TCLKB become counter clock input pins. 16TCNT2 counts both rising and falling edges of TCLKA and TCLKB, and counts up or down as follows.



#### 9. 16-Bit Timer

In phase counting mode channel 2 operates as above regardless of the external clock edges selected by bits CKEG1 and CKEG0 and the clock source selected by bits TPSC2 to TPSC0. Phase counting mode takes precedence over these settings.

The counter clearing condition selected by the CCLR1 and CCLR0 bits in 16TCR2 and the compare match/input capture settings and interrupt functions of TIOR2, TISRA, TISRB, TISRC remain effective in phase counting mode.

**Bit 5—Flag Direction (FDIR):** Designates the setting condition for the OVF flag in TISRC. The FDIR designation is valid in all modes in channel 2.



**Bits 4 and 3—Reserved:** These bits cannot be modified and are always read as 1.

**Bit 2—PWM Mode 2 (PWM2):** Selects whether channel 2 operates normally or in PWM mode.



When bit PWM2 is set to 1 to select PWM mode, pin  $TIOCA_2$  becomes a PWM output pin. The output goes to 1 at compare match with GRA2, and to 0 at compare match with GRB2.

**Bit 1—PWM Mode 1 (PWM1):** Selects whether channel 1 operates normally or in PWM mode.



When bit PWM1 is set to 1 to select PWM mode, pin  $TIOCA<sub>1</sub>$  becomes a PWM output pin. The output goes to 1 at compare match with GRA1, and to 0 at compare match with GRB1.

**Bit 0—PWM Mode 0 (PWM0):** Selects whether channel 0 operates normally or in PWM mode.



When bit PWM0 is set to 1 to select PWM mode, pin  $TIOCA_0$  becomes a PWM output pin. The output goes to 1 at compare match with GRA0, and to 0 at compare match with GRB0.

#### **9.2.4 Timer Interrupt Status Register A (TISRA)**

TISRA is an 8-bit readable/writable register that indicates GRA compare match or input capture and enables or disables general register compare match and input capture interrupt requests.



Note: \* Only 0 can be written, to clear the flag.

TISRA is initialized to H'88 by a reset and in standby mode.

**Bit 7—Reserved:** This bit cannot be modified and is always read as 1.

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**Bit 6—Input Capture/Compare Match Interrupt Enable A2 (IMIEA2):** Enables or disables the interrupt requested by the IMFA2 flag when IMFA2 is set to 1.



**Bit 5—Input Capture/Compare Match Interrupt Enable A1 (IMIEA1):** Enables or disables the interrupt requested by the IMFA1 flag when IMFA1 is set to 1.

# **Bit 5 IMIEA1 Description**  0 IMIA1 interrupt requested by IMFA1 flag is disabled (Initial value) 1 IMIA1 interrupt requested by IMFA1 flag is enabled

**Bit 4**⎯**Input Capture/Compare Match Interrupt Enable A0 (IMIEA0):** Enables or disables the interrupt requested by the IMFA0 flag when IMFA0 is set to 1.

# **Bit 4 IMIEA0 Description**  0 IMIA0 interrupt requested by IMFA0 flag is disabled (Initial value) 1 IMIA0 interrupt requested by IMFA0 flag is enabled

**Bit 3—Reserved:** This bit cannot be modified and is always read as 1.

**Bit 2—Input Capture/Compare Match Flag A2 (IMFA2):** This status flag indicates GRA2 compare match or input capture events.



**Bit 1—Input Capture/Compare Match Flag A1 (IMFA1):** This status flag indicates GRA1 compare match or input capture events.



**Bit 0—Input Capture/Compare Match Flag A0 (IMFA0):** This status flag indicates GRA0 compare match or input capture events.



### **9.2.5 Timer Interrupt Status Register B (TISRB)**

TISRB is an 8-bit readable/writable register that indicates GRB compare match or input capture and enables or disables general register compare match and input capture interrupt requests.



**Reserved bit**

Note: \* Only 0 can be written, to clear the flag.

TISRB is initialized to H'88 by a reset and in standby mode.

**Bit 7—Reserved:** This bit cannot be modified and is always read as 1.

**Bit 6—Input Capture/Compare Match Interrupt Enable B2 (IMIEB2):** Enables or disables the interrupt requested by the IMFB2 flag when IMFB2 is set to 1.



**Bit 5—Input Capture/Compare Match Interrupt Enable B1 (IMIEB1):** Enables or disables the interrupt requested by the IMFB1 flag when IMFB1 is set to 1.



**Bit 4**⎯**Input Capture/Compare Match Interrupt Enable B0 (IMIEB0):** Enables or disables the interrupt requested by the IMFB0 flag when IMFB0 is set to 1.

# **Bit 4 IMIEB0 Description**  0 IMIB0 interrupt requested by IMFB0 flag is disabled (Initial value) 1 IMIB0 interrupt requested by IMFB0 flag is enabled

Bit 3-Reserved: This bit cannot be modified and is always read as 1.

**Bit 2—Input Capture/Compare Match Flag B2 (IMFB2):** This status flag indicates GRB2 compare match or input capture events.



Bit 1-*Input Capture/Compare Match Flag B1* (IMFB1): This status flag indicates GRB1 compare match or input capture events.



Bit 0-*Input Capture/Compare Match Flag B0* (IMFB0): This status flag indicates GRB0 compare match or input capture events.





### **9.2.6 Timer Interrupt Status Register C (TISRC)**

TISRC is an 8-bit readable/writable register that indicates 16TCNT overflow or underflow and enables or disables overflow interrupt requests.



Note: \* Only 0 can be written, to clear the flag.

TISRC is initialized to H'88 by a reset and in standby mode.

**Bit 7—Reserved:** This bit cannot be modified and is always read as 1.

**Bit 6—Overflow Interrupt Enable 2 (OVIE2):** Enables or disables the interrupt requested by the OVF2 flag when OVF2 is set to 1.



**Bit 5—Overflow Interrupt Enable 1 (OVIE1):** Enables or disables the interrupt requested by the OVF1 flag when OVF1 is set to 1.

### **Bit 5**

**OVIE1 Description** 



**Bit 4—Overflow Interrupt Enable 0 (OVIE0):** Enables or disables the interrupt requested by the OVF0 flag when OVF0 is set to 1.

### **Bit 4**



**Bit 3—Reserved:** This bit cannot be modified and is always read as 1.

**Bit 2—Overflow Flag 2 (OVF2):** This status flag indicates 16TCNT2 overflow.



**Bit 1—Overflow Flag 1 (OVF1):** This status flag indicates 16TCNT1 overflow.



### **Bit 0—Overflow Flag 0 (OVF0):** This status flag indicates 16TCNT0 overflow.



### **9.2.7 Timer Counters (16TCNT)**



16TCNT is a 16-bit counter. The 16-bit timer has three 16TCNTs, one for each channel.

Each 16TCNT is a 16-bit readable/writable register that counts pulse inputs from a clock source.

The clock source is selected by bits TPSC2 to TPSC0 in 16TCR.

16TCNT0 and 16TCNT1 are up-counters. 16TCNT2 is an up/down-counter in phase counting mode and an up-counter in other modes.

16TCNT can be cleared to H'0000 by compare match with GRA or GRB or by input capture to GRA or GRB (counter clearing function).

When 16TCNT overflows (changes from H'FFFF to H'0000), the OVF flag is set to 1 in TISRC of the corresponding channel.

When 16TCNT underflows (changes from H'0000 to H'FFFF), the OVF flag is set to 1 in TISRC of the corresponding channel.

The 16TCNTs are linked to the CPU by an internal 16-bit bus and can be written or read by either word access or byte access.

Each 16TCNT is initialized to H'0000 by a reset and in standby mode.

### **9.2.8 General Registers (GRA, GRB)**

The general registers are 16-bit registers. The 16-bit timer has 6 general registers, two in each channel.



Read/Write R/W R/W

A general register is a 16-bit readable/writable register that can function as either an output compare register or an input capture register. The function is selected by settings in TIOR.

When a general register is used as an output compare register, its value is constantly compared with the 16TCNT value. When the two values match (compare match), the IMFA or IMFB flag is set to 1 in TISRA/TISRB. Compare match output can be selected in TIOR.

When a general register is used as an input capture register an external input capture signal are detected and the current 16TCNT value is stored in the general register. The corresponding IMFA or IMFB flag in TISRA/TISRB is set to 1 at the same time. The valid edge or edges of the input capture signal are selected in TIOR.

TIOR settings are ignored in PWM mode.

General registers are linked to the CPU by an internal 16-bit bus and can be written or read by either word access or byte access.

General registers are initialized to the output compare function (with no output signal) by a reset and in standby mode. The initial value is H'FFFF.



### **9.2.9 Timer Control Registers (16TCR)**

16TCR is an 8-bit register. The 16-bit timer has three 16TCRs, one in each channel.





Each 16TCR is an 8-bit readable/writable register that selects the timer counter clock source, selects the edge or edges of external clock sources, and selects how the counter is cleared.

16TCR is initialized to H'80 by a reset and in standby mode.

**Bit 7—Reserved:** This bit cannot be modified and is always read as 1.



**Bits 6 and 5—Counter Clear 1 and 0 (CCLR1, CCLR0):** These bits select how 16TCNT is cleared.

**Bits 4 and 3**⎯**Clock Edge 1 and 0 (CKEG1, CKEG0):** These bits select external clock input edges when an external clock source is used.



When channel 2 is set to phase counting mode, bits CKEG1 and CKEG0 in 16TCR2 are ignored. Phase counting takes precedence.



**Bit 2 TPSC2 Bit 1 TPSC1 Bit 0 TPSC0 Function**  0 0 0 Internal clock: φ (Initial value) 1 Internal clock:  $\phi$ /2 1 0 Internal clock:  $\phi$ /4 1 Internal clock:  $\phi$ /8 1 0 0 0 External clock A: TCLKA input 1 External clock B: TCLKB input 1 0 External clock C: TCLKC input 1 External clock D: TCLKD input

**Bits 2 to 0—Timer Prescaler 2 to 0 (TPSC2 to TPSC0):** These bits select the counter clock source.

When bit TPSC<sub>2</sub> is cleared to 0 an internal clock source is selected, and the timer counts only falling edges. When bit TPSC2 is set to 1 an external clock source is selected, and the timer counts the edge or edges selected by bits CKEG1 and CKEG0.

When channel 2 is set to phase counting mode (MDF = 1 in TMDR), the settings of bits TPSC2 to TPSC0 in 16TCR2 are ignored. Phase counting takes precedence.

### **9.2.10 Timer I/O Control Register (TIOR)**

TIOR is an 8-bit register. The 16-bit timer has three TIORs, one in each channel.

### **Channel Abbreviation Function**





### **Reserved bit**

Each TIOR is an 8-bit readable/writable register that selects the output compare or input capture function for GRA and GRB, and specifies the functions of the TIORA and TIORC pins. If the output compare function is selected, TIOR also selects the type of output. If input capture is selected, TIOR also selects the edge or edges of the input capture signal.

TIOR is initialized to H'88 by a reset and in standby mode.

**Bit 7—Reserved:** This bit cannot be modified and is always read as 1.



**Bits 6 to 4—I/O Control B2 to B0 (IOB2 to IOB0):** These bits select the GRB function.

Notes: 1. After a reset, the output conforms to the TOLR setting until the first compare match.

2. Channel 2 output cannot be toggled by compare match. This setting selects 1 output instead.

**Bit 3—Reserved:** This bit cannot be modified and is always read as 1.

**Bits 2 to 0—I/O Control A2 to A0 (IOA2 to IOA0):** These bits select the GRA function.



Notes: 1. After a reset, the output conforms to the TOLR setting until the first compare match.

 2. Channel 2 output cannot be toggled by compare match. This setting selects 1 output instead.

### **9.2.11 Timer Output Level Setting Register C (TOLR)**

TOLR is an 8-bit write-only register that selects the timer output level for channels 0 to 2.



**Reserved bits**

A TOLR setting can only be made when the corresponding bit in TSTR is 0.

TOLR is a write-only register. If it is read, all bits will return a value of 1.

TOLR is initialized to H'C0 by a reset and in standby mode.

**Bits 7 and 6—Reserved:** These bits cannot be modified.

**Bit 5—Output Level Setting B2 (TOB2):** Sets the value of timer output TIOCB<sub>2</sub>.



**Bit 4—Output Level Setting A2 (TOA2):** Sets the value of timer output TIOCA<sub>2</sub>.



**Bit 3—Output Level Setting B1 (TOB1):** Sets the value of timer output TIOCB<sub>1</sub>.



**Bit 2—Output Level Setting A1 (TOA1):** Sets the value of timer output TIOCA<sub>1</sub>.



**Bit 1—Output Level Setting B0 (TOB0):** Sets the value of timer output TIOCB<sub>0</sub>.



**Bit 0—Output Level Setting A0 (TOA0):** Sets the value of timer output TIOCA<sub>0</sub>.



# **9.3 CPU Interface**

### **9.3.1 16-Bit Accessible Registers**

The timer counters (16TCNTs), general registers A and B (GRAs and GRBs) are 16-bit registers, and are linked to the CPU by an internal 16-bit data bus. These registers can be written or read a word at a time, or a byte at a time.

Figures 9.4 and 9.5 show examples of word read/write access to a timer counter (16TCNT). Figures 9.6, 9.7, 9.8, and 9.9 show examples of byte read/write access to 16TCNTH and 16TCNTL.



**Figure 9.4 Access to Timer Counter (CPU Writes to 16TCNT, Word)** 



**Figure 9.5 Access to Timer Counter (CPU Reads 16TCNT, Word)** 



**Figure 9.6 Access to Timer Counter (CPU Writes to 16TCNTH, Upper Byte)** 



**Figure 9.7 Access to Timer Counter (CPU Writes to 16TCNTL, Lower Byte)** 



**Figure 9.8 Access to Timer Counter (CPU Reads 16TCNTH, Upper Byte)** 



**Figure 9.9 Access to Timer Counter (CPU Reads 16TCNTL, Lower Byte)** 

#### **9.3.2 8-Bit Accessible Registers**

The registers other than the timer counters and general registers are 8-bit registers. These registers are linked to the CPU by an internal 8-bit data bus.

Figures 9.10 and 9.11 show examples of byte read and write access to a 16TCR.

If a word-size data transfer instruction is executed, two byte transfers are performed.



**Figure 9.10 16TCR Access (CPU Writes to 16TCR)** 



**Figure 9.11 16TCR Access (CPU Reads 16TCR)** 

## **9.4 Operation**

### **9.4.1 Overview**

A summary of operations in the various modes is given below.

**Normal Operation:** Each channel has a timer counter and general registers. The timer counter counts up, and can operate as a free-running counter, periodic counter, or external event counter. General registers A and B can be used for input capture or output compare.

**Synchronous Operation:** The timer counters in designated channels are preset synchronously. Data written to the timer counter in any one of these channels is simultaneously written to the timer counters in the other channels as well. The timer counters can also be cleared synchronously if so designated by the CCLR1 and CCLR0 bits in the 16TCRs.

**PWM Mode:** A PWM waveform is output from the TIOCA pin. The output goes to 1 at compare match A and to 0 at compare match B. The duty cycle can be varied from 0% to 100% depending on the settings of GRA and GRB. When a channel is set to PWM mode, its GRA and GRB automatically become output compare registers.

**Phase Counting Mode:** The phase relationship between two clock signals input at TCLKA and TCLKB is detected and 16TCNT2 counts up or down accordingly. When phase counting mode is selected TCLKA and TCLKB become clock input pins and 16TCNT2 operates as an up/downcounter.

### **9.4.2 Basic Functions**

Counter Operation: When one of bits STR0 to STR2 is set to 1 in the timer start register (TSTR), the timer counter (16TCNT) in the corresponding channel starts counting. The counting can be free-running or periodic.

Sample setup procedure for counter Figure 9.12 shows a sample procedure for setting up a counter.



**Figure 9.12 Counter Setup Procedure (Example)** 

- 1. Set bits TPSC2 to TPSC0 in 16TCR to select the counter clock source. If an external clock source is selected, set bits CKEG1 and CKEG0 in 16TCR to select the desired edge(s) of the external clock signal.
- 2. For periodic counting, set CCLR1 and CCLR0 in 16TCR to have 16TCNT cleared at GRA compare match or GRB compare match.
- 3. Set TIOR to select the output compare function of GRA or GRB, whichever was selected in step 2.
- 4. Write the count period in GRA or GRB, whichever was selected in step 2.
- 5. Set the STR bit to 1 in TSTR to start the timer counter.

• Free-running and periodic counter operation

A reset leaves the counters (16TCNTs) in 16-bit timer channels 0 to 2 all set as free-running counters. A free-running counter starts counting up when the corresponding bit in TSTR is set to 1. When the count overflows from H'FFFF to H'0000, the OVF flag is set to 1 in TISRC. After the overflow, the counter continues counting up from H'0000. Figure 9.13 illustrates free-running counting.





When a channel is set to have its counter cleared by compare match, in that channel 16TCNT operates as a periodic counter. Select the output compare function of GRA or GRB, set bit CCLR1 or CCLR0 in 16TCR to have the counter cleared by compare match, and set the count period in GRA or GRB. After these settings, the counter starts counting up as a periodic counter when the corresponding bit is set to 1 in TSTR. When the count matches GRA or GRB, the IMFA or IMFB flag is set to 1 in TISRA/TISRB and the counter is cleared to H'0000. If the corresponding IMIEA or IMIEB bit is set to 1 in TISRA/TISRB, a CPU interrupt is requested at this time. After the compare match, 16TCNT continues counting up from H'0000. Figure 9.14 illustrates periodic counting.



**Figure 9.14 Periodic Counter Operation** 

- 16TCNT count timing
	- Internal clock source

Bits TPSC2 to TPSC0 in 16TCR select the system clock  $(\phi)$  or one of three internal clock sources obtained by prescaling the system clock  $(\phi/2, \phi/4, \phi/8)$ .

Figure 9.15 shows the timing.



**Figure 9.15 Count Timing for Internal Clock Sources** 

- External clock source

Bits TPSC2 to TPSC0 in 16TCR select an external clock input pin (TCLKA to TCLKD), and its valid edge or edges are selected by bits CKEG1 and CKEG0. The rising edge, falling edge, or both edges can be selected.

The pulse width of the external clock signal must be at least 1.5 system clocks when a single edge is selected, and at least 2.5 system clocks when both edges are selected. Shorter pulses will not be counted correctly.

Figure 9.16 shows the timing when both edges are detected.



**Figure 9.16 Count Timing for External Clock Sources (when Both Edges Are Detected)** 

**Waveform Output by Compare Match:** In 16-bit timer channels 0, 1 compare match A or B can cause the output at the TIOCA or TIOCB pin to go to 0, go to 1, or toggle. In channel 2 the output can only go to 0 or go to 1.

Sample setup procedure for waveform output by compare match

Figure 9.17 shows an example of the setup procedure for waveform output by compare match.



**Figure 9.17 Setup Procedure for Waveform Output by Compare Match (Example)** 

#### 9. 16-Bit Timer

Examples of waveform output

Figure 9.18 shows examples of 0 and 1 output. 16TCNT operates as a free-running counter, 0 output is selected for compare match A, and 1 output is selected for compare match B. When the pin is already at the selected output level, the pin level does not change.



**Figure 9.18 0 and 1 Output (TOA = 1, TOB = 0)** 

Figure 9.19 shows examples of toggle output. 16TCNT operates as a periodic counter, cleared by compare match B. Toggle output is selected for both compare match A and B.



**Figure 9.19 Toggle Output (TOA = 1, TOB = 0)** 

• Output compare output timing

The compare match signal is generated in the last state in which 16TCNT and the general register match (when 16TCNT changes from the matching value to the next value). When the compare match signal is generated, the output value selected in TIOR is output at the output compare pin (TIOCA or TIOCB). When 16TCNT matches a general register, the compare match signal is not generated until the next counter clock pulse.

Figure 9.20 shows the output compare timing.



**Figure 9.20 Output Compare Output Timing** 

**Input Capture Function:** The 16TCNT value can be captured into a general register when a transition occurs at an input capture/output compare pin (TIOCA or TIOCB). Capture can take place on the rising edge, falling edge, or both edges. The input capture function can be used to measure pulse width or period.

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Sample setup procedure for input capture

Figure 9.21 shows a sample procedure for setting up input capture.



**Figure 9.21 Setup Procedure for Input Capture (Example)** 

Examples of input capture

Figure 9.22 illustrates input capture when the falling edge of TIOCB and both edges of TIOCA are selected as capture edges. 16TCNT is cleared by input capture into GRB.



**Figure 9.22 Input Capture (Example)** 

• Input capture signal timing

Input capture on the rising edge, falling edge, or both edges can be selected by settings in TIOR. Figure 9.23 shows the timing when the rising edge is selected. The pulse width of the input capture signal must be at least 1.5 system clocks for single-edge capture, and 2.5 system clocks for capture of both edges.



**Figure 9.23 Input Capture Signal Timing** 

### **9.4.3 Synchronization**

The synchronization function enables two or more timer counters to be synchronized by writing the same data to them simultaneously (synchronous preset). With appropriate 16TCR settings, two or more timer counters can also be cleared simultaneously (synchronous clear). Synchronization enables additional general registers to be associated with a single time base. Synchronization can be selected for all channels (0 to 2).

**Sample Setup Procedure for Synchronization:** Figure 9.24 shows a sample procedure for setting up synchronization.



- simultaneously written in 16TCNT in the other channels.
- Set the CCLR1 or CCLR0 bit in 16TCR to have the counter cleared by compare match or input capture. 3.
- 4. Set the CCLR1 and CCLR0 bits in 16TCR to have the counter cleared synchronously.
- 5. Set the STR bits in TSTR to 1 to start the synchronized counters.

### **Figure 9.24 Setup Procedure for Synchronization (Example)**

**Example of Synchronization:** Figure 9.25 shows an example of synchronization. Channels 0, 1, and 2 are synchronized, and are set to operate in PWM mode. Channel 0 is set for counter clearing by compare match with GRB0. Channels 1 and 2 are set for synchronous counter clearing. The timer counters in channels 0, 1, and 2 are synchronously preset, and are synchronously cleared by compare match with GRB0. A three-phase PWM waveform is output from pins  $TIOCA<sub>0</sub>$ ,  $TIOCA<sub>1</sub>$ , and TIOCA<sub>2</sub>. For further information on PWM mode, see section 9.4.4, PWM Mode.



**Figure 9.25 Synchronization (Example)** 

### **9.4.4 PWM Mode**

In PWM mode GRA and GRB are paired and a PWM waveform is output from the TIOCA pin. GRA specifies the time at which the PWM output changes to 1. GRB specifies the time at which the PWM output changes to 0. If either GRA or GRB is selected as the counter clear source, a PWM waveform with a duty cycle from 0% to 100% is output at the TIOCA pin. PWM mode can be selected in all channels (0 to 2).

Table 9.4 summarizes the PWM output pins and corresponding registers. If the same value is set in GRA and GRB, the output does not change when compare match occurs.



#### **Table 9.4 PWM Output Pins and Registers**

**Sample Setup Procedure for PWM Mode:** Figure 9.26 shows a sample procedure for setting up PWM mode.



**Figure 9.26 Setup Procedure for PWM Mode (Example)** 

**Examples of PWM Mode:** Figure 9.27 shows examples of operation in PWM mode. In PWM mode TIOCA becomes an output pin. The output goes to 1 at compare match with GRA, and to 0 at compare match with GRB.

In the examples shown, 16TCNT is cleared by compare match with GRA or GRB. Synchronized operation and free-running counting are also possible.





Figure 9.28 shows examples of the output of PWM waveforms with duty cycles of 0% and 100%. If the counter is cleared by compare match with GRB, and GRA is set to a higher value than GRB,

the duty cycle is 0%. If the counter is cleared by compare match with GRA, and GRB is set to a higher value than GRA, the duty cycle is 100%.



**Figure 9.28 PWM Mode (Example 2)**
### **9.4.5 Phase Counting Mode**

In phase counting mode the phase difference between two external clock inputs (at the TCLKA and TCLKB pins) is detected, and 16TCNT2 counts up or down accordingly.

In phase counting mode, the TCLKA and TCLKB pins automatically function as external clock input pins and 16TCNT2 becomes an up/down-counter, regardless of the settings of bits TPSC2 to TPSC0, CKEG1, and CKEG0 in 16TCR2. Settings of bits CCLR1, CCLR0 in 16TCR2, and settings in TIOR2, TISRA, TISRB, TISRC, STR2 in TSTR, GRA2, and GRB2 are valid. The input capture and output compare functions can be used, and interrupts can be generated.

Phase counting is available only in channel 2.

**Sample Setup Procedure for Phase Counting Mode:** Figure 9.29 shows a sample procedure for setting up phase counting mode.





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**Example of Phase Counting Mode:** Figure 9.30 shows an example of operations in phase counting mode. Table 9.5 lists the up-counting and down-counting conditions for 16TCNT2.

In phase counting mode both the rising and falling edges of TCLKA and TCLKB are counted. The phase difference between TCLKA and TCLKB must be at least 1.5 states, the phase overlap must also be at least 1.5 states, and the pulse width must be at least 2.5 states.



**Figure 9.30 Operation in Phase Counting Mode (Example)** 







**Figure 9.31 Phase Difference, Overlap, and Pulse Width in Phase Counting Mode** 

### **9.4.6 Setting Initial Value of 16-Bit Timer Output**

Any desired value can be specified for the initial 16-bit timer output value when a timer count operation is started by making a setting in TOLR.

Figure 9.32 shows the timing for setting the initial output value with TOLR.

Only write to TOLR when the corresponding bit in TSTR is cleared to 0.



**Figure 9.32 Example of Timing for Setting Initial Value of 16-Bit Timer Output by Writing to TOLR** 

# **9.5 Interrupts**

The 16-bit timer has two types of interrupts: input capture/compare match interrupts, and overflow interrupts.

## **9.5.1 Setting of Status Flags**

**Timing of Setting of IMFA and IMFB at Compare Match:** IMFA and IMFB are set to 1 by a compare match signal generated when 16TCNT matches a general register (GR). The compare match signal is generated in the last state in which the values match (when 16TCNT is updated from the matching count to the next count). Therefore, when 16TCNT matches a general register, the compare match signal is not generated until the next 16TCNT clock input. Figure 9.33 shows the timing of the setting of IMFA and IMFB.



**Figure 9.33 Timing of Setting of IMFA and IMFB by Compare Match** 

**Timing of Setting of IMFA and IMFB by Input Capture:** IMFA and IMFB are set to 1 by an input capture signal. The 16TCNT contents are simultaneously transferred to the corresponding general register. Figure 9.34 shows the timing.



**Figure 9.34 Timing of Setting of IMFA and IMFB by Input Capture** 

**Timing of Setting of Overflow Flag (OVF):** OVF is set to 1 when 16TCNT overflows from H'FFFF to H'0000 or underflows from H'0000 to H'FFFF. Figure 9.35 shows the timing.





## **9.5.2 Timing of Clearing of Status Flags**

If the CPU reads a status flag while it is set to 1, then writes 0 in the status flag, the status flag is cleared. Figure 9.36 shows the timing.



**Figure 9.36 Timing of Clearing of Status Flags** 

### **9.5.3 Interrupt Sources and DMA Controller Activation**

Each 16-bit timer channel can generate a compare match/input capture A interrupt, a compare match/input capture B interrupt, and an overflow interrupt. In total there are nine interrupt sources of three kinds, all independently vectored. An interrupt is requested when the interrupt request flag are set to 1.

The priority order of the channels can be modified in interrupt priority register A (IPRA). For details see section 5, Interrupt Controller.

Compare match/input capture A interrupts in channels 0 to 2 can activate the DMA controller (DMAC). When the DMAC is activated a CPU interrupt is not requested.

Table 9.6 lists the interrupt sources.





### **Table 9.6 16-bit timer Interrupt Sources**

Note: \* The priority immediately after a reset is indicated. Inter-channel priorities can be changed by settings in IPRA.

## **9.6 Usage Notes**

This section describes contention and other matters requiring special attention during 16-bit timer operations.

**Contention between 16TCNT Write and Clear:** If a counter clear signal occurs in the  $T_3$  state of a 16TCNT write cycle, clearing of the counter takes priority and the write is not performed. See figure 9.37.



**Figure 9.37 Contention between 16TCNT Write and Clear** 

**Contention between 16TCNT Word Write and Increment:** If an increment pulse occurs in the T<sub>3</sub> state of a 16TCNT word write cycle, writing takes priority and 16TCNT is not incremented. Figure 9.38 shows the timing in this case.



**Figure 9.38 Contention between 16TCNT Word Write and Increment** 

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**Contention between 16TCNT Byte Write and Increment:** If an increment pulse occurs in the T<sub>2</sub> or  $T_3$  state of a 16TCNT byte write cycle, writing takes priority and 16TCNT is not incremented. The 16TCNT byte that was not written retains its previous value. See figure 9.39, which shows an increment pulse occurring in the  $T_2$  state of a byte write to 16TCNTH.



**Figure 9.39 Contention between 16TCNT Byte Write and Increment** 

**Contention between General Register Write and Compare Match:** If a compare match occurs in the  $T<sub>3</sub>$  state of a general register write cycle, writing takes priority and the compare match signal is inhibited. See figure 9.40.



**Figure 9.40 Contention between General Register Write and Compare Match** 

### 9. 16-Bit Timer

**Contention between 16TCNT Write and Overflow or Underflow:** If an overflow occurs in the T<sub>3</sub> state of a 16TCNT write cycle, writing takes priority and the counter is not incremented. OVF is set to 1. The same holds for underflow. See figure 9.41.



**Figure 9.41 Contention between 16TCNT Write and Overflow** 

**Contention between General Register Read and Input Capture:** If an input capture signal occurs during the  $T<sub>3</sub>$  state of a general register read cycle, the value before input capture is read. See figure 9.42.



**Figure 9.42 Contention between General Register Read and Input Capture** 

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**Contention between Counter Clearing by Input Capture and Counter Increment:** If an input capture signal and counter increment signal occur simultaneously, the counter is cleared according to the input capture signal. The counter is not incremented by the increment signal. The value before the counter is cleared is transferred to the general register. See figure 9.43.



**Figure 9.43 Contention between Counter Clearing by Input Capture and Counter Increment** 



**Contention between General Register Write and Input Capture:** If an input capture signal occurs in the  $T_3$  state of a general register write cycle, input capture takes priority and the write to the general register is not performed. See figure 9.44.



**Figure 9.44 Contention between General Register Write and Input Capture** 

**Note on Waveform Period Setting:** When a counter is cleared by compare match, the counter is cleared in the last state at which the 16TCNT value matches the general register value, at the time when this value would normally be updated to the next count. The actual counter frequency is therefore given by the following formula:

$$
f = \frac{\phi}{(N+1)}
$$

(f: counter frequency. φ: system clock frequency. N: value set in general register.)

### 9. 16-Bit Timer

**Note on Writes in Synchronized Operation:** When channels are synchronized, if a 16TCNT value is modified by byte write access, all 16 bits of all synchronized counters assume the same value as the counter that was addressed.

(Example) When channels 1 and 2 are synchronized

• Byte write to channel 1 or byte write to channel 2



Upper byte Lower byte

channel 1 or 2

Upper byte Lower byte

### **16-bit timer Operating Modes**





Legend:

 $\circ$  Setting available (valid)

Setting does not affect this mode

Note: \* The input capture function cannot be used in PWM mode. If compare match A and compare match B occur simultaneously, the compare match signal is inhibited.



### **Table 9.7 (b) 16-bit timer Operating Modes (Channel 1)**

Legend:

 $\circ$  Setting available (valid)

Setting does not affect this mode

Note: \* The input capture function cannot be used in PWM mode. If compare match A and compare match B occur simultaneously, the compare match signal is inhibited.



### **Table 9.7 (c) 16-bit timer Operating Modes (Channel 2)**

Legend:

 $\circ$  Setting available (valid)

- Setting does not affect this mode

Note: \* The input capture function cannot be used in PWM mode. If compare match A and compare match B occur simultaneously, the compare match signal is inhibited.



# Section 10 8-Bit Timers

## **10.1 Overview**

The H8/3006 and H8/3007 have a built-in 8-bit timer module with four channels (TMR0, TMR1, TMR2, and TMR3), based on 8-bit counters. Each channel has an 8-bit timer counter (8TCNT) and two 8-bit time constant registers (TCORA and TCORB) that are constantly compared with the 8TCNT value to detect compare match events. The timers can be used as multifunctional timers in a variety of applications, including the generation of a rectangular-wave output with an arbitrary duty cycle.

### **10.1.1 Features**

The features of the 8-bit timer module are listed below.

• Selection of four clock sources

The counters can be driven by one of three internal clock signals ( $\phi$ /8,  $\phi$ /64, or  $\phi$ /8192) or an external clock input (enabling use as an external event counter).

- Selection of three ways to clear the counters The counters can be cleared on compare match A or B, or input capture B.
- Timer output controlled by two compare match signals

The timer output signal in each channel is controlled by two independent compare match signals, enabling the timer to generate output waveforms with an arbitrary duty cycle or PWM output.

- A/D converter can be activated by a compare match
- Two channels can be cascaded
	- ⎯ Channels 0 and 1 can be operated as the upper and lower halves of a 16-bit timer (16-bit count mode).
	- ⎯ Channels 2 and 3 can be operated as the upper and lower halves of a 16-bit timer (16-bit count mode).
	- Channel 1 can count channel 0 compare match events (compare match count mode).
	- Channel 3 can count channel 2 compare match events (compare match count mode).
- Input capture function can be set

8-bit or 16-bit input capture operation is available.

• Twelve interrupt sources

There are twelve interrupt sources: four compare match sources, four compare match/input capture sources, four overflow sources.

Two of the compare match sources and two of the combined compare match/input capture sources each have an independent interrupt vector. The remaining compare match interrupts, combined compare match/input capture interrupts, and overflow interrupts have one interrupt vector for two sources.

### **10.1.2 Block Diagram**

The 8-bit timers are divided into two groups of two channels each: group 0 comprising channels 0 and 1, and group 1 comprising channels 2 and 3. Figure 10.1 shows a block diagram of 8-bit timer group 0.



**Figure 10.1 Block Diagram of 8-Bit Timer Unit (Two Channels: Group 0)** 

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## **10.1.3 Pin Configuration**

Table 10.1 summarizes the input/output pins of the 8-bit timer module.



## **Table 10.1 8-Bit Timer Pins**

### **10.1.4 Register Configuration**

Table 10.2 summarizes the registers of the 8-bit timer module.





Notes: 1. Indicates the lower 20 bits of the address in advanced mode.

2. Only 0 can be written to bits 7 to 5, to clear these flags.

Each pair of registers for channel 0 and channel 1 comprises a 16-bit register with the channel 0 register as the upper 8 bits and the channel 1 register as the lower 8 bits, so they can be accessed together by word access.

Similarly, each pair of registers for channel 2 and channel 3 comprises a 16-bit register with the channel 2 register as the upper 8 bits and the channel 3 register as the lower 8 bits, so they can be accessed together by word access.

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## **10.2 Register Descriptions**

### **10.2.1 Timer Counters (8TCNT)**



The timer counters (8TCNT) are 8-bit readable/writable up-counters that increment on pulses generated from an internal or external clock source. The clock source is selected by clock select bits 2 to 0 (CKS2 to CKS0) in the timer control register (8TCR). The CPU can always read or write to the timer counters.

The 8TCNT0 and 8TCNT1 pair, and the 8TCNT2 and 8TCNT3 pair, can each be accessed as a 16-bit register by word access.

8TCNT can be cleared by an input capture signal or compare match signal. Counter clear bits 1 and 0 (CCLR1 and CCLR0) in 8TCR select the method of clearing.

When 8TCNT overflows from H'FF to H'00, the overflow flag (OVF) in the timer control/status register (8TCSR) is set to 1.

Each 8TCNT is initialized to H'00 by a reset and in standby mode.





TCORA0 to TCORA3 are 8-bit readable/writable registers. The TCORA0 and TCORA1 pair, and the TCORA2 and TCORA3 pair, can each be accessed as a 16-bit register by word access.

The TCORA value is constantly compared with the 8TCNT value. When a match is detected, the corresponding compare match flag A (CMFA) is set to 1 in 8TCSR.

The timer output can be freely controlled by these compare match signals and the settings of output select bits 1 and 0 (OS1, OS0) in 8TCSR.

Each TCORA register is initialized to H'FF by a reset and in standby mode.



TCORB0 to TCORB3 are 8-bit readable/writable registers. The TCORB0 and TCORB1 pair, and the TCORB2 and TCORB3 pair, can each be accessed as a 16-bit register by word access.

The TCORB value is constantly compared with the 8TCNT value. When a match is detected, the corresponding compare match flag B (CMFB) is set to 1 in 8TCSR\*.

The timer output can be freely controlled by these compare match signals and the settings of output/input capture edge select bits 3 and 2 (OIS3, OIS2) in 8TCSR.

When TCORB is used for input capture, it stores the 8TCNT value on detection of an external input capture signal. At this time, the CMFB flag is set to 1 in the corresponding 8TCSR register. The detected edge of the input capture signal is set in 8TCSR.

Each TCORB register is initialized to H'FF by a reset and in standby mode.

Note: \* When channel 1 and channel 3 are designated for TCORB input capture, the CMFB flag is not set by a channel 0 or channel 2 compare match B.

### **10.2.4 Timer Control Register (8TCR)**



8TCR is an 8-bit readable/writable register that selects the input clock source and the time at which 8TCNT is cleared, and enables interrupts.

8TCR is initialized to H'00 by a reset and in standby mode.

For the timing, see section 10.4, Operation.

**Bit 7—Compare Match Interrupt Enable B (CMIEB):** Enables or disables the CMIB interrupt request when the CMFB flag is set to 1 in 8TCSR.



**Bit 6—Compare Match Interrupt Enable A (CMIEA):** Enables or disables the CMIA interrupt request when the CMFA flag is set to 1 in 8TCSR.



**Bit 5—Timer Overflow Interrupt Enable (OVIE):** Enables or disables the OVI interrupt request when the OVF flag is set to 1 in 8TCSR.



**Bits 4 and 3—Counter Clear 1 and 0 (CCLR1, CCLR0):** These bits specify the 8TCNT clearing source. Compare match A or B, or input capture B, can be selected as the clearing source.



Note: When input capture B is set as the 8TCNT1 and 8TCNT3 counter clear source, 8TCNT0 and 8TCNT2 are not cleared by compare match B.

**Bits 2 to 0—Clock Select 2 to 0 (CSK2 to CSK0):** These bits select whether the clock input to 8TCNT is an internal or external clock.

Three internal clocks can be selected, all divided from the system clock (φ): φ/8, φ/64, and φ/8192. The rising edge of the selected internal clock triggers the count.

When use of an external clock is selected, three types of count can be selected: at the rising edge, the falling edge, and both rising and falling edges.

When CKS2, CKS1,  $CKS0 = 1, 0, 0$ , channels 0 and 1 and channels 2 and 3 are cascaded.

The incrementing clock source is different when 8TCR0 and 8TCR2 are set, and when 8TCR1 and 8TCR3 are set.



Notes: 1. If the clock input of channel 0 is the 8TCNT1 overflow signal and that of channel 1 is the 8TCNT0 compare match signal, no incrementing clock is generated. Do not use this setting.

 2. If the clock input of channel 2 is the 8TCNT3 overflow signal and that of channel 3 is the 8TCNT2 compare match signal, no incrementing clock is generated. Do not use this setting.



### **10.2.5 Timer Control/Status Registers (8TCSR)**

#### 8TCSR0



The timer control/status registers (8TCSR) are 8-bit registers that indicate compare match/input capture and timer overflow statuses, and control compare match output/input capture edge selection.

Each 8TCSR is initialized to H'00 by a reset and in standby mode.

**Bit 7—Compare Match/Input Capture Flag B (CMFB):** Status flag that indicates the occurrence of a TCORB compare match or input capture.



**Bit 6—Compare Match Flag A (CMFA):** Status flag that indicates the occurrence of a TCORA compare match.



**Bit 5—Timer Overflow Flag (OVF):** Status flag that indicates that the 8TCNT has overflowed  $(H'FF \rightarrow H'00).$ 



**Bit 4**⎯**A/D Trigger Enable (ADTE) (8TCSR0):** In combination with TRGE in the A/D control register (ADCR), enables or disables A/D converter start requests by compare match A or an external trigger. Bit 4 of 8TCSR2 is reserved, but can be read and written.



Note: \* TRGE is bit 7 of the A/D control register (ADCR).

**Bit 4** 

**Bit 4—Reserved (In 8TCSR1):** This bit is a reserved bit, but can be read and written.

**Bit 4—Input Capture Enable (ICE) (In 8TCSR1 and 8TCSR3):** Selects the function of TCORB1 and TCORB3.



When bit ICE is set to 1 in 8TCSR1 or 8TCSR3, the operation of the TCORA and TCORB registers in channels 0 to 3 is as shown in the tables below.



### **Table 10.3 Operation of Channels 0 and 1 when Bit ICE is Set to 1 in 8TCSR1 Register**





**Bits 3 and 2**⎯**Output/Input Capture Edge Select B3 and B2 (OIS3, OIS2):** In combination with the ICE bit in 8TCSR1 (8TCSR3), these bits select the compare match B output level or the input capture input detected edge.

The function of TCORB1 (TCORB3) depends on the setting of bit 4 of 8TCSR1 (8TCSR3). TCORB0 and TCORB2 function as compare match registers regardless of the setting of bit 4 of 8TCSR1 (8TCSR3).



- When the compare match register function is used, the timer output priority order is: toggle  $output > 1$  output  $> 0$  output.
- If compare match A and B occur simultaneously, the output changes in accordance with the higher-priority compare match.
- When bits OIS3, OIS2, OS1, and OS0 are all cleared to 0, timer output is disabled.

### **Bits 1 and 0—Output Select A1 and A0 (OS1, OS0):** These bits select the compare match A output level.



- When the compare match register function is used, the timer output priority order is: toggle  $output > 1$  output  $> 0$  output.
- If compare match A and B occur simultaneously, the output changes in accordance with the higher-priority compare match.
- When bits OIS3, OIS2, OS1, and OS0 are all cleared to 0, timer output is disabled.

# **10.3 CPU Interface**

## **10.3.1 8-Bit Registers**

8TCNT, TCORA, TCORB, 8TCR, and 8TCSR are 8-bit registers. These registers are connected to the CPU by an internal 16-bit data bus and can be read and written a word at a time or a byte at a time.

Figures 10.2 and 10.3 show the operation in word read and write accesses to 8TCNT.

Figures 10.4 to 10.7 show the operation in byte read and write accesses to 8TCNT0 and 8TCNT1.



**Figure 10.2 8TCNT Access Operation (CPU Writes to 8TCNT, Word)** 



**Figure 10.3 8TCNT Access Operation (CPU Reads 8TCNT, Word)** 



**Figure 10.4 8TCNTH Access Operation (CPU Writes to 8TCNTH, Upper Byte)**


**Figure 10.5 8TCNT1 Access Operation (CPU Writes to 8TCNT1, Lower Byte)** 



**Figure 10.6 8TCNT0 Access Operation (CPU Reads 8TCNT0, Upper Byte)** 



**Figure 10.7 8TCNT1 Access Operation (CPU Reads 8TCNT1, Lower Byte)** 

# **10.4 Operation**

## **10.4.1 8TCNT Count Timing**

8TCNT is incremented by input clock pulses (either internal or external).

**Internal Clock:** Three different internal clock signals (φ/8, φ/64, or φ/8192) divided from the system clock ( $\phi$ ) can be selected by setting bits CKS2 to CKS0 in 8TCR. Figure 10.8 shows the count timing.



**Figure 10.8 Count Timing for Internal Clock Input**

Note: Even when the same internal clock is selected for both the 16- and 8-bit timers, they do not operate in the same manner because the count-up edge differs.

**External Clock:** Three incrementation methods can be selected by setting bits CKS2 to CKS0 in 8TCR: on the rising edge, the falling edge, and both rising and falling edges.

The pulse width of the external clock signal must be at least 1.5 serial clocks when a single edge is selected, and at least 2.5 system clocks when both edges are selected. Shorter pulses will not be counted correctly.



Figure 10.9 shows the timing for incrementation on both edges of the external clock signal.





### **10.4.2 Compare Match Timing**

**Timer Output Timing:** When compare match A or B occurs, the timer output is as specified by the OIS3, OIS2, OS1, and OS0 bits in 8TCSR (unchanged, 0 output, 1 output, or toggle output).

Figure 10.10 shows the timing when the output is set to toggle on compare match A.



**Figure 10.10 Timing of Timer Output** 

**Clear by Compare Match:** Depending on the setting of the CCLR1 and CCLR0 bits in 8TCR, 8TCNT can be cleared when compare match A or B occurs. Figure 10.11 shows the timing of this operation.



**Figure 10.11 Timing of Clear by Compare Match** 

**Clear by Input Capture:** Depending on the setting of the CCLR1 and CCLR0 bits in 8TCR, 8TCNT can be cleared when input capture B occurs. Figure 10.12 shows the timing of this operation.



**Figure 10.12 Timing of Clear by Input Capture** 

### **10.4.3 Input Capture Signal Timing**

Input capture on the rising edge, falling edge, or both edges can be selected by settings in 8TCSR.

Figure 10.13 shows the timing when the rising edge is selected.

The pulse width of the input capture input signal must be at least 1.5 system clocks when a single edge is selected, and at least 2.5 system clocks when both edges are selected.



**Figure 10.13 Timing of Input Capture Input Signal**

## **10.4.4 Timing of Status Flag Setting**

**Timing of CMFA/CMFB Flag Setting when Compare Match Occurs:** CMFA and CMFB in 8TCSR are set to 1 by the compare match signal output when the TCOR and 8TCNT values match. The compare match signal is generated in the last state of the match (when the matched 8TCNT count value is updated). Therefore, after the 8TCNT and TCOR values match, the compare match signal is not generated until an incrementing clock pulse is generated. Figure 10.14 shows the timing in this case.



**Figure 10.14 CMF Flag Setting Timing when Compare Match Occurs** 

**Timing of CMFB Flag Setting when Input Capture Occurs:** On generation of an input capture signal, the CMFB flag is set to 1 and at the same time the 8TCNT value is transferred to TCORB. Figure 10.15 shows the timing in this case.



**Figure 10.15 CMFB Flag Setting Timing when Input Capture Occurs** 

**Timing of Overflow Flag (OVF) Setting:** The OVF flag in 8TCSR is set to 1 by the overflow signal generated when 8TCNT overflows (from H'FF to H'00). Figure 10.16 shows the timing in this case.





### **10.4.5 Operation with Cascaded Connection**

If bits CKS2 to CKS0 are set to (100) in either 8TCR0 or 8TCR1, the 8-bit timers of channels 0 and 1 are cascaded. With this configuration, the two timers can be used as a single 16-bit timer (16-bit count mode), or channel 0 8-bit timer compare matches can be counted in channel 1 (compare match count mode). In this case, the timer operates as below. Similarly, if bits CKS2 to CKS0 are set to (100) in either 8TCR2 or 8TCR3, the 8-bit timers of channels 2 and 3 are cascaded. With this configuration, the two timers can be used as a single 16-bit timer (16-bit count mode), or channel 2 8-bit timer compare matches can be counted in channel 3 (compare match count mode). Timer operation in these cases is described below.

## **16-Bit Count Mode**

• Channels 0 and 1:

When bits CKS2 to CKS0 are set to (100) in 8TCR0, the timer functions as a single 16-bit timer with channel 0 occupying the upper 8 bits and channel 1 occupying the lower 8 bits.

- Setting when Compare Match Occurs
	- The CMF flag is set to 1 in 8TCR0 when a 16-bit compare match occurs.
	- The CMF flag is set to 1 in 8TCR1 when a lower 8-bit compare match occurs.
	- TMO0 pin output control by bits OIS3, OIS2, OS1, and OS0 in 8TCSR0 is in accordance with the 16-bit compare match conditions.
	- TMIO1 pin output control by bits OIS3, OIS2, OS1, and OS0 in 8TCSR1 is in accordance with the lower 8-bit compare match conditions.

- Setting when Input Capture Occurs
	- The CMFB flag is set to 1 in 8TCR0 and 8TCR1 when the ICE bit is 1 in 8TCSR1 and input capture occurs.
	- TMIO<sub>1</sub> pin input capture input signal edge detection is selected by bits OIS3 and OIS2 in 8TCSR0.
- ⎯ Counter Clear Specification
	- If counter clear on compare match or input capture has been selected by the CCLR1 and CCLR0 bits in 8TCR0, the 16-bit counter (both 8TCNT0 and 8TCNT1) is cleared.
	- The settings of the CCLR1 and CCLR0 bits in 8TCR1 are ignored. The lower 8 bits cannot be cleared independently.
- ⎯ OVF Flag Operation
	- The OVF flag is set to 1 in 8TCSR0 when the 16-bit counter (8TCNT0 and 8TCNT1) overflows (from H'FFFF to H'0000).
	- The OVF flag is set to 1 in 8TCSR1 when the 8-bit counter (8TCNT1) overflows (from H'FF to H'00).
- Channels 2 and 3:

When bits CKS2 to CKS0 are set to (100) in 8TCR2, the timer functions as a single 16-bit timer with channel 2 occupying the upper 8 bits and channel 3 occupying the lower 8 bits.

- Setting when Compare Match Occurs
	- The CMF flag is set to 1 in 8TCR2 when a 16-bit compare match occurs.
	- The CMF flag is set to 1 in 8TCR3 when a lower 8-bit compare match occurs.
	- TMO<sub>2</sub> pin output control by bits OIS3, OIS2, OS1, and OS0 in 8TCSR2 is in accordance with the 16-bit compare match conditions.
	- TMIO<sub>3</sub> pin output control by bits OIS3, OIS2, OS1, and OS0 in 8TCSR3 is in accordance with the lower 8-bit compare match conditions.
- Setting when Input Capture Occurs
	- The CMFB flag is set to 1 in 8TCR2 and 8TCR3 when the ICE bit is 1 in 8TCSR3 and input capture occurs.
	- TMIO<sub>3</sub> pin input capture input signal edge detection is selected by bits OIS3 and OIS2 in 8TCSR2.
- ⎯ Counter Clear Specification
	- If counter clear on compare match has been selected by the CCLR1 and CCLR0 bits in 8TCR2, the 16-bit counter (both 8TCNT2 and 8TCNT3) is cleared.
	- The settings of the CCLR1 and CCLR0 bits in 8TCR3 are ignored. The lower 8 bits cannot be cleared independently.

- OVF Flag Operation
	- The OVF flag is set to 1 in 8TCSR2 when the 16-bit counter (8TCNT2 and 8TCNT3) overflows (from H'FFFF to H'0000).
	- The OVF flag is set to 1 in 8TCSR3 when the 8-bit counter (8TCNT3) overflows (from H'FF to H'00).

### **Compare Match Count Mode**

• Channels 0 and 1:

When bits CKS2 to CKS0 are set to (100) in 8TCR1, 8TCNT1 counts channel 0 compare match A events.

Channels 0 and 1 are controlled independently. CMF flag setting, interrupt generation, TMO pin output, counter clearing, and so on, is in accordance with the settings for each channel.

• Channels 2 and 3:

When bits CKS2 to CKS0 are set to (100) in 8TCR3, 8TCNT3 counts channel 2 compare match A events.

Channels 2 and 3 are controlled independently. CMF flag setting, interrupt generation, TMO pin output, counter clearing, and so on, is in accordance with the settings for each channel.

**Caution:** Do not set 16-bit count mode and compare match count mode simultaneously within the same group, as the 8TCNT input clock will not be generated and the counters will not operate.

## **10.4.6 Input Capture Setting**

The 8TCNT value can be transferred to TCORB on detection of an input edge on the input capture/output compare pin  $(TMIO<sub>1</sub>$  or  $TMIO<sub>3</sub>$ ). Rising edge, falling edge, or both edge detection can be selected. In 16-bit count mode, 16-bit input capture can be used.

## **Setting Input Capture Operation in 8-Bit Timer Mode (Normal Operation)**

- Channel 1:
	- ⎯ Set TCORB1 as an 8-bit input capture register with the ICE bit in 8TCSR1.
	- $\sim$  Select rising edge, falling edge, or both edges as the input edge(s) for the input capture signal  $(TMIO<sub>1</sub>)$  with bits OIS3 and OIS2 in 8TCSR1.
	- Select the input clock with bits CKS2 to CKS0 in 8TCR1, and start the 8TCNT count.
- Channel 3:
	- ⎯ Set TCORB3 as an 8-bit input capture register with the ICE bit in 8TCSR3.
	- $\sim$  Select rising edge, falling edge, or both edges as the input edge(s) for the input capture signal  $(TMIO<sub>3</sub>)$  with bits OIS3 and OIS2 in 8TCSR3.

- Select the input clock with bits CKS2 to CKS0 in 8TCR3, and start the 8TCNT count.

Note: When TCORB1 in channel 1 is used for input capture, TCORB0 in channel 0 cannot be used as a compare match register. Similarly, when TCORB3 in channel 3 is used for input capture, TCORB2 in channel 2 cannot be used as a compare match register.

### **Setting Input Capture Operation in 16-Bit Count Mode**

- Channels 0 and 1:
	- In 16-bit count mode, TCORB0 and TCORB1 function as a 16-bit input capture register when the ICE bit is set to 1 in 8TCSR1.
	- $\sim$  Select rising edge, falling edge, or both edges as the input edge(s) for the input capture signal  $(TMIO<sub>1</sub>)$  with bits OIS3 and OIS2 in 8TCSR0. (In 16-bit count mode, the settings of bits OIS3 and OIS2 in 8TCSR1 are ignored.)
	- Select the input clock with bits CKS2 to CKS0 in 8TCR1, and start the 8TCNT count.
- Channels 2 and 3:
	- ⎯ In 16-bit count mode, TCORB2 and TCORB3 function as a 16-bit input capture register when the ICE bit is set to 1 in 8TCSR3.
	- ⎯ Select rising edge, falling edge, or both edges as the input edge(s) for the input capture signal (TMIO<sub>3</sub>) with bits OIS3 and OIS2 in 8TCSR2. (In 16-bit count mode, the settings of bits OIS3 and OIS2 in 8TCSR3 are ignored.)
	- Select the input clock with bits CKS2 to CKS0 in 8TCR3, and start the 8TCNT count.

## **10.5 Interrupt**

### **10.5.1 Interrupt Source**

The 8-bit timer unit can generate three types of interrupt: compare match A and B (CMIA and CMIB) and overflow (OVI). Table 10.5 shows the interrupt sources and their priority order. Each interrupt source is enabled or disabled by the corresponding interrupt enable bit in 8TCR. A separate interrupt request signal is sent to the interrupt controller by each interrupt source.





For compare match interrupts CMIA1/CMIB1 and CMIA3/CMIB3 and the overflow interrupts (TOVI0/TOVI1 and TOVI2/TOVI3), one vector is shared by two interrupts.

Table 10.6 lists the interrupt sources.

<b>Channel</b>	<b>Interrupt Source</b>	<b>Description</b>
0	CMIA0	TCORA0 compare match
	CMIB <sub>0</sub>	TCORB0 compare match/input capture
1	CMIA1/CMIB1	TCORA1 compare match, or TCORB1 compare match/input capture
0, 1	TOVI0/TOVI1	Counter 0 or counter 1 overflow
$\mathcal{P}$	CMIA <sub>2</sub>	TCORA2 compare match
	CMIB <sub>2</sub>	TCORB2 compare match/input capture
3	CMIA3/CMIB3	TCORA3 compare match, or TCORB3 compare match/input capture
2, 3	TOVI2/TOVI3	Counter 2 or counter 3 overflow

**Table 10.6 8-Bit Timer Interrupt Sources** 

## **10.5.2 A/D Converter Activation**

The A/D converter can only be activated by channel 0 compare match A.

When the CMFA flag in 8TCSR0 is set to 1 and the ADTE bit is also set to 1, activation of the A/D converter will be requested on generation of channel 0 compare match A. If the TRGE bit in ADCR is set to 1 at this time, the A/D converter will be activated. When ADTE bit in 8TCSR0 is set to 1, the A/D converter external trigger pin (ADTRG) input is disabled.

# **10.6 8-Bit Timer Application Example**

Figure 10.17 shows how the 8-bit timer module can be used to output pulses with any desired duty cycle. The settings for this example are as follows:

- Clear the CCLR1 bit to 0 and set the CCLR0 bit to 1 in 8TCR so that 8TCNT is cleared by a TCORA compare match.
- Set bits OIS3, OIS2, OS1, and OS0 to (0110) in 8TCSR so that 1 is output on a TCORA compare match and 0 is output on a TCORB compare match.

The above settings enable a waveform with the cycle determined by TCORA and the pulse width detected by TCORB to be output without software intervention.





## **10.7 Usage Notes**

Note that the following kinds of contention can occur in 8-bit timer operation.

## **10.7.1 Contention between 8TCNT Write and Clear**

If a timer counter clear signal occurs in the  $T_3$  state of a 8TCNT write cycle, clearing of the counter takes priority and the write is not performed. Figure 10.18 shows the timing in this case.



**Figure 10.18 Contention between 8TCNT Write and Clear** 

### **10.7.2 Contention between 8TCNT Write and Increment**

If an increment pulse occurs in the  $T_3$  state of a 8TCNT write cycle, writing takes priority and 8TCNT is not incremented. Figure 10.19 shows the timing in this case.



**Figure 10.19 Contention between 8TCNT Write and Increment** 

## **10.7.3 Contention between TCOR Write and Compare Match**

If a compare match occurs in the  $T_3$  state of a TCOR write cycle, writing takes priority and the compare match signal is inhibited. Figure 10.20 shows the timing in this case.



**Figure 10.20 Contention between TCOR Write and Compare Match** 



## **10.7.4 Contention between TCOR Read and Input Capture**

If an input capture signal occurs in the  $T_3$  state of a TCOR read cycle, the value before input capture is read. Figure 10.21 shows the timing in this case.



**Figure 10.21 Contention between TCOR Read and Input Capture** 

## **10.7.5 Contention between Counter Clearing by Input Capture and Counter Increment**

If an input capture signal and counter increment signal occur simultaneously, counter clearing by the input capture signal takes priority and the counter is not incremented. The value before the counter is cleared is transferred to TCORB. Figure 10.22 shows the timing in this case.



**Figure 10.22 Contention between Counter Clearing by Input Capture and Counter Increment** 



## **10.7.6 Contention between TCOR Write and Input Capture**

If an input capture signal occurs in the  $T_3$  state of a TCOR write cycle, input capture takes priority and the write to TCOR is not performed. Figure 10.23 shows the timing in this case.



**Figure 10.23 Contention between TCOR Write and Input Capture** 

# **10.7.7 Contention between 8TCNT Byte Write and Increment in 16-Bit Count Mode (Cascaded Connection)**

If an increment pulse occurs in the  $T_2$  or  $T_3$  state of a 8TCNT byte write cycle in 16-bit count mode, writing takes priority and 8TCNT is not incremented. The byte data for which a write was not performed retains its previous value. Figure 10.24 shows the timing when an increment pulse occurs in the  $T_2$  state of a byte write to 8TCNTH.



**Figure 10.24 Contention between 8TCNT Byte Write and Increment in 16-Bit Count Mode** 

### **10.7.8 Contention between Compare Matches A and B**

If compare matches A and B occur at the same time, the 8-bit timer operates according to the relative priority of the output states set for compare match A and compare match B, as shown in Table 10.5.



## **Table 10.5 Timer Output Priority Order**

## **10.7.9 8TCNT Operation at Internal Clock Source Switchover**

Switching internal clock sources may cause 8TCNT to increment, depending on the switchover timing. Table 10.6 shows the relation between the time of the switchover (by writing to bits CKS1 and CKS0) and the operation of 8TCNT.

The 8TCNT input clock is generated from the internal clock source by detecting the rising edge of the internal clock. If a switchover is made from a low clock source to a high clock source, as in case No. 3 in Table 10.6, the switchover will be regarded as a falling edge, a 8TCNT clock pulse will be generated, and 8TCNT will be incremented.

8TCNT may also be incremented when switching between internal and external clocks.

## **Table 10.6 Internal Clock Switchover and 8TCNT Operation**



## **No. CKS1 and CKS0 Write Timing 8TCNT Operation**

#### **No. CKS1 and CKS0 Write Timing 8TCNT Operation**



- Notes: 1. Including switchovers from a high clock source to the halted state, and from the halted state to a high clock source.
	- 2. Including switchover from the halted state to a low clock source.
	- 3. Including switchover from a low clock source to the halted state.
	- 4. The switchover is regarded as a rising edge, causing 8TCNT to increment.



# Section 11 Programmable Timing Pattern Controller (TPC)

# **11.1 Overview**

The H8/3006 and H8/3007 have a built-in programmable timing pattern controller (TPC) that provides pulse outputs by using the 16-bit timer as a time base. The TPC pulse outputs are divided into 4-bit groups (group 3 to group 0) that can operate simultaneously and independently.

## **11.1.1 Features**

TPC features are listed below.

• 16-bit output data

Maximum 16-bit data can be output. TPC output can be enabled on a bit-by-bit basis.

• Four output groups

Output trigger signals can be selected in 4-bit groups to provide up to four different 4-bit outputs.

- Selectable output trigger signals Output trigger signals can be selected for each group from the compare match signals of three 16-bit timer channels.
- Non-overlap mode

A non-overlap margin can be provided between pulse outputs.

• Can operate together with the DMA controller (DMAC)

The compare-match signals selected as trigger signals can activate the DMAC for sequential output of data without CPU intervention.

## **11.1.2 Block Diagram**

Figure 11.1 shows a block diagram of the TPC.





## **11.1.3 Pin Configuration**

Table 11.1 summarizes the TPC output pins.

## **Table 11.1 TPC Pins**



## **11.1.4 Register Configuration**

Table 11.2 summarizes the TPC registers.

## **Table 11.2 TPC Registers**



Notes: 1. Lower 20 bits of the address in advanced mode.

2. Bits used for TPC output cannot be written.

 3. The NDRA address is H'FFFA5 when the same output trigger is selected for TPC output groups 0 and 1 by settings in TPCR. When the output triggers are different, the NDRA address is H'FFFA7 for group 0 and H'FFFA5 for group 1. Similarly, the address of NDRB is H'FFFA4 when the same output trigger is selected for TPC output groups 2 and 3 by settings in TPCR. When the output triggers are different, the NDRB address is H'FFFA6 for group 2 and H'FFFA4 for group 3.



# **11.2 Register Descriptions**

## **11.2.1 Port A Data Direction Register (PADDR)**

PADDR is an 8-bit write-only register that selects input or output for each pin in port A.



Port A is multiplexed with pins  $TP_7$  to  $TP_0$ . Bits corresponding to pins used for TPC output must be set to 1. For further information about PADDR, see section 8.7, Port A.

## **11.2.2 Port A Data Register (PADR)**

PADR is an 8-bit readable/writable register that stores TPC output data for groups 0 and 1, when these TPC output groups are used.



These bits store output data for TPC output groups 0 and 1

Note: \* Bits selected for TPC output by NDERA settings become read-only bits.

For further information about PADR, see section 8.7, Port A.

## **11.2.3 Port B Data Direction Register (PBDDR)**

PBDDR is an 8-bit write-only register that selects input or output for each pin in port B.



**Port B data direction 7 to 0** These bits select input or output for port B pins

Port B is multiplexed with pins  $TP_{15}$  to  $TP_s$ . Bits corresponding to pins used for TPC output must be set to 1. For further information about PBDDR, see section 8.8, Port B.

## **11.2.4 Port B Data Register (PBDR)**

PBDR is an 8-bit readable/writable register that stores TPC output data for groups 2 and 3, when these TPC output groups are used.



These bits store output data for TPC output groups 2 and 3

Note: \* Bits selected for TPC output by NDERB settings become read-only bits.

For further information about PBDR, see section 8.8, Port B.

## **11.2.5 Next Data Register A (NDRA)**

NDRA is an 8-bit readable/writable register that stores the next output data for TPC output groups 1 and 0 (pins  $TP_7$  to  $TP_0$ ). During TPC output, when an 16-bit timer compare match event specified in TPCR occurs, NDRA contents are transferred to the corresponding bits in PADR. The address of NDRA differs depending on whether TPC output groups 0 and 1 have the same output trigger or different output triggers.

NDRA is initialized to H'00 by a reset and in hardware standby mode. It is not initialized in software standby mode.

**Same Trigger for TPC Output Groups 0 and 1:** If TPC output groups 0 and 1 are triggered by the same compare match event, the NDRA address is H'FFFA5. The upper 4 bits belong to group 1 and the lower 4 bits to group 0. Address H'FFFA7 consists entirely of reserved bits that cannot be modified and always read 1.

### Address H'FFFA5



**Different Triggers for TPC Output Groups 0 and 1:** If TPC output groups 0 and 1 are triggered by different compare match events, the address of the upper 4 bits of NDRA (group 1) is H'FFFA5 and the address of the lower 4 bits (group 0) is H'FFFA7. Bits 3 to 0 of address H'FFFA5 and bits 7 to 4 of address H'FFFA7 are reserved bits that cannot be modified and always read 1.

## Address H'FFFA5



## **11.2.6 Next Data Register B (NDRB)**

NDRB is an 8-bit readable/writable register that stores the next output data for TPC output groups 3 and 2 (pins  $TP_{15}$  to  $TP_8$ ). During TPC output, when an 16-bit timer compare match event specified in TPCR occurs, NDRB contents are transferred to the corresponding bits in PBDR. The address of NDRB differs depending on whether TPC output groups 2 and 3 have the same output trigger or different output triggers.

NDRB is initialized to H'00 by a reset and in hardware standby mode. It is not initialized in software standby mode.

**Same Trigger for TPC Output Groups 2 and 3:** If TPC output groups 2 and 3 are triggered by the same compare match event, the NDRB address is H'FFFA4. The upper 4 bits belong to group 3 and the lower 4 bits to group 2. Address H'FFFA6 consists entirely of reserved bits that cannot be modified and always read 1.

### Address H'FFFA4



**Different Triggers for TPC Output Groups 2 and 3:** If TPC output groups 2 and 3 are triggered by different compare match events, the address of the upper 4 bits of NDRB (group 3) is H'FFFA4 and the address of the lower 4 bits (group 2) is H'FFFA6. Bits 3 to 0 of address H'FFFA4 and bits 7 to 4 of address H'FFFA6 are reserved bits that cannot be modified and always read 1.

### Address H'FFFA4



Address H'FFFA6



### **11.2.7 Next Data Enable Register A (NDERA)**

NDERA is an 8-bit readable/writable register that enables or disables TPC output groups 1 and 0  $(TP_7$  to  $TP_0$ ) on a bit-by-bit basis.



If a bit is enabled for TPC output by NDERA, then when the 16-bit timer compare match event selected in the TPC output control register (TPCR) occurs, the NDRA value is automatically transferred to the corresponding PADR bit, updating the output value. If TPC output is disabled, the bit value is not transferred from NDRA to PADR and the output value does not change.

NDERA is initialized to H'00 by a reset and in hardware standby mode. It is not initialized in software standby mode.

**Bits 7 to 0—Next Data Enable 7 to 0 (NDER7 to NDER0):** These bits enable or disable TPC output groups 1 and 0 (TP<sub>7</sub> to TP<sub>0</sub>) on a bit-by-bit basis.



## **11.2.8 Next Data Enable Register B (NDERB)**

NDERB is an 8-bit readable/writable register that enables or disables TPC output groups 3 and 2  $(TP_{15} \text{ to } TP_{8})$  on a bit-by-bit basis.

Bit



**Next data enable 15 to 8** These bits enable or disable TPC output groups 3 and 2

If a bit is enabled for TPC output by NDERB, then when the 16-bit timer compare match event selected in the TPC output control register (TPCR) occurs, the NDRB value is automatically transferred to the corresponding PBDR bit, updating the output value. If TPC output is disabled, the bit value is not transferred from NDRB to PBDR and the output value does not change.

NDERB is initialized to H'00 by a reset and in hardware standby mode. It is not initialized in software standby mode.

**Bits 7 to 0—Next Data Enable 15 to 8 (NDER15 to NDER8):** These bits enable or disable TPC output groups 3 and 2 (TP<sub>15</sub> to TP<sub>8</sub>) on a bit-by-bit basis.



## **11.2.9 TPC Output Control Register (TPCR)**

TPCR is an 8-bit readable/writable register that selects output trigger signals for TPC outputs on a group-by-group basis.



TPCR is initialized to H'FF by a reset and in hardware standby mode. It is not initialized in software standby mode.

**Bits 7 and 6**⎯**Group 3 Compare Match Select 1 and 0 (G3CMS1, G3CMS0):** These bits select the compare match event that triggers TPC output group 3 (TP<sub>15</sub> to TP<sub>12</sub>).



**Bits 5 and 4—Group 2 Compare Match Select 1 and 0 (G2CMS1, G2CMS0):** These bits select the compare match event that triggers TPC output group 2 (TP<sub>11</sub> to TP<sub>8</sub>).



## **Bits 3 and 2—Group 1 Compare Match Select 1 and 0 (G1CMS1, G1CMS0):** These bits

select the compare match event that triggers TPC output group  $1 (TP_7 \text{ to } TP_4)$ .



**Bits 1 and 0—Group 0 Compare Match Select 1 and 0 (G0CMS1, G0CMS0):** These bits select the compare match event that triggers TPC output group  $0$  (TP<sub>3</sub> to TP<sub>0</sub>).



### **11.2.10 TPC Output Mode Register (TPMR)**

TPMR is an 8-bit readable/writable register that selects normal or non-overlapping TPC output for each group.


The output trigger period of a non-overlapping TPC output waveform is set in general register B (GRB) in the 16-bit timer channel selected for output triggering. The non-overlap margin is set in general register A (GRA). The output values change at compare match A and B. For details see section 11.3.4, Non-Overlapping TPC Output.

TPMR is initialized to H'F0 by a reset and in hardware standby mode. It is not initialized in software standby mode.

**Bits 7 to 4—Reserved:** These bits cannot be modified and are always read as 1.

**Bit 3—Group 3 Non-Overlap (G3NOV):** Selects normal or non-overlapping TPC output for group 3 (TP<sub>15</sub> to TP<sub>12</sub>).



**Bit 2—Group 2 Non-Overlap (G2NOV):** Selects normal or non-overlapping TPC output for group 2 (TP $_{11}$  to TP $_{8}$ ).



**Bit 1—Group 1 Non-Overlap (G1NOV):** Selects normal or non-overlapping TPC output for group 1 (TP<sub>7</sub> to TP<sub>4</sub>).



**Bit 0—Group 0 Non-Overlap (G0NOV):** Selects normal or non-overlapping TPC output for group  $0$  (TP<sub>3</sub> to TP<sub>0</sub>).



### **11.3 Operation**

### **11.3.1 Overview**

When corresponding bits in PADDR or PBDDR and NDERA or NDERB are set to 1, TPC output is enabled. The TPC output initially consists of the corresponding PADR or PBDR contents. When a compare-match event selected in TPCR occurs, the corresponding NDRA or NDRB bit contents are transferred to PADR or PBDR to update the output values.

Figure 11.2 illustrates the TPC output operation. Table 11.3 summarizes the TPC operating conditions.



**Figure 11.2 TPC Output Operation** 





Sequential output of up to 16-bit patterns is possible by writing new output data to NDRA and NDRB before the next compare match. For information on non-overlapping operation, see section 11.3.4, Non-Overlapping TPC Output.

### **11.3.2 Output Timing**

If TPC output is enabled, NDRA/NDRB contents are transferred to PADR/PBDR and output when the selected compare match event occurs. Figure 11.3 shows the timing of these operations for the case of normal output in groups 2 and 3, triggered by compare match A.





### **11.3.3 Normal TPC Output**

**Sample Setup Procedure for Normal TPC Output:** Figure 11.4 shows a sample procedure for setting up normal TPC output.



**Figure 11.4 Setup Procedure for Normal TPC Output (Example)** 

**Example of Normal TPC Output (Example of Five-Phase Pulse Output):** Figure 11.5 shows an example in which the TPC is used for cyclic five-phase pulse output.



- The 16-bit timer channel to be used as the output trigger channel is set up so that GRA is an output compare register and the counter will be cleared by compare match A. The trigger period is set in GRA. The IMIEA bit is set to 1 in TISRA to enable the compare match A interrupt.
- H'F8 is written in PBDDR and NDERB, and bits G3CMS1, G3CMS0, G2CMS1, and G2CMS0 are set in TPCR to select compare match in the 16-bit timer channel set up in step 1 as the output trigger. Output data H'80 is written in NDRB.
- The timer counter in this 16-bit timer channel is started. When compare match A occurs, the NDRB contents are transferred to PBDR and output. The compare match/input capture A (IMFA) interrupt service routine writes the next output data (H'C0) in NDRB.
- Five-phase overlapping pulse output (one or two phases active at a time) can be obtained by writing H'40, H'60, H'20, H'30, H'10, H'18, H'08, H'88É at successive IMFA interrupts. If the DMAC is set for activation by this interrupt, pulse output can be obtained without loading the CPU.

### **Figure 11.5 Normal TPC Output Example (Five-Phase Pulse Output)**

### **11.3.4 Non-Overlapping TPC Output**

**Sample Setup Procedure for Non-Overlapping TPC Output:** Figure 11.6 shows a sample procedure for setting up non-overlapping TPC output.



**Figure 11.6 Setup Procedure for Non-Overlapping TPC Output (Example)** 

**Example of Non-Overlapping TPC Output (Example of Four-Phase Complementary Non-Overlapping Output):** Figure 11.7 shows an example of the use of TPC output for four-phase complementary non-overlapping pulse output.



**Figure 11.7 Non-Overlapping TPC Output Example (Four-Phase Complementary Non-Overlapping Pulse Output)** 

### **11.3.5 TPC Output Triggering by Input Capture**

TPC output can be triggered by 16-bit timer input capture as well as by compare match. If GRA functions as an input capture register in the 16-bit timer channel selected in TPCR, TPC output will be triggered by the input capture signal. Figure 11.8 shows the timing.



**Figure 11.8 TPC Output Triggering by Input Capture (Example)** 

### **11.4 Usage Notes**

### **11.4.1 Operation of TPC Output Pins**

 $TP_0$  to  $TP_{15}$  are multiplexed with 16-bit timer, DMAC, address bus, and other pin functions. When 16-bit timer, DMAC, or address output is enabled, the corresponding pins cannot be used for TPC output. The data transfer from NDR bits to DR bits takes place, however, regardless of the usage of the pin.

Pin functions should be changed only under conditions in which the output trigger event will not occur.



### **11.4.2 Note on Non-Overlapping Output**

During non-overlapping operation, the transfer of NDR bit values to DR bits takes place as follows.

- 1. NDR bits are always transferred to DR bits at compare match A.
- 2. At compare match B, NDR bits are transferred only if their value is 0. Bits are not transferred if their value is 1.

Figure 11.9 illustrates the non-overlapping TPC output operation.



**Figure 11.9 Non-Overlapping TPC Output** 

Therefore, 0 data can be transferred ahead of 1 data by making compare match B occur before compare match A. NDR contents should not be altered during the interval from compare match B to compare match A (the non-overlap margin).

This can be accomplished by having the IMFA interrupt service routine write the next data in NDR, or by having the IMFA interrupt activate the DMAC. The next data must be written before the next compare match B occurs.

Figure 11.10 shows the timing relationships.



**Figure 11.10 Non-Overlapping Operation and NDR Write Timing** 



# Section 12 Watchdog Timer

### **12.1 Overview**

The H8/3006 and H8/3007 have an on-chip watchdog timer (WDT). The WDT has two selectable functions: it can operate as a watchdog timer to supervise system operation, or it can operate as an interval timer. As a watchdog timer, it generates a reset signal for the H8/3006 and H8/3007 chip if a system crash allows the timer counter (TCNT) to overflow before being rewritten. In interval timer operation, an interval timer interrupt is requested at each TCNT overflow.

### **12.1.1 Features**

WDT features are listed below.

- Selection of eight counter clock sources φ/2, φ /32, φ /64, φ /128, φ /256, φ /512, φ /2048, or φ /4096
- Interval timer option
- Timer counter overflow generates a reset signal or interrupt.

The reset signal is generated in watchdog timer operation. An interval timer interrupt is generated in interval timer operation.

• Watchdog timer reset signal resets the entire H8/3006 and H8/3007 internally, and can also be output externally.

The reset signal generated by timer counter overflow during watchdog timer operation resets the entire H8/3006 and H8/3007 internally. An external reset signal can be output from the RESO pin to reset other system devices simultaneously.

### **12.1.2 Block Diagram**

Figure 12.1 shows a block diagram of the WDT.



**Figure 12.1 WDT Block Diagram** 

### **12.1.3 Pin Configuration**

Table 12.1 describes the WDT output pin.

### **Table 12.1 WDT Pin**



Note: \* Open-drain output.

#### **12.1.4 Register Configuration**

Table 12.2 summarizes the WDT registers.

#### **Table 12.2 WDT Registers**

#### **Address**\* **1**



Notes: 1. Lower 20 bits of the address in advanced mode.

2. Write word data starting at this address.

3. Only 0 can be written in bit 7, to clear the flag.

### **12.2 Register Descriptions**

### **12.2.1 Timer Counter (TCNT)**

TCNT is an 8-bit readable and writable up-counter.



Note: TCNT is write-protected by a password. For details see section 12.2.4, Notes on Register Access.

When the TME bit is set to 1 in TCSR, TCNT starts counting pulses generated from an internal clock source selected by bits CKS2 to CKS0 in TCSR. When the count overflows (changes from H'FF to H'00), the OVF bit is set to 1 in TCSR. TCNT is initialized to H'00 by a reset and when the TME bit is cleared to 0.

### **12.2.2 Timer Control/Status Register (TCSR)**

TCSR is an 8-bit readable and writable register. Its functions include selecting the timer mode and clock source.



Status flag indicating overflow

Notes: TCSR is write-protected by a password. For details see section 12.2.4, Notes on Register Access.

\* Only 0 can be written, to clear the flag.

Bits 7 to 5 are initialized to 0 by a reset and in standby mode. Bits 2 to 0 are initialized to 0 by a reset. In software standby mode bits 2 to 0 are not initialized, but retain their previous values.

**Bit 7—Overflow Flag (OVF):** This status flag indicates that the timer counter has overflowed from H'FF to H'00.



**Bit 6—Timer Mode Select (WT/** $\overline{IT}$ **):** Selects whether to use the WDT as a watchdog timer or interval timer. If used as an interval timer, the WDT generates an interval timer interrupt request when TCNT overflows. If used as a watchdog timer, the WDT generates a reset signal when TCNT overflows.



**Bit 5—Timer Enable (TME):** Selects whether TCNT runs or is halted. When  $WT/\overline{IT} = 1$ , clear the software standby bit (SSBY) to 0 in SYSCR before setting TME. When setting SSBY to 1, TME should be cleared to 0.



**Bits 4 and 3—Reserved:** These bits cannot be modified and are always read as 1.

**Bits 2 to 0—Clock Select 2 to 0 (CKS2 to CKS0):** These bits select one of eight internal clock sources, obtained by prescaling the system clock  $(\phi)$ , for input to TCNT.



### **12.2.3 Reset Control/Status Register (RSTCSR)**

RSTCSR is an 8-bit readable and writable register that indicates when a reset signal has been generated by watchdog timer overflow, and controls external output of the reset signal.



Notes: RSTCSR is write-protected by a password. For details see section 12.2.4, Notes on Register Access.

\* Only 0 can be written in bit 7, to clear the flag.

Bits 7 and 6 are initialized by input of a reset signal at the  $\overline{RES}$  pin. They are not initialized by reset signals generated by watchdog timer overflow.

**Bit 7—Watchdog Timer Reset (WRST):** During watchdog timer operation, this bit indicates that TCNT has overflowed and generated a reset signal. This reset signal resets the entire H8/3006 and H8/3007 chip internally. If bit RSTOE is set to 1, this reset signal is also output (low) at the  $\overline{\text{RESO}}$ pin to initialize external system devices.



**Bit 6—Reset Output Enable (RSTOE):** Enables or disables external output at the RESO pin of the reset signal generated if TCNT overflows during watchdog timer operation.



**Bits 5 to 0—Reserved:** These bits cannot be modified and are always read as 1.

#### **12.2.4 Notes on Register Access**

The watchdog timer's TCNT, TCSR, and RSTCSR registers differ from other registers in being more difficult to write. The procedures for writing and reading these registers are given below.

**Writing to TCNT and TCSR:** These registers must be written by a word transfer instruction. They cannot be written by byte instructions. Figure 12.2 shows the format of data written to TCNT and TCSR. TCNT and TCSR both have the same write address. The write data must be contained in the lower byte of the written word. The upper byte must contain H'5A (password for TCNT) or H'A5 (password for TCSR). This transfers the write data from the lower byte to TCNT or TCSR.



### **Figure 12.2 Format of Data Written to TCNT and TCSR**

**Writing to RSTCSR:** RSTCSR must be written by a word transfer instruction. It cannot be written by byte transfer instructions. Figure 12.3 shows the format of data written to RSTCSR. To write 0 in the WRST bit, the write data must have H'A5 in the upper byte and H'00 in the lower byte. The data (H'00) in the lower byte is written to RSTCSR, clearing the WRST bit to 0. To write to the RSTOE bit, the upper byte must contain H'5A and the lower byte must contain the write data. Writing this word transfers a write data value into the RSTOE bit.

#### 12. Watchdog Timer



### **Figure 12.3 Format of Data Written to RSTCSR**

**Reading TCNT, TCSR, and RSTCSR:** For reads of TCNT, TCSR, and RSTCSR, address H'FFF8C is assigned to TCSR, address H'FFF8D to TCNT, and address H'FFF8F to RSTCSR. These registers are therefore read like other registers. Byte transfer instructions can be used for reading. Table 12.3 lists the read addresses of TCNT, TCSR, and RSTCSR.

### **Table 12.3 Read Addresses of TCNT, TCSR, and RSTCSR**



Note: \* Lower 20 bits of the address in advanced mode.

# **12.3 Operation**

Operations when the WDT is used as a watchdog timer and as an interval timer are described below.

### **12.3.1 Watchdog Timer Operation**

Figure 12.4 illustrates watchdog timer operation. To use the WDT as a watchdog timer, set the WT/IT and TME bits to 1 in TCSR. Software must prevent TCNT overflow by rewriting the TCNT value (normally by writing H'00) before overflow occurs. If TCNT fails to be rewritten and overflows due to a system crash etc., the H8/3006 and H8/3007 are internally reset for a duration of 518 states.

The watchdog reset signal can be externally output from the RESO pin to reset external system devices. The reset signal is output externally for 132 states. External output can be enabled or disabled by the RSTOE bit in RSTCSR.

A watchdog reset has the same vector as a reset generated by input at the RES pin. Software can distinguish a RES reset from a watchdog reset by checking the WRST bit in RSTCSR.



If a  $\overline{\text{RES}}$  reset and a watchdog reset occur simultaneously, the  $\overline{\text{RES}}$  reset takes priority.

**Figure 12.4 Operation in Watchdog Timer Mode** 

### **12.3.2 Interval Timer Operation**

Figure 12.5 illustrates interval timer operation. To use the WDT as an interval timer, clear bit WT/IT to 0 and set bit TME to 1 in TCSR. An interval timer interrupt request is generated at each TCNT overflow. This function can be used to generate interval timer interrupts at regular intervals.



**Figure 12.5 Interval Timer Operation** 

### **12.3.3 Timing of Setting of Overflow Flag (OVF)**

Figure 12.6 shows the timing of setting of the OVF flag. The OVF flag is set to 1 when TCNT overflows. At the same time, a reset signal is generated in watchdog timer operation, or an interval timer interrupt is generated in interval timer operation.



**Figure 12.6 Timing of Setting of OVF** 

#### **12.3.4 Timing of Setting of Watchdog Timer Reset Bit (WRST)**

The WRST bit in RSTCSR is valid when bits WT/IT and TME are both set to 1 in TCSR.

Figure 12.7 shows the timing of setting of WRST and the internal reset timing. The WRST bit is set to 1 when TCNT overflows and OVF is set to 1. At the same time an internal reset signal is generated for the entire H8/3006 and H8/3007 chip. This internal reset signal clears OVF to 0, but the WRST bit remains set to 1. The reset routine must therefore clear the WRST bit.





### **12.4 Interrupts**

During interval timer operation, an overflow generates an interval timer interrupt (WOVI). The interval timer interrupt is requested whenever the OVF bit is set to 1 in TCSR.

# **12.5 Usage Notes**

**Contention between TCNT Write and Increment:** If a timer counter clock pulse is generated during the  $T_3$  state of a write cycle to TCNT, the write takes priority and the timer count is not incremented. See figure 12.8.



**Figure 12.8 Contention between TCNT Write and Count up** 

**Changing CKS2 to CKS0 Bit:** Halt TCNT by clearing the TME bit to 0 in TCSR before changing the values of bits CKS2 to CKS0.

# Section 13 Serial Communication Interface

### **13.1 Overview**

The H8/3006 and H8/3007 have a serial communication interface (SCI) with three independent channels. All three channels have identical functions. The SCI can communicate in both asynchronous and synchronous mode. It also has a multiprocessor communication function for serial communication among two or more processors.

When the SCI is not used, it can be halted to conserve power. Each SCI channel can be halted independently. For details, see section 19.6, Module Standby Function.

The SCI also has a smart card interface function conforming to the ISO/IEC 7816-3 (Identification Card) standard. This function supports serial communication with a smart card. Switching between the normal serial communication interface and the smart card interface is carried out by means of a register setting.

### **13.1.1 Features**

SCI features are listed below.

• Selection of synchronous or asynchronous mode for serial communication

### **Asynchronous mode**

Serial data communication is synchronized one channel at a time. The SCI can communicate with a universal asynchronous receiver/transmitter (UART), asynchronous communication interface adapter (ACIA), or other chip that employs standard asynchronous communication. It can also communicate with two or more other processors using the multiprocessor communication function. There are twelve selectable serial data transfer formats.

- Data length: 7 or 8 bits
- Stop bit length: 1 or 2 bits
- Parity: even/odd/none
- $\sim$  Multiprocessor bit: 1 or 0
- Receive error detection: parity, overrun, and framing errors
- Break detection: by reading the RxD level directly when a framing error occurs

#### **Synchronous mode**

Serial data communication is synchronized with a clock signal. The SCI can communicate with other chips having a synchronous communication function.

There is a single serial data communication format.

- ⎯ Data length: 8 bits
- ⎯ Receive error detection: overrun errors
- Full-duplex communication

The transmitting and receiving sections are independent, so the SCI can transmit and receive simultaneously. The transmitting and receiving sections are both double-buffered, so serial data can be transmitted and received continuously.

- The following settings can be made for the serial data to be transferred:
	- ⎯ LSB-first or MSB-first transfer
	- Inversion of data logic level
- Built-in baud rate generator with selectable bit rates
- Selectable transmit/receive clock sources: internal clock from baud rate generator, or external clock from the SCK pin
- Four types of interrupts

Transmit-data-empty, transmit-end, receive-data-full, and receive-error interrupts are requested independently. The transmit-data-empty and receive-data-full interrupts from SCI0 can activate the DMA controller (DMAC) to transfer data.

Features of the smart card interface are listed below.

- Asynchronous communication
	- Data length: 8 bits
	- Parity bits generated and checked
	- Error signal output in receive mode (parity error)
	- Error signal detect and automatic data retransmit in transmit mode
	- ⎯ Supports both direct convention and inverse convention
- Built-in baud rate generator with selectable bit rates
- Three types of interrupts

Transmit-data-empty, receive-data-full, and transmit/receive-error interrupts are requested independently. The transmit-data-empty and receive-data-full interrupts can activate the DMA controller (DMAC) to transfer data.

#### **13.1.2 Block Diagram**





**Figure 13.1 SCI Block Diagram** 

### **13.1.3 Pin Configuration**

The SCI has serial pins for each channel as listed in table 13.1.

### **Table 13.1 SCI Pins**





#### **13.1.4 Register Configuration**

The SCI has internal registers as listed in table 13.2. These registers select asynchronous or synchronous mode, specify the data format and bit rate, control the transmitter and receiver sections, and specify switching between the serial communication interface and smart card interface.





Notes: 1. Indicates the lower 20 bits of the address in advanced mode.

2. Only 0 can be written, to clear flags.

# **13.2 Register Descriptions**

### **13.2.1 Receive Shift Register (RSR)**

RSR is the register that receives serial data.



The SCI loads serial data input at the RxD pin into RSR in the order received, LSB (bit 0) first, thereby converting the data to parallel data. When one byte of data has been received, it is automatically transferred to RDR. The CPU cannot read or write RSR directly.

### **13.2.2 Receive Data Register (RDR)**

RDR is the register that stores received serial data.



When the SCI has received one byte of serial data, it transfers the received data from RSR into RDR for storage, completing the receive operation. RSR is then ready to receive the next data. This double-buffering allows data to be received continuously.

RDR is a read-only register. Its contents cannot be modified by the CPU. RDR is initialized to H'00 by a reset and in standby mode.



#### **13.2.3 Transmit Shift Register (TSR)**

TSR is the register that transmits serial data.



The SCI loads transmit data from TDR to TSR, then transmits the data serially from the TxD pin, LSB (bit 0) first. After transmitting one data byte, the SCI automatically loads the next transmit data from TDR into TSR and starts transmitting it. If the TDRE flag is set to 1 in SSR, however, the SCI does not load the TDR contents into TSR. The CPU cannot read or write TSR directly.

#### **13.2.4 Transmit Data Register (TDR)**

TDR is an 8-bit register that stores data for serial transmission.



When the SCI detects that TSR is empty, it moves transmit data written in TDR from TDR into TSR and starts serial transmission. Continuous serial transmission is possible by writing the next transmit data in TDR during serial transmission from TSR.

The CPU can always read and write TDR. TDR is initialized to H'FF by a reset and in standby mode.

### **13.2.5 Serial Mode Register (SMR)**

SMR is an 8-bit register that specifies the SCI's serial communication format and selects the clock source for the baud rate generator.



The CPU can always read and write SMR. SMR is initialized to H'00 by a reset and in standby mode.

**Bit 7—Communication Mode (C/A)/GSM Mode (GM):** The function of this bit differs for the normal serial communication interface and for the smart card interface. Its function is switched with the SMIF bit in SCMR.

**For serial communication interface (SMIF bit in SCMR cleared to 0):** Selects whether the SCI operates in asynchronous or synchronous mode.



**For smart card interface (SMIF bit in SCMR set to 1):** Selects GSM mode for the smart card interface.



**Bit 6—Character Length (CHR):** Selects 7-bit or 8-bits data length in asynchronous mode. In synchronous mode, the data length is 8 bits regardless of the CHR setting,



Note: \* When 7-bit data is selected, the MSB (bit 7) of TDR is not transmitted.

**Bit 5—Parity Enable (PE):** In asynchronous mode, this bit enables or disables the addition of a parity bit to transmit data, and the checking of the parity bit in receive data. In synchronous mode, the parity bit is neither added nor checked, regardless of the PE bit setting.



**Bit 4—Parity Mode (O/E):** Selects even or odd parity. The O/E bit setting is only valid when the PE bit is set to 1, enabling parity bit addition and checking, in asynchronous mode. The  $O/\overline{E}$  bit setting is ignored in synchronous mode, or when parity addition and checking is disabled in asynchronous mode.



**Bit 3—Stop Bit Length (STOP):** Selects one or two stop bits in asynchronous mode. This setting is used only in asynchronous mode. In synchronous mod no stop bit is added, so the STOP bit setting is ignored.



In receiving, only the first stop bit is checked, regardless of the STOP bit setting. If the second stop bit is 1, it is treated as a stop bit. If the second stop bit is 0, it is treated as the start bit of the next incoming character.

**Bit 2—Multiprocessor Mode (MP):** Selects a multiprocessor format. When a multiprocessor format is selected, parity settings made by the PE and O/E bits are ignored. The MP bit setting is valid only in asynchronous mode. It is ignored in synchronous mode.

For further information on the multiprocessor communication function, see section 13.3.3, Multiprocessor Communication.



**Bits 1 and 0—Clock Select 1 and 0 (CKS1, CKS0):** These bits select the clock source for the onchip baud rate generator. Four clock sources are available:  $\phi$ ,  $\phi/4$ ,  $\phi/16$ , and  $\phi/64$ .

For the relationship between the clock source, bit rate register setting, and baud rate, see section 13.2.8, Bit Rate Register (BRR).



### **13.2.6 Serial Control Register (SCR)**

SCR register enables or disables the SCI transmitter and receiver, enables or disables serial clock output in asynchronous mode, enables or disables interrupts, and selects the transmit/receive clock source.



The CPU can always read and write SCR. SCR is initialized to H'00 by a reset and in standby mode.

**Bit 7—Transmit Interrupt Enable (TIE):** Enables or disables the transmit-data-empty interrupt (TXI) requested when the TDRE flag in SSR is set to 1 due to transfer of serial transmit data from TDR to TSR.

# **Bit 7**



**Bit 6—Receive Interrupt Enable (RIE):** Enables or disables the receive-data-full interrupt (RXI) requested when the RDRF flag in SSR is set to 1 due to transfer of serial receive data from RSR to RDR; also enables or disables the receive-error interrupt (ERI).



**Bit 5—Transmit Enable (TE):** Enables or disables the start of SCI serial transmitting operations.



Notes: 1. The TDRE flag is fixed at 1 in SSR.

 2. In the enabled state, serial transmission starts when the TDRE flag in SSR is cleared to 0 after writing of transmit data into TDR. Select the transmit format in SMR before setting the TE bit to 1.

**Bit 4—Receive Enable (RE):** Enables or disables the start of SCI serial receiving operations.



Notes: 1. Clearing the RE bit to 0 does not affect the RDRF, FER, PER, and ORER flags. These flags retain their previous values.

 2. In the enabled state, serial receiving starts when a start bit is detected in asynchronous mode, or serial clock input is detected in synchronous mode. Select the receive format in SMR before setting the RE bit to 1.

**Bit 3—Multiprocessor Interrupt Enable (MPIE):** Enables or disables multiprocessor interrupts. The MPIE bit setting is valid only in asynchronous mode, and only if the MP bit is set to 1 in SMR. The MPIE bit setting is ignored in synchronous mode or when the MP bit is cleared to 0.


**Bit 2—Transmit-End interrupt Enable (TEIE):** Enables or disables the transmit-end interrupt (TEI) requested if TDR does not contain valid transmit data when the MSB is transmitted.



**Bits 1 and 0—Clock Enable 1 and 0 (CKE1, CKE0):** The function of these bits differs for the normal serial communication interface and for the smart card interface. Their function is switched with the SMIF bit in SCMR.

**For serial communication interface (SMIF bit in SCMR cleared to 0):** These bits select the SCI clock source and enable or disable clock output from the SCK pin. Depending on the settings of CKE1 and CKE0, the SCK pin can be used for generic input/output, serial clock output, or serial clock input.

The CKE0 setting is valid only in asynchronous mode, and only when the SCI is internally clocked (CKE1 = 0). The CKE0 setting is ignored in synchronous mode, or when an external clock source is selected (CKE1 = 1). Select the SCI operating mode in SMR before setting the CKE1 and CKE0 bits. For further details on selection of the SCI clock source, see table 13.9 in section 13.3, Operation.



**Bit 0** 

**Bit 1** 

Notes: 1. Initial value

2. The output clock frequency is the same as the bit rate.

3. The input clock frequency is 16 times the bit rate.

**For smart card interface (SMIF bit in SCMR set to 1):** These bits, together with the GM bit in SMR, determine whether the SCK pin is used for generic input/output or as the serial clock output pin.





#### **13.2.7 Serial Status Register (SSR)**

SSR is an 8-bit register containing multiprocessor bit values, and status flags that indicate the operating status of the SCI.



Status flag indicating that transmit data has been transferred from TDR into TSR and new data can be written in TDR

- Notes: 1. Only 0 can be written, to clear the flag.
	- 2. Function differs between the normal serial communication interface and the smart card interface.

The CPU can always read and write SSR, but cannot write 1 in the TDRE, RDRF, ORER, PER, and FER flags. These flags can be cleared to 0 only if they have first been read while set to 1. The TEND and MPB flags are read-only bits that cannot be written.

SSR is initialized to H'84 by a reset and in standby mode.

**Bit 7—Transmit Data Register Empty (TDRE):** Indicates that the SCI has loaded transmit data from TDR into TSR and the next serial data can be written in TDR.



Bit 6-Receive Data Register Full (RDRF): Indicates that RDR contains new receive data.



**Bit 5—Overrun Error (ORER):** Indicates that data reception ended abnormally due to an overrun error.



**Bit 4** Framing Error (FER)/Error Signal Status (ERS): The function of this bit differs for the normal serial communication interface and for the smart card interface. Its function is switched with the SMIF bit in SCMR.

**For serial communication interface (SMIF bit in SCMR cleared to 0):** Indicates that data reception ended abnormally due to a framing error in asynchronous mode.



**For smart card interface (SMIF bit in SCMR set to 1):** Indicates the status of the error signal sent back from the receiving side during transmission. Framing errors are not detected in smart card interface mode.



**Bit 3—Parity Error (PER):** Indicates that data reception ended abnormally due to a parity error in asynchronous mode.



Notes: 1. Clearing the RE bit to 0 in SCR does not affect the PER flag, which retains its previous value.

 2. When a parity error occurs the SCI transfers the receive data into RDR but does not set the RDRF flag. Serial receiving cannot continue while the PER flag is set to 1. In synchronous mode, serial transmitting is also disabled.

**Bit 2—Transmit End (TEND):** The function of this bit differs for the normal serial

communication interface and for the smart card interface. Its function is switched with the SMIF bit in SCMR.

**For serial communication interface (SMIF bit in SCMR cleared to 0):** Indicates that when the last bit of a serial character was transmitted TDR did not contain valid transmit data, so transmission has ended. The TEND flag is a read-only bit and cannot be written.



**For smart card interface (SMIF bit in SCMR set to 1):** Indicates that when the last bit of a serial character was transmitted TDR did not contain valid transmit data, so transmission has ended. The TEND flag is a read-only bit and cannot be written.



Note: etu: Elementary time unit (time required to transmit one bit)

**Bit 1—Multiprocessor bit (MPB):** Stores the value of the multiprocessor bit in the receive data when a multiprocessor format is used in asynchronous mode. MPB is a read-only bit, and cannot be written.

# **Bit 1**



retains its previous value.

**Bit 0—Multiprocessor Bit Transfer (MPBT):** Stores the value of the multiprocessor bit added to transmit data when a multiprocessor format in selected for transmitting in asynchronous mode.

The MPBT bit setting is ignored in synchronous mode, when a multiprocessor format is not selected, or when the SCI cannot transmit.



### **13.2.8 Bit Rate Register (BRR)**

BRR is an 8-bit register that, together with the CKS1 and CKS0 bits in SMR that select the baud rate generator clock source, determines the serial communication bit rate.



The CPU can always read and write BRR. BRR is initialized to H'FF by a reset and in standby mode. Each SCI channel has independent baud rate generator control, so different values can be set in the three channels.

Table 13.3 shows examples of BRR settings in asynchronous mode. Table 13.4 shows examples of BRR settings in synchronous mode.

	$\phi$ (MHz)												
<b>Bit Rate</b>	$\mathbf{2}$			2.097152				2.4576			3		
(bit/s)	n	N	Error $(\%)$	$\mathbf n$	N	Error $(\%)$	n	N	Error $(\%)$	n	N	Error $(\%)$	
110	1	141	0.03	1		$148 - 0.04$	1		$174 -0.26$	1		212 0.03	
150	1		103 0.16	1		108 0.21	1		127 0.00	1		155 0.16	
300	0		207 0.16	0		217 0.21	0		255 0.00	1	77	0.16	
600	0		103 0.16	0		108 0.21	0		127 0.00	0		155 0.16	
1200	0	51	0.16	0	54	$-0.70$	0	63	0.00	0	77	0.16	
2400	0	25	0.16	0	26	1.14	0	31	0.00	0	38	0.16	
4800	0	12	0.16	0	13	$-2.48$	0	15	0.00	0	19	$-2.34$	
9600	0	6	$-6.99$	0	6	$-2.48$	0	7	0.00	0	9	$-2.34$	
19200	0	$\mathbf{2}$	8.51	0	$\overline{c}$	13.78	0	3	0.00	0	4	$-2.34$	
31250	0	1	0.00	0	1	4.86	0	1	22.88	0	2	0.00	
38400	0	1	$-18.62$	0	1	$-14.67$	0	1	0.00				

**Table 13.3 Examples of Bit Rates and BRR Settings in Asynchronous Mode** 

φ **(MHz)**

<b>Bit Rate</b>	3.6864				4		4.9152			5			
(bit/s)	n	N	Error $(\%)$	$\mathbf n$	N	Error $(\%)$	n	N	Error $(\%)$	n	N	Error $(\%)$	
110	$\mathbf{2}$	64	0.07	2	70	0.03	2	86	0.31	2	88	$-0.25$	
150	1	191	0.00	1	207	0.16	1		255 0.00	2	64	0.16	
300	1	95	0.00	1		103 0.16	1		127 0.00	1		129 0.16	
600	0		191 0.00	0		207 0.16	0		255 0.00	1	64	0.16	
1200	0	95	0.00	0		103 0.16	0	127	0.00	0		129 0.16	
2400	0	47	0.00	0	51	0.16	0	63	0.00	0	64	0.16	
4800	0	23	0.00	0	25	0.16	0	31	0.00	0	32	$-1.36$	
9600	0	11	0.00	0	12	0.16	0	15	0.00	0	15	1.73	
19200	0	5	0.00	0	6	$-6.99$	0	7	0.00	0	7	1.73	
31250				0	3	0.00	0	4	$-1.70$	0	4	0.00	
38400	0	2	0.00	0	$\overline{c}$	8.51	$\Omega$	3	0.00	0	3	1.73	

	$\phi$ (MHz)											
<b>Bit Rate</b>	6			6.144			7.3728			8		
(bit/s)	n	N	Error $(\%)$	n	N	Error $(\%)$	n	N	Error $(\%)$	n	N	Error $(\%)$
110	$\overline{c}$		$106 - 0.44$	$\overline{c}$	108	0.08	2		$130 -0.07$	2		141 0.03
150	$\overline{c}$	77	0.16	$\overline{c}$	79	0.00	$\overline{c}$	95	0.00	$\mathbf{2}$		103 0.16
300	1		155 0.16	1	159	0.00	1	191	0.00	1		207 0.16
600	1	77	0.16	1	79	0.00	1	95	0.00	1		103 0.16
1200	0		155 0.16	0		159 0.00	0	191	0.00	0		207 0.16
2400	0	77	0.16	0	79	0.00	0	95	0.00	0		103 0.16
4800	0	38	0.16	0	39	0.00	0	47	0.00	0	51	0.16
9600	0	19	$-2.34$	0	19	0.00	0	23	0.00	0	25	0.16
19200	0	9	$-2.34$	0	9	0.00	0	11	0.00	0	12	0.16
31250	0	5	0.00	$\Omega$	5	2.40	0	6	5.33	0	7	0.00
38400	0	4	$-2.34$	0	4	0.00	0	5	0.00	0	6	$-6.99$

φ **(MHz)**







φ **(MHz)** 

**Table 13.4 Examples of Bit Rates and BRR Settings in Synchronous Mode** 

Legend:

Blank: No setting available

-: Setting possible, but error occurs

\*: Continuous transmission/reception not possible

Note: Settings with an error of 1% or less are recommended.

The BRR setting is calculated as follows:

Asynchronous mode:

$$
N = \frac{\phi}{64 \times 2^{2n-1} \times B} \times 10^6 - 1
$$

Synchronous mode:

$$
N = \frac{\phi}{8 \times 2^{2n-1} \times B} \times 10^6 - 1
$$

Legend:

B: Bit rate (bit/s)

- N: BRR setting for baud rate generator ( $0 \le N \le 255$ )
- φ: System clock frequency (MHz)
- n: Baud rate generator clock source  $(n = 0, 1, 2, 3)$ (For the clock sources and values of n, see the following table.)



The bit rate error in asynchronous mode is calculated as follows:

$$
\text{Error } (\%) = \left\{ \frac{\phi \times 10^6}{(N+1) \times B \times 64 \times 2^{2n-1}} - 1 \right\} \times 100
$$

Table 13.5 shows the maximum bit rates in asynchronous mode for various system clock frequencies. Table 13.6 and 13.7 shows the maximum bit rates with external clock input.





$\phi$ (MHz)	<b>External Input Clock (MHz)</b>	Maximum Bit Rate (bit/s)
$\mathbf{2}$	0.5000	31250
2.097152	0.5243	32768
2.4576	0.6144	38400
3	0.7500	46875
3.6864	0.9216	57600
$\overline{4}$	1.0000	62500
4.9152	1.2288	76800
5	1.2500	78125
6	1.5000	93750
6.144	1.5360	96000
7.3728	1.8432	115200
8	2.0000	125000
9.8304	2.4576	153600
10	2.5000	156250
12	3.0000	187500
12.288	3.0720	192000
14	3.5000	218750
14.7456	3.6864	230400
16	4.0000	250000
17.2032	4.3008	268800
18	4.5000	281250
20	5.0000	312500

**Table 13.6 Maximum Bit Rates with External Clock Input (Asynchronous Mode)** 

$\phi$ (MHz)	<b>External Input Clock (MHz)</b>	Maximum Bit Rate (bit/s)
$\overline{2}$	0.3333	333333.3
$\overline{4}$	0.6667	666666.7
6	1.0000	1000000.0
8	1.3333	1333333.3
10	1.6667	1666666.7
12	2.0000	2000000.0
14	2.3333	2333333.3
16	2.6667	2666666.7
18	3.0000	3000000.0
20	3.3333	3333333.3

**Table 13.7 Maximum Bit Rates with External Clock Input (Synchronous Mode)** 

# **13.3 Operation**

### **13.3.1 Overview**

The SCI can carry out serial communication in two modes: asynchronous mode in which synchronization is achieved character by character, and synchronous mode in which synchronization is achieved with clock pulses. A smart card interface is also supported as a serial communication function for an IC card interface.

Selection of asynchronous or synchronous mode and the transmission format for the normal serial communication interface is made in SMR, as shown in table 13.8. The SCI clock source is selected by the C/A bit in SMR and the CKE1 and CKE0 bits in SCR, as shown in table 13.9.

For details of the procedures for switching between LSB-first and MSB-first mode and inverting the data logic level, see section 14.2.1, Smart Card Mode Register (SCMR).

For selection of the smart card interface format, see section 14.3.3, Data Format.

### **Asynchronous Mode**

- Data length is selectable: 7 or 8 bits
- Parity and multiprocessor bits are selectable, and so is the stop bit length (1 or 2 bits). These selections determine the communication format and character length.
- In receiving, it is possible to detect framing errors, parity errors, overrun errors, and the break state.

- An internal or external clock can be selected as the SCI clock source.
	- When an internal clock is selected, the SCI operates using the on-chip baud rate generator, and can output a serial clock signal with a frequency matching the bit rate.
	- ⎯ When an external clock is selected, the external clock input must have a frequency 16 times the bit rate. (The on-chip baud rate generator is not used.)

#### **Synchronous Mode**

- The communication format has a fixed 8-bit data length.
- In receiving, it is possible to detect overrun errors.
- An internal or external clock can be selected as the SCI clock source.
	- When an internal clock is selected, the SCI operates using the on-chip baud rate generator, and can output a serial clock signal to external devices.
	- ⎯ When an external clock is selected, the SCI operates on the input serial clock. The on-chip baud rate generator is not used.

#### **Smart Card Interface**

- One frame consists of 8-bit data and a parity bit.
- In transmitting, a guard time of at least two elementary time units (2 etu) is provided between the end of the parity bit and the start of the next frame. (An elementary time unit is the time required to transmit one bit.)
- In receiving, if a parity error is detected, a low error signal level is output for 1 etu, beginning 10.5 etu after the start bit..
- In transmitting, if an error signal is received, the same data is automatically transmitted again after at least 2 etu.
- Only asynchronous communication is supported. There is no synchronous communication function.

For details of smart card interface operation, see section 14, Smart Card Interface.



#### **Table 13.8 SMR Settings and Serial Communication Formats**

#### **Table 13.9 SMR and SCR Settings and SCI Clock Source Selection**



#### **13.3.2 Operation in Asynchronous Mode**

In asynchronous mode, each transmitted or received character begins with a start bit and ends with one or two stop bits. Serial communication is synchronized one character at a time.

The transmitting and receiving sections of the SCI are independent, so full-duplex communication is possible. The transmitter and the receiver are both double-buffered, so data can be written and read while transmitting and receiving are in progress, enabling continuous transmitting and receiving.

Figure 13.2 shows the general format of asynchronous serial communication. In asynchronous serial communication the communication line is normally held in the mark (high) state. The SCI monitors the line and starts serial communication when the line goes to the space (low) state, indicating a start bit. One serial character consists of a start bit (low), data (LSB first), parity bit (high or low), and one or two stop bits (high), in that order.

When receiving in asynchronous mode, the SCI synchronizes at the falling edge of the start bit. The SCI samples each data bit on the eighth pulse of a clock with a frequency 16 times the bit rate. Receive data is latched at the center of each bit.



### **Figure 13.2 Data Format in Asynchronous Communication (Example: 8-Bit Data with Parity and 2 Stop Bits)**

**Communication Formats:** Table 13.10 shows the 12 communication formats that can be selected in asynchronous mode. The format is selected by settings in SMR.





Legend:

S: Start bit

STOP: Stop bit

P: Parity bit

MPB: Multiprocessor bit

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**Clock:** An internal clock generated by the on-chip baud rate generator or an external clock input from the SCK pin can be selected as the SCI transmit/receive clock. The clock source is selected by the C/A bit in SMR and bits CKE1 and CKE0 in SCR. For details of SCI clock source selection, see table 13.9.

When an external clock is input at the SCK pin, it must have a frequency 16 times the desired bit rate.

When the SCI is operated on an internal clock, it can output a clock signal at the SCK pin. The frequency of this output clock is equal to the bit rate. The phase is aligned as shown in figure 13.3 so that the rising edge of the clock occurs at the center of each transmit data bit.





#### **Transmitting and Receiving Data:**

• SCI Initialization (Asynchronous Mode): Before transmitting or receiving data, clear the TE and RE bits to 0 in SCR, then initialize the SCI as follows.

When changing the communication mode or format, always clear the TE and RE bits to 0 before following the procedure given below. Clearing TE to 0 sets the TDRE flag to 1 and initializes TSR. Clearing RE to 0, however, does not initialize the RDRF, PER, FER, and ORER flags, or RDR, which retain their previous contents.

When an external clock is used the clock should not be stopped during initialization or subsequent operation, since operation will be unreliable in this case.

Figure 13.4 shows a sample flowchart for initializing the SCI.





• Transmitting Serial Data (Asynchronous Mode): Figure 13.5 shows a sample flowchart for transmitting serial data and indicates the procedure to follow.



**Figure 13.5 Sample Flowchart for Transmitting Serial Data** 

In transmitting serial data, the SCI operates as follows:

- The SCI monitors the TDRE flag in SSR. When the TDRE flag is cleared to 0, the SCI recognizes that TDR contains new data, and loads this data from TDR into TSR.
- After loading the data from TDR to TSR, the SCI sets the TDRE flag to 1 and starts transmitting. If the TIE bit is set to 1 in SCR, the SCI requests a transmit-data-empty interrupt (TXI) at this time.

Serial transmit data is transmitted in the following order from the TxD pin:

- Start bit: One 0 bit is output.
- ⎯ Transmit data: 7 or 8 bits are output, LSB first.
- Parity bit or multiprocessor bit: One parity bit (even or odd parity), or one multiprocessor bit is output. Formats in which neither a parity bit nor a multiprocessor bit is output can also be selected.
- ⎯ Stop bit(s): One or two 1 bits (stop bits) are output.
- Mark state: Output of 1 bits continues until the start bit of the next transmit data.
- The SCI checks the TDRE flag when it outputs the stop bit. If the TDRE flag is 0, the SCI loads new data from TDR into TSR, outputs the stop bit, then begins serial transmission of the next frame. If the TDRE flag is 1, the SCI sets the TEND flag to 1 in SSR, outputs the stop bit, then continues output of 1 bits in the mark state. If the TEIE bit is set to 1 in SCR, a transmitend interrupt (TEI) is requested at this time

Figure 13.6 shows an example of SCI transmit operation in asynchronous mode.



**Figure 13.6 Example of SCI Transmit Operation in Asynchronous Mode (8-Bit Data with Parity and One Stop Bit)** 

• Receiving Serial Data (Asynchronous Mode): Figure 13.7 shows a sample flowchart for receiving serial data and indicates the procedure to follow.



SCI initialization: the receive data input function of the RxD pin is selected automatically.

Receive error handling and break detection: if a receive error occurs, read the ORER, PER, and FER flags in SSR to identify the error. After executing the necessary error handling, clear the ORER, PER, and FER flags all to 0. Receiving cannot resume if any of these flags remains set to 1. When a framing error occurs, the RxD pin can be read to detect the break state.

SCI status check and receive data read: read SSR, check that the RDRF flag is set to 1, then read receive data from RDR and clear the RDRF flag to 0. Notification that the RDRF flag has changed from 0 to 1 can also be given by the RXI interrupt.

To continue receiving serial data: check the RDRF flag, read RDR, and clear the RDRF flag to 0 before the stop bit of the current frame is received. When the DMAC is activated by a receive-data-full interrupt request (RXI) to read RDR, the RDRF flag is cleared automatically.

**Figure 13.7 Sample Flowchart for Receiving Serial Data (1)** 



**Figure 13.7 Sample Flowchart for Receiving Serial Data (2)** 

In receiving, the SCI operates as follows:

- The SCI monitors the communication line. When it detects a start bit (0 bit), the SCI synchronizes internally and starts receiving.
- Receive data is stored in RSR in order from LSB to MSB.
- The parity bit and stop bit are received.

After receiving these bits, the SCI carries out the following checks:

- Parity check: The number of 1s in the receive data must match the even or odd parity setting of in the  $O/\overline{E}$  bit in SMR.
- Stop bit check: The stop bit value must be 1. If there are two stop bits, only the first is checked.
- ⎯ Status check: The RDRF flag must be 0, indicating that the receive data can be transferred from RSR into RDR.

If these all checks pass, the RDRF flag is set to 1 and the received data is stored in RDR. If one of the checks fails (receive error\*), the SCI operates as shown in table 13.11.

- Note: \* When a receive error occurs, further receiving is disabled. In receiving, the RDRF flag is not set to 1. Be sure to clear the error flags to 0.
- When the RDRF flag is set to 1, if the RIE bit is set to 1 in SCR, a receive-data-full interrupt (RXI) is requested. If the ORER, PER, or FER flag is set to 1 and the RIE bit in SCR is also set to 1, a receive-error interrupt (ERI) is requested.







Figure 13.8 shows an example of SCI receive operation in asynchronous mode.

#### **Figure 13.8 Example of SCI Receive Operation (8-Bit Data with Parity and One Stop Bit)**

#### **13.3.3 Multiprocessor Communication**

The multiprocessor communication function enables several processors to share a single serial communication line. The processors communicate in asynchronous mode using a format with an additional multiprocessor bit (multiprocessor format).

In multiprocessor communication, each receiving processor is addressed by an ID. A serial communication cycle consists of an ID-sending cycle that identifies the receiving processor, and a data-sending cycle. The multiprocessor bit distinguishes ID-sending cycles from data-sending cycles.

The transmitting processor stars by sending the ID of the receiving processor with which it wants to communicate as data with the multiprocessor bit set to 1. Next the transmitting processor sends transmit data with the multiprocessor bit cleared to 0.

Receiving processors skip incoming data until they receive data with the multiprocessor bit set to 1. When they receive data with the multiprocessor bit set to 1, receiving processors compare the data with their IDs. Processors with IDs not matching the received data skip further incoming data until they again receive data with the multiprocessor bit set to 1. Multiple processors can send and receive data in this way.

Figure 13.9 shows an example of communication among different processors using a multiprocessor format.

**Communication Formats:** Four formats are available. Parity bit settings are ignored when a multiprocessor format is selected. For details see table 13.10.

**Clock:** See the description of asynchronous mode.



**Figure 13.9 Example of Communication among Processors using Multiprocessor Format (Sending Data H'AA to Receiving Processor A)** 

#### **Transmitting and Receiving Data:**

• Transmitting Multiprocessor Serial Data: Figure 13.10 shows a sample flowchart for transmitting multiprocessor serial data and indicates the procedure to follow.



**Figure 13.10 Sample Flowchart for Transmitting Multiprocessor Serial Data** 

In transmitting serial data, the SCI operates as follows:

- The SCI monitors the TDRE flag in SSR. When the TDRE flag is cleared to 0, the SCI recognizes that TDR contains new data, and loads this data from TDR into TSR.
- After loading the data from TDR to TSR, the SCI sets the TDRE flag to 1 and starts transmitting. If the TIE bit is set to 1 in SCR, the SCI requests a transmit-data-empty interrupt (TXI) at this time.

Serial transmit data is transmitted in the following order from the TxD pin:

- Start bit: One 0 bit is output.
- ⎯ Transmit data: 7 or 8 bits are output, LSB first.
- ⎯ Multiprocessor bit: One multiprocessor bit (MPBT value) is output.
- ⎯ Stop bit(s): One or two 1 bits (stop bits) are output.
- Mark state: Output of 1 bits continues until the start bit of the next transmit data.
- The SCI checks the TDRE flag when it outputs the stop bit. If the TDRE flag is 0, the SCI loads new data from TDR into TSR, outputs the stop bit, then begins serial transmission of the next frame. If the TDRE flag is 1, the SCI sets the TEND flag to 1 in SSR, outputs the stop bit, then continues output of 1 bits in the mark state. If the TEIE bit is set to 1 in SCR, a transmitend interrupt (TEI) is requested at this time

Figure 13.11 shows an example of SCI transmit operation using a multiprocessor format.



**Figure 13.11 Example of SCI Transmit Operation (8-Bit Data with Multiprocessor Bit and One Stop Bit)** 

• Receiving Multiprocessor Serial Data: Figure 13.12 shows a sample flowchart for receiving multiprocessor serial data and indicates the procedure to follow.







**Figure 13.12 Sample Flowchart for Receiving Multiprocessor Serial Data (2)** 



Figure 13.13 shows an example of SCI receive operation using a multiprocessor format.

**Figure 13.13 Example of SCI Receive Operation (8-Bit Data with Multiprocessor Bit and One Stop Bit)** 

#### **13.3.4 Synchronous Operation**

In synchronous mode, the SCI transmits and receives data in synchronization with clock pulses. This mode is suitable for high-speed serial communication.

The SCI transmitter and receiver share the same clock but are otherwise independent, so fullduplex communication is possible. The transmitter and the receiver are also double-buffered, so continuous transmitting or receiving is possible by reading or writing data while transmitting or receiving is in progress.



Figure 13.14 shows the general format in synchronous serial communication.

**Figure 13.14 Data Format in Synchronous Communication** 

In synchronous serial communication, each data bit is placed on the communication line from one falling edge of the serial clock to the next. Data is guaranteed valid at the rise of the serial clock. In each character, the serial data bits are transferred in order from LSB (first) to MSB (last). After output of the MSB, the communication line remains in the state of the MSB. In synchronous mode the SCI receives data by synchronizing with the rise of the serial clock.

**Communication Format:** The data length is fixed at 8 bits. No parity bit or multiprocessor bit can be added.

**Clock:** An internal clock generated by the on-chip baud rate generator or an external clock input from the SCK pin can be selected by means of the C/A bit in SMR and the CKE1 and CKE0 bits in SCR. See table 13.9 for details of SCI clock source selection.

When the SCI operates on an internal clock, it outputs the clock source at the SCK pin. Eight clock pulses are output per transmitted or received character. When the SCI is not transmitting or receiving, the clock signal remains in the high state. If receiving in single-character units is required, an external clock should be selected.

#### **Transmitting and Receiving Data:**

• SCI Initialization (Synchronous Mode): Before transmitting or receiving data, clear the TE and RE bits to 0 in SCR, then initialize the SCI as follows.

When changing the communication mode or format, always clear the TE and RE bits to 0 before following the procedure given below. Clearing TE to 0 sets the TDRE flag to 1 and initializes TSR. Clearing RE to 0, however, does not initialize the RDRF, PER, FER, and ORER flags, or RDR, which retain their previous contents.

Figure 13.15 shows a sample flowchart for initializing the SCI.



#### **Figure 13.15 Sample Flowchart for SCI Initialization**
• Transmitting Serial Data (Synchronous Mode): Figure 13.16 shows a sample flowchart for transmitting serial data and indicates the procedure to follow.





In transmitting serial data, the SCI operates as follows.

• The SCI monitors the TDRE flag in SSR. When the TDRE flag is cleared to 0, the SCI recognizes that TDR contains new data, and loads this data from TDR into TSR.

• After loading the data from TDR to TSR, the SCI sets the TDRE flag to 1 and starts transmitting. If the TIE bit is set to 1 in SCR, the SCI requests a transmit-data-empty interrupt (TXI) at this time.

If clock output is selected, the SCI outputs eight serial clock pulses. If an external clock source is selected, the SCI outputs data in synchronization with the input clock. Data is output from the TxD pin n order from LSB (bit 0) to MSB (bit 7).

- The SCI checks the TDRE flag when it outputs the MSB (bit 7). If the TDRE flag is 0, the SCI loads data from TDR into TSR and begins serial transmission of the next frame. If the TDRE flag is 1, the SCI sets the TEND flag to 1 in SSR, and after transmitting the MSB, holds the TxD pin in the MSB state. If the TEIE bit is set to 1 in SCR, a transmit-end interrupt (TEI) is requested at this time
- After the end of serial transmission, the SCK pin is held in a constant state.





**Figure 13.17 Example of SCI Transmit Operation** 

• Receiving Serial Data (Synchronous Mode): Figure 13.18 shows a sample flowchart for receiving serial data and indicates the procedure to follow. When switching from asynchronous to synchronous mode, make sure that the ORER, PER, and FER flags are cleared to 0. If the FER or PER flag is set to 1 the RDRF flag will not be set and both transmitting and receiving will be disabled.



- SCI initialization: the receive data input function of the RxD pin is selected automatically.
- (2)(3) Receive error handling: if a receive error occurs, read the ORER flag in SSR, then after executing the necessary error handling, clear the ORER flag to 0. Neither transmitting nor receiving can resume while the ORER flag remains set to 1.
	- SCI status check and receive data read: read SSR, check that the RDRF flag is set to 1, then read receive data from RDR and clear the RDRF flag to 0. Notification that the RDRF flag has changed from 0 to 1 can also be given by the RXI interrupt.
	- To continue receiving serial data: check the RDRF flag, read RDR, and clear the RDRF flag to 0 before the MSB (bit 7) of the current frame is received. When the DMAC is activated by a receive-data-full interrupt request (RXI) to read RDR, the RDRF flag is cleared automatically.

**Figure 13.18 Sample Flowchart for Serial Receiving (1)** 



**Figure 13.18 Sample Flowchart for Serial Receiving (2)** 

In receiving, the SCI operates as follows:

- The SCI synchronizes with the serial clock input or output and performs receive operation.
- Receive data is stored in RSR in order from LSB to MSB.

After receiving the data, the SCI checks that the RDRF flag is 0, so that receive data can be transferred from RSR to RDR. If this check passes, the RDRF flag is set to 1 and the received data is stored in RDR. If the checks fails (receive error), the SCI operates as shown in table 13.11.

When a receive error has been identified in the error check, subsequent transmit and receive operations are disabled.

• When the RDRF flag is set to 1, if the RIE bit is set to 1 in SCR, a receive-data-full interrupt (RXI) is requested. If the ORER flag is set to 1 and the RIE bit in SCR is also set to 1, a receive-error interrupt (ERI) is requested.

Figure 13.19 shows an example of SCI receive operation.





**Figure 13.19 Example of SCI Receive Operation** 

• Transmitting and Receiving Data Simultaneously (Synchronous Mode): Figure 13.20 shows a sample flowchart for transmitting and receiving serial data simultaneously and indicates the procedure to follow.



**Figure 13.20 Sample Flowchart for Simultaneous Serial Transmitting and Receiving** 



# **13.4 SCI Interrupts**

The SCI has four interrupt request sources: transmit-end interrupt (TEI), receive-error (ERI), receive-data-full (RXI), and transmit-data-empty interrupt (TXI). Table 13.12 lists the interrupt sources and indicates their priority. These interrupts can be enabled or disabled by the TIE, RIE, and TEIE bits in SCR. Each interrupt request is sent separately to the interrupt controller.

A TXI interrupt is requested when the TDRE flag is set to 1 in SSR. A TEI interrupt is requested when the TEND flag is set to 1 in SSR. A TXI interrupt request can activate the DMAC to transfer data. Data transfer by the DMAC automatically clears the TDRE flag to 0. A TEI interrupt request cannot activate the DMAC.

An RXI interrupt is requested when the RDRF flag is set to 1 in SSR. An ERI interrupt is requested when the ORER, PER, or FER flag is set to 1 in SSR. An RXI interrupt can activate the DMAC to transfer data. Data transfer by the DMAC automatically clears the RDRF flag to 0. An ERI interrupt request cannot activate the DMAC.

The DMAC can be activated by interrupts from SCI channel 0.



#### **Table 13.12 SCI Interrupt Sources**

### **13.5 Usage Notes**

### **13.5.1 Notes on Use of SCI**

Note the following points when using the SCI.

**TDR Write and TDRE Flag:** The TDRE flag in SSR is a status flag indicating the loading of transmit data from TDR to TSR. The SCI sets the TDRE flag to 1 when it transfers data from TDR to TSR.

Data can be written into TDR regardless of the state of the TDRE flag. If new data is written in TDR when the TDRE flag is 0, the old data stored in TDR will be lost because this data has not yet been transferred to TSR. Before writing transmit data in TDR, be sure to check that the TDRE flag is set to 1.

**Simultaneous Multiple Receive Errors:** Table 13.13 shows the state of the SSR status flags when multiple receive errors occur simultaneously. When an overrun error occurs the RSR contents are not transferred to RDR, so receive data is lost.



### **Table 13.13 SSR Status Flags and Transfer of Receive Data**

**Break Detection and Processing:** Break signals can be detected by reading the RxD pin directly when a framing error (FER) is detected. In the break state the input from the RxD pin consists of all 0s, so the FER flag is set and the parity error flag (PER) may also be set. In the break state the SCI receiver continues to operate, so if the FER flag is cleared to 0 it will be set to 1 again.

**Sending a Break Signal:** The input/output condition and level of the TxD pin are determined by DR and DDR bits. This feature can be used to send a break signal.

After the serial transmitter is initialized, the DR value substitutes for the mark state until the TE bit is set to 1 (the TxD pin function is not selected until the TE bit is set to 1). The DDR and DR bits should therefore be set to 1 beforehand.

To send a break signal during serial transmission, clear the DR bit to 0 , then clear the TE bit to 0. When the TE bit is cleared to 0 the transmitter is initialized, regardless of its current state, so the TxD pin becomes an input/output outputting the value 0.

**Receive Error Flags and Transmitter Operation (Synchronous Mode Only):** When a receive error flag (ORER, PER, or FER) is set to 1 the SCI will not start transmitting, even if the TDRE flag is cleared to 0. Be sure to clear the receive error flags to 0 when starting to transmit. Note that clearing the RE bit to 0 does not clear the receive error flags to 0.

**Receive Data Sampling Timing in Asynchronous Mode and Receive Margin:** In asynchronous mode the SCI operates on a base clock with 16 times the bit rate frequency. In receiving, the SCI synchronizes internally with the fall of the start bit, which it samples on the base clock. Receive data is latched at the rising edge of the eighth base clock pulse. See figure 13.21.



**Figure 13.21 Receive Data Sampling Timing in Asynchronous Mode** 

The receive margin in asynchronous mode can therefore be expressed as shown in equation (1).

$$
M = \begin{bmatrix} (0.5 - \frac{1}{2N}) - (L - 0.5) F - \frac{|D - 0.5|}{N} & (1 + F) \end{bmatrix} \times 100\%
$$
 (1)

- M: Receive margin  $(\% )$
- N: Ratio of clock frequency to bit rate  $(N = 16)$
- D: Clock duty cycle  $(L = 0$  to 1.0)
- L: Frame length  $(L = 9$  to 12)
- F: Absolute deviation of clock frequency

From equation (1), if  $F = 0$  and  $D = 0.5$ , the receive margin is 46.875%, as given by equation (2).

D = 0.5, F = 0  
\nM = 
$$
(0.5 - \frac{1}{2 \times 16}) \times 100\%
$$
  
\n= 46.875% (2)

This is a theoretical value. A reasonable margin to allow in system designs is 20% to 30%.

#### **Restrictions on Use of DMAC:**

- When an external clock source is used for the serial clock, after the DMAC updates TDR, allow an inversion of at least five system clock  $(\phi)$  cycles before input of the serial clock to start transmitting. If the serial clock is input within four states of the TDR update, a malfunction may occur. (See figure 13.22)
- To have the DMAC read RDR, be sure to select the corresponding SCI receive-data-full interrupt (RXI) as the activation source with bits DTS2 to DTS0 in DTCR.



**Figure 13.22 Example of Synchronous Transmission Using DMAC** 

#### **Switching from SCK Pin Function to Port Pin Function:**

- Problem in Operation: When switching the SCK pin function to the output port function (highlevel output) by making the following settings while DDR = 1, DR = 1, C/A = 1, CKE1 = 0,  $CKE0 = 0$ , and  $TE = 1$  (synchronous mode), low-level output occurs for one half-cycle.
	- 1. End of serial data transmission
	- 2. TE bit  $= 0$
	- 3.  $C/\overline{A}$  bit = 0 ... switchover to port output
	- 4. Occurrence of low-level output (see figure 13.23)





• Sample Procedure for Avoiding Low-Level Output: As this sample procedure temporarily places the SCK pin in the input state, the SCK/port pin should be pulled up beforehand with an external circuit.

With DDR = 1, DR = 1,  $C/\overline{A}$  = 1, CKE1 = 0, CKE0 = 0, and TE = 1, make the following settings in the order shown.

- 1. End of serial data transmission
- 2. TE bit  $= 0$
- 3. CKE1 bit  $= 1$
- 4.  $C/\overline{A}$  bit = 0 ... switchover to port output
- 5. CKE1 bit  $= 0$



### **Figure 13.24 Operation when Switching from SCK Pin Function to Port Pin Function (Example of Preventing Low-Level Output)**

# Section 14 Smart Card Interface

### **14.1 Overview**

An IC card (smart card) interface conforming to the ISO/IEC 7816-3 (Identification Card) standard is supported as an extension of the serial communication interface (SCI) functions.

Switchover between the normal serial communication interface and the smart card interface is controlled by a register setting.

#### **14.1.1 Features**

Features of the smart card interface supported by the H8/3067 Group are listed below.

- Asynchronous communication
	- Data length: 8 bits
	- Parity bit generation and checking
	- Transmission of error signal (parity error) in receive mode
	- Error signal detection and automatic data retransmission in transmit mode
	- Direct convention and inverse convention both supported
- Built-in baud rate generator allows any bit rate to be selected
- Three interrupt sources
	- There are three interrupt sources transmit-data-empty, receive-data-full, and transmit/receive error — that can issue requests independently.
	- The transmit-data-empty interrupt and receive-data-full interrupt can activate the DMA controller (DMAC) to execute data transfer.

#### **14.1.2 Block Diagram**





**Figure 14.1 Block Diagram of Smart Card Interface**

#### **14.1.3 Pin Configuration**

Table 14.1 shows the smart card interface pins.

#### **Table 14.1 Smart Card Interface Pins**



#### **14.1.4 Register Configuration**

The smart card interface has the internal registers listed in table 14.2. The BRR, TDR, and RDR registers have their normal serial communication interface functions, as described in section 13, Serial Communication Interface.



#### **Table 14.2 Smart Card Interface Registers**

Notes: 1. Lower 20 bits of the address in advanced mode.

2. Only 0 can be written in bits 7 to 3, to clear the flags.

# **14.2 Register Descriptions**

This section describes the new or modified registers and bit functions in the smart card interface.

#### **14.2.1 Smart Card Mode Register (SCMR)**

SCMR is an 8-bit readable/writable register that selects smart card interface functions.



**Smart card data transfer direction**

Selects the serial/parallel conversion format

SCMR is initialized to H'F2 by a reset and in standby mode.

**Bits 7 to 4—Reserved:** Read-only bits, always read as 1.

**Bit 3—Smart Card Data Transfer Direction (SDIR):** Selects the serial/parallel conversion format. $*^1$ 



**Bit 2—Smart Card Data Invert (SINV):** Specifies inversion of the data logic level. This function is used in combination with the SDIR bit to communicate with inverse-convention cards.<sup>\*2</sup> The SINV bit does not affect the logic level of the parity bit. For parity settings, see section 14.3.4, Register Settings.



Bit 1-Reserved: Read-only bit, always read as 1.

**Bit 0—Smart Card Interface Mode Select (SMIF):** Enables the smart card interface function.



Notes: 1. The function for switching between LSB-first and MSB-first mode can also be used with the normal serial communication interface. Note that when the communication format data length is set to 7 bits and MSB-first mode is selected for the serial data to be transferred, bit 0 of TDR is not transmitted, and only bits 7 to 1 of the received data are valid.

 2. The data logic level inversion function can also be used with the normal serial communication interface. Note that, when inverting the serial data to be transferred, parity transmission and parity checking is based on the number of high-level periods at the serial data I/O pin, and not on the register value.

#### **14.2.2 Serial Status Register (SSR)**

The function of SSR bit 4 is modified in smart card interface mode. This change also causes a modification to the setting conditions for bit 2 (TEND).



Note: \* Only 0 can be written, to clear the flag.

**Bits 7 to 5:** These bits operate as in normal serial communication. For details see section 13.2.7, Serial Status Register (SSR).

**Bit 4—Error Signal Status (ERS):** In smart card interface mode, this flag indicates the status of the error signal sent from the receiving device to the transmitting device. The smart card interface does not detection framing errors.



Bits 3 to 0: These bits operate as in normal serial communication. For details see section 13.2.7, Serial Status Register (SSR). The setting conditions for transmit end (TEND, bit 2), however, are modified as follows.



Note: An etu (elementary time unit) is the time needed to transmit one bit.

#### **14.2.3 Serial Mode Register (SMR)**

The function of SMR bit 7 is modified in smart card interface mode. This change also causes a modification to the function of bits 1 and 0 in the serial control register (SCR).



**Bit 7—GSM Mode (GM):** With the normal smart card interface, this bit is cleared to 0. Setting this bit to 1 selects GSM mode, an additional mode for controlling the timing for setting the TEND flag that indicates completion of transmission, and the type of clock output used. The details of the additional clock output control mode are specified by the CKE1 and CKE0 bits in the serial control register (SCR).



**Bits 6 to 0:** These bits operate as in normal serial communication. For details see section 13.2.5, Serial Mode Register (SMR).

#### **14.2.4 Serial Control Register (SCR)**

The function of SCR bits 1 and 0 is modified in smart card interface mode.

7 TIE  $\Omega$ R/W 6 RIE  $\Omega$ R/W 5 TE  $\Omega$ R/W 4 RE  $\Omega$ R/W 3 MPIE  $\Omega$ R/W 0 CKE0  $\Omega$ R/W  $\mathfrak{p}$ TEIE  $\Omega$ R/W 1 CKE1  $\Omega$ R/W Bit Initial value Read/Write

**Bits 7 to 2:** These bits operate as in normal serial communication. For details see section 13.2.6, Serial Control Register (SCR).

**Bits 1 and 0—Clock Enable 1 and 0 (CKE1, CKE0):** These bits select the SCI clock source and enable or disable clock output from the SCK pin. In smart card interface mode, it is possible to specify a fixed high level or fixed low level for the clock output, in addition to the usual switching between enabling and disabling of the clock output.



### **14.3 Operation**

#### **14.3.1 Overview**

The main features of the smart card interface are as follows.

- One frame consists of 8-bit data plus a parity bit.
- In transmission, a guard time of at least 2 etu (elementary time units: the time for transfer of one bit) is provided between the end of the parity bit and the start of the next frame.
- If a parity error is detected during reception, a low error signal level is output for al etu period 10.5 etu after the start bit.
- If an error signal is detected during transmission, the same data is transmitted automatically after the elapse of 2 etu or longer.
- Only asynchronous communication is supported; there is no synchronous communication function.

#### **14.3.2 Pin Connections**

Figure 14.2 shows a pin connection diagram for the smart card interface.

In communication with a smart card, since both transmission and reception are carried out on a single data transmission line, the TxD pin and RxD pin should both be connected to this line. The data transmission line should be pulled up to  $V_{cc}$  with a resistor.

#### 14. Smart Card Interface

When the smart card uses the clock generated on the smart card interface, the SCK pin output is input to the CLK pin of the smart card. If the smart card uses an internal clock, this connection is unnecessary.

The reset signal should be output from one of this LSI's generic ports.

In addition to these pin connections, power and ground connections will normally also be necessary.





Note: If a smart card is not connected, and both TE and RE are set to 1, closed transmission/ reception is possible, enabling self-diagnosis to be carried out.

#### **14.3.3 Data Format**

Figure 14.3 shows the smart card interface data format. In reception in this mode, a parity check is carried out on each frame, and if an error is detected an error signal is sent back to the transmitting device to request retransmission of the data. In transmission, the error signal is sampled and the same data is retransmitted if the error signal is low.





**Figure 14.3 Smart Card Interface Data Format** 

The operating sequence is as follows.

- 1. When the data line is not in use it is in the high-impedance state, and is fixed high with a pullup resistor.
- 2. The transmitting device starts transfer of one frame of data. The data frame starts with a start bit (Ds, low-level), followed by 8 data bits (D0 to D7) and a parity bit (Dp).
- 3. With the smart card interface, the data line then returns to the high-impedance state. The data line is pulled high with a pull-up resistor.
- 4. The receiving device carries out a parity check. If there is no parity error and the data is received normally, the receiving device waits for reception of the next data. If a parity error occurs, however, the receiving device outputs an error signal (DE, low-level) to request retransmission of the data. After outputting the error signal for the prescribed length of time, the receiving device places the signal line in the high-impedance state again. The signal line is pulled high again by a pull-up resistor.
- 5. If the transmitting device does not receive an error signal, it proceeds to transmit the next data frame. If it receives an error signal, however, it returns to step 2 and transmits the same data again.

#### **14.3.4 Register Settings**

Table 14.3 shows a bit map of the registers used in the smart card interface. Bits indicated as 0 or 1 must be set to the value shown. The setting of other bits is described in this section.

						<b>Bit</b>			
Register	Address <sup>*1</sup>	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
<b>SMR</b>	H'FFFB0	<b>GM</b>	0		$O/\overline{E}$		0	CKS <sub>1</sub>	CKS <sub>0</sub>
<b>BRR</b>	H'FFFB1	BRR7	BRR <sub>6</sub>	BRR <sub>5</sub>	BRR4	BRR3	BRR <sub>2</sub>	BRR1	BRR <sub>0</sub>
<b>SCR</b>	H'FFFB2	TIE	<b>RIE</b>	ТE	<b>RE</b>	0	0	$CKE1*^2$	CKE0
<b>TDR</b>	H'FFFB3	TDR7	TDR6	TDR5	TDR4	TDR3	TDR2	TDR <sub>1</sub>	TDR0
<b>SSR</b>	H'FFFB4	<b>TDRE</b>	<b>RDRF</b>	ORER	<b>ERS</b>	<b>PER</b>	TEND	$\Omega$	0
<b>RDR</b>	H'FFFB5	RD <sub>R7</sub>	RDR <sub>6</sub>	RD <sub>R5</sub>	RDR4	RDR <sub>3</sub>	RD <sub>R2</sub>	RDR <sub>1</sub>	RDR <sub>0</sub>
<b>SCMR</b>	H'FFFB6					<b>SDIR</b>	<b>SINV</b>		<b>SMIF</b>

**Table 14.3 Smart Card Interface Register Settings** 

Notes:  $\equiv$  Unused bit.

1. Lower 20 bits of the address in advanced mode.

2. When GM is cleared to 0 in SMR, the CKE1 bit must also be cleared to 0.

**Serial Mode Register (SMR) Settings:** Clear the GM bit to 0 when using the normal smart card interface mode, or set to 1 when using GSM mode. Clear the O/E bit to 0 if the smart card is of the direct convention type, or set to 1 if of the inverse convention type.

Bits CKS1 and CKS0 select the clock source of the built-in baud rate generator. See section 14.3.5, Clock.

**Bit Rate Register (BRR) Settings:** BRR is used to set the bit rate. See section 14.3.5, Clock, for the method of calculating the value to be set.

**Serial Control Register (SCR) Settings:** The TIE, RIE, TE, and RE bits have their normal serial communication functions. See section 13, Serial Communication Interface, for details. The CKE1 and CKE0 bits specify clock output. To disable clock output, clear these bits to 00; to enable clock output, set these bits to 01. Clock output is not performed when the GM bit is set to 1 in SMR. Clock output can also be fixed low or high.

**Smart Card Mode Register (SCMR) Settings:** Clear both the SDIR bit and SINV bit cleared to 0 if the smart card is of the direct convention type, and set both to 1 if of the inverse convention type. To use the smart card interface, set the SMIF bit to 1.

The register settings and examples of starting character waveforms are shown below for two smart cards, one following the direct convention and one the inverse convention.

1. Direct Convention (SDIR = SINV = O/E = 0)  
\n
$$
\begin{array}{c|cccc}\n(Z) & A & Z & Z & A & Z & Z & A & A & Z & (Z) & State \\
\hline\nDs & D0 & D1 & D2 & D3 & D4 & D5 & D6 & D7 & Dp\n\end{array}
$$

With the direct convention type, the logic 1 level corresponds to state Z and the logic 0 level to state A, and transfer is performed in LSB-first order. In the example above, the first character data is H'3B. The parity bit is 1, following the even parity rule designated for smart cards.

2. Indirect Convention (SDIR = SINV = 
$$
O/\overline{E} = 1
$$
)



With the indirect convention type, the logic 1 level corresponds to state A and the logic 0 level to state Z, and transfer is performed in MSB-first order. In the example above, the first character data is H'3F. The parity bit is 0, corresponding to state Z, following the even parity rule designated for smart cards.

In the H8/3067 Group, inversion specified by the SINV bit applies only to the data bits, D7 to D0. For parity bit inversion, the  $O/E$  bit in SMR must be set to odd parity mode. This applies to both transmission and reception.

#### **14.3.5 Clock**

Only an internal clock generated by the on-chip baud rate generator can be used as the transmit/receive clock for the smart card interface. The bit rate is set with the bit rate register (BRR) and the CKS1 and CKS0 bits in the serial mode register (SMR). The equation for calculating the bit rate is shown below. Table 14.5 shows some sample bit rates.

If clock output is selected with CKE0 set to 1, a clock with a frequency of 372 times the bit rate is output from the SCK pin.

$$
B = \frac{\phi}{1488 \times 2^{2n-1} \times (N+1)} \times 10^6
$$

- where, N: BRR setting  $(0 \le N \le 255)$ 
	- B: Bit rate (bit/s)
	- φ: Operating frequency (MHz)
	- n: See table 14.4

### **Table 14.4 n-Values of CKS1 and CKS0 Settings**



Note: If the gear function is used to divide the clock frequency, use the divided frequency to calculate the bit rate. The equation above applies directly to 1/1 frequency division.

#### **Table 14.5 Bit Rates (bits/s) for Various BRR Settings (When n = 0)**



Note: Bit rates are rounded off to one decimal place.

The following equation calculates the bit rate register (BRR) setting from the operating frequency and bit rate. N is an integer from 0 to 255, specifying the value with the smaller error.

$$
N=\frac{\varphi}{1488\times2^{2n-1}\times B}\ \times 10^6-1
$$

**Table 14.6 BRR Settings for Typical Bit Rates (bits/s) (When n = 0)** 



$\phi$ (MHz)	<b>Maximum Bit Rate (bits/s)</b>	N	n	
7.1424	9600	0	0	
10.00	13441	n	0	
10.7136	14400		0	
13.00	17473		0	
14.2848	19200	O	0	
16.00	21505	ი	0	
18.00	24194	n	ი	
20.00	26882		0	

**Table 14.7 Maximum Bit Rates for Various Frequencies (Smart Card Interface Mode)** 

The bit rate error is given by the following equation:

$$
\text{Error } (\%)=\left(\begin{matrix}\phi\\\frac{\phi}{1488\times2^{2n-1}\times B\times(N+1)}\end{matrix}\right.\times\ 10^6-1\right)\times 100
$$

#### **14.3.6 Transmitting and Receiving Data**

**Initialization:** Before transmitting or receiving data, the smart card interface must be initialized as described below. Initialization is also necessary when switching from transmit mode to receive mode, or vice versa.

- 1. Clear the TE and RE bits to 0 in the serial control register (SCR).
- 2. Clear error flags ERS, PER, and ORER to 0 in the serial status register (SSR).
- 3. Set the parity bit  $(O/\overline{E})$  and baud rate generator select bits (CKS1 and CKS0) in the serial mode register (SMR). Clear the  $C/\overline{A}$ , CHR, and MP bits to 0, and set the STOP and PE bits to 1.
- 4. Set the SMIF, SDIR, and SINV bits in the smart card mode register (SCMR).

When the SMIF bit is set to 1, the TxD pin and RxD pin are both switched from port to SCI pin functions and go to the high-impedance state.

- 5. Set a value corresponding to the desired bit rate in the bit rate register (BRR).
- 6. Set the CKE0 bit in SCR. Clear the TIE, RIE, TE, RE, MPIE, TEIE, and CKE1 bits to 0. If the CKE0 bit is set to 1, the clock is output from the SCK pin.
- 7. Wait at least one bit interval, then set the TIE, RIE, TE, and RE bits in SCR. Do not set the TE bit and RE bit at the same time, except for self-diagnosis.

**Transmitting Serial Data:** As data transmission in smart card mode involves error signal sampling and retransmission processing, the processing procedure is different from that for the normal SCI. Figure 14.5 shows a sample transmission processing flowchart.

- 1. Perform smart card interface mode initialization as described in Initialization above.
- 2. Check that the ERS error flag is cleared to 0 in SSR.
- 3. Repeat steps 2 and 3 until it can be confirmed that the TEND flag is set to 1 in SSR.
- 4. Write the transmit data in TDR, clear the TDRE flag to 0, and perform the transmit operation. The TEND flag is cleared to 0.
- 5. To continue transmitting data, go back to step 2.
- 6. To end transmission, clear the TE bit to 0.

The above processing may include interrupt handling DMA transfer.

If transmission ends and the TEND flag is set to 1 while the TIE bit is set to 1 and interrupt requests are enabled, a transmit-data-empty interrupt (TXI) will be requested. If an error occurs in transmission and the ERS flag is set to 1 while the RIE bit is set to 1 and interrupt requests are enabled, a transmit/receive-error interrupt (ERI) will be requested.

The timing of TEND flag setting depends on the GM bit in SMR (see figure 14.4).

If the TXI interrupt activates the DMAC, the number of bytes designated in the DMAC can be transmitted automatically, including automatic retransmission.

For details, see Interrupt Operations and Data Transfer by DMAC in this section.



#### **Figure 14.4 Timing of TEND Flag Setting**



**Figure 14.5 Sample Transmission Processing Flowchart** 

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**Figure 14.6 Relation Between Transmit Operation and Internal Registers** 



**Figure 14.7 Timing of TEND Flag Setting** 

**Receiving Serial Data:** Data reception in smart card mode uses the same processing procedure as for the normal SCI. Figure 14.8 shows a sample reception processing flowchart.

- 1. Perform smart card interface mode initialization as described in Initialization above.
- 2. Check that the ORER flag and PER flag are cleared to 0 in SSR. If either is set, perform the appropriate receive error handling, then clear both the ORER and the PER flag to 0.
- 3. Repeat steps 2 and 3 until it can be confirmed that the RDRF flag is set to 1.
- 4. Read the receive data from RDR.
- 5. To continue receiving data, clear the RDRF flag to 0 and go back to step 2.
- 6. To end reception, clear the RE bit to 0.



**Figure 14.8 Sample Reception Processing Flowchart** 

The above procedure may include interrupt handling and DMA transfer.

If reception ends and the RDRF flag is set to 1 while the RIE bit is set to 1 and interrupt requests are enabled, a receive-data-full interrupt (RXI) will be requested. If an error occurs in reception and either the ORER flag or the PER flag is set to 1, a transmit/receive-error interrupt (ERI) will be requested.

If the RXI interrupt activates the DMAC, the number of bytes designated in the DMAC will be transferred, skipping receive data in which an error occurred.

For details, see Interrupt Operations and Data Transfer by DMAC in this section.

If a parity error occurs during reception and the PER flag is set to 1, the received data is transferred to RDR, so the erroneous data can be read.

**Switching Modes:** When switching from receive mode to transmit mode, first confirm that the receive operation has been completed, then start from initialization, clearing RE to 0 and setting TE to 1. The RDRF, PER, or ORER flag can be used to check that the receive operation has been completed.

When switching from transmit mode to receive mode, first confirm that the transmit operation has been completed, then start from initialization, clearing TE to 0 and setting RE to 1. The TEND flag can be used to check that the transmit operation has been completed.

**Fixing Clock Output:** When the GM bit is set to 1 in SMR, clock output can be fixed by means of the CKE1 and CKE0 bits in SCR. The minimum clock pulse width can be set to the specified width in this case.

Figure 14.9 shows the timing for fixing clock output. In this example,  $GM = 1$ ,  $CKE1 = 0$ , and the CKE0 bit is controlled.



**Figure 14.9 Timing for Fixing Cock Output** 

**Interrupt Operations:** The smart card interface has three interrupt sources: transmit-data-empty (TXI), transmit/receive-error (ERI), and receive-data-full (RXI). The transmit-end interrupt request (TEI) is not available in smart card mode.

A TXI interrupt is requested when the TEND flag is set to 1 in SSR. An RXI interrupt is requested when the RDRF flag is set to 1 in SSR. An ERI interrupt is requested when the ORER, PER, or ERS flag is set to 1 in SSR. These relationships are shown in table 14.8.





**Data Transfer by DMAC:** The DMAC can be used to transmit and receive data in smart card mode, as in normal SCI operations. In transmit mode, when the TEND flag is set to 1 in SSR, the TDRE flag is set simultaneously, generating a TXI interrupt. If the TXI request is designated beforehand as a DMAC activation source, the DMAC will be activated by the TXI request and will transfer the next transmit data. This data transfer by the DMAC automatically clears the TDRE and TEND flags to 0. In the event of an error, the SCI automatically retransmits the same data, keeping the TEND flag cleared to 0 so that the DMAC is not activated. The SCI and DMAC will therefore automatically transmit the designated number of bytes, including retransmission when an error occurs. When an error occurs, the ERS flag is not cleared automatically, so the RIE bit should be set to 1 to enable the error to generate an ERI request, and the ERI interrupt handler should clear ERS.

When using the DMAC to transmit or receive, first set up and enable the DMAC, then make SCI settings. DMAC settings are described in section 7, DMA controller.

In receive operations, an RXI interrupt is requested when the RDRF flag is set to 1 in SSR. If the RXI request is designated beforehand as a DMAC activation source, the DMAC will be activated by the RXI request and will transfer the received data. This data transfer by the DMAC automatically clears the RDRF flag to 0. When an error occurs, the RDRF flag is not set and an error flag is set instead. The DMAC is not activated. The ERI interrupt request is directed to the CPU. The ERI interrupt handler should clear the error flags.

**Examples of Operation in GSM Mode:** When switching between smart card interface mode and software standby mode, use the following procedures to maintain the clock duty cycle.

- Switching from smart card interface mode to software standby mode
- 1. Set the  $P9_4$  data register (DR) and data direction register (DDR) to the values for the fixed output state in software standby mode.

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- 2. Write 0 in the TE and RE bits in the serial control register (SCR) to stop transmit/receive operations. At the same time, set the CKE1 bit to the value for the fixed output state in software standby mode.
- 3. Write 0 in the CKE0 bit in SCR to stop the clock.
- 4. Wait for one serial clock cycle. During this period, the duty cycle is preserved and clock output is fixed at the specified level.
- 5. Write H'00 in the serial mode register (SMR) and smart card mode register (SCMR).
- 6. Make the transition to the software standby state.
- Returning from software standby mode to smart card interface mode
- 1′. Clear the software standby state.
- 2′. Set the CKE1 bit in SCR to the value for the fixed output state at the start of software standby (the current  $P9_4$  pin state).
- 3′. Set smart card interface mode and output the clock. Clock signal generation is started with the normal duty cycle.



**Figure 14.10 Procedure for Stopping and Restarting the Clock** 

Use the following procedure to secure the clock duty cycle after powering on.

- 1. The initial state is port input and high impedance. Use pull-up or pull-down resistors to fix the potential.
- 2. Fix at the output specified by the CKE1 bit in SCR.
- 3. Set SMR and SCMR, and switch to smart card interface mode operation.
- 4. Set the CKE0 bit to 1 in SCR to start clock output.

### **14.4 Usage Notes**

The following points should be noted when using the SCI as a smart card interface.

**Receive Data Sampling Timing and Receive Margin in Smart Card Interface Mode:** In smart card interface mode, the SCI operates on a base clock with a frequency of 372 times the transfer rate. In reception, the SCI synchronizes internally with the fall of the start bit, which it samples on the base clock. Receive data is latched at the rising edge of the 186th base clock pulse. The timing is shown in figure 14.11.



**Figure 14.11 Receive Data Sampling Timing in Smart Card Interface Mode** 

The receive margin can therefore be expressed as follows.

Receive margin in smart card interface mode:

$$
M = \left| (0.5 - \frac{1}{2N}) - (L - 0.5) F - \frac{|D - 0.5|}{N} (1 + F) \right| \times 100\%
$$

- M: Receive margin (%)
- N: Ratio of clock frequency to bit rate  $(N = 372)$

- D: Clock duty cycle  $(D = 0$  to 1.0)
- L: Frame length  $(L = 10)$
- F: Absolute deviation of clock frequency

From the above equation, if  $F = 0$  and  $D = 0.5$ , the receive margin is as follows.

When  $D = 0.5$  and  $F = 0$ :

 $M = (0.5 - 1/2 \times 372) \times 100\%$  $= 49.866%$ 

**Retransmission:** Retransmission is performed by the SCI in receive mode and transmit mode as described below.

• Retransmission when SCI is in Receive Mode

Figure 14.12 illustrates retransmission when the SCI is in receive mode.

- 1. If an error is found when the received parity bit is checked, the PER bit is automatically set to 1. If the RIE bit in SCR is set to the enable state, an ERI interrupt is requested. The PER bit should be cleared to 0 in SSR before the next parity bit sampling timing.
- 2. The RDRF bit in SSR is not set for the frame in which the error has occurred.
- 3. If no error is found when the received parity bit is checked, the PER bit is not set to 1 in SSR.
- 4. If no error is found when the received parity bit is checked, the receive operation is assumed to have been completed normally, and the RDRF bit is automatically set to 1 in SSR. If the RIE bit in SCR is set to the enable state, an RXI interrupt is requested. If RXI is enabled as a DMA transfer activation source, the RDR contents can be read automatically. When the DMAC reads the RDR data, the RDRF flag is automatically cleared to 0.
- 5. When a normal frame is received, the data pin is held in the high-impedance state at the error signal transmission timing.



**Figure 14.12 Retransmission in SCI Receive Mode**
• Retransmission when SCI is in Transmit Mode

Figure 14.13 illustrates retransmission when the SCI is in transmit mode.

- 6. If an error signal is sent back from the receiving device after transmission of one frame is completed, the ERS bit is set to 1 in SSR. If the RIE bit in SCR is set to the enable state, an ERI interrupt is requested. The ERS bit should be cleared to 0 in SSR before the next parity bit sampling timing.
- 7. The TEND bit in SSR is not set for the frame for which the error signal was received.
- 8. If an error signal is not sent back from the receiving device, the ERS flag is not set in SSR.
- 9. If an error signal is not sent back from the receiving device, transmission of one frame, including retransmission, is assumed to have been completed, and the TEND bit is set to 1 in SSR. If the TIE bit in SCR is set to the enable state, a TXI interrupt is requested. If TXI is enabled as a DMA transfer activation source, the next data can be written in TDR automatically. When the DMAC writes data in TDR, the TDRE bit is automatically cleared to 0.



**Figure 14.13 Retransmission in SCI Transmit Mode** 

**Note on Block Transfer Mode Support:** The smart card interface installed in the H8/3006 and H8/3007 support an IC card (smart card) interface with provision for ISO/IEC7816-3 T=0 (character transmission). Therefore, block transfer operations are not supported (error signal transmission, detection, and automatic data retransmission are not performed).



# Section 15 A/D Converter

### **15.1 Overview**

The H8/3006 and H8/3007 include a 10-bit successive-approximations A/D converter with a selection of up to eight analog input channels.

When the A/D converter is not used, it can be halted independently to conserve power. For details see section 19.6, Module Standby Function.

The H8/3006 and H8/3007 support 70/134-state conversion as a high-speed conversion mode. Note that it differs in this respect from the H8/3048 Group, which supports 134/266-state conversion.

#### **15.1.1 Features**

A/D converter features are listed below.

- 10-bit resolution
- Eight input channels
- Selectable analog conversion voltage range

The analog voltage conversion range can be programmed by input of an analog reference voltage at the  $V_{\text{per}}$  pin.

- High-speed conversion Conversion time: maximum 3.5 μs per channel (with 20 MHz system clock)
- Two conversion modes

Single mode: A/D conversion of one channel

Scan mode: continuous conversion on one to four channels

- Four 16-bit data registers A/D conversion results are transferred for storage into data registers corresponding to the channels.
- Sample-and-hold function
- Three conversion start sources The A/D converter can be activated by software, an external trigger, or an 8-bit timer compare match.
- A/D interrupt requested at end of conversion At the end of A/D conversion, an A/D end interrupt (ADI) can be requested.
- DMA controller (DMAC) activation The DMAC can be activated at the end of A/D conversion.

#### **15.1.2 Block Diagram**

Figure 15.1 shows a block diagram of the A/D converter.





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#### **15.1.3 Pin Configuration**

Table 15.1 summarizes the A/D converter's input pins. The eight analog input pins are divided into two groups: group 0 (AN<sub>0</sub> to AN<sub>3</sub>), and group 1 (AN<sub>4</sub> to AN<sub>7</sub>). AV<sub>cc</sub> and AV<sub>ss</sub> are the power supply for the analog circuits in the A/D converter.  $V_{REF}$  is the A/D conversion reference voltage.



#### **Table 15.1 A/D Converter Pins**

### **15.1.4 Register Configuration**

Table 15.2 summarizes the A/D converter's registers.

#### **Table 15.2 A/D Converter Registers**



Notes: 1. Lower 20 bits of the address in advanced mode.

2. Only 0 can be written in bit 7, to clear the flag.

### **15.2 Register Descriptions**

### **15.2.1 A/D Data Registers A to D (ADDRA to ADDRD)**



The four A/D data registers (ADDRA to ADDRD) are 16-bit read-only registers that store the results of A/D conversion.

An A/D conversion produces 10-bit data, which is transferred for storage into the A/D data register corresponding to the selected channel. The upper 8 bits of the result are stored in the upper byte of the A/D data register. The lower 2 bits are stored in the lower byte. Bits 5 to 0 of an A/D

data register are reserved bits that are always read as 0. Table 15.3 indicates the pairings of analog input channels and A/D data registers.

The CPU can always read the A/D data registers. The upper byte can be read directly, but the lower byte is read through a temporary register (TEMP). For details see section 15.3, CPU Interface.

The A/D data registers are initialized to H'0000 by a reset and in standby mode.

#### **Table 15.3 Analog Input Channels and A/D Data Registers**



### **15.2.2 A/D Control/Status Register (ADCSR)**



Note:  $*$  Only 0 can be written, to clear the flag.

ADCSR is an 8-bit readable/writable register that selects the mode and controls the A/D converter. ADCSR is initialized to H'00 by a reset and in standby mode.

**Bit 7—A/D End Flag (ADF):** Indicates the end of A/D conversion.



**Bit 6—A/D Interrupt Enable (ADIE):** Enables or disables the interrupt (ADI) requested at the end of A/D conversion.



**Bit 5—A/D Start (ADST):** Starts or stops A/D conversion. The ADST bit remains set to 1 during A/D conversion. It can also be set to 1 by external trigger input at the  $\overline{\text{ADTRG}}$  pin, or by an 8-bit timer compare match.



**Bit 4—Scan Mode (SCAN):** Selects single mode or scan mode. For further information on operation in these modes, see section 15.4, Operation. Clear the ADST bit to 0 before switching the conversion mode.



**Bit 3—Clock Select (CKS):** Selects the A/D conversion time. Clear the ADST bit to 0 before switching the conversion time.



**Group** 

**Bits 2 to 0—Channel Select 2 to 0 (CH2 to CH0):** These bits and the SCAN bit select the analog input channels. Clear the ADST bit to 0 before changing the channel selection.



**15.2.3 A/D Control Register (ADCR)** 



by an external trigger or 8-bit timer compare match

ADCR is an 8-bit readable/writable register that enables or disables starting of A/D conversion by external trigger input or an 8-bit timer compare match signal. ADCR is initialized to H'7E by a reset and in standby mode.

**Bit 7—Trigger Enable (TRGE):** Enables or disables starting of A/D conversion by an external trigger or 8-bit timer compare match.



External trigger pin and 8-bit timer selection are performed by the 8-bit timer. For details, see section 10, 8-Bit Timers.

**Bits 6 to 1—Reserved:** These bits cannot be modified and are always read as 1.

**Bit 0—Reserved:** This bit can be read or written, but should not be set to 1.

# **15.3 CPU Interface**

ADDRA to ADDRD are 16-bit registers, but they are connected to the CPU by an 8-bit data bus. Therefore, although the upper byte can be be accessed directly by the CPU, the lower byte is read through an 8-bit temporary register (TEMP).

An A/D data register is read as follows. When the upper byte is read, the upper-byte value is transferred directly to the CPU and the lower-byte value is transferred into TEMP. Next, when the lower byte is read, the TEMP contents are transferred to the CPU.

When reading an A/D data register, always read the upper byte before the lower byte. It is possible to read only the upper byte, but if only the lower byte is read, incorrect data may be obtained.





**Figure 15.2 A/D Data Register Access Operation (Reading H'AA40)** 

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### **15.4 Operation**

The A/D converter operates by successive approximations with 10-bit resolution. It has two operating modes: single mode and scan mode.

#### **15.4.1 Single Mode (SCAN = 0)**

Single mode should be selected when only one A/D conversion on one channel is required. A/D conversion starts when the ADST bit is set to 1 by software, or by external trigger input. The ADST bit remains set to 1 during A/D conversion and is automatically cleared to 0 when conversion ends.

When conversion ends the ADF bit is set to 1. If the ADIE bit is also set to 1, an ADI interrupt is requested at this time. To clear the ADF flag to 0, first read ADCSR, then write 0 in ADF.

When the mode or analog input channel must be switched during analog conversion, to prevent incorrect operation, first clear the ADST bit to 0 in ADCSR to halt A/D conversion. After making the necessary changes, set the ADST bit to 1 to start A/D conversion again. The ADST bit can be set at the same time as the mode or channel is changed.

Typical operations when channel  $1 (AN<sub>1</sub>)$  is selected in single mode are described next.

Figure 15.3 shows a timing diagram for this example.

1. Single mode is selected (SCAN = 0), input channel  $AN_1$  is selected (CH2 = CH1 = 0,  $CH0 = 1$ ), the A/D interrupt is enabled (ADIE = 1), and A/D conversion is started  $(ADST = 1).$ 

- 2. When A/D conversion is completed, the result is transferred into ADDRB. At the same time the ADF flag is set to 1, the ADST bit is cleared to 0, and the A/D converter becomes idle.
- 3. Since  $ADF = 1$  and  $ADIE = 1$ , an ADI interrupt is requested.
- 4. The A/D interrupt handling routine starts.
- 5. The routine reads ADCSR, then writes 0 in the ADF flag.
- 6. The routine reads and processes the conversion result (ADDRB).
- 7. Execution of the A/D interrupt handling routine ends. After that, if the ADST bit is set to 1, A/D conversion starts again and steps 2 to 7 are repeated.



**Figure 15.3 Example of A/D Converter Operation (Single Mode, Channel 1 Selected)** 

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#### **15.4.2 Scan Mode (SCAN = 1)**

Scan mode is useful for monitoring analog inputs in a group of one or more channels. When the ADST bit is set to 1 by software or external trigger input, A/D conversion starts on the first channel in the group ( $AN_0$  when CH2 = 0,  $AN_4$  when CH2 = 1). When two or more channels are selected, after conversion of the first channel ends, conversion of the second channel  $(AN_1$  or  $AN_5)$ starts immediately. A/D conversion continues cyclically on the selected channels until the ADST bit is cleared to 0. The conversion results are transferred for storage into the A/D data registers corresponding to the channels.

When the mode or analog input channel selection must be changed during analog conversion, to prevent incorrect operation, first clear the ADST bit to 0 in ADCSR to halt A/D conversion. After making the necessary changes, set the ADST bit to 1. A/D conversion will start again from the first channel in the group. The ADST bit can be set at the same time as the mode or channel selection is changed.

Typical operations when three channels in group  $0 (AN_0 \text{ to } AN_2)$  are selected in scan mode are described next. Figure 15.4 shows a timing diagram for this example.

- 1. Scan mode is selected (SCAN = 1), scan group 0 is selected (CH2 = 0), analog input channels AN<sub>0</sub> to AN<sub>2</sub> are selected (CH1 = 1, CH0 = 0), and A/D conversion is started (ADST = 1).
- 2. When A/D conversion of the first channel  $(AN_0)$  is completed, the result is transferred into ADDRA. Next, conversion of the second channel  $(AN_1)$  starts automatically.
- 3. Conversion proceeds in the same way through the third channel  $(AN_2)$ .
- 4. When conversion of all selected channels  $(AN_0$  to  $AN_2)$  is completed, the ADF flag is set to 1 and conversion of the first channel  $(AN_0)$  starts again. If the ADIE bit is set to 1, an ADI interrupt is requested at this time.
- 5. Steps 2 to 4 are repeated as long as the ADST bit remains set to 1. When the ADST bit is cleared to 0, A/D conversion stops. After that, if the ADST bit is set to 1, A/D conversion starts again from the first channel  $(AN_0)$ .



**Figure 15.4 Example of A/D Converter Operation (Scan Mode, Channels 3 AN<sup>0</sup> to AN<sup>2</sup> Selected)** 

#### **15.4.3 Input Sampling and A/D Conversion Time**

The A/D converter has a built-in sample-and-hold circuit. The A/D converter samples the analog input at a time  $t<sub>p</sub>$  after the ADST bit is set to 1, then starts conversion. Figure 15.5 shows the A/D conversion timing. Table 15.4 indicates the A/D conversion time.

As indicated in figure 15.5, the A/D conversion time includes  $t<sub>p</sub>$  and the input sampling time. The length of  $t<sub>p</sub>$  varies depending on the timing of the write access to ADCSR. The total conversion time therefore varies within the ranges indicated in table 15.4.

In scan mode, the values given in table 15.4 apply to the first conversion. In the second and subsequent conversions the conversion time is fixed at 128 states when  $CKS = 0$  or 66 states when  $CKS = 1$ .



**Figure 15.5 A/D Conversion Timing** 



### **Table 15.4 A/D Conversion Time (Single Mode)**

Note: Values in the table are numbers of states.

#### **15.4.4 External Trigger Input Timing**

A/D conversion can be externally triggered. When the TRGE bit is set to 1 in ADCR and the 8-bit timer's ADTE bit is cleared to 0, external trigger input is enabled at the ADTRG pin. A falling edge at the ADTRG pin sets the ADST bit to 1 in ADCSR, starting A/D conversion. Other operations, in both single and scan modes, are the same as if the ADST bit had been set to 1 by software. Figure 15.6 shows the timing.



**Figure 15.6 External Trigger Input Timing** 

### **15.5 Interrupts**

The A/D converter generates an interrupt (ADI) at the end of A/D conversion. The ADI interrupt request can be enabled or disabled by the ADIE bit in ADCSR. The ADI interrupt request can be designated as a DMAC activation source. In this case, an interrupt request is not sent to the CPU.

### **15.6 Usage Notes**

When using the A/D converter, note the following points:

- 1. Analog Input Voltage Range: During A/D conversion, the voltages input to the analog input pins should be in the range  $AV_{ss} \leq AN_{s} \leq V_{per}$ .
- 2. Relationships of  $AV_{cc}$  and  $AV_{ss}$  to  $V_{cc}$  and  $V_{ss}$ :  $AV_{cc}$ ,  $AV_{ss}$ ,  $V_{cc}$ , and  $V_{ss}$  should be related as follows:  $AV_{ss} = V_{ss}$ .  $AV_{cc}$  and  $AV_{ss}$  must not be left open, even if the A/D converter is not used.
- 3.  $V_{REF}$  Programming Range: The reference voltage input at the  $V_{REF}$  pin should be in the range  $V_{REF} \leq AV_{CC}$
- 4. Note on Board Design: In board layout, separate the digital circuits from the analog circuits as much as possible. Particularly avoid layouts in which the signal lines of digital circuits cross or closely approach the signal lines of analog circuits. Induction and other effects may cause the analog circuits to operate incorrectly, or may adversely affect the accuracy of A/D conversion.

The analog input signals ( $AN_0$  to  $AN_7$ ), analog reference voltage ( $V_{REF}$ ), and analog supply voltage  $(AV_{cc})$  must be separated from digital circuits by the analog ground  $(AV_{sc})$ . The analog ground  $(AV_{\rm ss})$  should be connected to a stable digital ground  $(V_{\rm ss})$  at one point on the board.

5. Note on Noise: To prevent damage from surges and other abnormal voltages at the analog input pins  $(AN_0$  to  $AN_7$ ) and analog reference voltage pin  $(V_{REF}$ ), connect a protection circuit like the one in figure 15.7 between  $AV_{cc}$  and  $AV_{ss}$ . The bypass capacitors connected to  $AV_{cc}$ and  $V_{REF}$  and the filter capacitors connected to  $AN_0$  to  $AN_7$  must be connected to  $AV_{ss}$ . If filter capacitors like the ones in figure 15.7 are connected, the voltage values input to the analog input pins  $(AN_0$  to  $AN_7$ ) will be smoothed, which may give rise to error. Error can also occur if A/D conversion is frequently performed in scan mode so that the current that charges and discharges the capacitor in the sample-and-hold circuit of the A/D converter becomes greater than that input to the analog input pins via input impedance  $R_{\mu}$ . The circuit constants should therefore be selected carefully.





#### **Table 15.5 Analog Input Pin Ratings**



When conversion time 134 states, V<sub>cc</sub> = 4.0 V to 5.5 V and  $\phi$   $\leq$  13 MHz. For details see section 20, Electrical Characteristics.





Note: Numeric values are approximate, except in table 15.5

- 6. A/D Conversion Accuracy Definitions: A/D conversion accuracy in the H8/3006 and H8/3007 are defined as follows:
	- Resolution

Digital output code length of A/D converter

⎯ Offset error

Deviation from ideal A/D conversion characteristic of analog input voltage required to raise digital output from minimum voltage value 0000000000 to 0000000001 (figure 15.10)

— Full-scale error

Deviation from ideal A/D conversion characteristic of analog input voltage required to raise digital output from 1111111110 to 1111111111 (figure 15.10)

— Ouantization error

Intrinsic error of the A/D converter; 1/2 LSB (figure 15.9)

- Nonlinearity error

Deviation from ideal A/D conversion characteristic in range from zero volts to full scale, exclusive of offset error, full-scale error, and quantization error.

- Absolute accuracy

Deviation of digital value from analog input value, including offset error, full-scale error, quantization error, and nonlinearity error.



**Figure 15.9 A/D Converter Accuracy Definitions (1)** 





**Figure 15.10 A/D Converter Accuracy Definitions (2)** 

7. Allowable Signal-Source Impedance: The analog inputs of the H8/3006 and H8/3007 are designed to assure accurate conversion of input signals with a signal-source impedance not exceeding 10 k $\Omega$ . The reason for this rating is that it enables the input capacitor in the sampleand-hold circuit in the A/D converter to charge within the sampling time. If the sensor output impedance exceeds 10 k $\Omega$ , charging may be inadequate and the accuracy of A/D conversion cannot be guaranteed.

If a large external capacitor is provided in single mode, then the internal  $10 - k\Omega$  input resistance becomes the only significant load on the input. In this case the impedance of the signal source is not a problem.

A large external capacitor, however, acts as a low-pass filter. This may make it impossible to track analog signals with high dv/dt (e.g. a variation of  $5 \text{ mV/}$ us) (figure 15.11). To convert high-speed analog signals or to use scan mode, insert a low-impedance buffer.

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8. Effect on Absolute Accuracy: Attaching an external capacitor creates a coupling with ground, so if there is noise on the ground line, it may degrade absolute accuracy. The capacitor must be connected to an electrically stable ground, such as  $AV_{\rm sc}$ .

If a filter circuit is used, be careful of interference with digital signals on the same board, and make sure the circuit does not act as an antenna.



**Figure 15.11 Analog Input Circuit (Example)** 



# Section 16 D/A Converter

# **16.1 Overview**

The H8/3006 and H8/3007 include a D/A converter with two channels.

### **16.1.1 Features**

D/A converter features are listed below.

- Eight-bit resolution
- Two output channels
- Conversion time: maximum 10 μs (with 20-pF capacitive load)
- Output voltage: 0 V to  $V_{REF}$
- D/A outputs can be sustained in software standby mode

#### **16.1.2 Block Diagram**

Figure 16.1 shows a block diagram of the D/A converter.



**Figure 16.1 D/A Converter Block Diagram** 

#### **16.1.3 Pin Configuration**

Table 16.1 summarizes the D/A converter's input and output pins.

#### **Table 16.1 D/A Converter Pins**



#### **16.1.4 Register Configuration**

Table 16.2 summarizes the D/A converter's registers.

#### **Table 16.2 D/A Converter Registers**



Note: \* Lower 20 bits of the address in advanced mode.

### **16.2 Register Descriptions**

#### **16.2.1 D/A Data Registers 0 and 1 (DADR0/1)**



The D/A data registers (DADR0 and DADR1) are 8-bit readable/writable registers that store the data to be converted. When analog output is enabled, the D/A data register values are constantly converted and output at the analog output pins.

The D/A data registers are initialized to H'00 by a reset and in standby mode.

When the DASTE bit is set to 1 in the D/A standby control register (DASTCR), the D/A registers are not initialized in software standby mode.

### **16.2.2 D/A Control Register (DACR)**



DACR is an 8-bit readable/writable register that controls the operation of the D/A converter. DACR is initialized to H'1F by a reset and in standby mode.

When the DASTE bit is set to 1 in DASTCR, the DACR is not initialized in software standby mode.

**Bit 7—D/A Output Enable 1 (DAOE1):** Controls D/A conversion and analog output.



**Bit 6—D/A Output Enable 0 (DAOE0):** Controls D/A conversion and analog output.



**Bit 5—D/A Enable (DAE):** Controls D/A conversion, together with bits DAOE0 and DAOE1. When the DAE bit is cleared to 0, analog conversion is controlled independently in channels 0 and 1. When the DAE bit is set to 1, analog conversion is controlled together in channels 0 and 1. Output of the conversion results is always controlled independently by DAOE0 and DAOE1.



When the DAE bit is set to 1, even if bits DAOE0 and DAOE1 in DACR and the ADST bit in ADCSR are cleared to 0, the same current is drawn from the analog power supply as during A/D and D/A conversion.

**Bits 4 to 0—Reserved:** These bits cannot be modified and are always read as 1.

#### **16.2.3 D/A Standby Control Register (DASTCR)**

DASTCR is an 8-bit readable/writable register that enables or disables D/A output in software standby mode.



DASTCR is initialized to H'FE by a reset and in hardware standby mode. It is not initialized in software standby mode.

**Bits 7 to 1—Reserved:** These bits cannot be modified and are always read as 1.

**Bit 0—D/A Standby Enable (DASTE):** Enables or disables D/A output in software standby mode.



### **16.3 Operation**

The D/A converter has two built-in D/A conversion circuits that can perform conversion independently.

D/A conversion is performed constantly while enabled in DACR. If the DADR0 or DADR1 value is modified, conversion of the new data begins immediately. The conversion results are output when bits DAOE0 and DAOE1 are set to 1.

An example of D/A conversion on channel 0 is given next. Timing is indicated in figure 16.2.

- 1. Data to be converted is written in DADR0.
- 2. Bit DAOE0 is set to 1 in DACR. D/A conversion starts and DA0 becomes an output pin. The converted result is output after the conversion time.

The output value is  $\frac{\text{DADR contents}}{256} \times V_{REF}$ 256

Output of this conversion result continues until the value in DADR0 is modified or the DAOE0 bit is cleared to 0.

- 3. If the DADR0 value is modified, conversion starts immediately, and the result is output after the conversion time.
- 4. When the DAOE0 bit is cleared to 0, DA0 becomes an input pin.





**Figure 16.2 Example of D/A Converter Operation** 

### **16.4 D/A Output Control**

In the H8/3006 and H8/3007, D/A converter output can be enabled or disabled in software standby mode.

When the DASTE bit is set to 1 in DASTCR, D/A converter output is enabled in software standby mode. The D/A converter registers retain the values they held prior to the transition to software standby mode.

When D/A output is enabled in software standby mode, the reference supply current is the same as during normal operation.



# Section 17 RAM

# **17.1 Overview**

The H8/3007 has 4 kbytes of high-speed static RAM on-chip. The H8/3006 has 2 kbytes. The RAM is connected to the CPU by a 16-bit data bus. The CPU accesses both byte data and word data in two states, making the RAM useful for rapid data transfer.

The on-chip RAM of the H8/3007 is assigned to addresses H'FEF20 to H'FFF1F in modes 1 and 2, and to addresses H'FFEF20 to H'FFFF1F in modes 3 and 4. The on-chip RAM of the H8/3006 are assigned to addresses H'FF720 to H'FFF1F in modes 1 and 2, and to addresses H'FFF720 to H'FFFF1F in modes 3 and 4. The RAM enable bit (RAME) in the system control register (SYSCR) can enable or disable the on-chip RAM.

#### **17.1.1 Block Diagram**





### **Figure 17.1 RAM Block Diagram**

### **17.1.2 Register Configuration**

The on-chip RAM is controlled by SYSCR. Table 17.1 gives the address and initial value of SYSCR.

#### **Table 17.1 System Control Register**



**17.2 System Control Register (SYSCR)** 



One function of SYSCR is to enable or disable access to the on-chip RAM. The on-chip RAM is enabled or disabled by the RAME bit in SYSCR. For details about the other bits, see section 3.3, System Control Register (SYSCR).

**Bit 0—RAM Enable (RAME):** Enables or disables the on-chip RAM. The RAME bit is initialized at the rising edge of the input at the RES pin. It is not initialized in software standby mode.



# **17.3 Operation**

When the RAME bit is set to 1, the on-chip RAM is enabled. Accesses to addresses H'FEF20 to H'FFF1F in the H8/3007 in modes 1 and 2, and to addresses H'FFEF20 to H'FFFF1F in the H8/3007 in modes 3 and 4, are directed to the on-chip RAM. In the H8/3006, accesses to addresses H'FF720 to H'FFF1F in modes 1 and 2, to addresses H'FFF720 to H'FFFF1F in modes 3 and 4, are directed to the on-chip RAM. In modes 1 to 4, when the RAME bit is cleared to 0, the off-chip address space is accessed.

Since the on-chip RAM is connected to the CPU by an internal 16-bit data bus, it can be written and read by word access. It can also be written and read by byte access. Byte data is accessed in two states using the upper 8 bits of the data bus. Word data starting at an even address is accessed in two states using all 16 bits of the data bus.

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# Section 18 Clock Pulse Generator

### **18.1 Overview**

The H8/3006 and H8/3007 have a built-in clock pulse generator (CPG) that generates the system clock ( $\phi$ ) and other internal clock signals ( $\phi/2$  to  $\phi/4096$ ). After duty adjustment, a frequency divider divides the clock frequency to generate the system clock (φ). The system clock is output at the  $\phi$  pin<sup>\*1</sup> and furnished as a master clock to prescalers that supply clock signals to the on-chip supporting modules. Frequency division ratios of 1/1, 1/2, 1/4, and 1/8 can be selected for the frequency divider by settings in a division control register  $(DIVCR)*^2$ . Power consumption in the chip is reduced in almost direct proportion to the frequency division ratio.

- Notes: 1. Usage of the φ pin differs depending on the chip operating mode and the PSTOP bit setting in the module standby control register (MSTCR). For details, see section 19.7, System Clock Output Disabling Function.
	- 2. The division ratio of the frequency divider can be changed dynamically during operation. The clock output at the  $\phi$  pin also changes when the division ratio is changed. The frequency output at the  $\phi$  pin is shown below.

 $\phi = EXTAL \times n$ 

where, EXTAL: Frequency of crystal resonator or external clock signal

n: Frequency division ratio  $(n = 1/1, 1/2, 1/4, \text{ or } 1/8)$ 

#### **18.1.1 Block Diagram**

Figure 18.1 shows a block diagram of the clock pulse generator.



#### **Figure 18.1 Block Diagram of Clock Pulse Generator**

# **18.2 Oscillator Circuit**

Clock pulses can be supplied by connecting a crystal resonator, or by input of an external clock signal.

#### **18.2.1 Connecting a Crystal Resonator**

**Circuit Configuration:** A crystal resonator can be connected as in the example in figure 18.2. The damping resistance Rd should be selected according to table 18.1. An AT-cut parallelresonance crystal should be used.



**Figure 18.2 Connection of Crystal Resonator (Example)** 

#### **Table 18.1 Damping Resistance Value**



Note: A crystal resonator between 2 MHz and 20 MHz can be used. If the chip is to be operated at less than 2 MHz, the on-chip frequency divider should be used. (A crystal resonator of less than 2 MHz cannot be used.)

**Crystal Resonator:** Figure 18.3 shows an equivalent circuit of the crystal resonator. The crystal resonator should have the characteristics listed in table 18.2.



**Figure 18.3 Crystal Resonator Equivalent Circuit** 





Use a crystal resonator with a frequency equal to the system clock frequency  $(\phi)$ .

**Notes on Board Design:** When a crystal resonator is connected, the following points should be noted:

Other signal lines should be routed away from the oscillator circuit to prevent induction from interfering with correct oscillation. See figure 18.4.

When the board is designed, the crystal resonator and its load capacitors should be placed as close as possible to the XTAL and EXTAL pins.





### **18.2.2 External Clock Input**

**Circuit Configuration:** An external clock signal can be input as shown in the examples in figure 18.5. If the XTAL pin is left open, the stray capacitance should not exceed 10 pF. If the stray capacitance at the XTAL pin exceeds 10 pF, use configuration b instead and hold the clock high in standby mode.



**Figure 18.5 External Clock Input (Examples)** 

**External Clock:** The external clock frequency should be equal to the system clock frequency when not divided by the on-chip frequency divider. Table 18.3 shows the clock timing, figure 18.6 shows the external clock input timing, and figure 18.7 shows the external clock output settling delay timing. When the appropriate external clock is input via the EXTAL pin, its waveform is corrected by the on-chip oscillator and duty adjustment circuit.

When the appropriate external clock is input via the EXTAL pin, its waveform is corrected by the on-chip oscillator and duty adjustment circuit. The resulting stable clock is output to external devices after the external clock settling time  $(t_{\text{DEXT}})$  has passed after the clock input. The system must remain reset with the reset signal low during  $t_{\text{DEXT}}$ , while the clock output is unstable.





Note:  $*$  t<sub>DEXT</sub> includes a 10 t<sub>cyc</sub> of  $\overline{\text{RES}}$  pulse width (t<sub>RESW</sub>).



**Figure 18.6 External Clock Input Timing** 



#### **Figure 18.7 External Clock Output Settling Delay Timing**

# **18.3 Duty Adjustment Circuit**

When the oscillator frequency is 5 MHz or higher, the duty adjustment circuit adjusts the duty cycle of the clock signal from the oscillator to generate φ.

### **18.4 Prescalers**

The prescalers divide the system clock  $(\phi)$  to generate internal clocks  $(\phi/2 \text{ to } \phi/4096)$ .

# **18.5 Frequency Divider**

The frequency divider divides the duty-adjusted clock signal to generate the system clock (φ). The frequency division ratio can be changed dynamically by modifying the value in DIVCR, as described below. Power consumption in the chip is reduced in almost direct proportion to the frequency division ratio. The system clock generated by the frequency divider can be output at the φ pin.



#### **18.5.1 Register Configuration**

Table 18.4 summarizes the frequency division register.

#### **Table 18.4 Frequency Division Register**



**18.5.2 Division Control Register (DIVCR)** 

DIVCR is an 8-bit readable/writable register that selects the division ratio of the frequency divider.



DIVCR is initialized to H'FC by a reset and in hardware standby mode. It is not initialized in software standby mode.

**Bits 7 to 2—Reserved:** These bits cannot be modified and are always read as 1.

**Bits 1 and 0—Divide (DIV1, DIV0):** These bits select the frequency division ratio, as follows.



#### **18.5.3 Usage Notes**

The DIVCR setting changes the  $\phi$  frequency, so note the following points.

- Select a frequency division ratio that stays within the assured operation range specified for the clock cycle time  $t_{\text{cyc}}$  in the AC electrical characteristics. Set  $\phi$ min to the lower limit of the operating frequency range, and ensure that φ does not fall below this lower limit.
- All on-chip module operations are based on φ. Note that the timing of timer operations, serial communication, and other time-dependent processing differs before and after any change in the division ratio. The waiting time for exit from software standby mode also changes when the division ratio is changed. For details, see section 19.4.3, Selection of Waiting Time for Exit from Software Standby Mode.



# Section 19 Power-Down State

### **19.1 Overview**

The H8/3006 and H8/3007 have a power-down state that greatly reduces power consumption by halting the CPU, and a module standby function that reduces power consumption by selectively halting on-chip modules.

The power-down state includes the following three modes:

- Sleep mode
- Software standby mode
- Hardware standby mode

The module standby function can halt on-chip supporting modules independently of the powerdown state. The modules that can be halted are the 16-bit timer, 8-bit timer, SCI0, SCI1, SCI2, DMAC, DRAM interface, and A/D converter.

Table 19.1 indicates the methods of entering and exiting the power-down modes and module standby mode, and gives the status of the CPU and on-chip supporting modules in each mode.



19. Power-Down State

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# RENESAS

MSTCRL: Module standby control register L

### **19.2 Register Configuration**

The H8/3006 and H8/3007 have a system control register (SYSCR) that controls the power-down state, and module standby control registers H (MSTCRH) and L (MSTCRL) that control the module standby function. Table 19.2 summarizes these registers.

#### **Table 19.2 Control Register**



Note: \* Lower 20 bits of the address in advanced mode.

#### **19.2.1 System Control Register (SYSCR)**



SYSCR is an 8-bit readable/writable register. Bit 7 (SSBY), bits 6 to 4 (STS2 to STS0), and bit 1 (SSOE) control the power-down state. For information on the other SYSCR bits, see section 3.3, System Control Register (SYSCR).

**Bit 7—Software Standby (SSBY):** Enables transition to software standby mode. When software standby mode is exited by an external interrupt, this bit remains set to 1 after the return to normal operation. To clear this bit, write 0.



**Bits 6 to 4—Standby Timer Select (STS2 to STS0):** These bits select the length of time the CPU and on-chip supporting modules wait for the clock to settle when software standby mode is exited by an external interrupt. If the clock is generated by a crystal resonator, set these bits according to the clock frequency so that the waiting time will be at least 7 ms (oscillation settling time). See table 19.3. If an external clock is used, any setting is permitted.



**Bit 1—Software Standby Output Port Enable (SSOE):** Specifies whether the address bus and bus control signals ( $\overline{CS}_0$  to  $\overline{CS}_7$ ,  $\overline{AS}$ ,  $\overline{RD}$ ,  $\overline{HWR}$ ,  $\overline{LWR}$ ,  $\overline{UCAS}$ ,  $\overline{LCAS}$ , and  $\overline{RFSH}$ ) are kept as outputs or fixed high, or placed in the high-impedance state in software standby mode.



#### **19.2.2 Module Standby Control Register H (MSTCRH)**

MSTCRH is an 8-bit readable/writable register that controls output of the system clock (φ). It also controls the module standby function, which places individual on-chip supporting modules in the standby state. Module standby can be designated for the SCI0, SCI1, SCI2.



MSTCRH is initialized to H'78 by a reset and in hardware standby mode. It is not initialized in software standby mode.

**Bit 7—**φ **Clock Stop (PSTOP):** Enables or disables output of the system clock (φ).



**Bits 6 to 3—Reserved:** These bits cannot be modified and are always read as 1.

**Bit 2—Module Standby H2 (MSTPH2):** Selects whether to place the SCI2 in standby.



**Bit 1—Module Standby H1 (MSTPH1):** Selects whether to place the SCI1 in standby.



**Bit 0—Module Standby H0 (MSTPH0):** Selects whether to place the SCI0 in standby.



#### **19.2.3 Module Standby Control Register L (MSTCRL)**

MSTCRL is an 8-bit readable/writable register that controls the module standby function, which places individual on-chip supporting modules in the standby state. Module standby can be designated for the DMAC, 16-bit timer, DRAM interface, 8-bit timer, and A/D converter modules.



MSTCRL is initialized to H'00 by a reset and in hardware standby mode. It is not initialized in software standby mode.

**Bit 7—Module Standby L7 (MSTPL7):** Selects whether to place the DMAC in standby.



**Bit 6—Reserved:** This bit can be written and read.

**Bit 5—Module Standby L5 (MSTPL5):** Selects whether to place the DRAM interface in standby.



**Bit 4—Module Standby L4 (MSTPL4):** Selects whether to place the 16-bit timer in standby.



**Bit 3—Module Standby L3 (MSTPL3):** Selects whether to place 8-bit timer channels 0 and 1 in standby.



**Bit 2—Module Standby L2 (MSTPL2):** Selects whether to place 8-bit timer channels 2 and 3 in standby.

**Bit 2** 

<b>MSTPL2</b>	<b>Description</b>
---------------	--------------------



**Bit 1—Reserved:** This bit can be written and read.

**Bit 0—Module Standby L0 (MSTPL0):** Selects whether to place the A/D converter in standby.



### **19.3 Sleep Mode**

#### **19.3.1 Transition to Sleep Mode**

When the SSBY bit is cleared to 0 in SYSCR, execution of the SLEEP instruction causes a transition from the program execution state to sleep mode. Immediately after executing the SLEEP instruction the CPU halts, but the contents of its internal registers are retained. The DMA controller (DMAC), DRAM interface, and on-chip supporting modules do not halt in sleep mode. Modules which have been placed in standby by the module standby function, however, remain halted.

#### **19.3.2 Exit from Sleep Mode**

Sleep mode is exited by an interrupt, or by input at the  $\overline{RES}$  or  $\overline{STBY}$  pin.

**Exit by Interrupt:** An interrupt terminates sleep mode and causes a transition to the interrupt exception handling state. Sleep mode is not exited by an interrupt source in an on-chip supporting module if the interrupt is disabled in the on-chip supporting module. Sleep mode is not exited by an interrupt other than NMI if the interrupt is masked by interrupt priority settings and the settings of the I and UI bits in CCR, IPR.

**Exit by <b>RES** Input: Low input at the **RES** pin exits from sleep mode to the reset state.

**Exit by <b>STBY** Input: Low input at the STBY pin exits from sleep mode to hardware standby mode.



### **19.4 Software Standby Mode**

#### **19.4.1 Transition to Software Standby Mode**

To enter software standby mode, execute the SLEEP instruction while the SSBY bit is set to 1 in **SYSCR** 

In software standby mode, current dissipation is reduced to an extremely low level because the CPU, clock, and on-chip supporting modules all halt. The DMAC and on-chip supporting modules are reset and halted. As long as the specified voltage is supplied, however, CPU register contents and on-chip RAM data are retained. The settings of the I/O ports and DRAM interface\* are also held.

When the WDT is used as a watchdog timer (WT/ $\overline{IT} = 1$ ), the TME bit must be cleared to 0 before setting SSBY. Also, when setting TME to 1, SSBY should be cleared to 0.

Clear the BRLE bit in BRCR (inhibiting bus release) before making a transition to software standby mode.

Note: \* RTCNT and bits 7 and 6 of RTMCSR are initialized. Other bits and registers hold their previous states.

#### **19.4.2 Exit from Software Standby Mode**

Software standby mode can be exited by input of an external interrupt at the NMI,  $IRQ_0$ ,  $IRQ_1$ , or  $IRQ<sub>2</sub>$  pin, or by input at the RES or STBY pin.

**Exit by Interrupt:** When an NMI,  $IRQ_0$ ,  $IRQ_1$ , or  $IRQ_2$  interrupt request signal is received, the clock oscillator begins operating. After the oscillator settling time selected by bits STS2 to STS0 in SYSCR, stable clock signals are supplied to the entire chip, software standby mode ends, and interrupt exception handling begins. Software standby mode is not exited if the interrupt enable bits of interrupts  $IRQ_0$ ,  $IRQ_1$ , and  $IRQ_2$  are cleared to 0, or if these interrupts are masked in the CPU.

**Exit by <b>RES** Input: When the RES input goes low, the clock oscillator starts and clock pulses are supplied immediately to the entire chip. The  $\overline{RES}$  signal must be held low long enough for the clock oscillator to stabilize. When RES goes high, the CPU starts reset exception handling.

**Exit by <b>STBY** Input: Low input at the STBY pin causes a transition to hardware standby mode.

#### **19.4.3 Selection of Waiting Time for Exit from Software Standby Mode**

Bits STS2 to STS0 in SYSCR and bits DIV1 and DIV0 in DIVCR should be set as follows.

**Crystal Resonator:** Set STS2 to STS0, DIV1, and DIV0 so that the waiting time (for the clock to stabilize) is at least 7 ms. Table 19.3 indicates the waiting times that are selected by STS2 to STS0, DIV1, and DIV0 settings at various system clock frequencies.

**External Clock:** Any values may be set.

#### **Table 19.3 Clock Frequency and Waiting Time for Clock to Settle**



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#### **19.4.4 Sample Application of Software Standby Mode**

Figure 19.1 shows an example in which software standby mode is entered at the fall of NMI and exited at the rise of NMI.

With the NMI edge select bit (NMIEG) cleared to 0 in SYSCR (selecting the falling edge), an NMI interrupt occurs. Next the NMIEG bit is set to 1 (selecting the rising edge) and the SSBY bit is set to 1; then the SLEEP instruction is executed to enter software standby mode.

Software standby mode is exited at the next rising edge of the NMI signal.



**Figure 19.1 NMI Timing for Software Standby Mode (Example)** 

#### **19.4.5 Note**

The I/O ports retain their existing states in software standby mode. If a port is in the high output state, its output current is not reduced.

# **19.5 Hardware Standby Mode**

### **19.5.1 Transition to Hardware Standby Mode**

Regardless of its current state, the chip enters hardware standby mode whenever the STBY pin goes low. Hardware standby mode reduces power consumption drastically by halting all functions of the CPU, DMAC, DRAM interface, and on-chip supporting modules. All modules are reset except the on-chip RAM. As long as the specified voltage is supplied, on-chip RAM data is retained. I/O ports are placed in the high-impedance state.

Clear the RAME bit to 0 in SYSCR before STBY goes low to retain on-chip RAM data.

The inputs at the mode pins (MD2 to MD0) should not be changed during hardware standby mode.

### **19.5.2 Exit from Hardware Standby Mode**

Hardware standby mode is exited by inputs at the STBY and RES pins. While RES is low, when  $\overline{\text{STBY}}$  goes high, the clock oscillator starts running. RES should be held low long enough for the clock oscillator to settle. When RES goes high, reset exception handling begins, followed by a transition to the program execution state.

#### **19.5.3 Timing for Hardware Standby Mode**

Figure 19.2 shows the timing relationships for hardware standby mode. To enter hardware standby mode, first drive  $\overline{\text{RES}}$  low, then drive  $\overline{\text{STBY}}$  low. To exit hardware standby mode, first drive STBY high, wait for the clock to settle, then bring RES from low to high.



**Figure 19.2 Hardware Standby Mode Timing** 

# **19.6 Module Standby Function**

#### **19.6.1 Module Standby Timing**

The module standby function can halt several of the on-chip supporting modules (SCI2, SCI1, SCI0, the DMAC, 16-bit timer, 8-bit timer, DRAM interface, and A/D converter) independently in the power-down state. This standby function is controlled by bits MSTPH2 to MSTPH0 in MSTCRH and bits MSTPL7 to MSTPL0 in MSTCRL. When one of these bits is set to 1, the corresponding on-chip supporting module is placed in standby and halts at the beginning of the next bus cycle after the MSTCR write cycle.

#### **19.6.2 Read/Write in Module Standby**

When an on-chip supporting module is in module standby, read/write access to its registers is disabled. Read access always results in H'FF data. Write access is ignored.

#### **19.6.3 Usage Notes**

When using the module standby function, note the following points.

**DMAC:** When setting a bit in MSTCR to 1 to place the DMAC or DRAM interface in module standby, make sure that the DMAC or DRAM interface is not currently requesting the bus right. If the corresponding bit in MSTCR is set to 1 when a bus request is present, operation of the bus arbiter becomes ambiguous and a malfunction may occur.

**DRAM Interface:** When the module standby function is used on the DRAM interface, set the MSTCR bit to 1 while DRAM space is deselected.

**Cancellation of Interrupt Handling:** Before setting a module standby bit, first disable interrupts by that module. When an on-chip supporting module is placed in standby by the module standby function, its registers are initialized, including registers with interrupt request flags.

**Pin States:** Pins used by an on-chip supporting module lose their module functions when the module is placed in module standby. What happens after that depends on the particular pin. For details, see section 8, I/O Ports. Pins that change from the input to the output state require special care. For example, if SCI1 is placed in module standby, the receive data pin loses its receive data function and becomes a port pin. If its port DDR bit is set to 1, the pin becomes a data output pin, and its output may collide with external SCI transmit data. Data collision should be prevented by clearing the port DDR bit to 0 or taking other appropriate action.

**Register Resetting:** When an on-chip supporting module is halted by the module standby function, all its registers are initialized. To restart the module, after its MSTCR bit is cleared to 0, its registers must be set up again. It is not possible to write to the registers while the MSTCR bit is set to 1.

**MSTCR Access from DMAC Disabled:** To prevent malfunctions, MSTCR can only be accessed from the CPU. It can be read by the DMAC, but it cannot be written by the DMAC.

# **19.7 System Clock Output Disabling Function**

Output of the system clock  $(\phi)$  can be controlled by the PSTOP bit in MSTCRH. When the PSTOP bit is set to 1, output of the system clock halts and the  $\phi$  pin is placed in the highimpedance state. Figure 19.3 shows the timing of the stopping and starting of system clock output. When the PSTOP bit is cleared to 0, output of the system clock is enabled. Table 19.4 indicates the state of the  $\phi$  pin in various operating states.



**Figure 19.3 Starting and Stopping of System Clock Output** 







# Section 20 Electrical Characteristics

# **20.1 Absolute Maximum Ratings**

Table 20.1 lists the absolute maximum ratings.

#### **Table 20.1 Absolute Maximum Ratings**



Caution: Permanent damage to the chip may result if absolute maximum ratings are exceeded.

### **20.2 Electrical Characteristics**

### **20.2.1 DC Characteristics**

Tables 20.2, 20.3 and 20.4 list the DC characteristics. Table 20.4 lists the permissible output currents.

#### **Table 20.2 DC Characteristics (1)**

Conditions:  $V_{cc} = 5.0 V \pm 10\%$ ,  $AV_{cc} = 5.0 V \pm 10\%$ ,  $V_{REF} = 4.5 V$  to  $AV_{cc}^{*1}$ ,  $V_{ss} = AV_{ss} = 0 V^{*1}$ ,  $T_a = -20°C$  to +75°C (regular specifications),  $T_a = -40\degree C$  to  $+85\degree C$  (wide-range specifications)





Notes: 1. Do not open the pin connections of the  $AV_{cc}$ ,  $V_{REF}$  and  $AV_{ss}$  pins while the A/D converter is not in use.

Connect the AV<sub>cc</sub> and V<sub>REF</sub> pins to the V<sub>cc</sub> and connect the AV<sub>SS</sub> pin to the V<sub>SS</sub>, respectively.

- 2. Given current consumption values are when all the output pins are made to unloaded state and, furthermore, when the on-chip pull-up MOS is turned off under conditions that  $V_{\mu}$  min =  $V_{\infty}$  – 0.5 V and V<sub>I</sub> max = 0.5 V. Also, the aforesaid current consumption values are when  $V_{\text{H}}$  min =  $V_{\text{cc}} \times 0.9$  and  $V_{\text{H}}$ max = 0.3 V under the condition of  $V_{\text{ram}} \le V_{\text{cc}}$  < 4.5 V.
- 3.  $I_{\text{cc}}$  max. (under normal operations) = 1.0 (mA) + 0.90 (mA/(MHz  $\times$  V))  $\times$  V<sub>cc</sub>  $\times$  f
	- $I_{cc}$  max. (when using the sleeve) = 1.0 (mA) + 0.65 (mA/(MHz  $\times$  V))  $\times$  V<sub>cc</sub>  $\times$  f

 $I_{cc}$  max. (when the sleeve + module are standing by)

= 1.0 (mA) + 0.45 (mA/(MHz × V)) × VCC × f

Also, the typ. values for current dissipation are reference values.



#### **Table 20.3 DC Characteristics (2)**

Conditions:  $VCC = 2.7$  to  $5.5$  V,  $AVCC = 2.7$  to  $5.5$  V,  $VREF = 2.7$  V to  $AVCC^*1$ ,  $VSS = AVSS = 0$   $V^*$ , Ta = -20°C to +75°C (regular specifications), Ta =  $-40^{\circ}$ C to  $+85^{\circ}$ C (wide-range specifications)





Notes: 1. Do not open the pin connections of the  $AV_{cc}$ ,  $V_{REF}$  and  $AV_{ss}$  pins while the A/D converter is not in use.

RAM standby voltage  $V_{RAM}$  2.0  $-V$ 

 $1$ dle  $-$  0.01 5.0  $\mu$ A DASTE = 0

Connect the AV<sub>cc</sub> and V<sub>REF</sub> pins to the V<sub>cc</sub> and connect the AV<sub>SS</sub> pin to the V<sub>SS</sub>, respectively.

 2. Given current consumption values are when all the output pins are made to unloaded state and, furthermore, when the on-chip pull-up MOS is turned off under conditions that  $V_{\mu}$  min =  $V_{\infty}$  – 0.5 V and V<sub>I</sub> max = 0.5 V. Also, the aforesaid current consumption values are when  $V_{\text{H}}$  min =  $V_{\text{cc}} \times 0.9$  and  $V_{\text{H}}$ 

max = 0.3 V under the condition of  $V_{\text{ram}} \le V_{\text{cc}}$  < 2.7 V.

3.  $I_{\text{cc}}$  max. (under normal operations) = 1.0 (mA) + 0.90 (mA/(MHz  $\times$  V))  $\times$  V<sub>cc</sub>  $\times$  f  $I_{\rm cc}$  max. (when using the sleeve) = 1.0 (mA) + 0.65 (mA/(MHz  $\times$  V))  $\times$  V<sub>cc</sub>  $\times$  f  $I_{cc}$  max. (when the sleeve + module are standing by)  $= 1.0$  (mA) + 0.45 (mA/(MHz  $\times$  V))  $\times$  V<sub>cc</sub>  $\times$  f

Also, the typ. values for current dissipation are reference values.

#### **Table 20.4 DC Characteristics (3)**

Conditions:  $V_{cc} = 3.0$  to 5.5 V,  $AV_{cc} = 3.0$  to 5.5 V,  $V_{REF} = 3.0$  V to  $AV_{cc}^{*1}$ ,  $V_{ss} = AV_{ss} = 0 V^{*1}$ ,  $T_a = -20°C$  to +75°C (regular specifications),  $T_a = -40\degree C$  to  $+85\degree C$  (wide-range specifications)







Notes: 1. Do not open the pin connections of the  $AV_{cc}$ ,  $V_{REF}$  and  $AV_{ss}$  pins while the A/D converter is not in use.

Connect the AV<sub>cc</sub> and V<sub>REF</sub> pins to the V<sub>cc</sub> and connect the AV<sub>SS</sub> pin to the V<sub>SS</sub>, respectively.

- 2. Given current consumption values are when all the output pins are made to unloaded state and, furthermore, when the on-chip pull-up MOS is turned off under conditions that  $V_{\mu}$  min =  $V_{\infty}$  – 0.5 V and V<sub>I</sub> max = 0.5 V. Also, the aforesaid current consumption values are when  $V_{\text{H}}$  min =  $V_{\text{cc}} \times 0.9$  and  $V_{\text{H}}$ max = 0.3 V under the condition of  $V_{\text{ram}} \le V_{\text{cc}}$  < 3.0 V.
- 3.  $I_{\text{cc}}$  max. (under normal operations) = 1.0 (mA) + 0.90 (mA/(MHz  $\times$  V))  $\times$  V<sub>cc</sub>  $\times$  f
	- $I_{cc}$  max. (when using the sleeve) = 1.0 (mA) + 0.65 (mA/(MHz  $\times$  V))  $\times$  V<sub>cc</sub>  $\times$  f

 $I_{cc}$  max. (when the sleeve + module are standing by)

= 1.0 (mA) + 0.45 (mA/(MHz × V)) × VCC × f

Also, the typ. values for current dissipation are reference values.



#### **Table 20.5 Permissible Output Currents**

Conditions:  $V_{cc} = 2.7 \text{ V}$  to 5.5 V,  $AV_{cc} = 2.7 \text{ V}$  to 5.5 V,  $V_{REF} = 2.7 \text{ V}$  to  $AV_{cc}$ ,  $V_{ss} = AV_{ss} = 0 V$ ,  $T_a = -20$ °C to +75°C (regular specifications),  $T_a = -40\degree C$  to  $+85\degree C$  (wide-range specifications)



Notes: 1. To protect chip reliability, do not exceed the output current values in table 20.5.

 2. When driving a darlington pair, always insert a current-limiting resistor in the output line, as shown in figures 20.1.



**Figure 20.1 Darlington Pair Drive Circuit (Example)** 

#### **20.2.2 AC Characteristics**

Clock timing parameters are listed in table 20.6, control signal timing parameters in table 20.7, and bus timing parameters in table 20.8. Timing parameters of the on-chip supporting modules are listed in table 20.9.

#### **Table 20.6 Clock Timing**

- Condition:  $= -20^{\circ}$ C to +75°C (regular specifications), T<sub>a</sub> = -40°C to +85°C (wide-range specifications)
- Condition A:  $V_{cc} = 2.7$  to 5.5 V,  $AV_{cc} = 2.7$  to 5.5 V,  $V_{REF} = 2.7$  to  $AV_{cc}$ ,  $V_{ss} = AV_{ss} = 0$  V,  $\phi = 1$  to 10 MHz

Condition B:  $V_{cc} = 3.0$  to 5.5 V,  $AV_{cc} = 3.0$  to 5.5 V,  $V_{REF} = 3.0$  to  $AV_{cc}$ ,  $V_{ss} = AV_{ss} = 0$  V,  $\phi = 1$  to 13 MHz

Condition C:  $V_{cc} = 5.0 V \pm 10\%$ ,  $AV_{cc} = 5.0 V \pm 10\%$ ,  $V_{REF} = 4.5$  to  $AV_{cc}$ ,  $V_{ss} = AV_{ss} = 0 V$ ,  $\phi = 1$  to 20 MHz



#### **Table 20.7 Control Signal Timing**

- Condition:  $= -20^{\circ}$ C to +75°C (regular specifications), T<sub>a</sub> = -40°C to +85°C (wide-range specifications)
- Condition A:  $V_{cc} = 2.7$  to 5.5 V,  $AV_{cc} = 2.7$  to 5.5 V,  $V_{REF} = 2.7$  to  $AV_{cc}$ ,  $V_{ss} = AV_{ss} = 0$  V,  $\phi = 1$  to 10 MHz
- Condition B:  $V_{cc} = 3.0$  to 5.5 V,  $AV_{cc} = 3.0$  to 5.5 V,  $V_{REF} = 3.0$  to  $AV_{cc}$ ,  $V_{ss} = AV_{ss} = 0$  V,  $\phi = 1$  to 13 MHz
- Condition C:  $V_{cc} = 5.0 V \pm 10\%$ ,  $AV_{cc} = 5.0 V \pm 10\%$ ,  $V_{REF} = 4.5$  to  $AV_{cc}$ ,  $V_{ss} = AV_{ss} = 0 V$ ,  $\phi = 1$  to 20 MHz



#### **Table 20.8 Bus Timing**

- Condition:  $= -20^{\circ}$ C to +75°C (regular specifications), T<sub>a</sub> = -40°C to +85°C (wide-range specifications)
- Condition A:  $V_{cc} = 2.7$  to 5.5 V,  $AV_{cc} = 2.7$  to 5.5 V,  $V_{REF} = 2.7$  to  $AV_{cc}$ ,  $V_{ss} = AV_{ss} = 0$  V,  $\phi = 1$  to 10 MHz
- Condition B:  $V_{cc} = 3.0$  to 5.5 V,  $AV_{cc} = 3.0$  to 5.5 V,  $V_{REF} = 3.0$  to  $AV_{cc}$ ,  $V_{ss} = AV_{ss} = 0$  V,  $\phi = 1$  to 13 MHz
- Condition C:  $V_{cc} = 5.0 V \pm 10\%$ ,  $AV_{cc} = 5.0 V \pm 10\%$ ,  $V_{REF} = 4.5$  to  $AV_{cc}$ ,  $V_{ss} = AV_{ss} = 0 V$ ,  $\phi = 1$  to 20 MHz






#### **Table 20.9 Timing of On-Chip Supporting Modules**

- Condition:  $= -20^{\circ}$ C to +75°C (regular specifications), T<sub>a</sub> = -40°C to +85°C (wide-range specifications)
- Condition A:  $V_{cc} = 2.7$  to 5.5 V,  $AV_{cc} = 2.7$  to 5.5 V,  $V_{REF} = 2.7$  to  $AV_{cc}$ ,  $V_{ss} = AV_{ss} = 0$  V,  $\phi = 1$  to 10 MHz
- Condition B:  $V_{cc} = 3.0$  to 5.5 V,  $AV_{cc} = 3.0$  to 5.5 V,  $V_{REF} = 3.0$  to  $AV_{cc}$ ,  $V_{ss} = AV_{ss} = 0$  V,  $\phi = 1$  to 13 MHz
- Condition C:  $V_{cc} = 5.0 V \pm 10\%$ ,  $AV_{cc} = 5.0 V \pm 10\%$ ,  $V_{REF} = 4.5$  to  $AV_{cc}$ ,  $V_{ss} = AV_{ss} = 0 V$ ,  $\phi = 1$  to 20 MHz







**Figure 20.2 Output Load Circuit** 

#### **20.2.3 A/D Conversion Characteristics**

Table 20.10 lists the A/D conversion characteristics.

#### **Table 20.10 A/D Conversion Characteristics**

- Condition:  $= -20^{\circ}$ C to +75°C (regular specifications), T<sub>a</sub> = -40°C to +85°C (wide-range specifications)
- Condition A:  $V_{cc} = 2.7$  to 5.5 V,  $AV_{cc} = 2.7$  to 5.5 V,  $V_{REF} = 2.7$  to  $AV_{cc}$ ,  $V_{ss} = AV_{ss} = 0$  V,  $fmax = 10 MHz$
- Condition B:  $V_{cc} = 3.0$  to 5.5 V,  $AV_{cc} = 3.0$  to 5.5 V,  $V_{REF} = 3.0$  to  $AV_{cc}$ ,  $V_{ss} = AV_{ss} = 0$  V,  $fmax = 13 MHz$
- Condition C:  $V_{cc} = 5.0 V \pm 10\%$ ,  $AV_{cc} = 5.0 V \pm 10\%$ ,  $V_{REF} = 4.5$  to  $AV_{cc}$ ,  $V_{ss} = AV_{ss} = 0 V$ ,  $f$ max = 20 MHz





## **20.2.4 D/A Conversion Characteristics**

Table 20.11 lists the D/A conversion characteristics.

## **Table 20.11 D/A Conversion Characteristics**

Condition:  $= -20^{\circ}$ C to +75°C (regular specifications),  $T_a = -40^{\circ}$ C to +85°C (wide-range specifications)

Condition A:  $V_{cc} = 2.7$  to 5.5 V,  $AV_{cc} = 2.7$  to 5.5 V,  $V_{REF} = 2.7$  to  $AV_{cc}$ ,  $V_{ss} = AV_{ss} = 0$  V,  $fmax = 10 MHz$ 

Condition B:  $V_{cc} = 3.0$  to 5.5 V,  $AV_{cc} = 3.0$  to 5.5 V,  $V_{REF} = 3.0$  to  $AV_{cc}$ ,  $V_{ss} = AV_{ss} = 0$  V,  $fmax = 13 MHz$ 

Condition C:  $V_{cc} = 5.0 V \pm 10\%$ ,  $AV_{cc} = 5.0 V \pm 10\%$ ,  $V_{REF} = 4.5$  to  $AV_{cc}$ ,  $V_{ss} = AV_{ss} = 0 V$ ,  $fmax = 20 MHz$ 



## **20.3 Operational Timing**

This section shows timing diagrams.

## **20.3.1 Clock Timing**

Clock timing is shown as follows:

- System clock timing Figure 20.3 shows the system clock timing.
- Oscillator settling timing Figure 20.4 shows the oscillator settling timing.



**Figure 20.3 System Clock Timing** 



**Figure 20.4 Oscillator Settling Timing** 

## **20.3.2 Control Signal Timing**

Control signal timing is shown as follows:

• Reset input timing

Figure 20.5 shows the reset input timing.

- Reset output timing Figure 20.6 shows the reset output timing.
- Interrupt input timing

Figure 20.7 shows the interrupt input timing for NMI and  $\overline{\text{IRQ}}_5$  to  $\overline{\text{IRQ}}_0$ .



**Figure 20.5 Reset Input Timing** 



**Figure 20.6 Reset Output Timing** 



**Figure 20.7 Interrupt Input Timing** 

#### **20.3.3 Bus Timing**

Bus timing is shown as follows:

- Basic bus cycle: two-state access Figure 20.8 shows the timing of the external two-state access cycle.
- Basic bus cycle: three-state access Figure 20.9 shows the timing of the external three-state access cycle.
- Basic bus cycle: three-state access with one wait state Figure 20.10 shows the timing of the external three-state access cycle with one wait state inserted.
- Burst ROM access timing: burst cycle two-state Figure 20.11 shows the timing of the burst cycle two-state access.
- Burst ROM access timing: burst cycle three-state Figure 20.12 shows the timing of the burst cycle three-state access.
- Bus-release mode timing Figure 20.13 shows the bus-release mode timing.



**Figure 20.8 Basic Bus Cycle: Two-State Access** 



**Figure 20.9 Basic Bus Cycle: Three-State Access** 



**Figure 20.10 Basic Bus Cycle: Three-State Access with One Wait State** 





**Figure 20.11 Burst ROM Access Timing: Two-State Access** 



**Figure 20.12 Burst ROM Access Timing: Three-State Access** 



**Figure 20.13 Bus-Release Mode Timing** 

## **20.3.4 DRAM Interface Bus Timing**

DRAM interface bus timing is shown as follows:

- DRAM bus timing: read and write access Figure 20.14 shows the timing of the read and write access.
- DRAM bus timing: CAS before RAS refresh Figure 20.15 shows the timing of the CAS before RAS refresh.
- DRAM bus timing: self-refresh Figure 20.16 shows the timing of the self-refresh.



**Figure 20.14 DRAM Bus Timing (Read/Write)** 



**Figure 20.15 DRAM Bus Timing (CAS before RAS Refresh)** 



**Figure 20.16 DRAM Bus Timing (Self-Refresh)** 

## **20.3.5 TPC and I/O Port Timing**

Figure 20.17 shows the TPC and I/O port input/output timing.



**Figure 20.17 TPC and I/O Port Input/Output Timing**

#### **20.3.6 Timer Input/Output Timing**

The timings of 16-bit and 8-bit timer are shown as follows:

• Timer input/output timing

Figure 20.18 shows the timer input/output timing.

Timer external clock input timing Figure 20.19 shows the timer external clock input timing.







**Figure 20.19 Timer External Clock Input Timing** 

## **20.3.7 SCI Input/Output Timing**

SCI timing is shown as follows:

• SCI input clock timing

Figure 20.20 shows the SCI input clock timing.

• SCI input/output timing (synchronous mode)

Figure 20.21 shows the SCI input/output timing in synchronous mode.



**Figure 20.20 SCI Input Clock Timing** 



**Figure 20.21 SCI Input/Output Timing in Synchronous Mode** 

#### **20.3.8 DMAC Timing**

DMAC timing is shown as follows.

- DMAC TEND output timing for 2 state access Figure 20.22 shows the DMAC TEND output timing for 2 state access.
- DMAC TEND output timing for 3 state access Figure 20.23 shows the DMAC TEND output timing for 3 state access.
- DMAC DREQ input timing Figure 20.24 shows DMAC DREQ input timing.



## **Figure 20.22 DMAC** TEND **Output Timing for 2 State Access**



**Figure 20.23 DMAC** TEND **Output Timing for 3 State Access** 



**Figure 20.24 DMAC** DREQ **Input Timing** 



# Appendix A Instruction Set

# **A.1 Instruction List**

## **Operand Notation**



(R0 to R7 and E0 to E7).

## **Condition Code Notation**





## **Table A.1 Instruction Set**

## 1. Data transfer instructions









## 2. Arithmetic instructions







## 3. Logic instructions



## 4. Shift instructions



## 5. Bit manipulation instructions





## 6. Branching instructions






#### 7. System control instructions



#### 8. Block transfer instructions



- Notes: 1. The number of states is the number of states required for execution when the instruction and its operands are located in on-chip memory. For other cases see appendix A.3, Number of States Required for Execution. Normal mode is not available in the H8/3006 and H8/3007.
	- 2. n is the value set in register R4L or R4.
		- (1) Set to 1 when a carry or borrow occurs at bit 11; otherwise cleared to 0.
		- (2) Set to 1 when a carry or borrow occurs at bit 27; otherwise cleared to 0.
		- (3) Retains its previous value when the result is zero; otherwise cleared to 0.
		- (4) Set to 1 when the adjustment produces a carry; otherwise retains its previous value.
		- (5) The number of states required for execution of an instruction that transfers data in synchronization with the E clock is variable.
		- (6) Set to 1 when the divisor is negative; otherwise cleared to 0.
		- (7) Set to 1 when the divisor is zero; otherwise cleared to 0.
		- (8) Set to 1 when the quotient is negative; otherwise cleared to 0.

## **A.2 Operation Code Maps**

## **Table A.2 Operation Code Map (1)**



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Instruction code:  $\begin{array}{|c|c|c|}\n\hline \hline \text{1st byte} & \text{2nd byte} \\
\hline \text{AH} & \text{AL} & \text{BH} \\
\hline \end{array}$ 1st byte 2nd byte  $\frac{AB}{AB}$  BH  $\frac{BL}{AB}$ Instruction code:



STC - Instruction when most significant bit of DH is 0.  $\leftarrow$  Instruction when most significant bit of DH is 1.  $S$ TC  $\sim$  STC  $\sim$ Instruction when most significant bit of DH is 0. Instruction when most significant bit of DH is 1. Щ AHALBH 0 1 2 3 4 5 6 7 8 9 A B 0 1 E F<br>ALBH 0 1406 201 MULXS MULXS DIVIS DIVI οg<br>Θ LDC LDC LDC Ш **STC**  $\Box$  $\overline{5}$  $\circ$ **STC**  $\omega$  $\overline{5}$  $\prec$ STC  $\circ$ LDC  $\infty$ BILD BIST BIST BILD  $\overline{a}$ BLD BLD BST BST 4th byte<br>DH DL  $\frac{CH}{CL}$  DH  $\frac{DL}{PL}$ BIAND BIAND AND BAND BAND  $\circ$ **BIXOR** 3rd byte BIXOR **U** OR XOR BXOR BXOR S  $\overline{H}$  $BIOR$ **BIOR**  $\rightarrow$  $\frac{1}{8}$ BOR 2nd byte BH BL 1st byte 2nd byte  $\frac{AB}{AB}$  BH  $\frac{BL}{AB}$ DIVXS BTST BTST BTST BTST  $\infty$ BCLR  $\Delta L$ MULXS BCLR BCLR BCLR 1st byte  $\sim$ AH<sup>|</sup> DIVIXS BNOT BNOT BNOT BNOT  $\leftarrow$ Instruction code: Instruction code: MULXS BSET BSET BSET BSET  $\circ$ \*1\*1\*1\*2\*2م<br>\*  $\vec{o}$ 7Eaa6 \* 01406 01C05 01D05 01F06 7Cr06 7Cr07 7Dr06 7Dr07 7Eaa7 7Faa6 7Faa7 HEH<br>ALBH **BLCH** 

Notes: 1. 2. r is the register designation field.

aa is the absolute address field.

## **Table A.2 Operation Code Map (3)**

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## **A.3 Number of States Required for Execution**

The tables in this section can be used to calculate the number of states required for instruction execution by the H8/300H CPU. Table A.4 indicates the number of instruction fetch, data read/write, and other cycles occurring in each instruction. Table A.3 indicates the number of states required per cycle according to the bus size. The number of states required for execution of an instruction can be calculated from these two tables as follows:

Number of states =  $I \times S_1 + J \times S_2 + K \times S_k + L \times S_L + M \times S_M + N \times S_N$ 

#### **Examples of Calculation of Number of States Required for Execution**

**Examples:** Advanced mode, stack located in external address space, on-chip supporting modules accessed with 8-bit bus width, external devices accessed in three states with one wait state and 16-bit bus width.

BSET #0, @FFFFC7:8

From table A.4,  $I = L = 2$  and  $J = K = M = N = 0$ From table A.3,  $S_1 = 4$  and  $S_2 = 3$ Number of states =  $2 \times 4 + 2 \times 3 = 14$ 

JSR @@30

From table A.4,  $I = J = K = 2$  and  $L = M = N = 0$ From table A.3,  $S_1 = S_1 = S_K = 4$ Number of states =  $2 \times 4 + 2 \times 4 + 2 \times 4 = 24$ 



#### **Table A.3 Number of States per Cycle**

Legend:

m: Number of wait states inserted into external device access





## **Table A.4 Number of Cycles per Instruction**

#### **Instruction Mnemonic Instruction Branch Fetch I Addr. Read Operation Access J Stack K Byte Data Word Data Internal L Access M Operation N**  Bcc BRA d:16 (BT d:16) BRN d:16 (BF d:16) BHI d:16 BLS d:16 BCC d:16 (BHS d:16) BCS d:16 (BLO d:16) BNE d:16 BEQ d:16 BVC d:16 BVS d:16 BPL d:16 BMI d:16 BGE d:16 BLT d:16 BGT d:16 BLE d:16 2  $\overline{2}$ 2 2  $\overline{2}$ 2 2  $\overline{2}$  $\mathfrak{p}$ 2  $\mathfrak{p}$ 2 2 2 2 2 2  $\overline{2}$  $\mathfrak{p}$ 2  $\overline{2}$ 2 2  $\mathfrak{p}$ 2 2  $\mathfrak{p}$ 2 2 2 2  $\mathfrak{p}$ BCLR BCLR #xx:3, Rd BCLR #xx:3, @ERd BCLR #xx:3, @aa:8 BCLR Rn, Rd BCLR Rn, @ERd BCLR Rn, @aa:8 1 2 2 1 2 2 2  $\mathfrak{p}$ 2 2 BIAND BIAND #xx:3, BIAND #xx:3, @ERd BIAND #xx:3, @aa:8 1 2 2 1 1 BILD BILD #xx:3, Rd BILD #xx:3, @ERd BILD #xx:3, @aa:8 1 2 2 1 1 BIOR BIOR #xx:8, Rd BIOR #xx:8, @ BIOR #xx:8, @aa:8 1 2 2 1 1 BIST BIST #xx:3, Rd BIST #xx:3, @ERd BIST #xx:3, @aa:8 1 2 2 2 2 BIXOR BIXOR #xx:3, Rd BIXOR #xx:3, @ BIXOR #xx:3, @aa:8 1 2 2 1 1 BLD BLD #xx:3, Rd 1

#### Appendix A Instruction Set

BLD #xx:3, @ERd BLD #xx:3, @aa:8 2 2

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1 1



#### Appendix A Instruction Set





#### Appendix A Instruction Set





Notes: 1. Not available in the H8/3006 and H8/3007.

2. n is the value set in register R4L or R4. The source and destination are accessed  $n + 1$ times each.

# Appendix B Internal I/O Registers

## **B.1 Addresses**



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### Appendix B Internal I/O Registers





### Appendix B Internal I/O Registers





### Appendix B Internal I/O Registers





#### Appendix B Internal I/O Registers



Legend:

WDT: Watchdog timer

TPC: Programmable timing pattern controller

SCI: Serial communication interface

- Notes: 1. For write access to TCSR, TCNT, and RSTCSR, see section 12.2.4, Notes on Register Access.
	- 2. The address depends on the output trigger setting.



## **B.2 Functions**













W

0 1

W

Port 9 input/output select

Generic input Generic output

W

W

W

Read/Write

 $\overline{\phantom{0}}$ 

 $\overline{\phantom{0}}$ 

W







0

1

1

Mode 4  $\overline{\phantom{0}}$  $\equiv$  $\overline{\phantom{0}}$ 



Note: \* Determined by the state of the mode pins (MD2 to MD0).



#### **SYSCR—System Control Register H'EE012** System control







IRQ5 to IRQ0 sense control









Note: \* Only 0 can be written, to clear the flag.





**IPRACE INTERFALLS** Interrupt Controller



1 Priority level 1 (high priority)

• Interrupt sources controlled by each bit



#### **IPRB—Interrupt Priority Register B** H'EE019 Interrupt Controller



• Interrupt sources controlled by each bit













Enables or disables φ clock output.





### CSCR—Chip Select Control Register **H'EE01F** Bus controller



Chip select 7 to 4 enable



Note:  $n = 7$  to 4




## **ASTCR—Access State Control Register H'EE021 Bus controller**



Area 7 to 0 access state control





## WCRH—Wait Control Register H **H'EE022** Bus controller



Area 7 wait control 1 and 0





#### Bit Initial value Read/Write 1 R/W 7 W31 1 R/W 6 W30 1 R/W 5 W21 1 R/W 4 W20 1 R/W 3 W11 1 R/W 2 W10 1 R/W 1 W01 1 R/W  $\overline{0}$ W00 Area 0 wait control 1 and 0  $\Omega$ 0 1 0 1 No program wait is inserted 1 program wait state is inserted 2 program wait states are inserted 1 1 3 program wait states are inserted Area 1 wait control 1 and 0 0 0 1 0 1 No program wait is inserted 1 program wait state is inserted 2 program wait states are inserted 1 1 3 program wait states are inserted Area 2 wait control 1 and 0 0 0 1 0 1 No program wait is inserted 1 program wait state is inserted 2 program wait states are inserted  $\frac{1}{1}$   $\frac{1}{3}$  program wait states are inserted

**WCRL—Wait Control Register L H'EE023** Bus controller

Area 3 wait control 1 and 0









## RENESAS





Note:  $*$  A single  $\overline{\text{CS}}_n$  pin serves as a common  $\overline{\text{RAS}}$  output pin for a number of areas. Unused  $\overline{\text{CS}}_n$  pins can be used as input/output ports.



### **DRCRB**⎯**DRAM Control Register B H'EE027 DRAM interface**







## RENESAS

### **RTMCSR**⎯**Refresh Timer Control/Status Register H'EE028 DRAM interface**



Note: \* Only 0 can be written to clear the flag.

When RTCNT = RTCOR





## **P4PCR—Port 4 Input Pull-Up Control Register H'EE03E** Port 4





Source or destination address



## **ETCR0A H/L**⎯**Execute Transfer Count Register 0A H/L H'FFF24 H'FFF25 DMAC0**







Short address mode : source or destination address Full address mode : not used



#### **DTCR0A—Data Transfer Control Register 0A** H'FFF27 DMAC0

#### Short address mode



## **DTCR0A**⎯**Data Transfer Control Register 0A (cont) H'FFF27 DMAC0**

## • Full address mode







Source or destination address



## **ETCR0B H/L**⎯**Execute Transfer Count Register 0B H/L H'FFF2C, H'FFF2D DMAC0**  • Short address mode — I/O mode and idle mode R/W R/W R/W R/W R/W R/W R/WR/W R/W R/W R/W R/W R/W R/W R/WR/W Read/Write 15 14 13 12 11 10 9 8 7 6 5 4 3 2 1 0 Bit Initial value Undetermined Transfer counter - Repeat mode Read/Write R/W R/W R/W R/W R/W R/W R/W R/W 7 6 5 4 3 2 1 0 7 6 5 4 3 2 1 0 R/W R/W R/W R/W R/W R/W R/W Bit Initial value Undetermined Transfer counter ETCR0BH Undetermined Initial count ETCR0BL • Full address mode — Normal mode Bit Initial value Read/Write R/W R/W R/W R/W R/W R/W R/WR/W R/W R/W R/W R/W R/W R/W R/WR/W Undetermined 15 14 13 12 11 10 9 8 7 6 5 4 3 2 1 0 Not used - Block transfer mode Bit Initial value<br>Read/Write Read/Write R/W R/W R/W R/W R/W R/W R/WR/W R/W R/W R/W R/W R/W R/W R/WR/W Undetermined 15 14 13 12 11 10 9 8 7 6 5 4 3 2 1 0 Block transfer counter

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Short address mode : source or destination address

Full address mode : not used



## **DTCR0B—Data Transfer Control Register 0B** H'FFF2F DMAC0

### • Short address mode





## **DTCR0B—Data Transfer Control Register 0B (cont) H'FFF2F DMAC0**

#### • Full address mode



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Note: Bit functions are the same as for DMAC0.

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Note: Bit functions are the same as for DMAC0.

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Note: Bit functions are the same as for DMAC0.







#### Timer sync 2



















Note: \* Only 0 can be written, to clear the flag.





Note: \* Only 0 can be written, to clear the flag.





Note: \* Only 0 can be written, to clear the flag.







### **TIOR0**⎯**Timer I/O Control Register 0 H'FFF69 16-Bit Timer Channel 0**





#### I/O control B2 to B0

ſ









Note: Bit functions are the same as for 16-bit timer channel 0.





Note: Bit functions are the same as for 16-bit timer channel 0.



Note: Bit functions are the same as for 16-bit timer channel 0.



Note: Bit functions are the same as for 16-bit timer channel 0.



Notes: 1. Bit functions are the same as for 16-bit timer channel 0.

 2. The settings of bits CKEG1 and CKEG0 and bits TPSC2 to TPSC0 in 16TCR2 are invalid when phase counting mode is selected for channel 2.

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#### **8TCR0**⎯**Timer Control Register 0 H'FFF80 8-bit timer channel 0 8TCR1**⎯**Timer Control Register 1 H'FFF81 8-bit timer channel 1**  Bit Initial value Read/Write 0 R/W 7 CMIEB 0 R/W 6 CMIEA 0 R/W 5 OVIE 0 R/W 4 CCLR1 0 R/W 3 CCLR0 0 R/W 2 CKS2 0 R/W 1 CKS1 0 R/W  $\overline{0}$ CK<sub>S0</sub> Clock select 2 to 0  $\overline{0}$  $\Omega$ 0 1  $\overline{O}$ 1  $\overline{0}$  $\overline{0}$ 1 1 0 1 1 Clock input is disabled Internal clock, counted on rising edge of φ/8 Internal clock, counted on rising edge of  $\frac{1}{6}$ /64 Internal clock, counted on rising edge of φ/8192 External clock, counted on falling edge External clock, counted on rising edge External clock, counted on both rising and falling edges Counter clear 1 and 0  $\Omega$ 0 1  $\Omega$ 1 Clearing is disabled Cleared by compare match A Cleared by compare match B/input capture B Cleared by input capture B 1 Timer overflow interrupt enable 0 1 OVI interrupt requested by OVF is disabled OVI interrupt requested by OVF is enabled Compare match interrupt enable A  $\Omega$ 1 CMIA interrupt requested by CMFA is disabled CMIA interrupt requested by CMFA is enabled Compare match interrupt enable B 0 CMIB interrupt requested by CMFB is disabled 1 Channel 0: Count on 8TCNT1 overflow signal\* Channel 1: Count on 8TCNT0 compare match A\* Note: \* If the clock input of channel 0 is the 8TCNT1 overflow signal and that of channel 1 is the 8TCNT0 compare match signal, no incrementing clock is generated. Do not use this setting.



CMIB interrupt requested by CMFB is enabled

1

#### **8TCSR0**⎯**Timer Control/Status Register 0 H'FFF82 8-bit timer channel 0**



Note: \* Only 0 can be written to bits 7 to 5, to clear these flags.


#### **8TCSR1**⎯**Timer Control/Status Register 1 H'FFF83 8-bit timer channel 1**



Note: \* Only 0 can be written to bits 7 to 5, to clear these flags.



TCORB functions as an input capture register.







Note: \* Only 0 can be written, to clear the flag.





Note: \* Only 0 can be written in bit 7, to clear the flag.



#### 8TCR2—Timer Control Register 2 **H'FFF90** 8-bit timer channel 2 8TCR3—Timer Control Register 3 **H'FFF91** 8-bit timer channel 3





1 CMIB interrupt requested by CMFB is enabled

### **8TCSR2**⎯**Timer Control/Status Register 2 H'FFF92 8-bit timer channel 2 8TCSR3**⎯**Timer Control/Status Register 3 H'FFF93 8-bit timer channel 3**



Note: \* Only 0 can be written to bits 7 to 5, to clear these flags.









D/A conversion data



#### **DACR**⎯**D/A Control Register H'FFF9E D/A**  Bit Initial value Read/Write  $\Omega$ R/W 7 DAOE1  $\Omega$ R/W 6 DAOE0  $\Omega$ R/W 5 DAE 4  $\overline{\phantom{0}}$ 1 -3 — 1 -2  $\overline{\phantom{a}}$ 1 -1 — 1 -0 — 1 -D/A enable Bit 7 DAOE1 D/A conversion is disabled in channels 0 and 1 D/A conversion is enabled in channel 0 D/A conversion is disabled in channel 1 D/A conversion is disabled in channel 0 D/A conversion is enabled in channel 1 Description D/A conversion is enabled in channels 0 and 1 D/A conversion is enabled in channels 0 and 1 D/A conversion is enabled in channels 0 and 1 Bit 6 Bit 5 DAOE0 DAE 0 0 0 1 1 1 0 1 1 0 0 1  $\overline{O}$ 1  $\overline{0}$ 1 D/A output enable 0 0 | DA0 analog output is disabled 1 Channel-0 D/A conversion and DA0 analog output are enabled ÷. ÷

D/A output enable 1











Group 3 compare match select 1 and 0



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### **TPCR—TPC Output Control Register H'FFFA1 TPC**



#### Next data enable 15 to 8





Next data enable 7 to 0



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#### **NDRB**⎯**Next Data Register B H'FFFA4/H'FFFA6 TPC**

• Same trigger for TPC output groups 2 and 3 - Address H'FFFA4



Store the next output data for TPC output group 3 Store the next output data for TPC output group 2

- Address H'FFFA6



• Different triggers for TPC output groups 2 and 3

- Address H'FFFA4



Store the next output data for TPC output group 3





#### **NDRA**⎯**Next Data Register A H'FFFA5/H'FFFA7 TPC**

• Same trigger for TPC output groups 0 and 1 - Address H'FFFA5



Store the next output data for TPC output group 1 Store the next output data for TPC output group 0

- Address H'FFFA7



• Different triggers for TPC output groups 0 and 1

⎯ Address H'FFFA5



Store the next output data for TPC output group 1





GSM mode (for smart card interface)



Note: \* etu: Elementary time unit (time required to transmit one bit)





Serial communication bit rate setting









Serial transmit data



#### Bit Initial value Read/Write 1  $R/(W)^*$ 7 TDRE  $\overline{0}$  $R/(W)^*$ 6 RDRF  $\overline{0}$  $R/(W)^*$ 5 ORER  $\overline{0}$  $R/(W)*$ 4 FER/ERS  $\overline{0}$  $R/(W)^*$ 3 PER 1 R  $\overline{2}$ **TEND**  $\overline{0}$ R 1 MPB  $\overline{0}$ R/W  $\Omega$ MPBT Transmit end (for serial communication interface)  $\Omega$ Multiprocessor bit transfer  $\Omega$ 1 Multiprocessor bit value in transmit data is 0 Multiprocessor bit value in transmit data is 1 Multiprocessor bit 0 Multiprocessor bit value in receive data is 0 1 Multiprocessor bit value in receive data is 1 [Clearing conditions] • Read TDRE when TDRE = 1, then write 0 in TDRE. • The DMAC writes data in TDR. [Setting conditions] Reset or transition to standby mode TE is cleared to 0 in SCR. • TDRE is 1 when last bit of 1-byte serial character is transmitted. Parity error  $\Omega$ 1 [Clearing conditions] • Reset or transition to standby mode • Read PER when PER = 1, then write 0 in PER. [Setting condition] Parity error (parity of receive data does not match parity setting of O/E bit in SMR) Framing error (for serial communication interface)  $\Omega$ [Clearing conditions] • Reset or transition to standby mode • Read FER when FER = 1, then write 0 in FER. [Setting condition] Framing error (stop bit is 0) Error signal status (for smart card interface) 0 [Clearing conditions] • Reset or transition to standby mode • Read ERS when ERS = 1, then write 0 in ERS. 1 **[Setting condition]** A low error signal is received. 1 Overrun error  $\Omega$ [Clearing conditions] • Reset or transition to standby mode Read ORER when ORER =  $1$ , then write 0 in ORER. 1 [Setting condition] Overrun error (reception of the next serial data ends when RDRF = 1) Receive data register full  $\Omega$ [Clearing conditions] • Reset or transition to standby mode • Read RDRF when RDRF = 1, then write 0 in RDRF. • The DMAC reads data from RDR. **ISetting condition]** Serial data is received normally and transferred from RSR to RDR. Transmit data register empty  $\Omega$ [Clearing conditions] • Read TDRE when TDRE = 1, then write 0 in TDRE. • The DMAC writes data in TDR. [Setting conditions] • Reset or transition to standby mode • TE is 0 in SCR. • Data is transferred from TDR to TSR, enabling new data to be written in TDR 1 1 Transmit end (for smart card interface)  $\Omega$ [Clearing conditions] Read TDRE when TDRE = 1, then write 0 in TDRE. • The DMAC writes data in TDR. [Setting conditions] • Reset or transition to standby mode • TE is cleared to 0 in SCR and FER/ERS is cleared to 0. • TDRE is 1 and FER/ERS is 0 (normal transmission) 2.5 etu\* (when GM = 0) or 1.0 etu (when GM = 1) after 1-byte serial character is transmitted. 1 Note: \* etu: Elementary time unit (time required to transmit one bit)

**SSR**⎯**Serial Status Register H'FFFB4 SCI0** 

Note: \* Only 0 can be written, to clear the flag.





1 Receive data is stored MSB-first in RDR





Note: Bit functions are the same as for SCI0.



Note: Bit functions are the same as for SCI0.



Note: Bit functions are the same as for SCI0.



Notes: Bit functions are the same as for SCI0.

\* Only 0 can be written, to clear the flag.



Note: Bit functions are the same as for SCI0.



Note: Bit functions are the same as for SCI0.



Note: Bit functions are the same as for SCI0.





\* Only 0 can be written, to clear the flag.



#### Appendix B Internal I/O Registers



0 R/W Data for port 4 pins Initial value Read/Write

P6DR—Port 6 Data Register **H'FFFD5** Port 6 \* R 7 P67 0 R/W 6 P66 0 R/W 5 P65 0 R/W 4 P64 0 R/W 3 P63 0 R/W 2 P62 0 R/W 1 P61 0 R/W 0 P60 Data for port 6 pins Bit Initial value Read/Write

0 R/W

Note:  $*$  Determined by pin  $P6<sub>7</sub>$ .



Data for port A pins









#### **ADCSR**⎯**A/D Control/Status Register H'FFFE8 A/D**



 $\Omega$  $R/(W)*$ 7 ADF  $\Omega$ R/W 6 ADIE 0 R/W 5 ADST 0 R/W 4 **SCAN** 0 R/W 3 **CKS** 0 R/W  $\mathfrak{p}$ CH2  $\Omega$ R/W 1 CH1  $\Omega$ R/W  $\Omega$ CH0 Channel select Group Selection Channel Selection  $\overline{0}$ 1 0 1 AN0 AN1 AN2 AN3 AN4 AN5 AN6 AN7 0 CH2 1  $\Omega$ 1  $\Omega$ 1 0 1 0 1 Description CH1 CH0 Single Mode Scan Mode Clock select  $\Omega$ 1 Conversion time = 134 states (maximum) Conversion time = 70 states (maximum) AN0 AN0, AN1 AN0 to AN2 AN0 to AN3 AN4 AN4, AN5 AN4 to AN6 AN4 to AN7 Scan mode  $\overline{0}$ 1 Single mode Scan mode A/D start 0 A/D conversion is stopped 1 1. Single mode: A/D conversion starts; ADST is automatically cleared to 0 when conversion ends 2. Scan mode: A/D conversion starts and continues, cycling among the selected channels ADST is cleared to 0 by software, by a reset, or by a transition to standby mode A/D interrupt enable 0 1 A/D end interrupt request is disabled A/D end interrupt request is enabled A/D end flag  $\overline{0}$  [Clearing conditions] • Read ADF when ADF = 1, then write 0 in ADF • The DMAC is activated by an ADI interrupt [Setting conditions] • Single mode: A/D conversion ends Scan mode: A/D conversion ends in all selected channels 1 Bit Initial value Read/Write

Note: \* Only 0 can be written, to clear the flag.

# Appendix C I/O Port Block Diagrams

## **C.1 Port 4 Block Diagram**





## **C.2 Port 6 Block Diagrams**



**Figure C.2** (a) Port 6 Block Diagram (Pin P6<sub>0</sub>)



**Figure C.2 (b) Port 6 Block Diagram (Pin P6<sup>1</sup> )** 



**Figure C.2 (c) Port 6 Block Diagram (Pin P6<sup>2</sup> )** 





**Figure C.2 (d) Port 6 Block Diagram (Pin P6<sup>7</sup> )** 

## **C.3 Port 7 Block Diagrams**



**Figure C.3** (a) Port 7 Block Diagram (Pins P7<sub>0</sub> to P7<sub>5</sub>)





**Figure C.3** (b) Port 7 Block Diagram (Pins P7<sub>6</sub> and P7<sub>7</sub>)



## **C.4 Port 8 Block Diagrams**



**Figure C.4** (a) Port 8 Block Diagram (Pin P8<sub>0</sub>)



**Figure C.4** (b) Port 8 Block Diagram (Pins P8<sub>1</sub>, P8<sub>2</sub>)


**Figure C.4 (c) Port 8 Block Diagram (Pin P8<sup>3</sup> )** 



**Figure C.4 (d) Port 8 Block Diagram (Pin P8<sup>4</sup> )** 

#### **C.5 Port 9 Block Diagrams**



**Figure C.5 (a) Port 9 Block Diagram (Pin P9<sub>0</sub>)** 



**Figure C.5 (b) Port 9 Block Diagram (Pin P9<sup>1</sup> )** 



**Figure C.5** (c) Port 9 Block Diagram (Pin P9<sub>2</sub>)



**Figure C.5 (d) Port 9 Block Diagram (Pin P9<sup>3</sup> )** 



**Figure C.5 (e) Port 9 Block Diagram (Pin P9<sup>4</sup> )** 



**Figure C.5 (f) Port 9 Block Diagram (Pin P9<sup>5</sup> )** 

#### **C.6 Port A Block Diagrams**



**Figure C.6 (a) Port A Block Diagram (Pins**  $PA_0$ **,**  $PA_1$ **)** 



**Figure C.6 (b) Port A Block Diagram (Pins PA<sub>2</sub>, PA<sub>3</sub>)** 



**Figure C.6 (c) Port A Block Diagram (Pins PA<sub>4</sub> to PA<sub>7</sub>)** 

#### **C.7 Port B Block Diagrams**



**Figure C.7** (a) Port B Block Diagram (Pins PB<sub>0</sub>, PB<sub>2</sub>)



**Figure C.7** (b) Port B Block Diagram (Pins PB<sub>1</sub>, PB<sub>3</sub>)



**Figure C.7 (c) Port B Block Diagram (Pin PB<sup>4</sup> )** 



**Figure C.7 (d) Port B Block Diagram (Pin PB<sup>5</sup> )** 



**Figure C.7 (e) Port B Block Diagram (Pin PB<sup>6</sup> )** 



**Figure C.7 (f) Port B Block Diagram (Pin PB<sup>7</sup> )** 

# Appendix D Pin States

### **D.1 Port States in Each Mode**

#### **Table D.1 Port States in Each Processing State**











Legend:

H: High

 $\mathsf{L} \cdot \mathsf{L}$  and  $\mathsf{L} \cdot \mathsf{L}$ 

T: High-impedance state

Keep: Input pins are in the high-impedance state; output pins maintain their previous state.

DDR: Data direction register

Notes: 1. Low only when WDT overflow causes a reset.

- 2. When bits DRAS2, DRAS1, and DRAS0 in DRCRA (DRAM control register A) are all cleared to 0.
- 3. When any of bits DRAS2, DRAS1, or DRAS0 in DRCRA (DRAM control register A) is set to 1.
- 4. When the setting of bits DRAS2, DRAS1, and DRAS0 in DRCRA (DRAM control register A) is 010, 100, or 101.
- 5. When the setting of bits DRAS2, DRAS1, and DRAS0 in DRCRA (DRAM control register A) is other than 010, 100, or 101.
- 6. When bit A23E, A22E, or A21E, respectively, in BRCR (bus release control register) is cleared to 0.
- 7 When bit A23E, A22E, or A21E, respectively, in BRCR (bus release control register) is set to 1.
- 8. When bit CS7E or CS6E, respectively, in CSCR (chip select control register) is set to 1.
- 9. When bit CS7E or CS6E, respectively, in CSCR (chip select control register) is cleared to 0.
- 10. When the setting of bits DRAS2, DRAS1, and DRAS0 in DRCRA (DRAM control register A) is 101.
- 11. When the setting of bits DRAS2, DRAS1, and DRAS0 in DRCRA (DRAM control register A) is other than 101, and bit CS5E in CSCR (chip select control register) is set to 1.
- 12. When the setting of bits DRAS2, DRAS1, and DRAS0 in DRCRA (DRAM control register A) is other than 101, and bit CS5E in CSCR (chip select control register) is cleared to 0.

- 13. When the setting of bits DRAS2, DRAS1, and DRAS0 in DRCRA (DRAM control register A) is 100, 101, or 110.
- 14. When the setting of bits DRAS2, DRAS1, and DRAS0 in DRCRA (DRAM control register A) is other than 100, 101, or 110, and bit CS4E in CSCR (chip select control register) is set to 1.
- 15. When the setting of bits DRAS2, DRAS1, and DRAS0 in DRCRA (DRAM control register A) is other than 100, 101, or 110, and bit CS4E in CSCR (chip select control register) is cleared to 0.
- 16. When any of bits DRAS2, DRAS1, or DRAS0 in DRCRA (DRAM control register A) is set to 1, and bit CSEL in DRCRB (DRAM control register B) is cleared to 0.
- 17. When any of bits DRAS2, DRAS1, or DRAS0 in DRCRA (DRAM control register A) is set to 1, and bit CSEL in DRCRB (DRAM control register B) is set to 1; or, when bits DRAS2, DRAS1, and DRAS0 are cleared to 0.

#### **D.2 Pin States at Reset**

**Modes 1 and 2:** Figure D.1 is a timing diagram for the case in which RES goes low during an external memory access in mode 1 or 2. As soon as  $\overline{\text{RES}}$  goes low, all ports are initialized to the input state.  $\overline{AS}$ ,  $\overline{RD}$ ,  $\overline{HWR}$ ,  $\overline{LWR}$ , and  $\overline{CS}$ <sub>0</sub> go high, and  $D_{15}$  to  $D_{0}$  go to the high-impedance state. The address bus is initialized to the low output level 2.5  $\phi$  clock cycles after the low level of  $\overline{\text{RES}}$ is sampled. Clock pin  $P6/\phi$  goes to the output state at the next rise of  $\phi$  after  $\overline{RES}$  goes low.



**Figure D.1 Reset during Memory Access (Modes 1 and 2)** 

**Modes 3 and 4:** Figure D.2 is a timing diagram for the case in which  $\overline{\text{RES}}$  goes low during an external memory access in mode 3 or 4. As soon as RES goes low, all ports are initialized to the input state.  $\overline{AS}$ ,  $\overline{RD}$ ,  $\overline{HWR}$ ,  $\overline{LWR}$ , and  $\overline{CS}$ <sub>0</sub> go high, and  $D_{15}$  to  $D_0$  go to the high-impedance state. The address bus is initialized to the low output level 2.5  $\phi$  clock cycles after the low level of  $\overline{\text{RES}}$ is sampled. However, when  $PA_4$  to  $PA_6$  are used as address bus pins, or when  $PB_3$  to  $PB_1$  and  $PB_0$  to  $PB_3$  are used as CS output pins, they go to the high-impedance state at the same time as  $\overline{RES}$  goes low. Clock pin P6, $\phi$  goes to the output state at the next rise of  $\phi$  after  $\overline{\text{RES}}$  goes low.



**Figure D.2 Reset during Memory Access (Modes 3 and 4)** 

# Appendix E Timing of Transition to and Recovery from Hardware Standby Mode

#### **Timing of Transition to Hardware Standby Mode**

(1) To retain RAM contents with the RAME bit set to 1 in SYSCR, drive the RES signal low 10 system clock cycles before the  $\overline{STBY}$  signal goes low, as shown below. RES must r⊕emain low until  $\overline{\text{STBY}}$  goes low (minimum delay from  $\overline{\text{STBY}}$  low to  $\overline{\text{RES}}$  high: 0 ns).



(2) To retain RAM contents with the RAME bit cleared to 0 in SYSCR, or when RAM contents do not need to be retained,  $\overline{RES}$  does not have to be driven low as in (1).

**Timing of Recovery from Hardware Standby Mode:** Drive the **RES** signal low approximately 100 ns before  $\overline{\text{STBY}}$  goes high.



# Appendix F List of Product Codes



#### **Table F.1 H8/3007, H8/3006 Product Code Lineup**

# Appendix G Package Dimensions

The package dimention that is shown in the Renesas Semiconductor Package Data Book has priority.



**Figure G.1 Package Dimensions (FP-100B)** 



**Figure G.2 Package Dimensions (TFP-100B)** 

Appendix G Package Dimensions



**Figure G.3 Package Dimensions (FP-100A)** 

# Appendix H Comparison of H8/300H Series Product Specifications

#### **H.1 Differences between H8/3067 and H8/3062 Group, H8/3048 Group, H8/3006 and H8/3007, and H8/3002**





#### Appendix H Comparison of H8/300H Series Product Specifications



#### **H.2 Comparison of Pin Functions of 100-Pin Package Products (FP-100B, TFP-100B)**

#### **Table H.1 Pin Arrangement of Each Product (FP-100B, TFP-100B)**



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#### Appendix H Comparison of H8/300H Series Product Specifications




Note: \* Functions as  $\overline{\text{RESO}}$  in the mask ROM versions, and as FWE in the flash memory and flash memory R versions.

# RENESAS



# **Renesas 16-Bit Single-Chip Microcomputer Hardware Manual H8/3006, H8/3007**



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